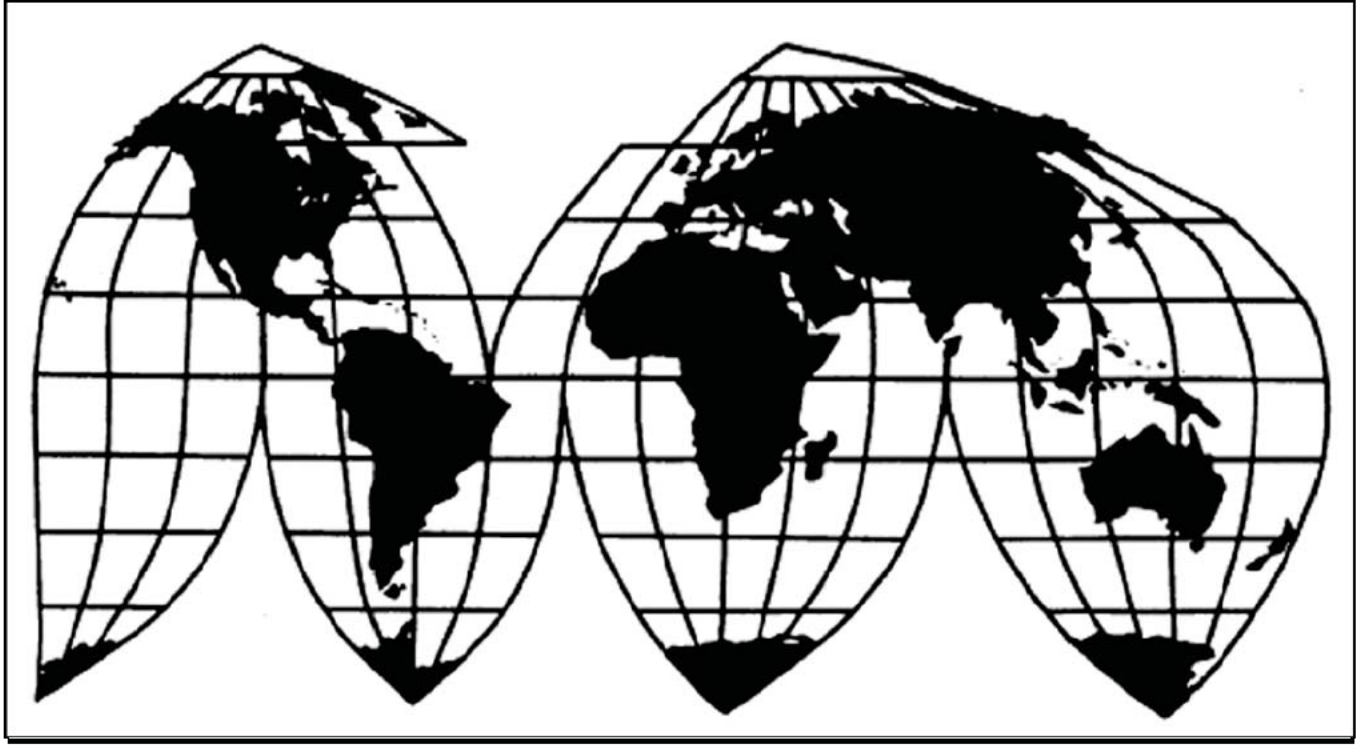
In the Matter of

Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same

Investigation No. 337-TA-605
Volume 2 of 2

Publication 4282 **November 2011**

U.S. International Trade Commission



Washington, DC 20436

U.S. International Trade Commission

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U.S. International Trade Commission

Washington, DC 20436
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APPENDIX A

FINAL EXHIBIT LISTS

UNITED STATES INTERNATIONAL TRADE COMMISSION
WASHINGTON, D.C. 20436

Before The Honorable Theodore R. Essex
Administrative Law Judge

In the Matter of CERTAIN SEMICONDUCTOR CHIPS WITH MINIMIZED CHIP PACKAGE SIZE AND PRODUCTS CONTAINING SAME	Investigation No. 337-TA-605

COMPLAINANT AND JOINT EXHIBITS – ALL EXHIBITS (CORRECTED)

Dated: August 5 2008

Respectfully submitted,

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Counsel for Complainant Tessera, Inc.

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	1					Withdrawn
CDX	2					Withdrawn
CDX	3					Withdrawn
CDX	4					Withdrawn
CDX	5					Withdrawn
CDX	6					Withdrawn
CDX	7					Withdrawn
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CDX	35					Withdrawn
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CDX	37					Withdrawn
CDX	38					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	39					Withdrawn
CDX	40					Withdrawn
CDX	41					Withdrawn
CDX	42					Withdrawn
CDX	43					Withdrawn
CDX	44					Withdrawn
CDX	45					Withdrawn
CDX	46					Withdrawn
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CDX	67					Withdrawn
CDX	68					Withdrawn
CDX	69					Withdrawn
CDX	70					Withdrawn
CDX	71					Withdrawn
CDX	72					Withdrawn
CDX	73					Withdrawn
CDX	74					Withdrawn
CDX	75	C	Dr. Qu Report Figure IV.1 – Example of Chip Package	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	76	C	Dr. Qu Report Figure III.5 – Solder Joints In a Package Assembly Are Subjected to Both Normal and Shear Strains Due To Differential Thermal Expansion And Warpage Caused By Differential Thermal Expansion	Qu	INFRNG/NON-INFRNG	Admitted
CDX	77	C	Dr. Qu Report Figure IV.2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	78	C	Qu Deposition Exhibit #269, Updated Figures and Tables from January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted
CDX	79	C	Dr. Qu Report Figure IXB.1 – An Example of Finite Element Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CDX	80	C	Expert Report of Dr. Qu, Exhibit 4 - Values of Constants Used in Finite Element Analysis	Qu	INFRNG/NON-INFRNG	Admitted
CDX	81	C	Dr. Qu Report Figure XII.61 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	83	C	Expert Report of Dr. Qu, Exhibit 3 - Individual Results for Five Samples	Qu	INFRNG/NON-INFRNG	Admitted
CDX	84	C	Dr. Qu Report Figure XA.5 – Points of interest on the moiré cut for ST-TFBGA-84 (a) is an overall view of the package cross section, (b) is a close-up of the cross-section, and (c) indicates where the package was cut	Qu	INFRNG/NON-INFRNG	Admitted
CDX	084					Withdrawn
CDX	85	C	Dr. Qu Report Figure IXA.3 – Schematic View of Diffraction Grating Replication Process	Qu	INFRNG/NON-INFRNG	Admitted
CDX	86	C	Dr. Qu Report Figure IXA.4 – Sample Module in Grating Replication Fixture	Qu	INFRNG/NON-INFRNG	Admitted
CDX	87	C	Dr. Qu Report Figure IXA.9 – Time History of the Temperature Profile Applied at the Aluminum Base Plate	Qu	INFRNG/NON-INFRNG	Admitted
CDX	88	C	Dr. Qu Report Figure IXA.7 – Cross-Section of the Specimen and the Peltier Device Setup on the Optical Table	Qu	INFRNG/NON-INFRNG	Admitted
CDX	89					Withdrawn
CDX	90	C	Dr. Qu Report Figure XB.7 – Geometric Dimensions and Material Properties for STM-TFBGA-84	Qu	INFRNG/NON-INFRNG	Admitted
CDX	91					Withdrawn
CDX	92	C	Dr. Qu Report Figure XII.48 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	93					Withdrawn
CDX	94	C	Dr. Qu Report Figure XII.50 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	95					Withdrawn
CDX	96	C	Dr. Qu Report Figure XII.52 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	97					Withdrawn
CDX	98	C	Dr. Qu Report Figure XII.54 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	99					Withdrawn
CDX	100	C	Dr. Qu Report Figure XII.56 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	101					Withdrawn
CDX	102	C	Dr. Qu Report Figure XII.58 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	103					Withdrawn
CDX	104	C	Dr. Qu Report Figure XII.60 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	105	C	Dr. Qu Report Figure XII.4 – Relative movement between points A and C in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	106					Withdrawn
CDX	107					Withdrawn
CDX	108	C	Dr. Qu Report Figure XII.42 – Relative movement between points A and C in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	109					Withdrawn
CDX	110	C	Dr. Qu Report Figure XII.44 – Relative movement between points A and C in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	111					Withdrawn
CDX	112	C	Dr. Qu Report Figure XII.46 – Relative movement between points A and C in STM-S-Moiré	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	113	C	Dr. Qu Report Figure XII.47 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	114					Withdrawn
CDX	115	C	Dr. Qu Report Figure XII.49 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	116	C	Dr. Qu Report Figure XII.5 – Relative movement between points A and C in ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	117					Withdrawn
CDX	118	C	Dr. Qu Report Figure XII.51 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	119					Withdrawn
CDX	120	C	Dr. Qu Report Figure XII.53 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	121					Withdrawn
CDX	122	C	Dr. Qu Report Figure XII.55 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	123					Withdrawn
CDX	124	C	Dr. Qu Report Figure XII.57 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	125					Withdrawn
CDX	126	C	Dr. Qu Report Figure XII.59 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	127	C	Dr. Qu Report Figure XII.6 – Relative movement between points A and C in ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	128	C	Dr. Qu Report Figure XII.7 – Relative movement between points A and C in ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	129	C	Dr. Qu Report Figure XII.8 – Relative movement between points A and C in ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	130	C	Dr. Qu Report Figure XII.9 – Relative movement between points A and C in ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	131	C	Dr. Qu Report Figure XII.10 – Relative movement between points A and C in FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	132	C	Dr. Qu Report Figure XII.11 – Relative movement between points A and C in FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	133	C	Dr. Qu Report Figure XII.12 – Relative movement between points A and C in FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	134	C	Dr. Qu Report Figure XII.13 – Relative movement between points A and C in FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	135					Withdrawn
CDX	136	C	Dr. Qu Report Figure XII.16 – Relative movement between points A and C in FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	137	C	Dr. Qu Report Figure XII.17 – Relative movement between points A and C in FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	138	C	Dr. Qu Report Figure XII.18 – Relative movement between points A and C in QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	139	C	Dr. Qu Report Figure XII.19 – Relative movement between points A and C in QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	140	C	Dr. Qu Report Figure XII.20 – Relative movement between points A and C in QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	141	C	Dr. Qu Report Figure XII.21 – Relative movement between points A and C in QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	142	C	Dr. Qu Report Figure XII.22 – Relative movement between points A and C in QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	143	C	Dr. Qu Report Figure XII.23 – Relative movement between points A and C in QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	144	C	Dr. Qu Report Figure XII.24 – Relative movement between points A and C in QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	145	C	Dr. Qu Report Figure XII.25 – Relative movement between points A and C in QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	146	C	Dr. Qu Report Figure XII.26 –Relative movement between points A and C in QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	147	C	Dr. Qu Report Figure XII.27 – Relative movement between points A and C in SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	148	C	Dr. Qu Report Figure XII.28 – Relative movement between points A and C in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	149	C	Dr. Qu Report Figure XII.29 – Relative movement between points A and C in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	150	C	Dr. Qu Report Figure XII.30 – Relative movement between points A and C in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	151	C	Dr. Qu Report Figure XII.31 – Relative movement between points A and C in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	152	C	Dr. Qu Report Figure XII.32 – Relative movement between points A and C in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	153	C	Dr. Qu Report Figure XII.33 – Relative movement between points A and C in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	154	C	Dr. Qu Report Figure XII.34 – Relative movement between points A and C in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	155	C	Dr. Qu Report Figure XII.35 – Relative movement between points A and C in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	156	C	Dr. Qu Report Figure XII.36 – Relative movement between points A and C in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	157	C	Dr. Qu Report Figure XII.37 – Relative movement between points A and C in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	158	C	Dr. Qu Report Figure XII.38 – Relative movement between points A and C in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	159	C	Dr. Qu Report Figure XII.39 – Relative movement between points A and C in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	160	C	Dr. Qu Report Figure XII.4 – Relative movement between points A and C in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	161	C	Dr. Qu Report Figure XII.40 – Relative movement between points A and C in STM-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	162	C	Dr. Qu Report Figure XII.41 – Relative movement between points A and C in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	163					Withdrawn
CDX	164	C	Dr. Qu Report Figure XII.43 – Relative movement between points A and C in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	165					Withdrawn
CDX	166	C	Dr. Qu Report Figure XII.45 – Relative movement between points A and C in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	167					Withdrawn
CDX	168	C	Dr. Qu Report Figure XII.2 – Illustration of Local Coordinate System in 2 Dimensions	Qu	INFRNG/NON-INFRNG	Admitted
CDX	169	C	Dr. Qu Report Figure XII.86 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	170	C	Dr. Qu Report Figure XII.87 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	171	C	Dr. Qu Report Figure XII.88 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	172	C	Dr. Qu Report Figure XII.89 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	173	C	Dr. Qu Report Figure XII.90 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	174	C	Dr. Qu Report Figure XII.91 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	175	C	Dr. Qu Report Figure XII.92 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	176	C	Dr. Qu Report Figure XII.93 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	177	C	Dr. Qu Report Figure XII.94 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	178	C	Dr. Qu Report Figure XII.95 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	179	C	Dr. Qu Report Figure XII.96 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	180	C	Dr. Qu Report Figure XII.97 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	181	C	Dr. Qu Report Figure XII.98 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	182	C	Dr. Qu Report Figure XII.99 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	183	C	Dr. Qu Report Figure XII.100 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	184	C	Dr. Qu Report Figure XII.101 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	185	C	Dr. Qu Report Figure XII.102 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	186	C	Dr. Qu Report Figure XII.103 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	187	C	Dr. Qu Report Figure XII.104 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	188	C	Dr. Qu Report Figure XII.105 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	189	C	Dr. Qu Report Figure XII.106 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	190	C	Dr. Qu Report Figure XII.107 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	191	C	Dr. Qu Report Figure XII.108 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	192	C	Dr. Qu Report Figure XII.109 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	193	C	Dr. Qu Report Figure XII.110 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	194	C	Dr. Qu Report Figure XII.111 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	195	C	Dr. Qu Report Figure XII.111 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	196	C	Dr. Qu Report Figure XII.112 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	197	C	Dr. Qu Report Figure XII.113 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	198	C	Dr. Qu Report Figure XII.114 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	199	C	Dr. Qu Report Figure XII.115 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	200	C	Dr. Qu Report Figure XII.116 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	201	C	Dr. Qu Report Figure XII.117 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	202	C	Dr. Qu Report Figure XII.118 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	203	C	Dr. Qu Report Figure XII.119 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	204	C	Dr. Qu Report Figure XII.120 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	205	C	Dr. Qu Report Figure XII.121 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	206	C	Dr. Qu Report Figure XII.122 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	207	C	Dr. Qu Report Figure XII.123 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	208	C	Dr. Qu Report Figure XII.124 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	209	C	Dr. Qu Report Figure XII.125 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	210	C	Dr. Qu Report Figure XII.126 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	211	C	Dr. Qu Report Figure XII.127 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	212	C	Dr. Qu Report Figure XII.128 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	213	C	Dr. Qu Report Figure XII.129 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CDX	214	C	Dr. Qu Report Figure XII.130 – Accumulated Plastic Work for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	215	C	Dr. Qu Report Figure XII.131 – Accumulated Plastic Work for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	216	C	Dr. Qu Report Figure XII.132 – Accumulated Plastic Work for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	217	C	Dr. Qu Report Figure XII.133 – Accumulated Plastic Work for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	218	C	Dr. Qu Report Figure XII.134 – Accumulated Plastic Work for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	219	C	Dr. Qu Report Figure XII.135 – Accumulated Plastic Work for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	220	C	Dr. Qu Report Figure XII.136 – Accumulated Plastic Work for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	221	C	Dr. Qu Report Figure XII.137 – Accumulated Plastic Work for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	222	C	Dr. Qu Report Figure XII.138 – Accumulated Plastic Work for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	223	C	Dr. Qu Report Figure XII.139 – Accumulated Plastic Work for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	224	C	Dr. Qu Report Figure XII.14 – Relative movement between points A and C in FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	225	C	Dr. Qu Report Figure XII.140 – Accumulated Plastic Work for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	226	C	Dr. Qu Report Figure XII.141 – Accumulated Plastic Work for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	227	C	Dr. Qu Report Figure XII.142 – Accumulated Plastic Work for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	228	C	Dr. Qu Report Figure XII.143 – Accumulated Plastic Work for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	229	C	Dr. Qu Report Figure XII.144 – Accumulated Plastic Work for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	230	C	Dr. Qu Report Figure XII.145 – Accumulated Plastic Work for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	231	C	Dr. Qu Report Figure XII.146 – Accumulated Plastic Work for QUA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	232	C	Dr. Qu Report Figure XII.147 – Accumulated Plastic Work for QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	233	C	Dr. Qu Report Figure XII.148 – Accumulated Plastic Work for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	234	C	Dr. Qu Report Figure XII.149 – Accumulated Plastic Work for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	235	C	Dr. Qu Report Figure XII.15 – Relative movement between points A and C in FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	236	C	Dr. Qu Report Figure XII.150 – Accumulated Plastic Work for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	237	C	Dr. Qu Report Figure XII.151 – Accumulated Plastic Work for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	238	C	Dr. Qu Report Figure XII.152 – Accumulated Plastic Work for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	239	C	Dr. Qu Report Figure XII.153 – Accumulated Plastic Work for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	240	C	Dr. Qu Report Figure XII.154 – Accumulated Plastic Work for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	241	C	Dr. Qu Report Figure XII.155 – Accumulated Plastic Work for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	242	C	Dr. Qu Report Figure XII.156 – Accumulated Plastic Work for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	243	C	Dr. Qu Report Figure XII.157 – Accumulated Plastic Work for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	244	C	Dr. Qu Report Figure XII.158 – Accumulated Plastic Work for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	245	C	Dr. Qu Report Figure XII.159 – Accumulated Plastic Work for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	246					Withdrawn
CDX	247	C	Dr. Qu Report Figure XII.160 – Accumulated Plastic Work for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	248	C	Dr. Qu Report Figure XII.161 – Accumulated Plastic Work for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	249	C	Dr. Qu Report Figure XII.162 – Accumulated Plastic Work for SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	250	C	Dr. Qu Report Figure XII.163 – Accumulated Plastic Work for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	251	C	Dr. Qu Report Figure XII.164 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	252	C	Dr. Qu Report Figure XII.165 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	253	C	Dr. Qu Report Figure XII.166 – Accumulated Plastic Work for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	254	C	Dr. Qu Report Figure XII.167 – Accumulated Plastic Work for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	255	C	Dr. Qu Report Figure XII.168 – Accumulated Plastic Work for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	256	C	Dr. Qu Report Figure XII.169 – Accumulated Plastic Work for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	257					Withdrawn
CDX	258	C	Dr. Qu Report Figure XII.170 – Accumulated Plastic Work for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	259	C	Dr. Qu Report Figure XII.171 – Accumulated Plastic Work for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	260	C	Dr. Qu Report Figure XII.172 – Accumulated Plastic Work for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	261	C	Dr. Qu Report Figure XII.173 – Accumulated Plastic Work for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CDX	262					Withdrawn
CDX	263	C	Dr. Qu Report Figure XIII.1 – Displacement vector of the solder due to both internal and external loads	Qu	INFRNG/NON-INFRNG	Admitted
CDX	264 - 285					Withdrawn
CDX	286	C	Dr. Qu Report Figure III.2 – Linear Stress-Strain Relationship	Qu	INFRNG/NON-INFRNG	Admitted
CDX	287	C	Dr. Qu Report Figure XIII.4 – Accumulated Plastic Work due to External Forces for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	288	C	Dr. Qu Report Figure XIII.5 – Accumulated Plastic Work due to External Forces for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	289	C	Dr. Qu Report Figure XIII.6 – Accumulated Plastic Work due to External Forces for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	290	C	Dr. Qu Report Figure XIII.7 – Accumulated Plastic Work due to External Forces for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	291	C	Dr. Qu Report Figure XIII.8 – Accumulated Plastic Work due to External Forces for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	292	C	Dr. Qu Report Figure XIII.9 – Accumulated Plastic Work due to External Forces for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	293					Withdrawn
CDX	294	C	Dr. Qu Report Figure XIII.11 – Accumulated Plastic Work due to External Forces for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	295					Withdrawn
CDX	296	C	Dr. Qu Report Figure XIII.13 – Accumulated Plastic Work due to External Forces for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	297					Withdrawn
CDX	298	C	Dr. Qu Report Figure XIII.15 – Accumulated Plastic Work due to External Forces for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	299					Withdrawn
CDX	300	C	Dr. Qu Report Figure XIII.17 – Accumulated Plastic Work due to External Forces for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	301					Withdrawn
CDX	302	C	Dr. Qu Report Figure XIII.19 – Accumulated Plastic Work due to External Forces for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	303					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	304	C	Dr. Qu Report Figure XIII.20 – Accumulated Plastic Work due to External Forces for QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	305					Withdrawn
CDX	306	C	Dr. Qu Report Figure XIII.22 – Accumulated Plastic Work due to External Forces for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	307					Withdrawn
CDX	308	C	Dr. Qu Report Figure XIII.24 – Accumulated Plastic Work due to External Forces for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	309					Withdrawn
CDX	310	C	Dr. Qu Report Figure XIII.26 – Accumulated Plastic Work due to External Forces for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	311					Withdrawn
CDX	312	C	Dr. Qu Report Figure XIII.28 – Accumulated Plastic Work due to External Forces for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	313					Withdrawn
CDX	314	C	Dr. Qu Report Figure XIII.3 – Applying the displacement vector uex(x, T) to the off-board package is equivalent to applying external loads to the package	Qu	INFRNG/NON-INFRNG	Admitted
CDX	315	C	Dr. Qu Report Figure XIII.30 – Accumulated Plastic Work due to External Forces for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	316	C	Dr. Qu Report Figure XIII.31 – Accumulated Plastic Work due to External Forces for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	317	C	Dr. Qu Report Figure XIII.32 – Accumulated Plastic Work due to External Forces for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	318	C	Dr. Qu Report Figure XIII.33 – Accumulated Plastic Work due to External Forces for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	319	C	Dr. Qu Report Figure XIII.34 – Accumulated Plastic Work due to External Forces for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	320	C	Dr. Qu Report Figure XIII.35 – Accumulated Plastic Work due to External Forces for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	321	C	Dr. Qu Report Figure XIII.36 – Accumulated Plastic Work due to External Forces for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	322	C	Dr. Qu Report Figure XIII.37 – Accumulated Plastic Work due to External Forces for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	323	C	Dr. Qu Report Figure XIII.38 – Accumulated Plastic Work due to External Forces for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	324	C	Dr. Qu Report Figure XIII.39 – Accumulated Plastic Work due to External Forces for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	325					Withdrawn
CDX	326	C	Dr. Qu Report Figure XIII.40 – Accumulated Plastic Work due to External Forces for STM-M-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	327					Withdrawn
CDX	328	C	Dr. Qu Report Figure XIII.41 – Accumulated Plastic Work due to External Forces for STM-M-HCS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	329	C	Dr. Qu Report Figure XIII.42 – Accumulated Plastic Work due to External Forces for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	330	C	Dr. Qu Report Figure XIII.43 – Accumulated Plastic Work due to External Forces for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	331	C	Dr. Qu Report Figure XIII.44 – Accumulated Plastic Work due to External Forces for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	332	C	Dr. Qu Report Figure XIII.45 – Accumulated Plastic Work due to External Forces for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	333	C	Dr. Qu Report Figure XIII.46 – Accumulated Plastic Work due to External Forces for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	334	C	Dr. Qu Report Figure XIII.47 – Accumulated Plastic Work due to External Forces for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CDX	335	C	Dr. Qu Report Figure XIV.45 – Compression due to external forces in ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	336	C	Dr. Qu Report Figure XIV.46 – Compression due to external forces in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	337	C	Dr. Qu Report Figure XIV.47 – Compression due to external forces in ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	338	C	Dr. Qu Report Figure XIV.48 – Compression due to external forces in ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	339	C	Dr. Qu Report Figure XIV.49 – Compression due to external forces in ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	340	C	Dr. Qu Report Figure XIV.5 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	341	C	Dr. Qu Report Figure XIV.50 – Compression due to external forces in ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	342	C	Dr. Qu Report Figure XIV.51 – Compression due to external forces in ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	343	C	Dr. Qu Report Figure XIV.52 – Compression due to external forces in FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	344	C	Dr. Qu Report Figure XIV.53 – Compression due to external forces in FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	345	C	Dr. Qu Report Figure XIV.54 – Compression due to external forces in FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	346	C	Dr. Qu Report Figure XIV.55 – Compression due to external forces in FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	347	C	Dr. Qu Report Figure XIV.56 – Compression due to external forces in FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	348	C	Dr. Qu Report Figure XIV.57 – Compression due to external forces in FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	349	C	Dr. Qu Report Figure XIV.58 – Compression due to external forces in FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	350	C	Dr. Qu Report Figure XIV.59 – Compression due to external forces in FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	351	C	Dr. Qu Report Figure XIV.6 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	352	C	Dr. Qu Report Figure XIV.60 – Compression due to external forces in QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	353	C	Dr. Qu Report Figure XIV.61 – Compression due to external forces in QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	354	C	Dr. Qu Report Figure XIV.62 – Compression due to external forces in QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	355	C	Dr. Qu Report Figure XIV.63 – Compression due to external forces in QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	356	C	Dr. Qu Report Figure XIV.64 – Compression due to external forces in QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	357	C	Dr. Qu Report Figure XIV.65 – Compression due to external forces in QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	358	C	Dr. Qu Report Figure XIV.66 – Compression due to external forces in QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	359	C	Dr. Qu Report Figure XIV.67 – Compression due to external forces in QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	360	C	Dr. Qu Report Figure XIV.68 – Compression due to external forces in QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	361	C	Dr. Qu Report Figure XIV.69 – Compression due to external forces in SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	362	C	Dr. Qu Report Figure XIV.7 – Deformation of the compliant layer from 125C to -25C for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	363	C	Dr. Qu Report Figure XIV.70 – Compression due to external forces in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	364	C	Dr. Qu Report Figure XIV.71 – Compression due to external forces in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	365	C	Dr. Qu Report Figure XIV.72 – Compression due to external forces in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	366	C	Dr. Qu Report Figure XIV.73 – Compression due to external forces in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	367	C	Dr. Qu Report Figure XIV.74 – Compression due to external forces in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	368	C	Dr. Qu Report Figure XIV.75 – Compression due to external forces in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	369	C	Dr. Qu Report Figure XIV.76 – Compression due to external forces in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	370	C	Dr. Qu Report Figure XIV.77– Compression due to external forces in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	371	C	Dr. Qu Report Figure XIV.78 – Compression due to external forces in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	372	C	Dr. Qu Report Figure XIV.79 – Compression due to external forces in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	373	C	Dr. Qu Report Figure XIV.8 – Deformation of the compliant layer from 125C to -25C for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	374	C	Dr. Qu Report Figure XIV.80 – Compression due to external forces in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	375	C	Dr. Qu Report Figure XIV.81 – Compression due to external forces in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	376	C	Dr. Qu Report Figure XIV.82 – Compression due to external forces in STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	377	C	Dr. Qu Report Figure XIV.83 – Compression due to external forces in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	378	C	Dr. Qu Report Figure XIV.84 – Compression due to external forces in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	379	C	Dr. Qu Report Figure XIV.85 – Compression due to external forces in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	380	C	Dr. Qu Report Figure XIV.86 – Compression due to external forces in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	381	C	Dr. Qu Report Figure XIV.87 – Compression due to external forces in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	382	C	Qu Deposition Exhibit #260, Errata Sheet for January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	383	C	Dr. Qu Report Figure IXB.6 – Assembled Packages with Two-Fold Symmetry	Qu	INFRNG/NON-INFRNG	Admitted
CDX	384					Withdrawn
CDX	385					Withdrawn
CDX	386 - 389					Withdrawn
CDX	390					Withdrawn
CDX	391					Withdrawn
CDX	392					Withdrawn
CDX	393					Withdrawn
CDX	394					Withdrawn
CDX	395 - 399					Withdrawn
CDX	400		Freyman Article, Figure 1	Ivey	VLD/INVLD	Admitted
CDX	401		Dual In-Line Package	Ivey	VLD/INVLD	Admitted
CDX	402		Pin Grid Array	Ivey	VLD/INVLD	Admitted
CDX	403		Bending Caused by Differential Thermal Expansion	Ivey	VLD/INVLD	Admitted
CDX	404		Modulus and CTE	Ivey	VLD/INVLD	Admitted
CDX	405		Differential Thermal Expansion in a BGA	Ivey	VLD/INVLD	Admitted
CDX	406		Glass Transition Temperature and Modulus of Elasticity	Ivey	VLD/INVLD	Admitted
CDX	407		CTE and Modulus	Ivey	VLD/INVLD	Admitted
CDX	408		Compliant Die Attach References	Ivey	VLD/INVLD	Admitted
CDX	409		First Level Problems in a BGA	Ivey	VLD/INVLD	Admitted
CDX	410		Ceramic Substrate	Ivey	VLD/INVLD	Admitted
CDX	411		Die Attach	Ivey	VLD/INVLD	Admitted
CDX	412		Saito Reference	Ivey	VLD/INVLD	Admitted
CDX	413		326 Patent, Figure 26	Ivey	VLD/INVLD	Admitted
CDX	414		Tessera's Licensees	Ivey	VLD/INVLD	Admitted
CDX	415		Solder Columns	Ivey	VLD/INVLD	Admitted
CDX	416		Quad Flat Pack and Leadless Chip Carrier	Ivey	VLD/INVLD	Admitted
CDX	417 - 424					Withdrawn
CDX	425					Withdrawn
CDX	426					Withdrawn
CDX	427					Withdrawn
CDX	428					Withdrawn
CDX	429					Withdrawn
CDX	430					Withdrawn
CDX	431					Withdrawn
CDX	432					Withdrawn
CDX	433					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	434					Withdrawn
CDX	435					Withdrawn
CDX	436					Withdrawn
CDX	437					Withdrawn
CDX	438					Withdrawn
CDX	439					Withdrawn
CDX	440					Withdrawn
CDX	441					Withdrawn
CDX	442					Withdrawn
CDX	443					Withdrawn
CDX	444					Withdrawn
CDX	445					Withdrawn
CDX	446					Withdrawn
CDX	447					Withdrawn
CDX	448					Withdrawn
CDX	449					Withdrawn
CDX	450					Withdrawn
CDX	451					Withdrawn
CDX	452					Withdrawn
CDX	453 - 459					Withdrawn
CDX	460					Withdrawn
CDX	461					Withdrawn
CDX	462					Withdrawn
CDX	463					Withdrawn
CDX	464					Withdrawn
CDX	465					Withdrawn
CDX	466					Withdrawn
CDX	467					Withdrawn
CDX	468					Withdrawn
CDX	469					Withdrawn
CDX	470					Withdrawn
CDX	471					Withdrawn
CDX	472					Withdrawn
CDX	473					Withdrawn
CDX	474					Withdrawn
CDX	475					Withdrawn
CDX	476					Withdrawn
CDX	477					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	478					Withdrawn
CDX	479					Withdrawn
CDX	480					Withdrawn
CDX	481					Withdrawn
CDX	482					Withdrawn
CDX	483					Withdrawn
CDX	484					Withdrawn
CDX	485					Withdrawn
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CDX	507					Withdrawn
CDX	508					Withdrawn
CDX	509					Withdrawn
CDX	510					Withdrawn
CDX	511					Withdrawn
CDX	512					Withdrawn
CDX	513					Withdrawn
CDX	514					Withdrawn
CDX	515					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	516					Withdrawn
CDX	517					Withdrawn
CDX	518					Withdrawn
CDX	519					Withdrawn
CDX	520					Withdrawn
CDX	521					Withdrawn
CDX	522					Withdrawn
CDX	523					Withdrawn
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CDX	541					Withdrawn
CDX	542					Withdrawn
CDX	543					Withdrawn
CDX	544					Withdrawn
CDX	545					Withdrawn
CDX	546					Withdrawn
CDX	547					Withdrawn
CDX	548					Withdrawn
CDX	549					Withdrawn
CDX	550					Withdrawn
CDX	551					Withdrawn
CDX	552					Withdrawn
CDX	553					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	554					Withdrawn
CDX	555					Withdrawn
CDX	556					Withdrawn
CDX	557					Withdrawn
CDX	558					Withdrawn
CDX	559					Withdrawn
CDX	560					Withdrawn
CDX	561					Withdrawn
CDX	562					Withdrawn
CDX	563					Withdrawn
CDX	564					Withdrawn
CDX	565					Withdrawn
CDX	566					Withdrawn
CDX	567					Withdrawn
CDX	568					Withdrawn
CDX	569	C	Table of Packages	Qu	INFRNG/NON-INFRNG	Admitted
CDX	570	C	Geometric Dimensions of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	571	C	Geometric Dimensions of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	572	C	Geometric Dimension of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	573	C	Geometric Dimension of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	574	C	Geometric Dimension of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	575	C	Geometric Dimension of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	576	C	Geometric Dimension of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	577	C	Geometric Dimension of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	578	C	CrossSection of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	579	C	CrossSection of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	580	C	CrossSection of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	581	C	CrossSection of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	582	C	CrossSection of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	583	C	CrossSection of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	584	C	CrossSection of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	585	C	CrossSection of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	586	C	Mesh for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	587	C	Mesh for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	588	C	Mesh for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	589	C	Mesh for STM-MC-TFBGA-103-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	590	C	Mesh for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	591	C	Mesh for STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	592	C	Mesh for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	593	C	Mesh for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	594	C	Material Property FEA Inputs	Qu	INFRNG/NON-INFRNG	Admitted
CDX	595	C	Column Displacement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	596	C	Column Displacement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	597	C	Column Displacement STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	598	C	Column Displacement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	599	C	Column Displacement STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	600	C	Column Displacement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	601	C	Column Displacement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	602	C	Column Displacement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	603	C	AC Movement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	604	C	AC Movement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	605	C	AC Movement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	606	C	AC Movement STM-SC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	607	C	AC Movement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	608	C	AC Movement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	609	C	AC Movement STM-SC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	610	C	AC Movement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	611	C	Plastic Work STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	612	C	Plastic Work STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	613	C	Plastic Work STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	614	C	Plastic Work STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	615	C	Plastic Work STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	616	C	Plastic Work STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	617	C	Plastic Work STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	618	C	Plastic Work STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	619	C	Percentage Life Improvement Table Method 1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	620	C	Percentage Life Improvement Graph For New ST Products	Qu	INFRNG/NON-INFRNG	Admitted
CDX	621	C	Percentage Life Improvement Graph Comparison	Qu	INFRNG/NON-INFRNG	Admitted
CDX	622	C	Symmetry Results Plot	Qu	INFRNG/NON-INFRNG	Admitted
CDX	623	C	Copper Layer Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CDX	624	C	Copper Layer Comparison Table	Qu	INFRNG/NON-INFRNG	Admitted
CDX	625	C	Polar Plot STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	626	C	Polar Plot STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	627	C	Polar Plot STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	628	C	Polar Plot STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	629	C	Polar Plot STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	630	C	Polar Plot STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	631	C	Polar Plot STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	632	C	Polar Plot STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	633	C	Plastic Work External STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	634	C	Plastic Work External STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	635	C	Plastic Work External STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	636	C	Plastic Work External STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	637	C	Plastic Work External STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	638	C	Plastic Work External STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	639	C	Plastic Work External STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	640	C	Plastic Work External STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	641	C	Percentage Life Improvement Table Method 2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	642	C	Compression for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	643	C	Compression for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	644	C	Compression for STM-SC-TBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	645	C	Compression for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	646	C	Compression for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	647	C	Compression for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	648	C	Compression for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	649	C	Compression for STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CPX	1	C	01.11.2008 Dr. Qu Back-Up Data 1 (including fre_mc_pbga_289_2; qua_mc_nsp_432; spa_mc_fbga_188_2; spa_mc_lrbga_080; spa_sc_lrbga_080; spa_sc_vfbga_044_2; and stm_sc_lbga_288)	Qu	INFRNG/NON-INFRNG	Admitted
CPX	2	C	01.11.2008 Dr. Qu Back-Up Data - 2 (including ati_mc_stfbga_259; fre_sc_pbga_244_1; fre_sc_pbga_244_2; qua_mc_msp_351a; qua_sc_csp_064_2; spa_mc_fbga_188_1; spa_sc_fbga_048; and spa_sc_vfbga_044_1)	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	3	C	01.11.2008 Dr. Qu Back-Up Data - 3 (including ati_mc_stfbga_259_moire; ati_sc_tfbga_104; ati_sc_tfbga_179_2; fre_sc_pbga_121; fre_sc_pbga_240; qua_sc_csp_060; qua_sc_csp_064; spa_mc_lrgba_064; spa_sc_frbga_064_moire; stm_mc_tfbga_088; stm_mc_tfbga_105; st	Qu	INFRNG/NON-INFRNG	Admitted
CPX	4	C	01.11.2008 Dr. Qu Back-Up Data - 4 (including ati_mc_stfbga_259_2; ati_sc_tfbga_179; fre_ms_pbga_289_1; fre_sc_pbga_280; moire_stm_sc_tfbga_084; qua_sc_csp_097; spa_mc_fbga_188_3; stm_mc_tfbga_044_1; stm_mc_tfbga_105_4cyc; stm_mc_tfbga_105_coarse; stm_mc	Qu	INFRNG/NON-INFRNG	Admitted
CPX	5	C	01.11.2008 Dr. Qu Back-Up Data - 5 (including ati_mc_lfbga_272; ati_sc_tfbga_104_2; ati_sc_tfbga_179_full; fre_sc_pbga_244_3; moire_qua_mc_csp_216; qua_mc_csp_216a; qua_mc_csp_216b; qua_mc_msp_351b; and stm_sc_tfbga_244)	Qu	INFRNG/NON-INFRNG	Admitted
CPX	6	C	01.25.2008 Dr. Qu Back-Up Data (including ati_mc_stfbga_257; qua_sc_csp_060_die_thk_177; supp_fre_sc_pbga_144; and supp_fre_sc_pbga_196)	Qu	INFRNG/NON-INFRNG	Admitted
CPX	7					Withdrawn
CPX	8					Withdrawn
CPX	9					Withdrawn
CPX	10					Withdrawn
CPX	11					Withdrawn
CPX	12					Withdrawn
CPX	13					Withdrawn
CPX	14					Withdrawn
CPX	15		Ceramic Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	16		FR-4 Prepreg 110 um Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	17		FR-4 CORE Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	18		FR-4 with Cu Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	19		BT Laminate .15 mm Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	20		BT Laminate 100um Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	21		BT Laminate 400um Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	22		Polyimide Substrate Sample	Griffin	RMDY, OWNR	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	23		Laminate Substrate Product: Intel 4050LOYBQ2, Motorola SLVR cellular phone	Griffin	RMDY, OWNR	Admitted
CPX	24		Laminate Substrate Product: Toshiba	Griffin	RMDY, OWNR	Admitted
CPX	25	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	26	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	27					Withdrawn
CPX	28	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	29	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	30	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	31	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	32	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	33	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	34	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	35	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	36	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	37	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	38	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	39	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	40	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	41(a)	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	41(b)	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	41(c)	C	Bottoms Up Database	Mitchell	Domestic Industry	Admitted
CPX	41(d)	C	Tessera Royalty Databases ("Bottom-Up"), 2003-2005	Mitchell	RMDY, DI	Admitted
CPX	42	C	Khandros Laboratory Notebook **NOTE: This is exhibit is being held by Complainant per agreement among the parties**	DiStefano	OWNR	Admitted
CPX	43					Withdrawn
CPX	44					Withdrawn
CPX	45					Withdrawn
CPX	46					Withdrawn
CPX	47					Withdrawn
CPX	48					Withdrawn
CPX	49					Withdrawn
CPX	50					Withdrawn
CPX	51					Withdrawn
CPX	52					Withdrawn
CPX	53					Withdrawn
CPX	54					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	55					Withdrawn
CPX	56					Withdrawn
CPX	57					Withdrawn
CPX	58					Withdrawn
CPX	59					Withdrawn
CPX	60					Withdrawn
CPX	61					Withdrawn
CPX	62					Withdrawn
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CPX	69					Withdrawn
CPX	70					Withdrawn
CPX	71					Withdrawn
CPX	72					Withdrawn
CPX	73					Withdrawn
CPX	74					Withdrawn
CPX	75					Withdrawn
CPX	76					Withdrawn
CPX	77					Withdrawn
CPX	78					Withdrawn
CPX	79					Withdrawn
CPX	80					Withdrawn
CPX	81	C	Mawer Deposition Exhibit #022, Freescale Bill of Materials (This is the physical version of JX-083C)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
CPX	82	C	Chopin Deposition Exhibit #003, Freescale Bill of Materials (This is the physical version of JX-084C)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
CPX	83	C	Mawer Deposition Exhibit #024, Freescale Bill of Materials (This is the physical version of JX-085C)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	84	C	Mawer Deposition Exhibit #10	Qu, Sitaraman, Mawer, Chopin, Kellar	Infrng/Non-infrng	Admitted
CPX	85	C	Older style chip packages **NOTE: This is exhibit is being held by Complainant per agreement among the parties**	DiStefano	OWNR	Admitted
CX	1					Withdrawn
CX	2	C	Second Amendment to TCC License Agreement (Tessera & Walton Advanced Electronic, Ltd.)	Pickett	RMDY, OWNR	Admitted
CX	3					Withdrawn
CX	4	C	TCC License Agreement (Tessera & Toshiba Corp.)	Pickett	RMDY, OWNR	Admitted
CX	5					Withdrawn
CX	6					Withdrawn
CX	7					Withdrawn
CX	8	C	Limited TCC License Agreement (Tessera & Amkor Electronics, Inc.)	Griffin	RMDY, OWNR	Admitted
CX	9					Withdrawn
CX	10					Withdrawn
CX	11					Withdrawn
CX	12					Withdrawn
CX	13					Withdrawn
CX	14					Withdrawn
CX	15					Withdrawn
CX	16					Withdrawn
CX	17					Withdrawn
CX	18					Withdrawn
CX	19	C	License Agreement in conjunction with settlement of pending litigation (Tessera & Sharp Corp.)	Pickett	RMDY, OWNR	Admitted
CX	20	C	License Agreement in conjunction with settlement of pending litigation (Tessera & Texas Instruments, Inc.)	Pickett	RMDY, OWNR	Admitted
CX	21					Withdrawn
CX	22					Withdrawn
CX	23					Withdrawn
CX	24					Withdrawn
CX	25					Withdrawn
CX	26					Withdrawn
CX	27	C	Restated TCC License Agreement (Tessera & Samsung Electronics, Co.)	Pickett	RMDY, OWNR	Admitted
CX	28					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	29					Withdrawn
CX	30					Withdrawn
CX	31					Withdrawn
CX	32					Withdrawn
CX	33					Withdrawn
CX	34					Withdrawn
CX	35					Withdrawn
CX	36					Withdrawn
CX	37	C	Third Amendment to Limited TCC License Agreement between Tessera, Inc. and Intel Corporation	Pickett	RMDY, OWNR	Admitted
CX	38					Withdrawn
CX	39					Withdrawn
CX	40	C	Amendment to Immunity Agreement between Tessera, Inc. and Sharp Corporation	Pickett	RMDY, OWNR	Admitted
CX	41					Withdrawn
CX	42	C	Second Addendum to the Master License Agreement between Tessera, Inc. and Sony Corporation	Pickett	RMDY, OWNR	Admitted
CX	43					Withdrawn
CX	44	C	TCC Patent License Amendment Between Rohm Co., Ltd. and Tessera, Inc.	Pickett	RMDY, OWNR	Admitted
CX	45	C	First Amendment to TCC License Agreement between Tessera, Inc. and EEMS Italia, SpA	Pickett	RMDY, OWNR	Admitted
CX	46					Withdrawn
CX	47	C	Letter Amendment to TCC Master License Agreement, between Hitachi Ltd. and Tessera, Inc.	Pickett	RMDY, OWNR	Admitted
CX	48					Withdrawn
CX	49	C	TCC License Agreement between Tessera and Shinko Electric Industries	Pickett	RMDY, OWNR	Admitted
CX	50					Withdrawn
CX	51					Withdrawn
CX	52					Withdrawn
CX	53					Withdrawn
CX	54					Withdrawn
CX	55					Withdrawn
CX	56					Withdrawn
CX	57					Withdrawn
CX	58	C	01.11.08 Expert Report of Dr. Qu	Qu	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	59	C	Expert Report of Dr. Qu, Exhibit 1 - CV of Jianmin Qu		INFRNG/NON-INFRNG	Admitted
CX	60	C	Expert Report of Dr. Qu, Exhibit 2 - Documents Considered by Dr. Qu		INFRNG/NON-INFRNG	Admitted
CX	61	C	Expert Report of Dr. Qu, Exhibit 3 - Individual Results for Five Samples	Qu	INFRNG/NON-INFRNG	Admitted
CX	62	C	Expert Report of Dr. Qu, Exhibit 4 - Values of Constants Used in Finite Element Analysis	Qu	INFRNG/NON-INFRNG	Admitted
CX	63					Withdrawn
CX	64(1)					Withdrawn
CX	64(2)					Withdrawn
CX	65					Withdrawn
CX	66					Withdrawn
CX	67					Withdrawn
CX	68					Withdrawn
CX	69					Withdrawn
CX	70					Withdrawn
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CX	90					Withdrawn
CX	91					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	92					Withdrawn
CX	93					Withdrawn
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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	130					Withdrawn
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CX	167					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	168					Withdrawn
CX	169					Withdrawn
CX	170					Withdrawn
CX	171					Withdrawn
CX	172					Withdrawn
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CX	205					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	206					Withdrawn
CX	207					Withdrawn
CX	208					Withdrawn
CX	209					Withdrawn
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CX	243					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	244					Withdrawn
CX	245					Withdrawn
CX	246					Withdrawn
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CX	281					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	282		Lin '278 Patent	Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	283					Withdrawn
CX	284					Withdrawn
CX	285					Withdrawn
CX	286					Withdrawn
CX	287					Withdrawn
CX	288	C	Dr. Qu Report Figure III.2 – Linear Stress-Strain Relationship	Qu	INFRNG/NON-INFRNG	Admitted
CX	289					Withdrawn
CX	290					Withdrawn
CX	291					Withdrawn
CX	292	C	Dr. Qu Report Figure III.5 – Solder Joints In a Package Assembly Are Subjected to Both Normal and Shear Strains Due To Differential Thermal Expansion And Warpage Caused By Differential Thermal Expansion	Qu	INFRNG/NON-INFRNG	Admitted
CX	293					Withdrawn
CX	294					Withdrawn
CX	295	C	Dr. Qu Report Figure IV.1 – Example of Chip Package	Qu	INFRNG/NON-INFRNG	Admitted
CX	296	C	Dr. Qu Report Figure IV.2	Qu	INFRNG/NON-INFRNG	Admitted
CX	297					Withdrawn
CX	298					Withdrawn
CX	299					Withdrawn
CX	300					Withdrawn
CX	301					Withdrawn
CX	302					Withdrawn
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CX	304					Withdrawn
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CX	311					Withdrawn
CX	312					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	313					Withdrawn
CX	314					Withdrawn
CX	315					Withdrawn
CX	316	C	Dr. Qu Report Figure IXA.3 – Schematic View of Diffraction Grating Replication Process	Qu	INFRNG/NON-INFRNG	Admitted
CX	317	C	Dr. Qu Report Figure IXA.4 – Sample Module in Grating Replication Fixture	Qu	INFRNG/NON-INFRNG	Admitted
CX	318					Withdrawn
CX	319					Withdrawn
CX	320	C	Dr. Qu Report Figure IXA.7 – Cross-Section of the Specimen and the Peltier Device Setup on the Optical Table	Qu	INFRNG/NON-INFRNG	Admitted
CX	321					Withdrawn
CX	322	C	Dr. Qu Report Figure IXA.9 – Time History of the Temperature Profile Applied at the Aluminum Base Plate	Qu	INFRNG/NON-INFRNG	Admitted
CX	323	C	Dr. Qu Report Figure IXB.1 – An Example of Finite Element Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CX	324					Withdrawn
CX	325					Withdrawn
CX	326					Withdrawn
CX	327					Withdrawn
CX	328					Withdrawn
CX	329	C	Dr. Qu Report Figure IXB.6 – Assembled Packages with Two-Fold Symmetry	Qu	INFRNG/NON-INFRNG	Admitted
CX	330					Withdrawn
CX	331					Withdrawn
CX	332					Withdrawn
CX	333					Withdrawn
CX	334					Withdrawn
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CX	343					Withdrawn

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CX	344					Withdrawn
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CX	356					Withdrawn
CX	357	C	Dr. Qu Report Figure VIIIE.5 – Picture of solder joint failure study performed by AMD at SPAN-ITC 035311	Qu	INFRNG/NON-INFRNG	Admitted
CX	358					Withdrawn
CX	359					Withdrawn
CX	360					Withdrawn
CX	361					Withdrawn
CX	362	C	Dr. Qu Report Figure XA.5 – Points of interest on the moiré cut for ST-TFBGA-84 (a) is an overall view of the package cross section, (b) is a close-up of the cross-section, and (c) indicates where the package was cut	Qu	INFRNG/NON-INFRNG	Admitted
CX	363					Withdrawn
CX	364					Withdrawn
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CX	366					Withdrawn
CX	367					Withdrawn
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CX	378					Withdrawn
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CX	383					Withdrawn
CX	384					Withdrawn
CX	385	C	Dr. Qu Report Figure XB.7 – Geometric Dimensions and Material Properties for STM-TFBGA-84	Qu	INFRNG/NON-INFRNG	Admitted
CX	386					Withdrawn
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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	415					Withdrawn
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CX	472					Withdrawn
CX	473					Withdrawn
CX	474					Withdrawn
CX	475					Withdrawn
CX	476	C	Dr. Qu Report Figure XII.10 – Relative movement between points A and C in FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	477	C	Dr. Qu Report Figure XII.100 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	478	C	Dr. Qu Report Figure XII.101 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	479	C	Dr. Qu Report Figure XII.102 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	480	C	Dr. Qu Report Figure XII.103 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-B	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	481	C	Dr. Qu Report Figure XII.104 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	482	C	Dr. Qu Report Figure XII.105 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	483	C	Dr. Qu Report Figure XII.106 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	484	C	Dr. Qu Report Figure XII.107 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	485	C	Dr. Qu Report Figure XII.108 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	486	C	Dr. Qu Report Figure XII.109 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	487	C	Dr. Qu Report Figure XII.11 - Relative movement between points A and C in FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	488	C	Dr. Qu Report Figure XII.110 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	489	C	Dr. Qu Report Figure XII.111 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	490	C	Dr. Qu Report Figure XII.112 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	491	C	Dr. Qu Report Figure XII.113 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	492	C	Dr. Qu Report Figure XII.114 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	493	C	Dr. Qu Report Figure XII.115 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	494	C	Dr. Qu Report Figure XII.116 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	495	C	Dr. Qu Report Figure XII.117 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	496	C	Dr. Qu Report Figure XII.118 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CX	497	C	Dr. Qu Report Figure XII.119 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	498	C	Dr. Qu Report Figure XII.12 – Relative movement between points A and C in FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	499	C	Dr. Qu Report Figure XII.120 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	500	C	Dr. Qu Report Figure XII.121 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	501	C	Dr. Qu Report Figure XII.122 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	502	C	Dr. Qu Report Figure XII.123 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	503	C	Dr. Qu Report Figure XII.124 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	504	C	Dr. Qu Report Figure XII.125 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	505	C	Dr. Qu Report Figure XII.126 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	506	C	Dr. Qu Report Figure XII.127 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	507	C	Dr. Qu Report Figure XII.128 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	508	C	Dr. Qu Report Figure XII.129 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CX	509	C	Dr. Qu Report Figure XII.13 – Relative movement between points A and C in FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	510	C	Dr. Qu Report Figure XII.130 – Accumulated Plastic Work for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	511	C	Dr. Qu Report Figure XII.131 – Accumulated Plastic Work for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	512	C	Dr. Qu Report Figure XII.132 – Accumulated Plastic Work for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	513	C	Dr. Qu Report Figure XII.133 – Accumulated Plastic Work for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	514	C	Dr. Qu Report Figure XII.134 – Accumulated Plastic Work for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	515	C	Dr. Qu Report Figure XII.135 – Accumulated Plastic Work for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	516	C	Dr. Qu Report Figure XII.136 – Accumulated Plastic Work for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	517	C	Dr. Qu Report Figure XII.137 – Accumulated Plastic Work for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	518	C	Dr. Qu Report Figure XII.138 – Accumulated Plastic Work for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	519	C	Dr. Qu Report Figure XII.139 – Accumulated Plastic Work for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	520	C	Dr. Qu Report Figure XII.14 – Relative movement between points A and C in FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	521	C	Dr. Qu Report Figure XII.140 – Accumulated Plastic Work for FRE-S-SCB-I	Qu	INFRNG/NON-INFRNG	Admitted
CX	522	C	Dr. Qu Report Figure XII.141 – Accumulated Plastic Work for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	523	C	Dr. Qu Report Figure XII.142 – Accumulated Plastic Work for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	524	C	Dr. Qu Report Figure XII.143 – Accumulated Plastic Work for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	525	C	Dr. Qu Report Figure XII.144 – Accumulated Plastic Work for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	526	C	Dr. Qu Report Figure XII.145 – Accumulated Plastic Work for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	527	C	Dr. Qu Report Figure XII.146 – Accumulated Plastic Work for QUA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	528	C	Dr. Qu Report Figure XII.147 – Accumulated Plastic Work for QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	529	C	Dr. Qu Report Figure XII.148 – Accumulated Plastic Work for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	530	C	Dr. Qu Report Figure XII.149 – Accumulated Plastic Work for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	531	C	Dr. Qu Report Figure XII.15 – Relative movement between points A and C in FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	532	C	Dr. Qu Report Figure XII.150 – Accumulated Plastic Work for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	533	C	Dr. Qu Report Figure XII.151 – Accumulated Plastic Work for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	534	C	Dr. Qu Report Figure XII.152 – Accumulated Plastic Work for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	535	C	Dr. Qu Report Figure XII.153 – Accumulated Plastic Work for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	536	C	Dr. Qu Report Figure XII.154 – Accumulated Plastic Work for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	537	C	Dr. Qu Report Figure XII.155 – Accumulated Plastic Work for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	538	C	Dr. Qu Report Figure XII.156 – Accumulated Plastic Work for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	539	C	Dr. Qu Report Figure XII.157 – Accumulated Plastic Work for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	540	C	Dr. Qu Report Figure XII.158 – Accumulated Plastic Work for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	541	C	Dr. Qu Report Figure XII.159 – Accumulated Plastic Work for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	542	C	Dr. Qu Report Figure XII.16 – Relative movement between points A and C in FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	543	C	Dr. Qu Report Figure XII.160 – Accumulated Plastic Work for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	544	C	Dr. Qu Report Figure XII.161 – Accumulated Plastic Work for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	545	C	Dr. Qu Report Figure XII.162 – Accumulated Plastic Work for SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	546	C	Dr. Qu Report Figure XII.163 – Accumulated Plastic Work for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	547	C	Dr. Qu Report Figure XII.164 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	548	C	Dr. Qu Report Figure XII.165 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	549	C	Dr. Qu Report Figure XII.166 – Accumulated Plastic Work for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	550	C	Dr. Qu Report Figure XII.167 – Accumulated Plastic Work for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	551	C	Dr. Qu Report Figure XII.168 – Accumulated Plastic Work for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	552	C	Dr. Qu Report Figure XII.169 – Accumulated Plastic Work for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	553	C	Dr. Qu Report Figure XII.17 – Relative movement between points A and C in FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	554	C	Dr. Qu Report Figure XII.170 – Accumulated Plastic Work for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	555	C	Dr. Qu Report Figure XII.171 – Accumulated Plastic Work for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	556	C	Dr. Qu Report Figure XII.172 – Accumulated Plastic Work for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	557	C	Dr. Qu Report Figure XII.173 – Accumulated Plastic Work for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CX	558	C	Dr. Qu Report Figure XII.174 – Shear Strain	Qu	INFRNG/NON-INFRNG	Admitted
CX	559	C	Dr. Qu Report Figure XII.18 – Relative movement between points A and C in QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	560	C	Dr. Qu Report Figure XII.19 – Relative movement between points A and C in QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	561	C	Dr. Qu Report Figure XII.2 – Illustration of Local Coordinate System in 2 Dimensions	Qu	INFRNG/NON-INFRNG	Admitted
CX	562	C	Dr. Qu Report Figure XII.20 – Relative movement between points A and C in QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	563	C	Dr. Qu Report Figure XII.21 – Relative movement between points A and C in QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	564	C	Dr. Qu Report Figure XII.22 – Relative movement between points A and C in QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	565	C	Dr. Qu Report Figure XII.23 – Relative movement between points A and C in QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	566	C	Dr. Qu Report Figure XII.24 – Relative movement between points A and C in QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	567	C	Dr. Qu Report Figure XII.25 – Relative movement between points A and C in QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	568	C	Dr. Qu Report Figure XII.26 – Relative movement between points A and C in QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	569	C	Dr. Qu Report Figure XII.27 – Relative movement between points A and C in SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	570	C	Dr. Qu Report Figure XII.28 – Relative movement between points A and C in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	571	C	Dr. Qu Report Figure XII.29 – Relative movement between points A and C in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	572	C	Dr. Qu Report Figure XII.3 – Relative movement between points A and C in ATI-M-S-1			Admitted
CX	573	C	Dr. Qu Report Figure XII.30 – Relative movement between points A and C in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	574	C	Dr. Qu Report Figure XII.31 – Relative movement between points A and C in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	575	C	Dr. Qu Report Figure XII.32 – Relative movement between points A and C in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	576	C	Dr. Qu Report Figure XII.33 – Relative movement between points A and C in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	577	C	Dr. Qu Report Figure XII.34 – Relative movement between points A and C in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	578	C	Dr. Qu Report Figure XII.35 – Relative movement between points A and C in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	579	C	Dr. Qu Report Figure XII.36 – Relative movement between points A and C in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	580	C	Dr. Qu Report Figure XII.37 – Relative movement between points A and C in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	581	C	Dr. Qu Report Figure XII.38 – Relative movement between points A and C in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	582	C	Dr. Qu Report Figure XII.39 – Relative movement between points A and C in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	583	C	Dr. Qu Report Figure XII.4 – Relative movement between points A and C in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	584	C	Dr. Qu Report Figure XII.40 – Relative movement between points A and C in STM-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	585	C	Dr. Qu Report Figure XII.41 – Relative movement between points A and C in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	586	C	Dr. Qu Report Figure XII.42 – Relative movement between points A and C in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	587	C	Dr. Qu Report Figure XII.43 – Relative movement between points A and C in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	588	C	Dr. Qu Report Figure XII.44 – Relative movement between points A and C in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	589	C	Dr. Qu Report Figure XII.45 – Relative movement between points A and C in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	590	C	Dr. Qu Report Figure XII.46 – Relative movement between points A and C in STM-S-Moiré	Qu	INFRNG/NON-INFRNG	Admitted
CX	591	C	Dr. Qu Report Figure XII.47 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	592	C	Dr. Qu Report Figure XII.48 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	593	C	Dr. Qu Report Figure XII.49 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	594	C	Dr. Qu Report Figure XII.5 – Relative movement between points A and C in ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	595	C	Dr. Qu Report Figure XII.50 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	596	C	Dr. Qu Report Figure XII.51 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	597	C	Dr. Qu Report Figure XII.52 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	598	C	Dr. Qu Report Figure XII.53 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	599	C	Dr. Qu Report Figure XII.54 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	600	C	Dr. Qu Report Figure XII.55 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	601					Withdrawn
CX	602					Withdrawn
CX	603					Withdrawn
CX	604					Withdrawn
CX	605					Withdrawn
CX	606					Withdrawn
CX	607					Withdrawn
CX	608					Withdrawn
CX	609					Withdrawn
CX	610					Withdrawn
CX	611					Withdrawn
CX	612					Withdrawn
CX	613					Withdrawn
CX	614					Withdrawn
CX	615					Withdrawn
CX	616	C	Dr. Qu Report Figure X11.7 - Relative movement between points A and C in ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	617					Withdrawn
CX	618					Withdrawn
CX	619					Withdrawn
CX	620					Withdrawn
CX	621					Withdrawn
CX	622					Withdrawn
CX	623					Withdrawn
CX	624					Withdrawn
CX	625					Withdrawn
CX	626					Withdrawn
CX	627	C	Dr. Qu Report Figure XII.8 – Relative movement between points A and C in ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	628					Withdrawn
CX	629					Withdrawn
CX	630					Withdrawn
CX	631					Withdrawn
CX	632					Withdrawn
CX	633					Withdrawn
CX	634	C	Dr. Qu Report Figure XII.86 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-I	Qu	INFRNG/NON-INFRNG	Admitted
CX	635	C	Dr. Qu Report Figure XII.87 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	636	C	Dr. Qu Report Figure XII.88 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	637	C	Dr. Qu Report Figure XII.89 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	638	C	Dr. Qu Report Figure XII.9 – Relative movement between points A and C in ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	639	C	Dr. Qu Report Figure XII.90 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	640	C	Dr. Qu Report Figure XII.91 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	641	C	Dr. Qu Report Figure XII.92 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	642	C	Dr. Qu Report Figure XII.93 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	643	C	Dr. Qu Report Figure XII.94 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	644	C	Dr. Qu Report Figure XII.95 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	645	C	Dr. Qu Report Figure XII.96 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	646	C	Dr. Qu Report Figure XII.97 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	647	C	Dr. Qu Report Figure XII.98 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	648	C	Dr. Qu Report Figure XII.99 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	649	C	Dr. Qu Report Figure XIII.1 – Displacement vector of the solder due to both internal and external loads	Qu	INFRNG/NON-INFRNG	Admitted
CX	650	C	Dr. Qu Report Figure XIII.10 – Accumulated Plastic Work due to External Forces for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	651	C	Dr. Qu Report Figure XIII.11 – Accumulated Plastic Work due to External Forces for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	652	C	Dr. Qu Report Figure XIII.12 – Accumulated Plastic Work due to External Forces for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	653	C	Dr. Qu Report Figure XIII.13 – Accumulated Plastic Work due to External Forces for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	654	C	Dr. Qu Report Figure XIII.14 – Accumulated Plastic Work due to External Forces for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	655	C	Dr. Qu Report Figure XIII.15 – Accumulated Plastic Work due to External Forces for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	656	C	Dr. Qu Report Figure XIII.16 – Accumulated Plastic Work due to External Forces for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	657	C	Dr. Qu Report Figure XIII.17 – Accumulated Plastic Work due to External Forces for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	658	C	Dr. Qu Report Figure XIII.18 – Accumulated Plastic Work due to External Forces for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	659	C	Dr. Qu Report Figure XIII.19 – Accumulated Plastic Work due to External Forces for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	660	C	Dr. Qu Report Figure XIII.2 – Displacement vector of the solder due to both internal loads	Qu	INFRNG/NON-INFRNG	Admitted
CX	661	C	Dr. Qu Report Figure XIII.20 – Accumulated Plastic Work due to External Forces for QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	662	C	Dr. Qu Report Figure XIII.21 – Accumulated Plastic Work due to External Forces for QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	663	C	Dr. Qu Report Figure XIII.22 – Accumulated Plastic Work due to External Forces for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	664	C	Dr. Qu Report Figure XIII.23 – Accumulated Plastic Work due to External Forces for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	665	C	Dr. Qu Report Figure XIII.24 – Accumulated Plastic Work due to External Forces for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	666	C	Dr. Qu Report Figure XIII.25 – Accumulated Plastic Work due to External Forces for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	667	C	Dr. Qu Report Figure XIII.26 – Accumulated Plastic Work due to External Forces for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	668	C	Dr. Qu Report Figure XIII.27 – Accumulated Plastic Work due to External Forces for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	669	C	Dr. Qu Report Figure XIII.28 – Accumulated Plastic Work due to External Forces for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	670	C	Dr. Qu Report Figure XIII.29 – Accumulated Plastic Work due to External Forces for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	671	C	Dr. Qu Report Figure XIII.3 – Applying the displacement vector uex(x, T) to the off-board package is equivalent to applying external loads to the package	Qu	INFRNG/NON-INFRNG	Admitted
CX	672	C	Dr. Qu Report Figure XIII.30 – Accumulated Plastic Work due to External Forces for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	673	C	Dr. Qu Report Figure XIII.31 – Accumulated Plastic Work due to External Forces for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	674	C	Dr. Qu Report Figure XIII.32 – Accumulated Plastic Work due to External Forces for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	675	C	Dr. Qu Report Figure XIII.33 – Accumulated Plastic Work due to External Forces for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	676	C	Dr. Qu Report Figure XIII.34 – Accumulated Plastic Work due to External Forces for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	677	C	Dr. Qu Report Figure XIII.35 – Accumulated Plastic Work due to External Forces for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	678	C	Dr. Qu Report Figure XIII.36 – Accumulated Plastic Work due to External Forces for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CX	679	C	Dr. Qu Report Figure XIII.37 – Accumulated Plastic Work due to External Forces for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	680	C	Dr. Qu Report Figure XIII.38 – Accumulated Plastic Work due to External Forces for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	681	C	Dr. Qu Report Figure XIII.39 – Accumulated Plastic Work due to External Forces for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	682	C	Dr. Qu Report Figure XIII.4 – Accumulated Plastic Work due to External Forces for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	683	C	Dr. Qu Report Figure XIII.40 – Accumulated Plastic Work due to External Forces for STM-M-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	684	C	Intentionally Left Blank	Qu	INFRNG/NON-INFRNG	Admitted
CX	685	C	Dr. Qu Report Figure XIII.41 – Accumulated Plastic Work due to External Forces for STM-M-HCS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	686	C	Dr. Qu Report Figure XIII.42 – Accumulated Plastic Work due to External Forces for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	687	C	Dr. Qu Report Figure XIII.43 – Accumulated Plastic Work due to External Forces for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	688	C	Dr. Qu Report Figure XIII.44 – Accumulated Plastic Work due to External Forces for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	689	C	Dr. Qu Report Figure XIII.45 – Accumulated Plastic Work due to External Forces for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	690	C	Dr. Qu Report Figure XIII.46 – Accumulated Plastic Work due to External Forces for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	691	C	Dr. Qu Report Figure XIII.47 – Accumulated Plastic Work due to External Forces for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CX	692	C	Dr. Qu Report Figure XIII.5 – Accumulated Plastic Work due to External Forces for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	693	C	Dr. Qu Report Figure XIII.6 – Accumulated Plastic Work due to External Forces for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	694	C	Dr. Qu Report Figure XIII.7 – Accumulated Plastic Work due to External Forces for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	695	C	Dr. Qu Report Figure XIII.8 – Accumulated Plastic Work due to External Forces for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	696	C	Dr. Qu Report Figure XIII.9 – Accumulated Plastic Work due to External Forces for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	697					Withdrawn
CX	698					Withdrawn
CX	699					Withdrawn
CX	700					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	701					Withdrawn
CX	702					Withdrawn
CX	703					Withdrawn
CX	704					Withdrawn
CX	705					Withdrawn
CX	706					Withdrawn
CX	707					Withdrawn
CX	708					Withdrawn
CX	709					Withdrawn
CX	710					Withdrawn
CX	711					Withdrawn
CX	712					Withdrawn
CX	713					Withdrawn
CX	714					Withdrawn
CX	715					Withdrawn
CX	716					Withdrawn
CX	717					Withdrawn
CX	718					Withdrawn
CX	719					Withdrawn
CX	720					Withdrawn
CX	721					Withdrawn
CX	722					Withdrawn
CX	723					Withdrawn
CX	724					Withdrawn
CX	725					Withdrawn
CX	726					Withdrawn
CX	727					Withdrawn
CX	728					Withdrawn
CX	729					Withdrawn
CX	730					Withdrawn
CX	731					Withdrawn
CX	732					Withdrawn
CX	733					Withdrawn
CX	734					Withdrawn
CX	735					Withdrawn
CX	736	C	Dr. Qu Report Figure XIV.45 – Compression due to external forces in ATI-M-S-1	QU	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	737	C	Dr. Qu Report Figure XIV.46 – Compression due to external forces in ATI-M-S-2	QU	INFRNG/NON-INFRNG	Admitted
CX	738	C	Dr. Qu Report Figure XIV.47 – Compression due to external forces in ATI-M-S-3	QU	INFRNG/NON-INFRNG	Admitted
CX	739	C	Dr. Qu Report Figure XIV.48 – Compression due to external forces in ATI-S-H-1	QU	INFRNG/NON-INFRNG	Admitted
CX	740	C	Dr. Qu Report Figure XIV.49 – Compression due to external forces in ATI-S-H-2	QU	INFRNG/NON-INFRNG	Admitted
CX	741	C	Dr. Qu Report Figure XIV.5 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-2	QU	INFRNG/NON-INFRNG	Admitted
CX	742	C	Dr. Qu Report Figure XIV.50 – Compression due to external forces in ATI-S-H-3	QU	INFRNG/NON-INFRNG	Admitted
CX	743	C	Dr. Qu Report Figure XIV.51 – Compression due to external forces in ATI-S-S	QU	INFRNG/NON-INFRNG	Admitted
CX	744	C	Dr. Qu Report Figure XIV.52 – Compression due to external forces in FRE-S-HCB	QU	INFRNG/NON-INFRNG	Admitted
CX	745	C	Dr. Qu Report Figure XIV.53 – Compression due to external forces in FRE-S-HFB	QU	INFRNG/NON-INFRNG	Admitted
CX	746	C	Dr. Qu Report Figure XIV.54 – Compression due to external forces in FRE-S-HFT	QU	INFRNG/NON-INFRNG	Admitted
CX	747	C	Dr. Qu Report Figure XIV.55 – Compression due to external forces in FRE-S-SCB-1	QU	INFRNG/NON-INFRNG	Admitted
CX	748	C	Dr. Qu Report Figure XIV.56 – Compression due to external forces in FRE-S-SCB-2	QU	INFRNG/NON-INFRNG	Admitted
CX	749	C	Dr. Qu Report Figure XIV.57 – Compression due to external forces in FRE-S-SFB-1	QU	INFRNG/NON-INFRNG	Admitted
CX	750	C	Dr. Qu Report Figure XIV.58 – Compression due to external forces in FRE-S-SFB-2	QU	INFRNG/NON-INFRNG	Admitted
CX	751	C	Dr. Qu Report Figure XIV.59 – Compression due to external forces in FRE-S-SFT	QU	INFRNG/NON-INFRNG	Admitted
CX	752	C	Dr. Qu Report Figure XIV.6 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-3	QU	INFRNG/NON-INFRNG	Admitted
CX	753	C	Dr. Qu Report Figure XIV.60 – Compression due to external forces in QUA-M-H-1	QU	INFRNG/NON-INFRNG	Admitted
CX	754	C	Dr. Qu Report Figure XIV.61 – Compression due to external forces in QUA-M-H-2-A	QU	INFRNG/NON-INFRNG	Admitted
CX	755	C	Dr. Qu Report Figure XIV.62 – Compression due to external forces in QUA-M-H-2-B	QU	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	756	C	Dr. Qu Report Figure XIV.63 – Compression due to external forces in QUA-M-SCB-A	QU	INFRNG/NON-INFRNG	Admitted
CX	757	C	Dr. Qu Report Figure XIV.64 – Compression due to external forces in QUA-M-SCB-B	QU	INFRNG/NON-INFRNG	Admitted
CX	758	C	Dr. Qu Report Figure XIV.65 – Compression due to external forces in QUA-S-HFB	QU	INFRNG/NON-INFRNG	Admitted
CX	759	C	Dr. Qu Report Figure XIV.66 – Compression due to external forces in QUA-S-HFT-1	QU	INFRNG/NON-INFRNG	Admitted
CX	760	C	Dr. Qu Report Figure XIV.67 – Compression due to external forces in QUA-S-HFT-2	QU	INFRNG/NON-INFRNG	Admitted
CX	761	C	Dr. Qu Report Figure XIV.68 – Compression due to external forces in QUA-S-SFT	QU	INFRNG/NON-INFRNG	Admitted
CX	762	C	Dr. Qu Report Figure XIV.69 – Compression due to external forces in SPA-M-H-1	QU	INFRNG/NON-INFRNG	Admitted
CX	763	C	Dr. Qu Report Figure XIV.7 – Deformation of the compliant layer from 125C to -25C for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	764	C	Dr. Qu Report Figure XIV.70 – Compression due to external forces in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	765	C	Dr. Qu Report Figure XIV.71 – Compression due to external forces in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	766	C	Dr. Qu Report Figure XIV.72 – Compression due to external forces in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	767	C	Dr. Qu Report Figure XIV.73 – Compression due to external forces in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	768	C	Dr. Qu Report Figure XIV.74 – Compression due to external forces in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	769	C	Dr. Qu Report Figure XIV.75 – Compression due to external forces in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	770	C	Dr. Qu Report Figure XIV.76 – Compression due to external forces in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	771	C	Dr. Qu Report Figure XIV.77– Compression due to external forces in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	772	C	Dr. Qu Report Figure XIV.78 – Compression due to external forces in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	773	C	Dr. Qu Report Figure XIV.79 – Compression due to external forces in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	774	C	Dr. Qu Report Figure XIV.8 – Deformation of the compliant layer from 125C to -25C for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	775	C	Dr. Qu Report Figure XIV.80 – Compression due to external forces in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	776	C	Dr. Qu Report Figure XIV.81 – Compression due to external forces in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	777	C	Dr. Qu Report Figure XIV.82 – Compression due to external forces in STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	778	C	Dr. Qu Report Figure XIV.83 – Compression due to external forces in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	779	C	Dr. Qu Report Figure XIV.84 – Compression due to external forces in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	780	C	Dr. Qu Report Figure XIV.85 – Compression due to external forces in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	781	C	Dr. Qu Report Figure XIV.86 – Compression due to external forces in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	782	C	Dr. Qu Report Figure XIV.87 – Compression due to external forces in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	783					Withdrawn
CX	784					Withdrawn
CX	785					Withdrawn
CX	786					Withdrawn
CX	787					Withdrawn
CX	788					Withdrawn
CX	789					Withdrawn
CX	790					Withdrawn
CX	791					Withdrawn
CX	792					Withdrawn
CX	793					Withdrawn
CX	794					Withdrawn
CX	795					Withdrawn
CX	796					Withdrawn
CX	797					Withdrawn
CX	798					Withdrawn
CX	799	C	Technical design document	Qu	Infrng/Non-infrng	Admitted
CX	800					Withdrawn
CX	801					Withdrawn
CX	802					Withdrawn
CX	803		http://www.freescale.com/webapp/sps/site/homepage.jsp?nodeId=06		Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	804		http://www.freescale.com/webapp/sps/site/overview.jsp?nodeID=060A60		Importation, Remedies	Admitted
CX	805					Withdrawn
CX	806					Withdrawn
CX	807					Withdrawn
CX	808	C	Motorola's Third Amended Responses to Tessera's First Set of Interrogatories with Appendices	Qu	Infrng/Non-infrng	Admitted
CX	809	C	ST-NV's First Amended Response to Tessera's First Set of Interrogatories with Appendices	Qu	Infrng/Non-infrng	Admitted
CX	810	C	ST-NV's Response to Tessera's Seventh Set of Interrogatories	Qu	Infrng/Non-infrng	Admitted
CX	811	C	Tessera's First Set of Interrogatories to ST-NV	Qu	Infrng/Non-infrng	Admitted
CX	812	C	Tessera's Objections and Responses to Qualcomm's First Set of Interrogatories	Schaper	VLD/INVLD	Admitted
CX	813	C	Bonding Diagrams	Qu	Infrng/Non-infrng	Admitted
CX	814					Withdrawn
CX	815	C	Qualcomm, "280 CSP Board Level Characterization Plan/Report", 09.11.2002	Qu	INFRNG/NON-INFRNG	Admitted
CX	816					Withdrawn
CX	817					Withdrawn
CX	818	C	AMD FBGA User's Guide, Version 2.3.1	Qu	INFRNG/NON-INFRNG	Admitted
CX	819	C	AMD Paper: "Characterization of a Novel Fine-pitch Ball Grid Array Package for Flash Memory Application" by Sidharth, et al.; Electronics Component and Technology Conference	Qu	INFRNG/NON-INFRNG	Admitted
CX	820	C	AMD Paper: "Reliability Evaluation of Chip Scale Packages" by Gannamani, et al.	Qu	INFRNG/NON-INFRNG	Admitted
CX	821	C	Wire Bond Diagrams	Qu	INFRNG/NON-INFRNG	Admitted
CX	822	C	AMD FBGA User's Guide, Ch. 4, Board Design and Layout Considerations	Qu	INFRNG/NON-INFRNG	Admitted
CX	823					Withdrawn
CX	824		"Design Analysis of TFBGA with Customized Solder Joint Fatigue Model," T. Lee, M. Lim etc.	Qu	Infrng/Non-infrng	Admitted
CX	825					Withdrawn
CX	826					Withdrawn
CX	827					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	828					Withdrawn
CX	829					Withdrawn
CX	830	C	Qualcomm's Responses to Tessera's Interrogatory No. 6 with Appendices	Stipulation	Infrng/Non-infrng	Admitted
CX	831	C	Qualcomm's Supplemental Response to Tessera's Interrogatory No. 6 with Appendices	Stipulation	Infrng/Non-infrng	Admitted
CX	832					Withdrawn
CX	833	C	Amkor Drawings related to Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	834	C	Amkor Drawings related to Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	835	C	AT Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	836	C	ATI Diagram related to W2240G	Qu	Infrng/Non-infrng	Admitted
CX	837	C	ATI Diagram related to W2240G	Qu	Infrng/Non-infrng	Admitted
CX	838	C	ATI Diagrams for Customer Device Name: W2240G(B11)	Qu	Infrng/Non-infrng	Admitted
CX	839	C	ATI Drawings for Customer Device Name: W2240G(B12)	Qu	Infrng/Non-infrng	Admitted
CX	840	C	ATI Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	841	C	ATI Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	842	C	ATI Substrate Design for 104L TFBGA (8x8 MM)	Qu	Infrng/Non-infrng	Admitted
CX	843	C	ATI Substrate Design for 104L TFBGA (8x8 MM)	Qu	Infrng/Non-infrng	Admitted
CX	844	C	ATI Substrate Design for 179L TFBGA (10x10 MM) for Device Name W2240G(B11)	Qu	Infrng/Non-infrng	Admitted
CX	845	C	ATI Wire Bond Diagram for Customer Device W2240G(B11)	Qu	Infrng/Non-infrng	Admitted
CX	846	C	Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	847	C	Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	848	C	Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	849	C	Bonding Diagrams for W2240A	Qu	Infrng/Non-infrng	Admitted
CX	850	C	Bonding Diagrams for W2240A	Qu	Infrng/Non-infrng	Admitted
CX	851					Withdrawn
CX	852					Withdrawn
CX	853					Withdrawn
CX	854					Withdrawn
CX	855					Withdrawn
CX	856					Withdrawn
CX	857					Withdrawn
CX	858	C	Package Outline Drawing for TFBGA, 10x10, Drawing No. 002153L	Qu	Infrng/Non-infrng	Admitted
CX	859	C	Reliability Test Report for Qualifcation Test of LFBGA (12x12) 272L	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	860	C	Reliability Test Report for Qualification Test of TFBGA (8x) 104L	Qu	Infrng/Non-infrng	Admitted
CX	861	C	SPIL All Wires Drawing for W2284J	Qu	Infrng/Non-infrng	Admitted
CX	862	C	SPIL Drawing for W2288J	Qu	Infrng/Non-infrng	Admitted
CX	863					Withdrawn
CX	864	C	SPIL Drawing for W2288J	Qu	Infrng/Non-infrng	Admitted
CX	865	C	STATSChipPAC Assembly Report for ATI 215W2240BPB12NG	Qu	Infrng/Non-infrng	Admitted
CX	866	C	STATSChipPAC Bonding Diagram for Customer Device Name: W2240A	Qu	Infrng/Non-infrng	Admitted
CX	867	C	STATSChipPAC Drawing Number 010081Adrd for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	868	C	STATSChipPAC Drawings for Device Name: W2240A	Qu	Infrng/Non-infrng	Admitted
CX	869	C	Substrate Design 104L TFBGA (8x MM) for Customer Device Name W2240A	Qu	Infrng/Non-infrng	Admitted
CX	870	C	Substrate Design 104L TFBGA (8x MM) for Customer Device Name W2240A	Qu	Infrng/Non-infrng	Admitted
CX	871	C	98ARE10502D	Qu	INFRNG/NON-INFRNG	Admitted
CX	872	C	98ARE10525D	Qu	Infrng/Non-infrng	Admitted
CX	873	C	98ARE10527D	Qu	Infrng/Non-infrng	Admitted
CX	874					Withdrawn
CX	875					Withdrawn
CX	876	C	Freescale's Amended Appendix A and B to Tessera's Interrogatory No. 6	Qu	Infrng/Non-infrng	Admitted
CX	877	C	409 CSP Package Secification	Qu	Infrng/Non-infrng	Admitted
CX	878	C	Ablestik Pilot Technical Datasheet for Ablebond 2300 Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	879	C	Ablestik Technical Datasheet for Ablebond 2000, Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	880	C	Assembly Material Set, MSM6500, 409CSP	Qu	Infrng/Non-infrng	Admitted
CX	881	C	Assembly Material Sets	Qu	Infrng/Non-infrng	Admitted
CX	882	C	Marking Diagram/Assembly Material Set for Digital Die	Qu	Infrng/Non-infrng	Admitted
CX	883	C	Marking Diagram/Assembly Material Set for MSM6000	Qu	Infrng/Non-infrng	Admitted
CX	884	C	Marking Diagram/Assembly Material Set for Material Die	Qu	Infrng/Non-infrng	Admitted
CX	885	C	Marking Diagram/Assembly Material Sets	Qu	Infrng/Non-infrng	Admitted
CX	886					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	887					Withdrawn
CX	888					Withdrawn
CX	889					Withdrawn
CX	890	C	Package Specifications	Qu	Infrng/Non-infrng	Admitted
CX	891	C	Package Specifications	Qu	Infrng/Non-infrng	Admitted
CX	892	C	Qualcomm BGA Package User Guide, 80-V2560-1 Rev. R	Qu	Infrng/Non-infrng	Admitted
CX	893	C	Supplier Substrate Drawings	Qu	Infrng/Non-infrng	Admitted
CX	894	C	Supplier Substrate Drawings	Qu	Infrng/Non-infrng	Admitted
CX	895					Withdrawn
CX	896					Withdrawn
CX	897					Withdrawn
CX	898					Withdrawn
CX	899					Withdrawn
CX	900					Withdrawn
CX	901					Withdrawn
CX	902					Withdrawn
CX	903	C	Reliabililty Qualification re LSC080	Qu	Infrng/Non-infrng	Admitted
CX	904	C	Reliability Qualification re LSA064	Qu	Infrng/Non-infrng	Admitted
CX	905	C	Reliability Qualification re BEA188	Qu	Infrng/Non-infrng	Admitted
CX	906	C	Reliability Qualification re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	907					Withdrawn
CX	908					Withdrawn
CX	909	C	Reliability Qualification re Package VDE044	Qu	Infrng/Non-infrng	Admitted
CX	910	C	Reliability Qualification re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	911	C	Spec F04-0027131 Henkel-QMI 546	Qu	Infrng/Non-infrng	Admitted
CX	912	C	Spec F04-0027803 Rev. A Hitachi Chemical HS-231 W Insulated Film Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	913	C	Spec F04-0028082 Rev. B Hitachi Chemical HS232 Insulated Film Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	914	C	Spec F04-0029734 Rev. A Hitachi Chemical FH-900T-20 Tape	Qu	Infrng/Non-infrng	Admitted
CX	915	C	Technical Drawing re Package BEA188	Qu	Infrng/Non-infrng	Admitted
CX	916	C	Technical Drawings re 64 Ball LBGA	Qu	Infrng/Non-infrng	Admitted
CX	917	C	Technical Drawings re BEA188	Qu	Infrng/Non-infrng	Admitted
CX	918	C	Technical Drawings re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	919	C	Technical Drawings re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	920	C	Technical Drawings re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	921					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	922					Withdrawn
CX	923	C	Technical Drawings re LAA080	Qu	Infrng/Non-infrng	Admitted
CX	924	C	Technical Drawings re LSC080 Package 27828	Qu	Infrng/Non-infrng	Admitted
CX	925	C	Technical Drawings re Package 188 Ball FBGA	Qu	Infrng/Non-infrng	Admitted
CX	926	C	Technical Drawings re Package FBC048	Qu	Infrng/Non-infrng	Admitted
CX	927	C	Technical Drawings re Package LSA064	Qu	Infrng/Non-infrng	Admitted
CX	928	C	Technical Drawings re Package LSA064	Qu	Infrng/Non-infrng	Admitted
CX	929	C	Technical Drawings re Package LSC080	Qu	Infrng/Non-infrng	Admitted
CX	930	C	Technical Drawings re Section 4.1: LRBGA-R Package LSA064	Qu	Infrng/Non-infrng	Admitted
CX	931	C	Technical Drawings re Section 4.1: LRBGA-R Package LSC080	Qu	Infrng/Non-infrng	Admitted
CX	932	C	Technical Drawings re Section 4.1: LBGA Packages	Qu	Infrng/Non-infrng	Admitted
CX	933	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	934	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	935	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	936	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	937	C	Technical Drawings for Various Packages	Qu	Infrng/Non-infrng	Admitted
CX	938	C	Ablestik Pilot Technical Datasheet for Ablebond 2025D High Performance Adhesive for Array Packaging	Qu	Infrng/Non-infrng	Admitted
CX	939	C	Ablestik Pilot Technical Datasheet for Ablebond 2300 Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	940	C	98ASE19645D	Qu	Infrng/Non-infrng	Admitted
CX	941	C	Spansion's Amended Appendix A and B to Tessera's Interrogatory No. 6	Qu	Infrng/Non-infrng	Admitted
CX	942	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	943	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	944	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	945	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	946	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	947	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	948	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	949		Documents relating to Freescale Representative Products	Mawer	INFRNG/NON-INFRNG	Admitted
CX	950	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	951		Documents relating to Freescale Representative Products	Mawer	INFRNG/NON-INFRNG	Admitted
CX	952	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	953	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	954	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	955	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	956	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	957	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	958					Withdrawn
CX	959					Withdrawn
CX	960					Withdrawn
CX	961					Withdrawn
CX	962	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	963	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	964	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	965	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	966		Balog Deposition Exhibit #002, Tessera's Notice of Deposition of Motorola, Inc.	Balog	RMDY	Admitted
CX	967	C	Balog Deposition Exhibit #003, Tessera's Notice of Deposition of Motorola, Inc., of December 21, 2007	Balog	RMDY	Admitted
CX	968	C	Balog Deposition Exhibit #004, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Balog	RMDY	Admitted
CX	969	C	Balog Deposition Exhibit #005, Verification	Balog	RMDY	Admitted
CX	970	C	Balog Deposition Exhibit #006, Respondent Motorola Inc.'s Responses to Complainant Tessera's Amended Fifth Set of Interrogatories (32-79)	Balog	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	971	C	Balog Deposition Exhibit #007, Motorola chart of semiconductor parts	Balog	RMDY	Admitted
CX	972	C	Balog Deposition Exhibit #008, Chart with shipping information from one of Motorola's suppliers	Balog	RMDY	Admitted
CX	973					Withdrawn
CX	974	C	Balog Deposition Exhibit #010, PCNs chart	Balog	RMDY	Admitted
CX	975	C	Balog Deposition Exhibit #011, Component Review Report	Balog	RMDY	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	976	C	Balog Deposition Exhibit #012, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (#6-20)	Balog	RMDY	Admitted
CX	977					Withdrawn
CX	978	C	Balog Deposition Exhibit #015, Excel spreadsheet from Motorola's Enterprise Mobility group and sales information of their respective products from Jan. 1-Nov. 30 2007	Balog	RMDY	Admitted
CX	979		Balog Deposition Exhibit #1, Tessera's Notice of Deposition of Motorola, Inc.	Balog	RMDY	Admitted
CX	980					Withdrawn
CX	981					Withdrawn
CX	982					Withdrawn
CX	983					Withdrawn
CX	984					Withdrawn
CX	985					Withdrawn
CX	986					Withdrawn
CX	987	C	Bradley Deposition Exhibit #007, List of components and their purchase price	Bradley	INFRNG/NON-INFRNG	Admitted
CX	988					Withdrawn
CX	989					Withdrawn
CX	990	C	Bradley Deposition Exhibit #010, CTE Component Report for 5170200A58	Bradley	INFRNG/NON-INFRNG	Admitted
CX	991	C	Bradley Deposition Exhibit #011, Chart: Investigation 337-TA-605	Bradley	INFRNG/NON-INFRNG	Admitted
CX	992					Withdrawn
CX	993					Withdrawn
CX	994					Withdrawn
CX	995					Withdrawn
CX	996					Withdrawn
CX	997	C	Brda Deposition Exhibit #002, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Brda	RMDY	Admitted
CX	998	C	Brda Deposition Exhibit #004, Document entitled "Mobile Devices- All Products"	Brda	RMDY	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	999		Brda Deposition Exhibit #005, Respondent Motorola, Inc.'s Response to Complainant Tessera's Amended Firfth Set of Interrogatories (32-79)	Brda	RMDY	Admitted
CX	1000	C	Brda Deposition Exhibit #006, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-29)	Brda	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1001		Brown Deposition Exhibit #001, Tessera's Notice of Deposition of Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1002		Brown Deposition Exhibit #002, Complaintant Tessera's First Set of Interrogatories (1-5) to Respondent Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1003		Brown Deposition Exhibit #003, Complaintant Tessera's Second Set of Interrogatories (6-20) to Respondent Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1004	C	Brown Deposition Exhibit #004, Respondent Motorola, Inc.'s Second Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Brown	Infrng/Non-infrng	Admitted
CX	1005	C	Brown Deposition Exhibit #005, Respondent Motorola, Inc.'s Second Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-20)	Brown	Infrng/Non-infrng	Admitted
CX	1006		Brown Deposition Exhibit #006, Motorola Product Page from the Motorola U.S. Website	Brown	INFRNG/NON-INFRNG	Admitted
CX	1007	C	Brown Deposition Exhibit #007, Atlas Ultra-Lite Preliminary Detailed Technical Specification Rev 2.3	Brown	INFRNG/NON-INFRNG	Admitted
CX	1008	C	Brown Deposition Exhibit #008, M36LOR8060T1, M36L0R8060B1 Multi-Chip Package Technical Specification	Brown	INFRNG/NON-INFRNG	Admitted
CX	1009	C	Brown Deposition Exhibit #009, Motorola Material or Method Specification No. 51R99190J01	Qu	INFRNG/NON-INFRNG	Admitted
CX	1010	C	Brown Deposition Exhibit #010, Motorola Material or Methods Specification No. 51R85353D38 Javelin IC	Brown	INFRNG/NON-INFRNG	Admitted
CX	1011	C	Brown Deposition Exhibit #011, Motorola Atlas UL Mechanical Strength Characterization Multiple Hit to Failure by Mat Brown	Brown	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1012	C	Brown Deposition Exhibit #012, J0201 Update Presentation by Tony Gallagher of Libertyville (MOT/TES 001596-001627) and BGA Mechanical Reliability Design Process by Matt Brown and Tony Galagher (MOT/TES 001628-001651)	Brown	INFRNG/NON-INFRNG	Admitted
CX	1013	C	Brown Deposition Exhibit #013, Motorola Material or Methods Specification No. 62G13933D51 Specification Template for Integrated Circuits	Brown	INFRNG/NON-INFRNG	Admitted
CX	1014	C	Brown Deposition Exhibit #014, Motorola Material or Methods Specification No. 12G02897W18 Controlled and Reportable Materials Disclosure	Brown	INFRNG/NON-INFRNG	Admitted
CX	1015	C	Brown Deposition Exhibit #015, Motorola Material or Methods Specification No. 71M70269A30 IC Design Requirements and Recommendations for Manufacturing (BGA and LGA devices)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1016	C	Brown Deposition Exhibit #016, Motorola Material or Methods Specification No. 12M09195A97 Dynamic 4-Point Bend Test: BGA & LGA	Brown	INFRNG/NON-INFRNG	Admitted
CX	1017	C	Brown Deposition Exhibit #017, Motorola Specification No. 71G13933J03 Component Padstack Specification	Brown	INFRNG/NON-INFRNG	Admitted
CX	1018	C	Brown Deposition Exhibit #018, Motorola Materials or Methods Specification No. 51R999190J02	Brown	INFRNG/NON-INFRNG	Admitted
CX	1019	C	Brown Deposition Exhibit #019, Motorola Materials or Methods Specification No. 51R85941F60	Qu	Infrng/Non-infrng	Admitted
CX	1020		Brown II Deposition Exhibit #001, Tessera's Notice of Deposition of Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1021	C	Brown II Deposition Exhibit #002, Respondent Motorola, Inc.'s Second Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Brown	INFRNG/NON-INFRNG	Admitted
CX	1022	C	Brown II Deposition Exhibit #003, Document CIMT-570: Physical Symbol Specification for Master Component Library CDS Engineering Design Automation	Brown	INFRNG/NON-INFRNG	Admitted
CX	1023	C	Brown II Deposition Exhibit #004, Master Component Library Geometry Specification 71G13933j21	Brown	INFRNG/NON-INFRNG	Admitted
CX	1024	C	Brown II Deposition Exhibit #005, NPI Dashboard Mobile Devices Search Results	Brown	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1025	C	Brown II Deposition Exhibit #006, Document entitled "Multi Phys Table"	Brown	INFRNG/NON-INFRNG	Admitted
CX	1026	C	Brown II Deposition Exhibit #007, Email from David Patten to Anthony Gallagher and Mark Guilford re Questions on LTE2 Daisy Chains from STATS	Brown	INFRNG/NON-INFRNG	Admitted
CX	1027	C	Brown II Deposition Exhibit #008, Motorola Material or Methods Specification, File: Qualification Procedure for Integrated Circuits	Brown	INFRNG/NON-INFRNG	Admitted
CX	1028	C	Brown II Deposition Exhibit #009, Freescale Sphere Shorting on Argon PoP 15X15 Warpage Evaluation & Optimization Plan, Version 1	Brown	INFRNG/NON-INFRNG	Admitted
CX	1029	C	Brown II Deposition Exhibit #010, Motorola PCS: BGA Reliability	Qu	INFRNG/NON-INFRNG	Admitted
CX	1030	C	Brown II Deposition Exhibit #011, Technical Paper: Reliability Considerations of Electrically Conductive Adhesives by Darryl J. Small (Loctite Corporation)	Brown	INFRNG/NON-INFRNG	Admitted
CX	1031	C	Brown II Deposition Exhibit #012, Indium's SAC-X Solder Alloy Mechanical Reliability Study by Matthew Brown	Brown	INFRNG/NON-INFRNG	Admitted
CX	1032	C	Brown II Deposition Exhibit #013, Introduction of a Few Optical Measurement Methods by YinYan Want (Motorola Labs MATC Predictive Reliability Group)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1033	C	Brown II Deposition Exhibit #014, Predictive Reliability - How We Win	Qu	INFRNG/NON-INFRNG	Admitted
CX	1034	C	Brown II Deposition Exhibit #015, Motorola Finite Element Model	Qu	INFRNG/NON-INFRNG	Admitted
CX	1035	C	Brown II Deposition Exhibit #016, Motorola Requirements for Evaluation of Advanced IC Packages	Brown	INFRNG/NON-INFRNG	Admitted
CX	1036	C	Brown II Deposition Exhibit #017, Motorola Personal Communications Sector CTE-Materials & Failure Analysis Laboratory	Brown	INFRNG/NON-INFRNG	Admitted
CX	1037	C	Brown II Deposition Exhibit #018, Multi-Packaging Solutions for Portable Applications	Brown	INFRNG/NON-INFRNG	Admitted
CX	1038	C	Brown II Deposition Exhibit #019, Multi-Packaging Technology Update	Brown	INFRNG/NON-INFRNG	Admitted
CX	1039		Chopin Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1040	C	Chopin Deposition Exhibit #002, E-mail to T. David et al from S. Wilson regarding Package Intrinsic Reliability	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1041	C	Chopin Deposition Exhibit #004, Freescale Bill of Materials	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1042	C	Chopin Deposition Exhibit #005, Sumitomo Meeting - Place Holder E-mail	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1043					Withdrawn
CX	1044	C	Chopin Deposition Exhibit #007, Appointment e-mail regarding Ablestik's meeting with Freescale	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1045	C	Chopin Deposition Exhibit #008, Appointment e-mail for meeting for review of material propery data	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1046					Withdrawn
CX	1047					Withdrawn
CX	1048	C	DiStefano Deposition Exhibit #149, Confidentail photographs of Chip Packages	DiStefano	OWNR	Admitted
CX	1049	C	Foong Deposition Exhibit #002, Spansion Bill of Materials	Qu	Infrng/Non-infrng	Admitted
CX	1050					Withdrawn
CX	1051					Withdrawn
CX	1052					Withdrawn
CX	1053					Withdrawn
CX	1054					Withdrawn
CX	1055					Withdrawn
CX	1056	C	Frankel Deposition Exhibit #003, Qualcomm Presentation	Frankel	RMDY	Admitted
CX	1057					Withdrawn
CX	1058	C	Frankel Deposition Exhibit #005, Email from L. Pineda to M. Frankel	Frankel	RMDY	Admitted
CX	1059					Withdrawn
CX	1060	C	Gerfin Deposition Exhibit #002, Respondent Qualcomm Incorporated's First Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcom Inc.	Gerfin	Importation, Remedies	Admitted
CX	1061	C	Gerfin Deposition Exhibit #004	Gerfin	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1062	C	Gerfin Deposition Exhibit #005	Gerfin	RMDY	Admitted
CX	1063	C	Gerfin Deposition Exhibit #003	Gerfin	RMDY	Admitted
CX	1064	C	Gerfin Deposition Exhibit #006	Gerfin	RMDY	Admitted
CX	1065	C	Gerfin Deposition Exhibit #007	Gerfin	RMDY	Admitted
CX	1066					Withdrawn
CX	1067					Withdrawn
CX	1068					Withdrawn
CX	1069					Withdrawn
CX	1070	C	Greb Deposition Exhibit #005, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1071	C	Greb Deposition Exhibit #006, Respondent Motorola, Inc.'s Confidential Responses and Objections to Complainant Tessera's Fourth Set of Interrogatories (31)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1072	C	Greb Deposition Exhibit #007, Chart of Supplier Name and Part	Greb	RMDY, DI	Admitted
CX	1073	C	Greb Deposition Exhibit #008, Respondent Motorola Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-20)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1074	C	Greb Deposition Exhibit #009, Respondent Motorola, Inc.'s Responses to Complainant Tessera's Amended Fifth Set of Interrogatories (32-79)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1075					Withdrawn
CX	1076					Withdrawn
CX	1077					Withdrawn
CX	1078					Withdrawn
CX	1079					Withdrawn
CX	1080					Withdrawn
CX	1081	C	Greb Deposition Exhibit #016, Lot Number Inventory Spreadsheet	Greb	RMDY, DI	Admitted
CX	1082	C	Greb Deposition Exhibit #017, Import Entry Data for Mobile Devices Iden Phones Chart	Greb	RMDY, DI	Admitted
CX	1083	C	Greb Deposition Exhibit #018, Import Entry Data for Mobile Devices' Products	Greb	RMDY, DI	Admitted
CX	1084	C	Greb Deposition Exhibit #019, List of Part Numbers deemed to potentially include the accused chips	Greb	RMDY, DI	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1085		Gregorich Deposition Exhibit #001, Tessera's Notice of Deposition of Qualcomm, Inc.	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1086		Gregorich Deposition Exhibit #002, Complaintant Tessera's First Set of Interrogatories (1-5) to Respondent Qualcomm, Inc.	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1087	C	Gregorich Deposition Exhibit #003, Respondent Qualcomm Incorporated's Second Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1088		Gregorich Deposition Exhibit #012, U.S. Patent No. 5,852,326 (Khandros, et al.)- Face-Up Semiconductor Chip Assembly dated 12/22/1998	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1089		Gregorich Deposition Exhibit #013, U.S. Patent No. 6,433,419 B2 (Khandros et al.)- Face-Up Semiconductor Chip Assemblies dated 8/13/2002	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1090	C	Gregorich Deposition Exhibit #18, Email from J. Riley to E. Reyes et al., re Micro-BGA Data	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1091	C	Gregorich Deposition Exhibit #23, Finite Element	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1092		Holmes Deposition Exhibit #001, Tessera's Notice of Deposition of Qualcomm	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1093					Withdrawn
CX	1094					Withdrawn
CX	1095	C	Holmes Deposition Exhibit #004, Qualcomm's Second Supplemental Response to Tessera's First Set of Interrogatories	Holmes	Infrng/Non-infrng	Admitted
CX	1096					Withdrawn
CX	1097					Withdrawn
CX	1098	C	Holmes Deposition Exhibit #008, Documents for product name MBP1600 - Document 1	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1099	C	Holmes Deposition Exhibit #009, Documents for product name MSM6280	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1100	C	Holmes Deposition Exhibit #010, Documents for product name MSM6280	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1101	C	Holmes Deposition Exhibit #011, Package Outline Drawing, 409 CSP Drawing Number NT90-V2970-1	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1102	C	Holmes Deposition Exhibit #012, Documents for product name BTS4050	Holmes	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1103	C	Holmes Deposition Exhibit #013, Documents for product number MSM6025	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1104	C	Holmes Deposition Exhibit #014, Qualcomm's Response to Tessera's Fourth Set of Interrogatories	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1105	C	Holmes Deposition Exhibit #015, Qualcomm's First Supplemental Response to Tessera's Second Set of Interrogatories	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1106	C	Holmes Deposition Exhibit #016-I, Qualcomm Process Flow Chart Specification for 2-DIE Stacked CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1107	C	Holmes Deposition Exhibit #016-J, Process Flow Chart Specification for Package on Package (POP) CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1108	C	Holmes Deposition Exhibit #016-K, Qualcomm Process Flow Chart Specification for 3-DIE Stacked CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1109	C	Holmes Deposition Exhibit #017, Qualcomm CDMA Technologies Package Outline Drawing, 409CSP, Drawing Number NT90-V2970-2	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1110	C	Holmes Deposition Exhibit #018, Qualcomm Bonding Diagram WFB4130/XXX, 289FBGA	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1111	C	Holmes Deposition Exhibit #019, Qualcomm Bonding Diagram MSM7600 (XXX) Drawing Number BL90-VB720-3	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1112					Withdrawn
CX	1113					Withdrawn
CX	1114					Withdrawn
CX	1115					Withdrawn
CX	1116					Withdrawn
CX	1117					Withdrawn
CX	1118		Homes II Deposition Exhibit #001, Tessera's Notice of Deposition of Qualcomm, Inc.	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1119	C	Homes II Deposition Exhibit #002, Documents collectively marked (Assembly Material Set, MSM6500 , 409CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1120	C	Homes II Deposition Exhibit #003, Email from Thuyen Dinh re Material Data Sheet on Livelinks dated 08/11/2000	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1121					Withdrawn
CX	1122					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1123	C	Homes II Deposition Exhibit #006, Documents for production name 543 CSP collectively marked	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1124	C	Homes II Deposition Exhibit #007, Bill of Materials for Product MSM7200A	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1125	C	Homes II Deposition Exhibit #008, Documents collectively marked (Bonding Diagrams)	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1126	C	Homes II Deposition Exhibit #009, Bill of Materials for Product MSM6250A	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1127	C	Homes II Deposition Exhibit #010, Documents collectively marked (208 FBGA Package Specification)	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1128	C	Homes II Deposition Exhibit #011, Bill of Materials for Product MSM5105	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1129	C	Homes II Deposition Exhibit #012, Email chain beginning 10/28/2002	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1130	C	Homes II Deposition Exhibit #015, Email from Rick Horvath	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1131	C	Kellar Deposition Exhibit #007, Freescale Circuit Configuration 252 I/O MAP PBGS, 21 x 21 PKG, 1.27 MM PITCH	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1132	C	Kellar Deposition Exhibit #008, Document Action Request regarding 252 STD BGA (56305/56301) .30 SAW STREET 84ARS24067W	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1133	C	Kellar Deposition Exhibit #009, Updated document request form for Document: 84ARS24067W submitted by Carol Armendariz	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1134	C	Kellar Deposition Exhibit #010, Freescale Circuit Configuration 252 I/O MAP PBGS, 21 x 21 PKG, 1.27 MM PITCH	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1135	C	Kellar Deposition Exhibit #011, ReadMe files re: part #84ARS24067W001_B and W002	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1136	C	Kellar Deposition Exhibit #012, Screen shot of directory structure	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1137	C	Kellar Deposition Exhibit #013, Document the Freescale Administration puts together before submitting something to the SAP to release it as an official part number regarding 84ARS24067W	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1138	C	Kellar Deposition Exhibit #014, Bonding Diagram Information Forms NPI, REV O for Device Name 56301	Kellar	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1139	C	Kellar Deposition Exhibit #015, Wire Bond Diagram Document for the Device Name ONYX 56301_56305	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1140	C	Kellar Deposition Exhibit #016, Bonding Diagram Information Forms for Device Name ONYX 56301_56305	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1141		Kellar Deposition Exhibit #1, Tessera's First Amended Notice of Deposition of Freescale Semiconductor, Inc.	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1142		Kellar Deposition Exhibit #2, Complaintant Tessera's First Set of Interrogatories (1-5) to Respondent Freescale Semiconductor, Inc.	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1143		Kellar Deposition Exhibit #3, Complaintant Tessera's Second Set of Interrogatories (6-20) to Respondent Freescale Semiconductor, Inc.	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1144	C	Kellar Deposition Exhibit #4, Respondent Freescale Semiconductor, Inc.'s Supplemental Responses to Complainant Tesesera's First Set of Interrogatories (Nos. 1-5)	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1145	C	Kellar Deposition Exhibit #5, Respondent Freescale Semiconductor, Inc.'s Supplemental Responses to Complainant Tessera's Second Set of Interrogatories (Nos. 6-20)	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1146		Leoni Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1147	C	Leoni Deposition Exhibit #002, Tessera ITC Investigation No. 337-TA-605 Complaint	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1147					Withdrawn
CX	1148	C	Leoni Deposition Exhibit #003, Optical Photos of Freescale SC13890P23A	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1149		Leoni Deposition Exhibit #004, Tessera's First Set of Interrogatories (1-5) to Freescale	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1150	C	Leoni Deposition Exhibit #005, Freescale's Supplemental Responses to Tessera's First Set of Interrogatories (1-5)	Leoni	Infrng/Non-infrng	Admitted
CX	1151					Withdrawn
CX	1152					Withdrawn
CX	1153		Mawer Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1154	C	Mawer Deposition Exhibit #002, Freescale's Supplemental Responses to Tessera's Second Set of Interrogatories (Nos. 6-20)	Mawer	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1155	C	Mawer Deposition Exhibit #003, Motorola document titled,"PBGA Solder Joint Reliability Improvement Study"	Qu	INFRNG/NON-INFRNG	Admitted
CX	1156	C	Mawer Deposition Exhibit #004, Motorola Presentation titled,"BAT-1 CBGA Ball Attach Solder Paste and Ball Type Qualification Results"	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1157	C	Mawer Deposition Exhibit #005, Meeting Notification e-mail for the meeting regarding Delphi-Jupiter update	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1158	C	Mawer Deposition Exhibit #006, Meeting Notification e-mail for the meeting regarding PQ38 Pkg NPI - Carlsbad I	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1159	C	Mawer Deposition Exhibit #008, E-mail from F. Utama to C. Foong et al regarding TSO Thermal Moire with the TSO - WPSL Kuala Lumpur Material Research Laboratory Report	Qu	INFRNG/NON-INFRNG	Admitted
CX	1160	C	Mawer Deposition Exhibit #009, E-mail from T. Koschmieder to D. Wells et al regarding meeting and the HDP presenation titled,"Thermo-Electromigration in WL-CSP Pb-Free Solder Joints" by K. N. Tu	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1161	C	Mawer Deposition Exhibit #011, E-mail from M. Ding to F. Wulfert et al regarding SnAgCu => SnAg solder ball	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1162	C	Mawer Deposition Exhibit #012, E-mail from T. Koschmieder to S. Safai, A. Mawer, T. Burnette, and P. Galles regarding Python SJR results	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1163	C	Mawer Deposition Exhibit #013, E-mail from M. Tsuriya to B. Carpenter regarding GPE Japan Weekly: WW21-07	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1164	C	Mawer Deposition Exhibit #014, E-mail from V. Marquez to T. Burnette regarding APEC1. Package Code: 5253 MAPBGA 208 17*17*0.8P1.0 (lead free)	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1165	C	Mawer Deposition Exhibit #015, E-mail from T. Koschmieder to M. Tsuriya et al regarding HDP-ug: Mechanical Fatigue Test for Solder Joint Test	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1166	C	Mawer Deposition Exhibit #016, E-mail from M. Tsuriya to T. Koschmieder regarding Japan GAP - 0.4mmP BLR Test	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1167	C	Mawer Deposition Exhibit #017, E-mail from T. Koschmieder to W. Lindsay et al regarding ramblings on FC-PBGA ball size	Mawer	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1168	C	Mawer Deposition Exhibit #018, E-mail from M. Tsuriya to A. Mawer et al regarding JEITA Spec: BGA Package Warpage during Reflow	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1169	C	Mawer Deposition Exhibit #019, E-mail from A. Mawer to L. Leon et el regarding Moccasin/Viper Substrate Qual Update	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1170	C	Mawer Deposition Exhibit #020, Freescale Drawing Number: 67ARE10249D for Device Name: XPC8260OZU	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1171	C	Mawer Deposition Exhibit #021, Freescale Drawing Number: 67ARE11089D for Device Name: Neptune LTE2C90	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1172					Withdrawn
CX	1173	C	Mawer Deposition Exhibit #026, E-mail from A. Mawer to W. Demarco regarding OMPAC Die Attach in Early 1990s	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1174		McLellan Deposition Exhibit #001, Tessera's Notice of Deposition of ATI Technologies, Inc.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1175		McLellan Deposition Exhibit #002, Complainant Tessera's First Set of Interrogatories (1-5) to Respondent ATI Technologies, ULC	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1176		McLellan Deposition Exhibit #003, Complainant Tessera's Second Set of Interrogatories (6-20) to Respondent ATI Technologies, ULC	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1177	C	McLellan Deposition Exhibit #004, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's First Set of Interrogatories (Nos. 1, 2, 3 and 5)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1178	C	McLellan Deposition Exhibit #005, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's First Set of Interrogatories (Nos. 1, 2, 3 and 5)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1179	C	McLellan Deposition Exhibit #006, Respondent ATI Technologies, ULC's Amended Responses to Tessera's Second Set of Interrogatories (No. 6, 7, 8, 10, 11, 12, 17, 19 and 20)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1180	C	McLellan Deposition Exhibit #007, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's Second Set of Interrogatories (No. 6, 7, 8, 10, 11, 12, 17, 19 and 20)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted

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CX	1181	C	McLellan Deposition Exhibit #008, Package ID W2040	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1182	C	McLellan Deposition Exhibit #009, Package ID W2250	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1183	C	McLellan Deposition Exhibit #010, Package ID W2240	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1184	C	McLellan Deposition Exhibit #011, Package ID W2282	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1185	C	McLellan Deposition Exhibit #012, Package ID W2261	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1186	C	McLellan Deposition Exhibit #013, Package ID W2182	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1187	C	McLellan Deposition Exhibit #014, Package ID W2284	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1188	C	McLellan Deposition Exhibit #015, Package ID W2262	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1189	C	McLellan Deposition Exhibit #016, BT Materials for IC Plastic Package with attachments	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1190		McLellan II Deposition Exhibit #101, Tessera's Notice of Deposition of ATI Technologies, Inc.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1191		McLellan II Deposition Exhibit #102, Complainant {sic} Tessera's First Set of Interrogatories to Respondent ATI Technologies, Inc.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1192	C	McLellan II Deposition Exhibit #103, Amended Appendix A	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1193	C	McLellan II Deposition Exhibit #104, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's Second Set of Interrogatories (No. 6-12, 17, 19, 20), Amended Appendix A	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1194		McLellan II Deposition Exhibit #105, U.S. Patent No. 5,852,326 (Khandros et al.)- Face-Up Semiconductor Chip Assembly	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1195		McLellan II Deposition Exhibit #106, U.S. Patent No. 6,433,419 B2 (Khandros et al.)- Face-Up Semiconductor Chip Assemblies	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1196	C	McLellan II Deposition Exhibit #107, Advanced Payment Agreement	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted

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CX	1197	C	McLellan II Deposition Exhibit #108-1, Package ID W2282	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1198	C	McLellan II Deposition Exhibit #108-2, Continuation: Package ID W2282	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1199		McLellan II Deposition Exhibit #109, Complainant {sic} Tessera's First Set of Interrogatories to Production of Documents and Things (No. 1-13) to Respondent ATI Technologies, ULC.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1200		McLellan II Deposition Exhibit #110, Complainant {sic} tessera's Second Set of Requests for Production of Documents and Things (Nos. 4-56) to Respondent ATI Technologies, ULC,	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1201	C	McLellan II Deposition Exhibit #111, Purchase Order Terms and Conditions	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1202	C	McLellan II Deposition Exhibit #112, Chart	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1203	C	McLellan II Deposition Exhibit #113, Loctite Technical Data Sheet, Hysol QMI 546	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1204	C	McLellan II Deposition Exhibit #114, Material Safety Data Sheet	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1205					Withdrawn
CX	1206	C	McLellan II Deposition Exhibit #116, SPIL New Package/Device/Material Qualification Report	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1207	C	McLellan II Deposition Exhibit #117, Branding Diagram for MINIME 215W2240BKB12G	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1208	C	McLellan II Deposition Exhibit #118, ATI Spreadsheet of January - June 2007 Actuals for Motorola	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1209	C	McLellan II Deposition Exhibit #119, "Reliability Evaluation of Chip Sale Packages," by R. Gannamani, et al.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1210					Withdrawn
CX	1211		McShane Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	McShane	INFRNG/NON-INFRNG	Admitted
CX	1212		McShane Deposition Exhibit #002, Tessera's First Set of Interrogatories (1-5) to Freescale	McShane	INFRNG/NON-INFRNG	Admitted
CX	1213	C	McShane Deposition Exhibit #004, Motorola PBGA Presentation	McShane	INFRNG/NON-INFRNG	Admitted

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CX	1214	C	McShane Deposition Exhibit #005, Freescale document titled,"Freescale Low K Expoxy Mold Compound Development Challenges & Methods"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1215	C	McShane Deposition Exhibit #006, Presentation with Equations and specifications	McShane	INFRNG/NON-INFRNG	Admitted
CX	1216	C	McShane Deposition Exhibit #007, Motorola document titled,"Non-Conductive Die Attach Final Recommendation Management Summary"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1217	C	McShane Deposition Exhibit #008, Ablestik presentation titled,"Curing Conditions and Bond line Thickness Effect on Warpage of Ablebond 8290" by C. Deekitwong	McShane	INFRNG/NON-INFRNG	Admitted
CX	1218	C	McShane Deposition Exhibit #009, Ablestik presentation titled,"Basic Die Attach Adhesive Properties"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1219	C	McShane Deposition Exhibit #010, Sumitomo Bakelite Co. document titled,"2.2.1 Concept to achieve higher MSL performance"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1220	C	McShane Deposition Exhibit #011, Tessera Presentation titled,"Multi-Die Packaging Technology Update"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1221	C	McShane Deposition Exhibit #013, Motorola Presentation titled,"Tessera 46 µBGA Board-Level Thermal Cycling Data"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1222		Montgomery Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1223		Montgomery Deposition Exhibit #002, Tessera ITC Investigation No. 337-TA-605 Complaint	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1224		Montgomery Deposition Exhibit #003, Complaintant Tessera's First Set of Interrogatories (1-5) to Freescale	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1225	C	Montgomery Deposition Exhibit #004, Freescale's Supplemental Responses to Tessera's First Set of Interrogatories (1-5)	Montgomery	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1226					Withdrawn
CX	1227	C	Montgomery Deposition Exhibit #005, Freescale's Supplemental Responses to Tessera's Second Set of Interrogatories (Nos. 6-20)	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted

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CX	1228	C	Montgomery Deposition Exhibit #012, Freescale list regarding Part Ids and Corporations who purchased them in 2007	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1229	C	Montgomery Deposition Exhibit #014, Freescale list regarding Part Ids	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1230		O'Leary Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor, Inc.	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1231	C	O'Leary Deposition Exhibit #002, Respondent Freescale Semiconductor, Inc.'s Supplemental Response to Complaint Tessera's First Set of Interrogatories (Nos. 1-5)	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1232	C	O'Leary Deposition Exhibit #003, Respondent Freescale Semiconductor, Inc.'s Supplemental Responses to Complainant Tessera's Second Set of Interrogatories (Nos. 6-20)	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1233	C	O'Leary Deposition Exhibit #004, Freescale Semiconductor, Inc.'s Confidential Business Information	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1234	C	O'Leary Deposition Exhibit #005, Piece Part Document, "IBM-Bromont Piece Parts", Doc.# 01ARS10523D, Issue II, 3 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1235	C	O'Leary Deposition Exhibit #006, Contract House Piece Parts, "STATS Singapore Piece Part Document", Doc.# 01ACM1059D, Issue IV, 8 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1236	C	O'Leary Deposition Exhibit #007, Contract House Piece Parts, "ASE-TAIWAN Piece Parts Document", Doc.# 01ASH00613A", Issue KB, 24 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1237	C	O'Leary Deposition Exhibit #008, Contract House Piece Parts, "Piece Part Document", Doc.# 01ASA10523D, Issue DN, 13 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1238	C	O'Leary Deposition Exhibit #009, Contract House Piece Parts, "ANAM Piece Part Document", Doc.# 17CSH00482A, Issue GT, 19 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1239	C	O'Leary Deposition Exhibit #010, Contract House Piece Parts, "ANAM Piece Part Document", Doc.# 17ARE10001W, Issue AU, 4 pgs	O'Leary	INFRNG/NONINFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1240	C	O'Leary Deposition Exhibit #011, Piece Part Document, "Final Manufacturing Operation, Misc. Contract Piece Parts", Doc. # 01ASH70609A, Issue DM, 11 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1241					Withdrawn
CX	1242					Withdrawn
CX	1243					Withdrawn
CX	1244	C	Preecha Deposition Exhibit #002, Qualcomm's Second Supplemental Response to Tessera's First Set of Interrogatories	Preecha	Infrng/Non-infrng	Admitted
CX	1245					Withdrawn
CX	1246		Roosien Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor, Inc.	Roosien	RMDY, DI	Admitted
CX	1247	C	Roosien Deposition Exhibit #002, Respondent Freescale Semiconductor, Inc.'s Responses to Complainant Tessera's First Set of Interrogatories (Nos. 1-5)	Roosien	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1248					Withdrawn
CX	1249					Withdrawn
CX	1250	C	Roosien Deposition Exhibit #005, Email from Park Changhae to Robert Rodriguez, Michael Noonan and Paul Reidy re Freescale Royalty	Roosien	RMDY, DI	Admitted
CX	1251	C	Roosien Deposition Exhibit #006, Redacted Email String re Second Amendment on Freescale Immunity Agreement	Roosien	RMDY, DI	Admitted
CX	1252					Withdrawn
CX	1253	C	Roosien Deposition Exhibit #008, Immunity Agreement by and between Motorola, Inc. and AMKOR Electronics, Inc.	Roosien	RMDY, DI	Admitted
CX	1254	C	Roosien Deposition Exhibit #009, Motorola Inter-Office Correspondencce to Jim Smith re Immunity from Suit Agreement for ASE and the SPS vault	Roosien	RMDY, DI	Admitted
CX	1255					Withdrawn
CX	1256					Withdrawn
CX	1257					Withdrawn
CX	1258					Withdrawn
CX	1259					Withdrawn
CX	1260					Withdrawn
CX	1261					Withdrawn
CX	1262					Withdrawn

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CX	1263					Withdrawn
CX	1264					Withdrawn
CX	1265					Withdrawn
CX	1266					Withdrawn
CX	1267		Suresh Deposition Exhibit #002, Respondents Spansion Inc. and Spansion LLC's Repsponses to Tesserea's Second Set of Interrogatories (6-20)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1268	C	Suresh Deposition Exhibit #003, Report regarding the Bill of Materials for Certain Packages	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1269	C	Suresh Deposition Exhibit #004, Report regarding the Bill of Materials for Certain Packages	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1270	C	Suresh Deposition Exhibit #005, Documents containing names and information of customers of Spansion	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1271	C	Suresh Deposition Exhibit #006, Respondents Spansion Inc. and Spansion LLC's Supplemental Responses to Tessera's Second Set of Interrogatories (6, 8)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1272	C	Suresh Deposition Exhibit #007, Complaintant Tessera's Second Set of Interrogatories (6-20) To Respondent Spansion, INc.	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1273	C	Suresh Deposition Exhibit #008, Reliability Qualifaction Document for Package ASD188	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1274	C	Suresh Deposition Exhibit #009, Collection of technical documents relating to ASD188 that were cited in Amended Appendix A and Appendix B	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1275	C	Suresh Deposition Exhibit #010, FBA48 Package Using 98F08 in Bangkok for MSD Project #224 by Shankar Subramanian	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1276	C	Suresh Deposition Exhibit #011, Technical Drawing Document relating to Package No. 27383	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1277	C	Suresh Deposition Exhibit #012, TSD 084 (MCP) Package for XS257A6K3 (Micron) Device Assembled in BKK/PNG/SUZ by Alex Tain (completed 09/01/2005)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1278	C	Suresh Deposition Exhibit #013, Technical Drawing Document relating to TFRBGA-R Package - TSD 084	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1279	C	Suresh Deposition Exhibit #014, AMD Advance Information Report for AM29N128J/Am29N643J	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1280		Suresh Deposition Exhibit #1, Tessera's Notice of Deposition of Spansion, Inc.	Suresh	INFRNG/NON-INFRNG	Admitted

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CX	1281		Suresh Deposition Exhibit #101, Tessera's Notice of Deposition of Spansion, Inc.	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1282		Suresh Deposition Exhibit #102, Tessera's Notice of Deposition of Spansion, Inc.	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1283	C	Suresh Deposition Exhibit #103, Document titled "Spansion's Confidential Business Information- Listing of Spansion Products"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1284	C	Suresh Deposition Exhibit #104, Document entitled "Concode for FBGA & MCP Package Family (Per F09-000)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1285	C	Suresh Deposition Exhibit #105, Document entitled "Reliability Qualification, Project Name: 98U03A VBH084 QUAL"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1286	C	Suresh Deposition Exhibit #106, Document entitled "Henkel-QMI 546 DIE ATTACH PASTE"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1287	C	Suresh Deposition Exhibit #107, Document entitled "Technical Data Sheet- Hysol QMI 546"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1288	C	Suresh Deposition Exhibit #108, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0X28289"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1289	C	Suresh Deposition Exhibit #109, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec #F04-0028082"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1290	C	Suresh Deposition Exhibit #110, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0027803"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1291	C	Suresh Deposition Exhibit #111, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0029734"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1292	C	Suresh Deposition Exhibit #112, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0X29759"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1293	C	Suresh Deposition Exhibit #113, Document entitled "Critical Functional Quality Criteria- Molded Product"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1294	C	Suresh Deposition Exhibit #114, Document entitled "Request for Engineering Build"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1295	C	Suresh Deposition Exhibit #115, Document entitled "LAA064 Package Qualification"	Suresh	INFRNG/NON-INFRNG	Admitted

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CX	1296	C	Suresh Deposition Exhibit #116, Document relating to LAC064 Package	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1297	C	Suresh Deposition Exhibit #117, Email from Foong, YH to Tina Chow, John Yan, Du Yong, Bharalwaj Ramakrishnan, LK Suresh, Bruce Symons and Niranjan Vijayaragavan re Assembly Data	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1298	C	Suresh Deposition Exhibit #118, Email from Weera Mahajuntakam to W. Sabyeying, D. Duong, G. Subramanian, S. Foong, S. Samaititchon, V. Valluri, P. Kirawongsapiwat and N. Chuenpeng re Critical Dimensional Inspection on JCI Substrate- 27628	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1299	C	Suresh Deposition Exhibit #119, VBL088 (VFBGA) Package for 98U03A Device Assembled in BKK, MSD Project # 3714	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1300	C	Suresh Deposition Exhibit #120, Email from G. Subramanian to J. Gomez et al., re LAA daisy chain for customer	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1301	C	Suresh Deposition Exhibit #121, PDL128G Package Options	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1302	C	Suresh Deposition Exhibit #122, Email from E.T. Yeoh to J. Chang et al., re 98R08A FBE63 & LAA64 Qual Summary	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1303					Withdrawn
CX	1304	C	Suresh Deposition Exhibit #124, Email from F. Classe to M. Mizutani et al., re VBN048 Issue (98M57)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1305	C	Suresh Deposition Exhibit #125, Document titled "98K03 LLA064 1mm FBGA Package Qualification	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1306	C	Suresh II Deposition Exhibit #126, Reliability Qualification, Project Name PGN 64/64.FSA063JIC0.45BALL	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1307	C	Suresh II Deposition Exhibit #127, FSA 063 Wire Bond Diagram	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1308	C	Suresh II Deposition Exhibit #128, Group of Emails beginning with email to Bansal, Dhiraj, et al., from Smamatitchon, Surasez re LV640 Device	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1309	C	Suresh II Deposition Exhibit #129, Email string beginning with email to Garcia, Margot, from Tanaka, Neal re WS128J VBH084 Package	Suresh	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1310	C	Veatch Deposition Exhibit #001, Respondent Qualcomm Incorporated's Second Supplementak Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated.	Veatch	INFRNG/NONINFRNG	Admitted
CX	1311	C	Veatch Deposition Exhibit #002, Monthly report from Nov. 2001 for the IC Package engineering department	Veatch	INFRNG/NONINFRNG	Admitted
CX	1312	C	Veatch Deposition Exhibit #003, Email from C. Bai to Mark Veatch et al., re January 2002 Activity Report	Veatch	INFRNG/NONINFRNG	Admitted
CX	1313	C	Veatch Deposition Exhibit #004, Monthy report inputs for February, 2002	Veatch	INFRNG/NONINFRNG	Admitted
CX	1314	C	Veatch Deposition Exhibit #005, Summary of CSP development Activities for the Package Engineering Group	Veatch	INFRNG/NONINFRNG	Admitted
CX	1315	C	Veatch Deposition Exhibit #006, Qualcomm Memorandum from James Burrell to Mark Veatch & C. Bai re Toshiba PDA System Level Thermal Analysis	Veatch	INFRNG/NONINFRNG	Admitted
CX	1316	C	Veatch Deposition Exhibit #007, August 2005 monthly report for the package engineering department	Veatch	INFRNG/NONINFRNG	Admitted
CX	1317	C	Veatch Deposition Exhibit #008, IC Package Characterization Requirements	Veatch	INFRNG/NONINFRNG	Admitted
CX	1318	C	Veatch Deposition Exhibit #009, Email from K. Kaskoun to info@tessera.com re Through Silicon Stacking	Veatch	INFRNG/NONINFRNG	Admitted
CX	1319					Withdrawn
CX	1320	C	Veatch Deposition Exhibit #011, Email from amri-support@qualcomm.com to Mark Veatch re Electronic MR 1196601 changes	Veatch	INFRNG/NONINFRNG	Admitted
CX	1321	C	Veatch Deposition Exhibit #014, TSMC Thermal and Mechanical Core Competency Development	Veatch	INFRNG/NONINFRNG	Admitted
CX	1322					Withdrawn
CX	1323					Withdrawn
CX	1324	C	Witten Deposition Exhibit #003, Tessera Product Family and Item Numbers.xls	Witten	RMDY	Admitted
CX	1325	C	Witten Deposition Exhibit #004, Qualcomm's First Supplemental Response to Tessera's First Set of Interrogatories to Qualcomm	Witten	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1326	C	Witten Deposition Exhibit #006, Tessera Import data Jan 1 2007-November 30 2007 Spreadsheet	Witten	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1327	C	Witten Deposition Exhibit #007, Diebank Inventory Status List	Witten	RMDY	Admitted
CX	1328	C	Witten Deposition Exhibit #008, Tessera Inventory report	Witten	RMDY	Admitted
CX	1329					Withdrawn
CX	1330	C	DiStefano Deposition Exhibit #147, Highly Confidential document entitled "Record"	DiStefano	OWNR	Admitted
CX	1331	C	Balog Deposition Exhibit #013, Motorola excel spreadsheet used by sourcing team to do cost modeling of devices	Balog	RMDY	Admitted
CX	1332	C	Qu Deposition Exhibit #260, Errata Sheet for January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted
CX	1333	C	Qu Deposition Exhibit #269, Updated Figures and Tables from January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted
CX	1334		Hundt Deposition Exhibit #005 - Form 20-F, filed March 14, 2007	Qu	INFRNG/NON-INFRNG	Admitted
CX	1335		Hundt Deposition Exhibit #008 - Advanced Packaging - Plastic BGA - Low profile fine pitch BGA - Thin Fine Pitch BGA	Qu	INFRNG/NON-INFRNG	Admitted
CX	1336	C	Hundt Deposition Exhibit #010, Pilot Technical Datasheet for Ablebond 2300	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1337	C	Hundt Deposition Exhibit #011, Technical Datasheet for Loctite Die Attach Materials	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1338	C	Hundt Deposition Exhibit #012, Technical Datasheet for Hitachi Chemical Die Bonding Pastes	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1339	C	Hundt Deposition Exhibit #013, Design for Package and Board Level Reliability with CAE	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1340	C	Hundt Deposition Exhibit #014 - How to Solder a BGA on a Printed Circuit board	Qu	INFRNG/NON-INFRNG	Admitted
CX	1341	C	Malone Deposition Exhibit #003, Document Entitled, "ST-NV Form 20F"	Malone	INFRNG/NON-INFRNG	Admitted
CX	1342		Malone Deposition Exhibit #014, Document Entitled, "Response of STMicroelectronics N.V. to the Complaint, as Supplemented, Under Section 337 of the Tariff Act of 1930, as Amended"	Malone	INFRNG/NON-INFRNG	Admitted
CX	1343		Malone Deposition Exhibit #017, STMicroelectronics Digital Satellite Broadcast Chips Enable In-Vehicle Sirius Backseat TV	Malone	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1344		Malone Deposition Exhibit #018 - Document Entitled, "STA264 Sirius overlay decoder"	Malone	INFRNG/NON-INFRNG	Admitted
CX	1345	C	Richards Deposition Exhibit #002, Motorola Failure Analysis Report on GSM T720 Phone	Richards	INFRNG/NONINFRNG	Admitted
CX	1346	C	Richards Deposition Exhibit #003, Motorola Email re: Approval of STM Flash on GSM V3	Richards	INFRNG/NONINFRNG	Admitted
CX	1347	C	Richards Deposition Exhibit #004, Motorola Component Report on Part No. 5199190J01 (STM Flash Memory)	Richards	INFRNG/NONINFRNG	Admitted
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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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CX	1555					Withdrawn
CX	1556	C	Qualcomm Presentation	Qu	Infrng/Non-infrng	Admitted
CX	1557	C	ATI All Wires Diagram for Device W2284D, Version G	Qu	Infrng/Non-infrng	Admitted
CX	1558	C	ATI Package Outline Drawing, Drawing No. POD 100100025905001	Qu	Infrng/Non-infrng	Admitted
CX	1559	C	ATI Substrate Design for Customer Dwg. No. SUB-W2284GDB11g_1A-Rev B	Qu	Infrng/Non-infrng	Admitted
CX	1560	C	ATI Wire Bond Diagram for Customer Device W2284D	Qu	Infrng/Non-infrng	Admitted
CX	1561	C	ATI Wire Bond Diagram for Customer Device W2284D	Qu	Infrng/Non-infrng	Admitted
CX	1562					Withdrawn
CX	1563	C	SPIL Reliability Test Report for ATI STFBGA259(10*10)(LF) New Device Qual, No. R0605250789	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1564	C	Customer Applications Support and Reliability Test Center," PBGA Customer Presentation	Qu	Infrng/Non-infrng	Admitted
CX	1565	C	Digital DNA from Motorola Presentation entitled, "Customer Applications Support and Reliability Test Center"	Qu	Infrng/Non-infrng	Admitted
CX	1566	C	Freesale Wire Bond Drawing, Dwg. No. 67ASA11241D	Qu	Infrng/Non-infrng	Admitted
CX	1567	C	Freescale Circuit Configuration Drawing, Dwg. No. 84ARE11469D	Qu	Infrng/Non-infrng	Admitted
CX	1568	C	Freescale Circuit Configuration Drawing, Dwg. No. 84ASA10642D	Qu	Infrng/Non-infrng	Admitted
CX	1569		Freescale MPC8XXFADS Design Specification - Rev. 0.1, Preliminary	Qu	Infrng/Non-infrng	Admitted
CX	1570	C	Freescale Wire Bond Drawing, Dwg. No. 67ARE11027D	Qu	Infrng/Non-infrng	Admitted
CX	1571	C	Motorola Materials or Methods Specification, "Manufacturing Requirements for IC Packages (BGA and LGA devices)"	Qu	Infrng/Non-infrng	Admitted
CX	1572	C	Chart of Supplier Parent, Parts	Qu	Infrng/Non-infrng	Admitted
CX	1573					Withdrawn
CX	1574					Withdrawn
CX	1575					Withdrawn
CX	1576	C	Spansion Amended Appendix A	Qu	Infrng/Non-infrng	Admitted
CX	1577					Withdrawn
CX	1578					Withdrawn
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CX	1591					Withdrawn
CX	1592		AMD Am29DL800B Advanced Information	Qu	Infrng/Non-infrng	Admitted
CX	1593		AMD FBGA User's Guide, Version 2.3.1	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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CX	1624	C	AMD FBGA User's Guide, Version 2.3.1	Qu	Infrng/Non-infrng	Admitted
CX	1625	C	*Concode for FBGA & MCP Package Family (per F09-000)*	*Qu*	*Infrng/Non-infrng*	*Admitted*
CX	1626		Package code nomenclature for single chip packages	Qu	Infrng/Non-infrng	Admitted
CX	1627	C	Reliability Qualification for Project 96M73 MASK REVISION, Internal Device 98M73A2E	Qu	Infrng/Non-infrng	Admitted
CX	1628	C	Spansion Package Outline Drawing, Spec Number F16-038.9	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1629	C	Spansion Substrate Drawing, Dwg. No. 0028598	Qu	Infrng/Non-infrng	Admitted
CX	1630	C	Freescale Mechanical Outlines Dictionary, Document No. 98ARS23882W	Qu	Infrng/Non-infrng	Admitted
CX	1631					Withdrawn
CX	1632					Withdrawn
CX	1633		Certified Assignment of U.S. Patent No. 5,679,977 - Exhibit #16 to Complaint	DiStefano	OWNR	Admitted
CX	1634					Withdrawn
CX	1635					Withdrawn
CX	1636	C	Confidential Domestic Industry Information - Exhibit #5 to Complaint	Mitchell	RMDY, DI	Admitted
CX	1637	C	Confidential List of Licensees of the Asserted Patents - Exhibit #4 to Complaint	Griffin	RMDY, OWNR	Admitted
CX	1638					Withdrawn
CX	1639					Withdrawn
CX	1640					Withdrawn
CX	1641					Withdrawn
CX	1642					Withdrawn
CX	1643					Withdrawn
CX	1644					Withdrawn
CX	1645		Memorandum Opinion and Order on Claim Construction in *Tessera, Inc. v. Micron Technology, Inc., et al.* , Case No. 2:05cv94 - Exhibit #22 to Complaint	Qu	INFRNG/NON-INFRNG	Admitted
CX	1646		Order Construing Disputed Claims and Terms in *Samsung Electronics Co., Ltd., v. Tessera Technologies, Inc.* , Case No. C 02-5837 CW - Exhibit #20 to Complaint	Qu / Griffin	INFRNG/NON-INFRNG, RMDY, OWNR	Admitted
CX	1647		Order on Cross-Motions for Summary Judgment on Patent Issues, TI's Motion to Dismiss and Tessera's Motion for Summary Judgment on Contract Issues in *Texas Instruments, Inc. v. Tessera, Inc* ., Case No. C-00-2114 CW - Exhibit #19 to Complaint	Griffin / Ivey	RMDY, OWNR, VLD/INVLD	Admitted
CX	1648		Order on Parties' Cross Motions for Summary Judgment and Defendants' Motion to Amend in *Samsung Electronics Co., Ltd., v. Tessera Technologies, Inc.,* Case No. C 02-5837 CW - Exhibit #21 to Complaint	Griffin	RMDY, OWNR	Admitted
CX	1649					Withdrawn
CX	1650					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1651					Withdrawn
CX	1652		Initial Determination in the Matter of Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same, ITC Inv. No. 432 - Public Version - Exhibit #7 to Complaint	Qu / Ivey / Pickett	INFRNG/NON-INFRNG, Invalid, OWNR, RMDY	Admitted
CX	1653	C	Order #13 - Initial Determination in the Matter of Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same, ITC Inv. No. 432 - Confidential - Exhibit #3 to Complaint	Mitchell	RMDY, DI	Admitted
CX	1654		Order Construing Claims in Texas Instruments, Inc. v. Tessera, Inc., Case No. C-00-2114 CW - Exhibit #18 to Complaint	Qu / Griffin	INFRNG/NON-INFRNG, RMDY, OWNR	Admitted
CX	1655	C	Khandros Notebook	Ivey	VLD/INVLD	Admitted
CX	1656					Withdrawn
CX	1657					Withdrawn
CX	1658	C	Bottoms Up Database	Mitchell	RMDY, DI	Admitted
CX	1659					Withdrawn
CX	1660		Tessera 10-K	Mitchell	RMDY, DI	Admitted
CX	1661		Tessera 10-Q	Mitchell	RMDY, DI	Admitted
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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

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CX	1779					Withdrawn
CX	1780					Withdrawn
CX	1781					Withdrawn
CX	1782					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1783					Withdrawn
CX	1784					Withdrawn
CX	1785					Withdrawn
CX	1786					Withdrawn
CX	1787					Withdrawn
CX	1788					Withdrawn
CX	1789					Withdrawn
CX	1790					Withdrawn
CX	1791(A)					Withdrawn
CX	1791(B)					Withdrawn
CX	1791(C)					Withdrawn
CX	1791(D)					Withdrawn
CX	1791(E)					Withdrawn
CX	1792					Withdrawn
CX	1793(A)					Withdrawn
CX	1793(B)					Withdrawn
CX	1794					Withdrawn
CX	1795(A)					Withdrawn
CX	1795(B)					Withdrawn
CX	1796					Withdrawn
CX	1797					Withdrawn
CX	1798					Withdrawn
CX	1799					Withdrawn
CX	1800					Withdrawn
CX	1801					Withdrawn
CX	1802					Withdrawn
CX	1803					Withdrawn
CX	1804					Withdrawn
CX	1805					Withdrawn
CX	1806(A)					Withdrawn
CX	1806(B)					Withdrawn
CX	1807					Withdrawn
CX	1808					Withdrawn
CX	1809					Withdrawn
CX	1810					Withdrawn
CX	1811					Withdrawn
CX	1812					Withdrawn
CX	1813					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1814					Withdrawn
CX	1815					Withdrawn
CX	1816					Withdrawn
CX	1817					Withdrawn
CX	1818					Withdrawn
CX	1819					Withdrawn
CX	1820					Withdrawn
CX	1821					Withdrawn
CX	1822					Withdrawn
CX	1823					Withdrawn
CX	1824					Withdrawn
CX	1825					Withdrawn
CX	1826					Withdrawn
CX	1827					Withdrawn
CX	1828					Withdrawn
CX	1829					Withdrawn
CX	1830	C	ATI's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1831	C	Freescale's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1832	C	Motorola's Amended Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1833	C	Motorola's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1834	C	Qualcomm's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1835					Withdrawn
CX	1836	C	Spansion's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1837	C	STM's Supplemental Response to Tessera's Fifth Set of Interrogatories (#32-43)	Stipulation	Importation, Remedies	Admitted
CX	1838	C	STM's Supplemental Response to Tessera's Second Set of Interrogatories	Stipulation	Importation, Remedies	Admitted
CX	1839	C	STM's Supplemental Response to Tessera's Seventh Set of Interrogatories (#71-101)	Stipulation	Importation, Remedies	Admitted
CX	1840	C	STM's Supplemental Response to Tessera's Sixth Set of Interrogatories	Stipulation	Importation, Remedies	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1841	C	Supplemental Responses of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Duces Tecum	Mitchell and/or Pickett	Importation, Remedies	Admitted
CX	1842					Withdrawn
CX	1843					Withdrawn
CX	1844					Withdrawn
CX	1845					Withdrawn
CX	1846					Withdrawn
CX	1847	C	Spansion Inventory Report	Stipulation	Importation, Remedies	Admitted
CX	1848					Withdrawn
CX	1849					Withdrawn
CX	1850					Withdrawn
CX	1851					Withdrawn
CX	1852					Withdrawn
CX	1853		Freescale Form 10-Q for the Period Ending 09/28/07	Stipulation	Importation, Remedies	Admitted
CX	1854		Motorola 2007 Financial Analyst Update	Brda	RMDY	Admitted
CX	1855		Motorola Form 10-K for the Period Ending 12/31/06	Stipulation	Importation, Remedies	Admitted
CX	1856		Motorola Inc Q4 Earnings Call Transcript	Brda	RMDY	Admitted
CX	1857					Withdrawn
CX	1858					Withdrawn
CX	1859		Murray Exhibit #3: Pages from the Freescale website related to Manufacturing	Murray		Admitted
CX	1860		Qualcomm 10-K for the Fisal Year Ended Septemer 30, 2007	Stipulation	Importation, Remedies	Admitted
CX	1861		Qualcomm 10-Q for the Quarter Ended December 31, 2007	Stipulation	Importation, Remedies	Admitted
CX	1862		Qualcomm Form 10-K for the Period Ending 09/30/07	Qu	INFRNG/NON-INFRNG	Admitted
CX	1863		Qualcomm Form 10-Q for the Period Ending 04/01/07	Stipulation	Importation, Remedies	Admitted
CX	1864					Withdrawn
CX	1865					Withdrawn
CX	1866					Withdrawn
CX	1867					Withdrawn
CX	1868					Withdrawn
CX	1869					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1870					Withdrawn
CX	1871					Withdrawn
CX	1872					Withdrawn
CX	1873					Withdrawn
CX	1874					Withdrawn
CX	1875					Withdrawn
CX	1876					Withdrawn
CX	1877					Withdrawn
CX	1878	C	Motorola Personal Communications Sector, CTE - Materials & Failure Analysis Laboratory	Qu	Infrng/Non-infrng	Admitted
CX	1879	C	4-Dimensional Design Optimization of System-In-Package with CAE - PPT with BGA Package Structure	Qu	Infrng/Non-infrng	Admitted
CX	1880	C	9/23/97 Email - Die Attach	Qu	Infrng/Non-infrng	Admitted
CX	1881	C	Advanced Assembly and Substrate Design Rules Manual for Mixed Interconnect Modules BGA/LGA	Qu	Infrng/Non-infrng	Admitted
CX	1882	C	ANSYS Input files used in ST's FEA analysis of BGA packages (file paths:\STITC00122311\INTERPOSER2\DESIGN1A.MAC and DESIGN1F.MAC)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1883	C	BGA Board Level Interconnect Reliability - PPT with BGA Package Structure	Qu	Infrng/Non-infrng	Admitted
CX	1884	C	Board Level Solder Joint Reliability Analysis and Optimization of Pyramidal Stacked Die BGA Packages	Qu	Infrng/Non-infrng	Admitted
CX	1885	C	Board Level Solder Joint Reliability Analysis of Stacked Die Mixed Flip-Chip and Wirebond BGA	Qu	Infrng/Non-infrng	Admitted
CX	1886	C	Board Level Solder Joint Reliability Modeling and Testing of TFBGA Packages for Telecommunication Applications	Qu	Infrng/Non-infrng	Admitted
CX	1887	C	Board Level Solder Joint Reliability Modeling and Testing of TFBGA Packages for Telecommunication Applications	Qu	Infrng/Non-infrng	Admitted
CX	1888	C	Built Sheet Assembly for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1889	C	Built Sheet Assembly for G52K*V440CAJ (STLC2500C)	Qu	Infrng/Non-infrng	Admitted
CX	1890	C	Built Sheet Assembly for M36L0R8060B7ZAQ	Qu	Infrng/Non-infrng	Admitted
CX	1891	C	Built Sheet Assembly for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
CX	1892	C	Built Sheet Assembly for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1893	C	Built Sheet Assembly for RL ADSY*N9YC8K9 (NAND512R3A2BZA6F)	Qu	Infrng/Non-infrng	Admitted
CX	1894	C	Built Sheet Assembly for RL FD2Z*5M5FS99 (M36P0R9070E0ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1895	C	Built Sheet Assembly for RL FD2Z*5M5GS99 (M36P0R9060E0ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1896	C	Built Sheet Assembly for RL ND2Z*5M9PA99 (M36P0R9070E1ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1897	C	Built Sheet Assembly for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1898	C	Built Sheet Assembly for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1899	C	Built Sheet Assembly for XCOZ*W4QN5KO (XCOZW4QN5KOT706U)	Qu	Infrng/Non-infrng	Admitted
CX	1900	C	Built Sheet Assembly for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1901	C	Comprehensive Design Analysis of QFN and Power QFN Packages for Enhanced Board Level Solder Joint Reliability	Qu	Infrng/Non-infrng	Admitted
CX	1902	C	CSP at ST Microelectronics	Qu	Infrng/Non-infrng	Admitted
CX	1903	C	Design Analysis and Optomization for Wirebond Stacked Die BGA Packages for Improved Board Level Solder Joint Reliabillity	Qu	Infrng/Non-infrng	Admitted
CX	1904	C	Design Analysis of QFN Package for Enhanced Solder Joint Reliability	Qu	Infrng/Non-infrng	Admitted
CX	1905	C	Design Analysis of Solder Joint Reliability for Stacked Die Mixed Flip-Chip and Wirebond BGA	Qu	Infrng/Non-infrng	Admitted
CX	1906	C	Design for Package with Board Level Reliabilty with CAE	Qu	Infrng/Non-infrng	Admitted
CX	1907	C	Development and Application of Lead-Free Solder Joint Fatigue Model for CSP	Qu	Infrng/Non-infrng	Admitted
CX	1908	C	Email from Laurent Herard attaching ST-NV TFBGA Development, Project Update, March 1999 - PPT with BGA Package Structure	Qu	INFRNG/NON-INFRNG	Admitted
CX	1909	C	Email message; Task Force BGA Material Cost, notes of Second Meeting in Grenoble, France, dated June 26, 1997; Journal Article mentioning Tessera Licensees	Qu	INFRNG/NON-INFRNG	Admitted
CX	1910					Withdrawn
CX	1911	C	Fine Pitch Ball Grid Array (fpBGA) Assembly Flow Chart in ASAT (HK)	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1912	C	Integrated Modeling and Testing of Fine-Pitch CSP Under Board Level Drop Test, Bend Test, and Thermal Cycling Test	Qu	Infrng/Non-infrng	Admitted
CX	1913	C	July 1, 1997 Email from Luc Mary (ST-NV) to Jacques Ferrera (ST-NV)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1914	C	July 29, 1999 Email from Patrick Perillat to Laurent Herard	Qu	INFRNG/NON-INFRNG	Admitted
CX	1915	C	June 22, 1997 Email - uBGA	Qu	Infrng/Non-infrng	Admitted
CX	1916	C	Mount & Bond Diagram for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1917	C	Mount & Bond Diagram for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1918	C	Mount & Bond Diagram for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1919	C	Mount & Bond Diagram for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1920	C	Mount & Bond Diagram for XCAIP5JF5KOB706F	Qu	Infrng/Non-infrng	Admitted
CX	1921	C	Mount & Bond Diagram for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1922	C	November 5, 1999 Email from Laurent Herard to Robert Bronner and Andre Clement	Qu	INFRNG/NON-INFRNG	Admitted
CX	1923	C	Package Outline Assembly for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1924	C	Package Outline Assembly for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1925	C	Package Outline Assembly for M36L0R8060B7ZAQ	Qu	Infrng/Non-infrng	Admitted
CX	1926	C	Package Outline Assembly for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1927	C	Package Outline Assembly for MDR05363A99T705U	Qu	Infrng/Non-infrng	Admitted
CX	1928	C	Package Outline Assembly for TFBGA 8x11x1.20 (M36P0R9060E0ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1929	C	Package Outline Assembly for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1930	C	Package Outline Assembly for WFBGA 4.5x4.5x0.8 (STLC2500C)	Qu	Infrng/Non-infrng	Admitted
CX	1931	C	Package Outline Assembly for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1932	C	Product Specification for ADSY*N9YC8K8 in Manufacturing Phase T&F (NAND512R3A2BZA6F)	Qu	Infrng/Non-infrng	Admitted
CX	1933					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1934	C	SGS Thompson Training Schedule and Cover Letter, 1997	Qu	Infrng/Non-infrng	Admitted
CX	1935	C	ST Datasheet for M36W0R6040T0 et al. (M36WOR6040T1ZAQF)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1936	C	ST Datasheet for M39P0R9070E0 (M39POR9070E2ZADF / M39POR9070E4ZADF)	Qu	Infrng/Non-infrng	Admitted
CX	1937	C	ST Datasheet for NAND512-A et al. (NAND512R3A2BZA6F)	Qu	Infrng/Non-infrng	Admitted
CX	1938	C	ST Datasheet for STLC2500C (STLC2500C)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1939	C	ST Datasheet for STLC2590 (STLC2590)	Qu	Infrng/Non-infrng	Admitted
CX	1940	C	ST Datasheet for STLC2592 (STLC2592)	Qu	Infrng/Non-infrng	Admitted
CX	1941	C	ST Datasheet for STw4141 (STW41411/T)	Qu	Infrng/Non-infrng	Admitted
CX	1942					Withdrawn
CX	1943	C	Substrate Technical Specs. For M36L0R8060B7ZAQ	Qu	Infrng/Non-infrng	Admitted
CX	1944	C	Substrate Technical Specs. for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1945	C	Substrate Technical Specs. for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1946	C	TCD-TFBGA121 Daisy Chain Package Datasheet	Qu	Infrng/Non-infrng	Admitted
CX	1947					Withdrawn
CX	1948					Withdrawn
CX	1949					Withdrawn
CX	1950		A Complete Vision in Smartcard Technology	Qu	Infrng/Non-infrng	Admitted
CX	1951	C	BGA Substrate Technology Roadmap 2006 Rev. 2.0, Corporate Packaging & Automation	Qu	Infrng/Non-infrng	Admitted
CX	1952		CEA signs research contract with the partners of the Crolles2 Alliance for development of 45 nm and 32 nm CMOS nanoelectric technologies	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
CX	1953		Consortium of Semiconductor and Consumer Electronics Companies Unveils Complete Joint Proposal for IEEE 802.11 Task Group N	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
CX	1954					Withdrawn
CX	1955					Withdrawn
CX	1956					Withdrawn
CX	1957					Withdrawn
CX	1958					Withdrawn
CX	1959					Withdrawn
CX	1960					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1961					Withdrawn
CX	1962					Withdrawn
CX	1963					Withdrawn
CX	1964					Withdrawn
CX	1965		Enhanced efficiency and data security in health care 9,000,000 health cards for Lombardy	Tessera Designee	Vldy/Invldy	Admitted
CX	1966					Withdrawn
CX	1967		Infineon, Philips, and ST Welcome Freescale to E3 lead-free initiative	Qu	Infrng/Non-infrng, Remedy	Admitted
CX	1968		Interfacial Reaction and Shear Strength of Pb-free SnAg2.5Cu0.8Sb0.5 and SnAg3.0Cu0.5Sb0.2 Solder Bumps on Au/Ni(P) Metallization	Qu	INFRNG/NON-INFRNG	Admitted
CX	1969	C	Leadfree PBGA Balls Soldering Quality Improvement for Ni-Au BGA pads	Qu	INFRNG/NON-INFRNG	Admitted
CX	1970	C	Materials and Process Considerations for Lead-Free Electronic Assembly	Qu	INFRNG/NON-INFRNG	Admitted
CX	1971		Mechanical Properties of Lead-Free Solders	Qu	Infrng/Non-infrng	Admitted
CX	1972		Motorola and SGS-Thomson to Provide Interoperability of Microcontrollers for Contactless Smartcards and Readers	Qu	Infrng/Non-infrng	Admitted
CX	1973		Motorola, Philips and STMicroelectronics Introduces Debut Industry's First 90-Nanometer CMOS Design Platform	Qu	Infrng/Non-infrng	Admitted
CX	1974	C	Package Outline Assembly for LFBGA 16x16x1.7 (Package Code HY)	Qu	Infrng/Non-infrng	Admitted
CX	1975					Withdrawn
CX	1976		Pilot Technical Datasheet for Ablebond 2025D	Qu	INFRNG/NON-INFRNG	Admitted
CX	1977		Pilot Technical Datasheet for Ablebond 2300	Qu	Infrng/Non-infrng	Admitted
CX	1978	C	Presentation: Thermal-mechanical Simulation of Cu/Low-k FCBGA	Qu	INFRNG/NON-INFRNG	Admitted
CX	1979					Withdrawn
CX	1980					Withdrawn
CX	1981					Withdrawn
CX	1982					Withdrawn
CX	1983					Withdrawn
CX	1984					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1985		Semiconductor Packaging Materials Product Selector Guide	Qu	Infrng/Non-infrng	Admitted
CX	1986		ST Website - "Talk with more intelligence"	Qu	Infrng/Non-infrng, Remedy	Admitted
CX	1987		ST Website - "We put more intelligence into everything"	Qu	Infrng/Non-infrng, Remedy	Admitted
CX	1988		ST Website - Glossary of Terms A-Z	Qu	Infrng/Non-infrng	Admitted
CX	1989		ST Website - Press Release - 16MBIT 3V Supply Flash Memory	Qu	Infrng/Non-infrng	Admitted
CX	1990		ST Website - Press Release - 8 MBIT 3v Supply Flash Memory	Qu	Infrng/Non-infrng	Admitted
CX	1991		ST Website - Products Index	Qu	Infrng/Non-infrng	Admitted
CX	1992		ST Website - Strategic Segments - "Behind Great Smartcards..."	Qu	Infrng/Non-infrng	Admitted
CX	1993		ST Website - Strategic Segments - "Inside Every Great Auto Design..."	Qu	Infrng/Non-infrng	Admitted
CX	1994		ST Website - Strategic Segments - "Inside Every Great Computer Design..."	Qu	Infrng/Non-infrng	Admitted
CX	1995		ST Website - Strategic Segments - "Inside Every Great Product Design..."	Qu	Infrng/Non-infrng	Admitted
CX	1996		ST Website - Strategic Segments - "Inside Great Wireless Systems..."	Qu	Infrng/Non-infrng	Admitted
CX	1997		ST Website - Technical Document - "STV0976 - 1.0 Megapixel SMIA Processor"	Qu	Infrng/Non-infrng	Admitted
CX	1998		ST Website - Technical Document - "STw5095 - Low Power Asynchronous Stereo Audio Codec with Integrated Power Amplifiers" Data Brief	Qu	INFRNG/NON-INFRNG	Admitted
CX	1999		ST Website - Testimonials - Altec Lansing - When Altec-Lansing Wanted to Bring Full Spectrum Sound to a Desktop ...ST's Systems'on-Silicon Struck All the Right Chords"	Qu	Infrng/Non-infrng	Admitted
CX	2000		ST Website - Testimonials - BMW - "We Helped the BMW Group Negotiate Technical Obstacles with our Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2001		ST Website - Testimonials - Bosch - "We Helped Bosch Accelerate the Move to Greener Diesel Engine Management With Our Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2002		ST Website - Testimonials - Bose -"We Helped Bosch Accelerate the Move to Greener Diesel Engine Management With Our Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2003		ST Website - Testimonials - HP - "When Hewlett-Packard Wanted to Distance Themselves From the Competition ST's Systems-on-Silicon Gave Them a Head Start"	Qu	Infrng/Non-infrng	Admitted
CX	2004		ST Website - Testimonials - Jeep - "We Helped The Jeep Platform Create Roadmaps to Systems Solutions with Our Advanced Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2005		ST Website - Testimonials - Lutron	Qu	Infrng/Non-infrng	Admitted
CX	2006		ST Website - Testimonials - Pace	Qu	Infrng/Non-infrng	Admitted
CX	2007		ST Website - Testimonials - Pioneer - "Pioneer Car Audion Sound Found the Road to Higher Powe with ST's Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2008		ST Website - Testimonials - RCA - "Now Showing! Theater-Quality Movies with RCA Digital TV's Featuring ST Systems on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2009		ST Website - Testimonials - Schlumberger	Qu	Infrng/Non-infrng	Admitted
CX	2010		ST Website - Testimonials - Scientific-Atlanta - "When Scientific-Atlanta wanted to get on the multimedia superhighway ... ST's Systems-on-Silicon helped to pave the way"	Qu	Infrng/Non-infrng	Admitted
CX	2011		ST Website - Testimonials - Siemens	Qu	Infrng/Non-infrng	Admitted
CX	2012		ST Website - Testimonials - Visa	Qu	Infrng/Non-infrng	Admitted
CX	2013		ST Website - Testimonials - Visteon	Qu	Infrng/Non-infrng	Admitted
CX	2014		STMicroelectronics and IDEX Announce Agreement to Develop Fingerprint Recognition and Pointer Technology for the Wireless Market	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2015		STMicroelectronics Announces Shipment of Two Million Chipsets for XM Satellite Radio Receivers; Delivers Latest System-on-Chip Solution	Qu	Remedy, Vldy/Invldy	Admitted
CX	2016		STMicroelectronics N.V. Company Presentation	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
CX	2017		STMicroelectronics Receives Best Supplier Award from Seagate	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2018					Withdrawn
CX	2019					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2020					Withdrawn
CX	2021		STMicroelectronics Rises in Buoyant Automotive Market	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2022		STMicroelectronics Ships 355,000 XM Satellite Radio Chipsets to Radio Manufacturers	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2023		STMicroelectronics Ships One-Millionth XM Satellite Radio Chipset to Radio Manufacturers	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2024		STMicroelectronics Sustainable Development Report 2003	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2025		Strategic Alliances and Industry Partnerships	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2026		STw5095 Low-power asynchronous stereo audio Codec with integrated power amplifiers Features	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2027		STw5095/E01 STw5095 evaluation board Features	Qu	INFRNG/NON-INFRNG	Admitted
CX	2028		Technical Datasheet for Hitachi Chemical Die Bonding Pastes	Qu	INFRNG/NON-INFRNG	Admitted
CX	2029		Technical Datasheet for Loctite Die Attach Materials	Qu	INFRNG/NON-INFRNG	Admitted
CX	2030					Withdrawn
CX	2031		Two More World Leaderships Confirmed for STMicroelectronics	Qu	Infrng/Non-infrng	Admitted
CX	2032		Unprecedented Alliance Created for Breakthrough Semiconductor R&D	Qu	Infrng/Non-infrng	Admitted
CX	2033					Withdrawn
CX	2034		World First for Sagem Communication and STMicroelectronics: First MPEG4 Set-Top Boxes Based on Single-Chip Video Decoder	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2035					Withdrawn
CX	2036					Withdrawn
CX	2037	C	Hundt Deposition - March 28, 2007 - Exhibit 233 - Email regarding Micro BGA Evaluation Test Plan	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2038	C	01/11/08 Letter from Nokia to Anthony Downs and suppl. response/objection with sales papers	Qu	Infrng/Non-infrng	Admitted
CX	2039	C	Hundt Deposition - March 28, 2007 - Exhibit 225 - Document entitled, "Solder Joint Reliability Modeling of Sirius Radio LBGA288"	Hundt	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2040		Hundt Deposition - March 28, 2007 - Exhibit 227 - Definitions - "Geometric Dimensions" and "Material Properties"	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2041	C	Hundt Deposition - March 29, 2007 - Exhibit 236 - Extract of Master Spreadsheet of BGA Shipments	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2042	C	Hundt Deposition - October 18, 2006 - Exhibit 7 - Dec. of Michael J. Hundt re So Called Exemplary Products	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2043	C	Hundt Deposition - October 18, 2006 - Exhibit 8 - Dec. of Michael J. Hundt pursuant to paragraph 1B& 2A of the 9-08-06 Order	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2044	C	Letter from David Young to Sony Ericsson attaching list with boxes drawn around accusable ST chips	Qu	Infrng/Non-infrng	Admitted
CX	2045	C	Letter From Nokia to Anthony Downs and response/objection with Attachment A listing respondents' chips in Nokia products	Qu	Infrng/Non-infrng	Admitted
CX	2046	C	Letter from Sony Ericsson to David Young attaching list of ST chips	Qu	Infrng/Non-infrng	Admitted
CX	2047	C	Letter from Sony Ericsson to David Young attaching spreadsheet of ST chips	Qu	Infrng/Non-infrng	Admitted
CX	2048					Withdrawn
CX	2049					Withdrawn
CX	2050					Withdrawn
CX	2051	C	Respondent Motorola, Inc.'s Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Stipulation	Infrng/Non-infrng	Admitted
CX	2052	C	Respondent Motorola, Inc.'s Fourth Amended Confidential Responses and Objections to Complainant Tessera's First set of Interrogatories (1-5)	Stipulation	Infrng/Non-infrng	Admitted
CX	2053	C	Respondent Motorola, Inc.'s Fourth Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-20)	Stipulation	Infrng/Non-infrng	Admitted
CX	2054	C	Respondent Motorola, Inc.'s Responses to Complainant Tessera's Amended Fifth Set of Interrogatories (32-79)	Stipulation	Infrng/Non-infrng	Admitted
CX	2055					Withdrawn
CX	2056	C	Respondent STMicroelectrics N.V.'s Responses to Tessera's Second Set of Interrogatorries (6 - 20)	Stipulation	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2057	C	Respondent STMicroelectronics N.V.'S Response to Tessera's Second Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	2058	C	Respondent STMicroelectronics N.V.'s First Amended Response to Tessera's First Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	2059	C	Respondent STMicroelectronics N.V.'s Response to Tessera's First Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	2060		Respondent STMicroelectronics N.V.'s Responses to Tessera's First Set of Interrogatories (1 - 5)	Stipulation	Infrng/Non-infrng	Admitted
CX	2061	C	Response and Objections of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Ad Tesitificandum (sic)	Qu	Infrng/Non-infrng	Admitted
CX	2062		Response and Objections of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Duces Tecum	Qu	Infrng/Non-infrng	Admitted
CX	2063		Response of ST-NV to the Complaint, as Supplemented, Under Section 337 of the Tariff Act of 1930, as Amended	Shah		Admitted
CX	2064		Seagate Technology LLC's Objections and Response to Subpoena Duces Tecum and Subpoena Ad Testificandum	Qu	Infrng/Non-infrng	Admitted
CX	2065					Withdrawn
CX	2066	C	ST-NV's Response to Tessera's Seventh Set of Interrogatories, No. 71	Stipulation	Infrng/Non-infrng	Admitted
CX	2067	C	ST's 1st Amended Response to Tessera's First Set of Interrogatories, Nos. 1-5	Stipulation	Infrng/Non-infrng	Admitted
CX	2068	C	Supplemental Responses of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Duces Tecum	Qu	Infrng/Non-infrng	Admitted
CX	2069					Withdrawn
CX	2070					Withdrawn
CX	2071					Withdrawn
CX	2072	C	Chart of Top Parent, Supplier Parent, Part descriptions	Stipulation	Importation, Remedies	Admitted
CX	2073	C	Network Business Segment Motorola Part Numbers	Stipulation	Importation, Remedies	Admitted
CX	2074	C	*Spreadsheet showing import entry data*	Stipulation	Importation, Remedies	Admitted
CX	2075	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2076	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2077	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2078	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2079	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2080	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2081	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2082	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2083	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2084	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2085	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2086	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2087	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2088	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2089	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2090	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2091	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2092	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2093	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2094	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2095	C	Spreadsheet showing monthly sales for various parts for 2007	Stipulation	Importation, Remedies	Admitted
CX	2096					Withdrawn
CX	2097					Withdrawn
CX	2098					Withdrawn
CX	2099	C	ATI's Amended Responses to Tessera's First Set of Interrogatories (#1, 2, 3 and 5)	Stipulation	Importation, Remedies	Admitted
CX	2100	C	ATI's Amended Responses to Tessera's Second Set of Interrogatores (#6-8, #10-12, 17, 19-20)	Stipulation	Importation, Remedies	Admitted
CX	2101		ATI's Responses to Tessera's Fifth Set of Interrogatories (#32-79)	Stipulation	Importation, Remedies	Admitted
CX	2102		ATI's Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2103	C	ATI's Responses to Tessera's First Set of Requests for Admissions (#1-3)	Stipulation	Importation, Remedies	Admitted
CX	2104	C	ATI's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2105	C	ATI's Second Amended Responses to Tessera's First Set of Interrogatories (#1, 2, 3 and 5)	Stipulation	Importation, Remedies	Admitted
CX	2106	C	ATI's Second Amended Responses to Tessera's Second Set of Interrogatores (#6-8, #10-12, 17, 19-20)	Stipulation	Importation, Remedies	Admitted
CX	2107		ATI's Supplemental Responses to Tessera's Fifth Set of Interrogatories (37-39, 41 and 42)	Stipulation	Importation, Remedies	Admitted
CX	2108	C	Frankel Deposition Exhibit #002, Qualcomm's Fourth Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Frankel	Importation, Remedies	Admitted
CX	2109	C	Freescale's Responses to Tessera's Amended Fifth Set of Interrogatories (#32-83)	Stipulation	Importation, Remedies	Admitted
CX	2110	C	Freescale's Responses to Tessera's First Request for Admissions (#1-3)	Stipulation	Importation, Remedies	Admitted
CX	2111	C	Freescale's Responses to Tessera's First Set of Interrogatories (#1-5) including attached Schedule A	Stipulation	Importation, Remedies	Admitted
CX	2112	C	Freescale's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2113	C	Freescale's Second Supplemental Responses to Tessera's First Set of Interrogatories (#1) including attached Schedule A	Stipulation	Importation, Remedies	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2114	C	Freescale's Supplemental Response to Tessera's First Request for Admissions (#2-3)	Stipulation	Importation, Remedies	Admitted
CX	2115	C	Freescale's Supplemental Responses to Tessera's First Set of Interrogatories (#1-5) including attached Schedule A	Montgomery	Importation, Remedies	Admitted
CX	2116	C	Freescale's Supplemental Responses to Tessera's Second Set of Interrogatories (#6-20)	Montgomery	Importation, Remedies	Admitted
CX	2117	C	Motorla's Supplemental Response to Tessera's Interrogatories #20, 32, 36, 40, and 51 including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2118	C	Motorola's Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices A-G	Stipulation	Importation, Remedies	Admitted
CX	2119	C	Motorola's Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2120	C	Motorola's Fourth Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2121	C	Motorola's Fourth Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2122	C	Motorola's Responses to Tessera's Amended Fifth Set of Interrogatories (32-79)	Stipulation	Importation, Remedies	Admitted
CX	2123	C	Motorola's Responses to Tessera's First Request for Admissions (#2-3)	Stipulation	Importation, Remedies	Admitted
CX	2124	C	Motorola's Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices A-G	Stipulation	Importation, Remedies	Admitted
CX	2125	C	Motorola's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2126	C	Motorola's Second Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2127	C	Motorola's Second Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2128	C	Motorola's Third Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2129	C	Motorola's Third Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2130	C	Qualcomm's Response to Tessera's First Request for Admissions (#1-4)	Stipulation	Importation, Remedies	Admitted
CX	2131	C	Qualcomm's Responses to Tessera's Amended Fifth Set of Interrogatories (#32-84)	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2132	C	Qualcomm's Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2133	C	Qualcomm's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2134	C	Qualcomm's Revised Appendix B in Response to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2135	C	Qualcomm's Second Revised Appendix A in Response to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2136	C	Qualcomm's Second Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2137	C	Qualcomm's Second Supplemental Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2138	C	Qualcomm's Supplemental Responses to Tessera's Amended Fifth Set of Interrogatories (#32-84)	Stipulation	Importation, Remedies	Admitted
CX	2139	C	Qualcomm's Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2140	C	Qualcomm's Supplemental Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2141	C	Qualcomm's Third Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2142	C	Spansion's Response to Tessera's First Request for Admissions (#1-3)	Stipulation	Importation, Remedies	Admitted
CX	2143	C	Spansion's Responses to Tessera's Fifth Set of Interrogatories (#32-79)	Stipulation	Importation, Remedies	Admitted
CX	2144	C	Spansion's Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2145	C	Spansion's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2146	C	Spansion's Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2147					Withdrawn
CX	2148					Withdrawn
CX	2149					Withdrawn
CX	2150					Withdrawn
CX	2151					Withdrawn
CX	2152					Withdrawn
CX	2153					Withdrawn
CX	2154					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2155					Withdrawn
CX	2156					Withdrawn
CX	2157	C	Amkor Reliability Test Report for CZBGA 10x10/179LD for Qual	Qu	Infrng/Non-infrng	Admitted
CX	2158	C	Amkor Reliability Test Report for SCSP 10x10/259 LD for Qual	Qu	Infrng/Non-infrng	Admitted
CX	2159	C	ASE Group Reliability Test Report for Qualification Test of STKLFBGA (10x10) 2591 for AMD	Qu	Infrng/Non-infrng	Admitted
CX	2160					Withdrawn
CX	2161					Withdrawn
CX	2162	C	Reliability Test Report for ATI Package VFBGA (10*10) 191L	Qu	Infrng/Non-infrng	Admitted
CX	2163	C	Reliability Test Report for Qualification Test of LFBGA (12X12) 272L	Qu	Infrng/Non-infrng	Admitted
CX	2164	C	Reliability Test Report for Qualification Test of STKLFBGA (10x10) 259L for ATI	Qu	Infrng/Non-infrng	Admitted
CX	2165	C	Reliability Test Report for Reliability Test of TFBGA (8x0) 104L for ATI	Qu	Infrng/Non-infrng	Admitted
CX	2166	C	SPIL Reliability Test Interim Report for ATI-CA STFBGA259(10x10)(LF)Device:W228 QUAL	Qu	Infrng/Non-infrng	Admitted
CX	2167	C	SPIL Reliability Test Report for ATI W2182 New Device Qual	Qu	Infrng/Non-infrng	Admitted
CX	2168					Withdrawn
CX	2169					Withdrawn
CX	2170					Withdrawn
CX	2171	C	2600BT.pdf	Qu	Infrng/Non-infrng	Admitted
CX	2172		Abletherm 2600BT.pdf	Qu	Infrng/Non-infrng	Admitted
CX	2173	C	Absorbond - Datasheet - Rev7.pdf	Qu	Infrng/Non-infrng	Admitted
CX	2174					Withdrawn
CX	2175					Withdrawn
CX	2176					Withdrawn
CX	2177					Withdrawn
CX	2178					Withdrawn
CX	2179					Withdrawn
CX	2180					Withdrawn
CX	2181					Withdrawn
CX	2182					Withdrawn
CX	2183					Withdrawn

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2184					Withdrawn
CX	2185					Withdrawn
CX	2186					Withdrawn
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CX	2220					Withdrawn
CX	2221					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2222					Withdrawn
CX	2223					Withdrawn
CX	2224					Withdrawn
CX	2225					Withdrawn
CX	2226					Withdrawn
CX	2227					Withdrawn
CX	2228					Withdrawn
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CX	2255					Withdrawn
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CX	2258					Withdrawn
CX	2259					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2260					Withdrawn
CX	2261					Withdrawn
CX	2262					Withdrawn
CX	2263					Withdrawn
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CX	2297					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2298					Withdrawn
CX	2299					Withdrawn
CX	2300					Withdrawn
CX	2301					Withdrawn
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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2336					Withdrawn
CX	2337					Withdrawn
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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2374					Withdrawn
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CX	2393					Withdrawn
CX	2394					Withdrawn
CX	2395					Withdrawn
CX	2396					Withdrawn
CX	2397					Withdrawn
CX	2398					Withdrawn
CX	2399					Withdrawn
CX	2400					Withdrawn
CX	2401					Withdrawn
CX	2402					Withdrawn
CX	2403					Withdrawn
CX	2404					Withdrawn
CX	2405	C	Product Description for Ablebond 2100A, Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2406	C	Product Description for Ablebond 2100A, Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2407	C	Product Description for Ablebond 8360, Electrically Conductive Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2408	C	Product Description for Ablebond 8510AA, Fast Cure Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2409					Withdrawn
CX	2410					Withdrawn
CX	2411					Withdrawn
CX	2412					Withdrawn
CX	2413					Withdrawn
CX	2414					Withdrawn
CX	2415					Withdrawn
CX	2416					Withdrawn
CX	2417					Withdrawn
CX	2418					Withdrawn
CX	2419					Withdrawn
CX	2420					Withdrawn
CX	2421					Withdrawn
CX	2422					Withdrawn
CX	2423					Withdrawn
CX	2424					Withdrawn
CX	2425					Withdrawn
CX	2426					Withdrawn
CX	2427	C	98K03 LAA064 1mm FBGA Package.Qualification	Qu	Infrng/Non-infrng	Admitted
CX	2428	C	98K03 LAA064 1mm FBGA Package Qualification RQ4688	Qu	Infrng/Non-infrng	Admitted
CX	2429					Withdrawn
CX	2430					Withdrawn
CX	2431					Withdrawn
CX	2432					Withdrawn
CX	2433	C	LAA064 Package Qualification	Qu	Infrng/Non-infrng	Admitted
CX	2434	C	PDL128G Package Options by Valluri and Suresh	Qu	Infrng/Non-infrng	Admitted
CX	2435	C	Reliability Qualification re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2436	C	Reliability Qualification re Package LAA064	Qu	Infrng/Non-infrng	Admitted
CX	2437					Withdrawn
CX	2438					Withdrawn
CX	2439					Withdrawn
CX	2440					Withdrawn
CX	2441					Withdrawn
CX	2442					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2443	C	Email string from A. Simphliphan to Various Recipients re D/A design rules evaluation (Sent 5:08 AM)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	2444					Withdrawn
CX	2445					Withdrawn
CX	2446					Withdrawn
CX	2447					Withdrawn
CX	2448					Withdrawn
CX	2449					Withdrawn
CX	2450					Withdrawn
CX	2451					Withdrawn
CX	2452					Withdrawn
CX	2453					Withdrawn
CX	2454					Withdrawn
CX	2455					Withdrawn
CX	2456					Withdrawn
CX	2457					Withdrawn
CX	2458					Withdrawn
CX	2459					Withdrawn
CX	2460					Withdrawn
CX	2461					Withdrawn
CX	2462					Withdrawn
CX	2463					Withdrawn
CX	2464					Withdrawn
CX	2465					Withdrawn
CX	2466					Withdrawn
CX	2467					Withdrawn
CX	2468					Withdrawn
CX	2469					Withdrawn
CX	2470					Withdrawn
CX	2471					Withdrawn
CX	2472					Withdrawn
CX	2473					Withdrawn
CX	2474					Withdrawn
CX	2475					Withdrawn
CX	2476					Withdrawn
CX	2477					Withdrawn
CX	2478					Withdrawn
CX	2479					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2480					Withdrawn
CX	2481					Withdrawn
CX	2482					Withdrawn
CX	2483					Withdrawn
CX	2484					Withdrawn
CX	2485					Withdrawn
CX	2486					Withdrawn
CX	2487					Withdrawn
CX	2488					Withdrawn
CX	2489					Withdrawn
CX	2490					Withdrawn
CX	2491	C	Reliability Qualification re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2492	C	Technical Drawings re Package FEA/TSD 084	Qu	Infrng/Non-infrng	Admitted
CX	2493	C	Technical Drawings re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2494	C	Technical Drawings re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2495					Withdrawn
CX	2496					Withdrawn
CX	2497	C	Motorola's Third Amended Responses and Objections to Tessera's First Set of Interrogatories (1-5)	Stipulation	Importation, Remedies	Admitted
CX	2498					Withdrawn
CX	2499					Withdrawn
CX	2500					Withdrawn
CX	2501		Facsimile from J. Smith to R. Bowlby regarding Proposed License to Tessera patents	Pickett	RMDY, OWNR	Admitted
CX	2502					Withdrawn
CX	2503					Withdrawn
CX	2504					Withdrawn
CX	2505					Withdrawn
CX	2506					Withdrawn
CX	2507					Withdrawn
CX	2508					Withdrawn
CX	2509					Withdrawn
CX	2510					Withdrawn
CX	2511					Withdrawn
CX	2512					Withdrawn
CX	2513					Withdrawn
CX	2514					Withdrawn
CX	2515					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2516					Withdrawn
CX	2517					Withdrawn
CX	2518					Withdrawn
CX	2519					Withdrawn
CX	2520					Withdrawn
CX	2521					Withdrawn
CX	2522					Withdrawn
CX	2523					Withdrawn
CX	2524					Withdrawn
CX	2525					Withdrawn
CX	2526	C	Letter from L. Pfulghaupt to R. Warren regarding forwarding information about uBGA electronic chip packaging	Pickett	RMDY, OWNR	Admitted
CX	2527					Withdrawn
CX	2528					Withdrawn
CX	2529					Withdrawn
CX	2530					Withdrawn
CX	2531					Withdrawn
CX	2532					Withdrawn
CX	2533					Withdrawn
CX	2534					Withdrawn
CX	2535					Withdrawn
CX	2536					Withdrawn
CX	2537					Withdrawn
CX	2538					Withdrawn
CX	2539					Withdrawn
CX	2540					Withdrawn
CX	2541					Withdrawn
CX	2542					Withdrawn
CX	2543					Withdrawn
CX	2544					Withdrawn
CX	2545					Withdrawn
CX	2546					Withdrawn
CX	2547					Withdrawn
CX	2548					Withdrawn
CX	2549					Withdrawn
CX	2550					Withdrawn
CX	2551					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2552					Withdrawn
CX	2553					Withdrawn
CX	2554					Withdrawn
CX	2555					Withdrawn
CX	2556					Withdrawn
CX	2557					Withdrawn
CX	2558					Withdrawn
CX	2559					Withdrawn
CX	2560					Withdrawn
CX	2561					Withdrawn
CX	2562					Withdrawn
CX	2563					Withdrawn
CX	2564					Withdrawn
CX	2565					Withdrawn
CX	2566					Withdrawn
CX	2567					Withdrawn
CX	2568					Withdrawn
CX	2569					Withdrawn
CX	2570					Withdrawn
CX	2571					Withdrawn
CX	2572					Withdrawn
CX	2573					Withdrawn
CX	2574					Withdrawn
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CX	2576					Withdrawn
CX	2577					Withdrawn
CX	2578					Withdrawn
CX	2579					Withdrawn
CX	2580					Withdrawn
CX	2581					Withdrawn
CX	2582					Withdrawn
CX	2583					Withdrawn
CX	2584					Withdrawn
CX	2585					Withdrawn
CX	2586					Withdrawn
CX	2587					Withdrawn
CX	2588					Withdrawn
CX	2589					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2590					Withdrawn
CX	2591					Withdrawn
CX	2592	C	First Amendment to Intel and Tessera Limited TCC License Agreement	Pickett	RMDY, OWNR	Admitted
CX	2593	C	IBM/MHT/Tessera Confidentiality Agreement	Pickett	RMDY, OWNR	Admitted
CX	2594	C	Letter & Memorandum of Understanding between IBM & Tessera	Pickett	RMDY, OWNR	Admitted
CX	2595					Withdrawn
CX	2596					Withdrawn
CX	2597					Withdrawn
CX	2598	C	Claim Chart for Respondent ATI	Qu	INFRNG/NON-INFRNG	Admitted
CX	2599	C	Claim Chart for Respondent Freescale	Qu	INFRNG/NON-INFRNG	Admitted
CX	2600	C	Claim Chart for Respondent Motorola	Qu	INFRNG/NON-INFRNG	Admitted
CX	2601	C	Claim Chart for Respondent Qualcomm	Qu	INFRNG/NON-INFRNG	Admitted
CX	2602	C	Claim Chart for Respondent Spansion	Qu	INFRNG/NON-INFRNG	Admitted
CX	2603	C	Claim Chart for Respondent ST, N.V	Qu	INFRNG/NON-INFRNG	Admitted
CX	2604					Withdrawn
CX	2605		CX-2605 - Mawer "Plastic Ball Grid Array (PBGA)," Motorola Semiconductor Technical Data	Ivey / Sitaraman	VLD/INVLD, INFRNG/NON-INFRNG.	Admitted
CX	2606					Withdrawn
CX	2607	C	Witness Statement of Christopher Pickett	Pickett	OWNR	Admitted
CX	2608	C	CX-2608C - Witness Statement for Mitchell	Mitchell	RMDY, DI	Admitted
CX	2609	C	Witness Statement for Marucci	Marcucci	RMDY	Admitted
CX	2610					Withdrawn
CX	2611					Withdrawn
CX	2612					Withdrawn
CX	2613					Withdrawn
CX	2614	C	Suhir Deposition Exhibit #159, Declaration of Dr. Ephraim Suhir	Ivey	Vldy/Invldy	Admitted
CX	2615		Ablestik Semiconductor Packaging Materials Product Selector Guide	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2616		Ablestik Technical Data Sheet for Ablebond 2000 Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2617	C	Ablestik Pilot Technical Datasheet for Ablebond 2000B Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2618		Ablestik Technical Data Sheet for Ablebond 2000T Electrically Conductive Epoxy Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2619		Ablestik Technical Data Sheet for Ablebond 2025D High Performance Adhesive for Array Packaging	Qu	Infrng/Non-infrng	Admitted
CX	2620		Ablestik Technical Data Sheet for Ablebond 2025DSI High Reliability Non-Conductive Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2621		Ablestik Technical Data Sheet for Ablebond 2100A Electrically Conductive Adhestive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2622		Ablestik Technical Data Sheet for Ablebond 2300 Electrically Conductive Adhestive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2623		Ablestik Technical Data Sheet for Ablebond 8355F Electrically Conductie Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2624		Ablestik Technical Data Sheet for Ablebond 8510AA Fast Cure Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2625					Withdrawn
CX	2626		Loctite Technical Data Sheet for Hysol QMI 536, Non-Electrically Conductive Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2627	C	Loctite Technical Data Sheet for Hysol QMI 546 Non-Electrically Conductie Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2628		Ablestik Website List of Products	Qu	Infrng/Non-infrng	Admitted
CX	2629	C	Frankel Deposition Exhibit #008, Email from R. Tessitore to T. Gregorich	Frankel	RMDY	Admitted
CX	2630	C	2000-2000B-2100A-2300 Comparison	Qu	Infrng/Non-infrng	Admitted
CX	2631		Ablebond 2100A Technical Data Sheet	Qu	Infrng/Non-infrng	Admitted
CX	2632	C	Ablebond 2100A Data Package	Qu	Infrng/Non-infrng	Admitted
CX	2633	C	Ablestik 2053	Qu	Infrng/Non-infrng	Admitted
CX	2634	C	Hitachi CEL 9200	Qu	Infrng/Non-infrng	Admitted
CX	2635	C	Hitachi CEL 9200ZHF10FA, 9700HF10 9700ZHF10 Report	Qu	Infrng/Non-infrng	Admitted
CX	2636	C	CRM 1525 and 1580A	Qu	Infrng/Non-infrng	Admitted
CX	2637	C	CRM 1525 Thermal Die Attaches	Qu	Infrng/Non-infrng	Admitted
CX	2638	C	CRM 1525 Catalog	Qu	Infrng/Non-infrng	Admitted
CX	2639	C	CRM 1560 Catalog	Qu	Infrng/Non-infrng	Admitted
CX	2640	C	CRM 1580A and DC 7920 Material Properties	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2641	C	CRM 1580A Version 2	Qu	Infrng/Non-infrng	Admitted
CX	2642	C	CRM 1580A	Qu	Infrng/Non-infrng	Admitted
CX	2643	C	FH-900 Material Safety Data Sheet	Qu	Infrng/Non-infrng	Admitted
CX	2644	C	FH-900 Presentation	Qu	Infrng/Non-infrng	Admitted
CX	2645	C	Freescale Die Attach Thickness	Qu	Infrng/Non-infrng	Admitted
CX	2646	C	Sumitomo - G760 Material Specifications	Qu	Infrng/Non-infrng	Admitted
CX	2647	C	Hitachi CEL 9750HF 10 AK	Qu	Infrng/Non-infrng	Admitted
CX	2648	C	Hitachi Technical Data Sheet for CEL 9200HF 10 FA	Qu	Infrng/Non-infrng	Admitted
CX	2649	C	Hitachi E679 Lineup design guide	Qu	Infrng/Non-infrng	Admitted
CX	2650	C	Hitachi E679FBG	Qu	Infrng/Non-infrng	Admitted
CX	2651	C	Hitachi H230 Series (HS-231, HS-232) Product Description	Qu	Infrng/Non-infrng	Admitted
CX	2652	C	HS-231 and HS-232 Safety Data Sheet	Qu	Infrng/Non-infrng	Admitted
CX	2653		AMTECH Advanced SMT Solder Products, Product Data Sheet for Premium Case Bar Solder AMT 105	Qu	Infrng/Non-infrng	Admitted
CX	2654	C	Nitto GE-100L	Qu	Infrng/Non-infrng	Admitted
CX	2655	C	Nitto GE-100LFCS-V	Qu	Infrng/Non-infrng	Admitted
CX	2656	C	Sumitomo Bakelite Sumikon, EME-G760 Type SY	Qu	Infrng/Non-infrng	Admitted
CX	2657	C	Sumitomo Bakelite Sumikon, EME-G770	Qu	Infrng/Non-infrng	Admitted
CX	2658	C	Specification for HS-231	Qu	Infrng/Non-infrng	Admitted
CX	2659	C	Specification for HS-232	Qu	Infrng/Non-infrng	Admitted
CX	2660	C	Specification for FH-900T-40 Die Attach	Qu	Infrng/Non-infrng	Admitted
CX	2661	C	Specification for FH-900T-20 Die Attach	Qu	Infrng/Non-infrng	Admitted
CX	2662	C	Shinetsu Specification for Epoxy Molding Compound, KMC-358OLVA	Qu	Infrng/Non-infrng	Admitted
CX	2663	C	Shinetsu Material Safety Data Sheet for KMVC-358OLVA	Qu	Infrng/Non-infrng	Admitted
CX	2664	C	Markman Order (8 May 2007) in *Tessera, Inc. (USA) v. Amkor Technology, Inc. (USA)*, Case No ICC 14265/EBS	Qu	INFRNG/NON-INFRNG	Admitted
CX	2665	C	ATI's Responses to Tessera's Seventh Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2666					Withdrawn
CX	2667		ATI's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2668	C	Expert Rebuttal Report of Peter Ivey, Exhibit 5 - AMICON C 990 J SPEC 333 M 1, Technical Data Sheet for Electrically Conductive Epoxy Adhesive for Microelectronics	Ivey	VLD/INVLD	Admitted
CX	2669		Expert Rebuttal Report of Peter Ivey, Exhibit 6 - Declaration of Glenn Urbish in *In re Reexamination of U.S. Patent No. 6,433,419*	Ivey	VLD/INVLD	Admitted
CX	2670	C	Expert Rebuttal Report of Peter Ivey, Exhibit 8 - Tessera's Proposed Claim Constructions for the Disputed Claim Terms	Qu / Ivey	INFRNG/NON-INFRNG, VLD/INVLD	Admitted
CX	2671					Withdrawn
CX	2672	C	Freescale's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2673					Withdrawn
CX	2674					Withdrawn
CX	2675					Withdrawn
CX	2676					Withdrawn
CX	2677					Withdrawn
CX	2678					Withdrawn
CX	2679					Withdrawn
CX	2680		"Development of Low Elastic Modulus Die Attach Material and Clean Cure Process," by K. Suzuki, et al., Electronic Components and Technology Conference Proceedings, 40th	Ivey	VLD/INVLD	Admitted
CX	2681					Withdrawn
CX	2682		"Die Attach Reliability Prediction," K. Heinen, 1st International SAMPE Electronics Conference	Ivey	VLD/INVLD	Admitted
CX	2683		"Die Attachment Design and Its Influence on Thermal Stresses in the Die and the Attachment," by E. Suhir, Electronic Components Conference Proceedings, 37th	Ivey / Qu	INFRNG/NON-INFRNG, VLD/INVLD	Admitted
CX	2684					Withdrawn
CX	2685					Withdrawn
CX	2686		"Finite Element Analysis of Compliant Coating," by F. Shoraka, et al., Electronic Components Conference Proceedings, 38th IEEE 0569-5503/88/0000-0461	Ivey	VLD/INVLD	Admitted
CX	2687					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2688		"Flexible Silicone Adhesive with High Electrical Conductivity," by M. Lutz and R. Cole, Electronic Components Conference Proceedings, 39th, IEEE 0569-5503/89/0083	Ivey	VLD/INVLD	Admitted
CX	2689					Withdrawn
CX	2690		"High Reliability Mechanism of New Silicone Gel Sealing in Accelerated Environment Test," by K. Otsuka, et al., Proceedings of the Sixth Annual International Electronics Packaging Society Conference	Ivey	VLD/INVLD	Admitted
CX	2691					Withdrawn
CX	2692					Withdrawn
CX	2693		"Method of Testing Chips and Joining Chips to Substrates," F.E. Doany, et al., IBM Technical Disclosure Bulletin	Ivey	VLD/INVLD	Admitted
CX	2694		"Microelectronics Packaging Handbook," by R. Tummala and E. Rymaszewski	Ivey	VLD/INVLD	Admitted
CX	2695					Withdrawn
CX	2696					Withdrawn
CX	2697					Withdrawn
CX	2698					Withdrawn
CX	2699					Withdrawn
CX	2700		Freescale's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2701					Withdrawn
CX	2702					Withdrawn
CX	2703					Withdrawn
CX	2704					Withdrawn
CX	2705					Withdrawn
CX	2706					Withdrawn
CX	2707					Withdrawn
CX	2708					Withdrawn
CX	2709		Hinrichsmeyer, IBM Technical Disclosure Bulletin	Ivey	VLD/INVLD	Admitted
CX	2710		"Stress Management Via Low Modulus Urethane Adhesives for Electronic Applications," by J. Vaccaro, Hybrid Circuit Technology	Ivey	VLD/INVLD	Admitted
CX	2711					Withdrawn
CX	2712					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2713					Withdrawn
CX	2714					Withdrawn
CX	2715					Withdrawn
CX	2716					Withdrawn
CX	2717					Withdrawn
CX	2718					Withdrawn
CX	2719					Withdrawn
CX	2720					Withdrawn
CX	2721					Withdrawn
CX	2722					Withdrawn
CX	2723		Amendment (traversing rejections) for '419 patent	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2724					Withdrawn
CX	2725		Declaration of Glenn Urbish in '419 Patent Reexamination	Urbish	INFRNG/NON-INFRNG	Admitted
CX	2726					Withdrawn
CX	2727					Withdrawn
CX	2728					Withdrawn
CX	2729					Withdrawn
CX	2730					Withdrawn
CX	2731					Withdrawn
CX	2732					Withdrawn
CX	2733					Withdrawn
CX	2734					Withdrawn
CX	2735					Withdrawn
CX	2736					Withdrawn
CX	2737					Withdrawn
CX	2738					Withdrawn
CX	2739					Withdrawn
CX	2740					Withdrawn
CX	2741		Expert Rebuttal Report of Peter Ivey, Exhibit 1 - CV of Professor Peter Ivey	Ivey	VLD/INVLD	Admitted
CX	2742		Expert Rebuttal Report of Peter Ivey, Exhibit 2 - Materials Considered	Ivey	VLD/INVLD	Admitted
CX	2743					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2744					Withdrawn
CX	2745					Withdrawn
CX	2746					Withdrawn
CX	2747					Withdrawn
CX	2748					Withdrawn
CX	2749					Withdrawn
CX	2750					Withdrawn
CX	2751					Withdrawn
CX	2752					Withdrawn
CX	2753					Withdrawn
CX	2754					Withdrawn
CX	2755					Withdrawn
CX	2756					Withdrawn
CX	2757					Withdrawn
CX	2758		Japanese Patent Application No. 61-177759 (Okinaga) (including translation)	Ivey	VLD/INVLD	Admitted
CX	2759					Withdrawn
CX	2760					Withdrawn
CX	2761		Japanese Unexamined Patent Application No. 63-51196 (Saito) (including translation)	Ivey	VLD/INVLD	Admitted
CX	2762					Withdrawn
CX	2763					Withdrawn
CX	2764					Withdrawn
CX	2765		Motorola's Responses and Objections to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2766		Notice of Allowability (approving Asserted Claims for Issue)	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2767					Withdrawn
CX	2768					Withdrawn
CX	2769					Withdrawn
CX	2770					Withdrawn
CX	2771					Withdrawn
CX	2772					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2773		Patent Office, Ex Parte Reexamination Filing Data	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2774		Patent Office, Inter Partes Reexamination Filing Data	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2775					Withdrawn
CX	2776					Withdrawn
CX	2777	C	Qualcomm's Response to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2778					Withdrawn
CX	2779					Withdrawn
CX	2780					Withdrawn
CX	2781					Withdrawn
CX	2782					Withdrawn
CX	2783		Respondents' Proposed Construction of Disputed Claim Terms	Ivey	VLD/INVLD	Admitted
CX	2784					Withdrawn
CX	2785		Response to Official Action regarding Reexamination of '419 patent	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2786		Spansion's Responses to Tessera's Third Set of Interrogatories (21-30), August 29, 2007	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2787		Spansion's Responses to Tessera's Third Set of Interrogatories (21, 23), December 7, 2007	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2788		STMicroelectronic's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2789		Supplemental Declaration of Ephraim Suhir in the Reexamination of U.S. Patent No. 6,433,419	Ivey, Mitchell and/or Griffin	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2790		Tessera Supplemental Response in Reexamination of '419 patent	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2791	C	Tessera's First Supplemental Objections and Responses to Freescale's First Set of Interrogatories	Schaper	VLD/INVLD	Admitted
CX	2792					Withdrawn
CX	2793					Withdrawn
CX	2794					Withdrawn
CX	2795		U.S. Patent Application No. 07/586,758	Ivey	VLD/INVLD	Admitted
CX	2796		U.S. Patent Application No. 07/673,020	Ivey	VLD/INVLD	Admitted
CX	2797					Withdrawn
CX	2798					Withdrawn
CX	2799					Withdrawn
CX	2800					Withdrawn
CX	2801					Withdrawn
CX	2802		U.S. Patent No. 4,601,526 (White, et al.)	Ivey	VLD/INVLD	Admitted
CX	2803					Withdrawn
CX	2804					Withdrawn
CX	2805		U.S. Patent No. 4,700,276 (Freyman et al.)	Ivey	VLD/INVLD	Admitted
CX	2806					Withdrawn
CX	2807					Withdrawn
CX	2808					Withdrawn
CX	2809					Withdrawn
CX	2810					Withdrawn
CX	2811					Withdrawn
CX	2812					Withdrawn
CX	2813					Withdrawn
CX	2814					Withdrawn
CX	2815					Withdrawn
CX	2816					Withdrawn
CX	2817		U.S. Patent No. 4,975,765 (Ackerman, et al.)	Ivey	VLD/INVLD	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2818					Withdrawn
CX	2819					Withdrawn
CX	2820					Withdrawn
CX	2821					Withdrawn
CX	2822					Withdrawn
CX	2823		U.S. Patent No. 5,216,278 (Lin)	Sitaraman / Ivey	INFRNG/NON-INFRNG, VLD/INVLD	Admitted
CX	2824		U.S. Patent No. 5,241,133 (Mullen)	Freyman / Urbish	INFRNG/NON-INFRNG	Admitted
CX	2825					Withdrawn
CX	2826					Withdrawn
CX	2827					Withdrawn
CX	2828		U.S. Patent No. 5,679,977	Griffin / Ivey	RMDY, OWNR, VLD/INVLD	Admitted
CX	2829					Withdrawn
CX	2830					Withdrawn
CX	2831					Withdrawn
CX	2832					Withdrawn
CX	2833					Withdrawn
CX	2834					Withdrawn
CX	2835					Withdrawn
CX	2836					Withdrawn
CX	2837	C	Tessera, Inc.'s Objections and Responses to Spansion Inc. and Spansion LLC's First Set of Interrogatories (16), July 23, 2007	Schaper	VLD/INVLD	Admitted
CX	2838					Withdrawn
CX	2839					Withdrawn
CX	2840					Withdrawn
CX	2841					Withdrawn
CX	2842					Withdrawn
CX	2843					Withdrawn
CX	2844					Withdrawn
CX	2845					Withdrawn
CX	2846					Withdrawn
CX	2847					Withdrawn
CX	2848					Withdrawn
CX	2849					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2850					Withdrawn
CX	2851					Withdrawn
CX	2852					Withdrawn
CX	2853					Withdrawn
CX	2854					Withdrawn
CX	2855					Withdrawn
CX	2856					Withdrawn
CX	2857					Withdrawn
CX	2858					Withdrawn
CX	2859					Withdrawn
CX	2860					Withdrawn
CX	2861					Withdrawn
CX	2862					Withdrawn
CX	2863					Withdrawn
CX	2864					Withdrawn
CX	2865					Withdrawn
CX	2866		R&D Magazine article, 100 Most Technologically Significant Products of theYear	Ivey	OWNR	Admitted
CX	2867		"High Density Plastic 672-pin Package Enhances the HG72G/E Gate Array and Embedded Array Family," Hitachi	Ivey	OWNR	Admitted
CX	2868		Electronic Design, "Chip-Scale Packages Bridge the Gap Between Bare Die and BGAs"	Ivey	OWNR	Admitted
CX	2869					Withdrawn
CX	2870		1995 Milton S. Kiver Awards: "And the Winners Are..."	Ivey	OWNR	Admitted
CX	2871		1996 Solid State Technology magazine article	Ivey	OWNR	Admitted
CX	2872					Withdrawn
CX	2873		1996 Electronic News article on Intel's adoption of Tessera technology	Ivey	OWNR	Admitted
CX	2874		1996 Electronic News article on Intel's adoption of Tessera technology	Ivey	OWNR	Admitted
CX	2875		The Red Herring - "The Top 100 Technology Companies 1997"	Ivey	OWNR	Admitted
CX	2876					Withdrawn
CX	2877					Withdrawn
CX	2878					Withdrawn
CX	2879					Withdrawn
CX	2880					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2881					Withdrawn
CX	2882					Withdrawn
CX	2883					Withdrawn
CX	2884					Withdrawn
CX	2885					Withdrawn
CX	2886					Withdrawn
CX	2887					Withdrawn
CX	2888		TESST 017178	Ivey	OWNR	Admitted
CX	2889					Withdrawn
CX	2890					Withdrawn
CX	2891					Withdrawn
CX	2892(A)					Withdrawn
CX	2892(B)					Withdrawn
CX	2892(C)					Withdrawn
CX	2892(D)		Advanced Packaging Award for Best New Product in Package Design and Analysis to Tessera	Ivey	VLD/INVLD	Admitted
CX	2892(E)					Withdrawn
CX	2893					Withdrawn
CX	2894					Withdrawn
CX	2895					Withdrawn
CX	2896					Withdrawn
CX	2897					Withdrawn
CX	2898					Withdrawn
CX	2899					Withdrawn
CX	2900					Withdrawn
CX	2901					Withdrawn
CX	2902					Withdrawn
CX	2903					Withdrawn
CX	2904					Withdrawn
CX	2905					Withdrawn
CX	2906					Withdrawn
CX	2907					Withdrawn
CX	2908					Withdrawn
CX	2909	C	Freescale's response to Interrogatory No. 42	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2910					Withdrawn
CX	2911					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2912					Withdrawn
CX	2913					Withdrawn
CX	2914					Withdrawn
CX	2915					Withdrawn
CX	2916					Withdrawn
CX	2917					Withdrawn
CX	2918					Withdrawn
CX	2919					Withdrawn
CX	2920					Withdrawn
CX	2921					Withdrawn
CX	2922					Withdrawn
CX	2923					Withdrawn
CX	2924		U.S. Patent No. 5,241,133 (Mullen)	Ivey	VLD/INVLD	Admitted
CX	2925					Withdrawn
CX	2926					Withdrawn
CX	2927					Withdrawn
CX	2928					Withdrawn
CX	2929					Withdrawn
CX	2930					Withdrawn
CX	2931					Withdrawn
CX	2932					Withdrawn
CX	2933					Withdrawn
CX	2934					Withdrawn
CX	2935					Withdrawn
CX	2936					Withdrawn
CX	2937					Withdrawn
CX	2938					Withdrawn
CX	2939					Withdrawn
CX	2940					Withdrawn
CX	2941	C	Montgomery Exhibit 13: Referenced in Freescale Response to Interrogatories 50, 51	Montgomery / Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2942					Withdrawn
CX	2943		Spansion Response to Request for Admission Nos.: 1-3	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2944		Amended Appendix A: Referenced in Spansion Response to Interrogatory No. 1	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2945	C	SPAN-ITC 036484 - 036923	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2946					Withdrawn
CX	2947					Withdrawn
CX	2948					Withdrawn
CX	2949					Withdrawn
CX	2950					Withdrawn
CX	2951					Withdrawn
CX	2952					Withdrawn
CX	2953					Withdrawn
CX	2954					Withdrawn
CX	2955	C	ATI Chart in Response to Interrogatory No. 6 (1/7/08)	Stipulation	Infrng/Non-infrng	Admitted
CX	2956	C	ATI Chart in Response to Interrogatory No. 6 (12/17/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2957	C	ATI's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2958	C	Spansion's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2959	C	Freescale's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2960	C	Freescale's Second Supplemental Responses to Tessera's Second Set of Interrogatories (1/11/08)	Stipulation	Infrng/Non-infrng	Admitted
CX	2961	C	Motorola's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2962		Mennitt '857 Patent	Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	2963		Declaration of Christopher M. Pickett, from In re Inter Partes Reexamination of US Patent No. 6,433,419 (2/9/07)	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2964		Rule 132 Declaration of Scot A. Griffin from In re Reexamination of US Patent No. 6,433,419	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2965		Petition to Strike Requestor's Comments, from In re Reexamination Application of: Khandros et al. (2/9/07)	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2966					Withdrawn
CX	2967					Withdrawn
CX	2968(A)					Withdrawn
CX	2968(B)					Withdrawn
CX	2970					Withdrawn
CX	2971					Withdrawn
CX	2972					Withdrawn
CX	2973					Withdrawn
CX	2974					Withdrawn
CX	2975	C	Leonard Deposition Exhibit #003 - Confidential Exhibit 4 - List of Licenses of the Asserted Patents	Leonard	RMDY	Admitted
CX	2976		Leonard Deposition Exhibit #004 - Document entitled "Texas Instruments Update: Gradual Recovery, Analog to Lead" dated 4/23/07	Leonard	RMDY	Admitted
CX	2977		Leonard Deposition Exhibit #005 - Article: Broadcom and Verizon Wiless Enter into Licensing Agreement Allowing Verizon Wireless to Offer Cell Phones Banned by ITC; Companies Annouce Broad-Based Strategic Alliance	Leonard	RMDY	Admitted
CX	2978					Withdrawn
CX	2979					Withdrawn
CX	2980					Withdrawn
CX	2981		Leonard Deposition Exhibit #009 - U.S. Securities and Exchange Commision, Form 10-Q : Quarterly Report Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934	Leonard	RMDY	Admitted
CX	2982		Leonard Deposition Exhibit #010 - Motorola Inc. Q4 2007 Earnings Call Transcript	Leonard	RMDY	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	2983					Withdrawn
CX	2984					Withdrawn
CX	2985					Withdrawn
CX	2986					Withdrawn
CX	2987					Withdrawn
CX	2988					Withdrawn
CX	2989					Withdrawn
CX	2990					Withdrawn
CX	2991					Withdrawn
CX	2992					Withdrawn
CX	2993					Withdrawn
CX	2994					Withdrawn
CX	2995					Withdrawn
CX	2996					Withdrawn
CX	2997					Withdrawn
CX	2998					Withdrawn
CX	2999					Withdrawn
CX	3000					Withdrawn
CX	3001					Withdrawn
CX	3002		Russell Deposition Exhibit # 2 - Notice of Deposition of Spansion, Inc.	Russell	RMDY	Admitted
CX	3003	C	Russell Deposition Exhibit # 3	Russell	RMDY	Admitted
CX	3004	C	Russell Deposition Exhibit # 4 - Spansion Financial Data 2007	Russell	RMDY	Admitted
CX	3005	C	Russell Deposition Exhibit # 5	Russell	RMDY	Admitted
CX	3006	C	Russell Deposition Exhibit # 6	Russell	RMDY	Admitted
CX	3007	C	Russell Deposition Exhibit # 7	Russell	RMDY	Admitted
CX	3008	C	Russell Deposition Exhibit # 8	Russell	RMDY	Admitted
CX	3009					Withdrawn
CX	3010					Withdrawn
CX	3011					Withdrawn
CX	3012					Withdrawn
CX	3013					Withdrawn
CX	3014					Withdrawn
CX	3015					Withdrawn
CX	3016					Withdrawn
CX	3017					Withdrawn
CX	3018					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3019					Withdrawn
CX	3020					Withdrawn
CX	3021					Withdrawn
CX	3022					Withdrawn
CX	3023	C	Khandros Performance Evaluation	Romankiw	OWNR	Admitted
CX	3024					Withdrawn
CX	3025					Withdrawn
CX	3026					Withdrawn
CX	3027	C	3/1990 Projects In Order of Priority, Romankiw	Romankiw	OWNR	Admitted
CX	3028	C	Sussenguth to Academy Members, Technical Agenda Report	Romankiw	OWNR	Admitted
CX	3029	C	Romankiw Academic Institution Interactions; Electrochemical Technology Environment, IBM vs. Competition	Romankiw	OWNR	Admitted
CX	3030	C	Pittler memo re Review of MR Plan	Romankiw	OWNR	Admitted
CX	3031	C	8/10/1988 Guibesault memo re D/431 All Managers Meeting	Romankiw	OWNR	Admitted
CX	3032	C	Romankiw Progress Report	Romankiw	OWNR	Admitted
CX	3033					Withdrawn
CX	3034	C	11/17/1997 Harris to DiStefano re proposal for a joint development effort with IBM on wafer level packaging	DiStefano	OWNR	Admitted
CX	3035					Withdrawn
CX	3036					Withdrawn
CX	3037					Withdrawn
CX	3038					Withdrawn
CX	3039					Withdrawn
CX	3040	C	Taheri to Smith encl Memorandum of Understanding between Tessera and IBM	DiStefano	OWNR	Admitted
CX	3041					Withdrawn
CX	3042					Withdrawn
CX	3043					Withdrawn
CX	3044					Withdrawn
CX	3045					Withdrawn
CX	3046					Withdrawn
CX	3047					Withdrawn
CX	3048					Withdrawn
CX	3049					Withdrawn
CX	3050	C	Mitchell Memorandum Re IBM	DiStefano	OWNR	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3051					Withdrawn
CX	3052					Withdrawn
CX	3053					Withdrawn
CX	3054					Withdrawn
CX	3055					Withdrawn
CX	3056					Withdrawn
CX	3057	C	DiStefano To Brown Enclosing Memorandum	DiStefano	OWNR	Admitted
CX	3058					Withdrawn
CX	3059					Withdrawn
CX	3060					Withdrawn
CX	3061					Withdrawn
CX	3062					Withdrawn
CX	3063					Withdrawn
CX	3064					Withdrawn
CX	3065	C	Respondent STMicroelectronics First Amended and Supplemental Response to Tessera's Second Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	3066					Withdrawn
CX	3067	C	Product Specs for MDRO *5363A99	Qu	Infrng/Non-infrng	Admitted
CX	3068	C	Mount & Bond Diagram for R0*5363	Qu	Infrng/Non-infrng	Admitted
CX	3069	C	Base LBGA 288L 19X19MM 2LY DP7.6x6.9MM Pitch 1MM	Qu	Infrng/Non-infrng	Admitted
CX	3070	C	RR V476 NEW MUAR - 0959/GNB - 0325	Qu	Infrng/Non-infrng	Admitted
CX	3071	C	Product Specs for F5RR*V476BDQ in Manufacturing Phase ASSY Plant MU1A ST MUAR - MALAYSIA 0959	Qu	Infrng/Non-infrng	Admitted
CX	3072	C	POA for LBGA 288 / 19x19x1.7 / 4R18 1.0 POA-ASG (GNB Package Outline)	Qu	Infrng/Non-infrng	Admitted
CX	3073					Withdrawn
CX	3074					Withdrawn
CX	3075	C	Letter regarding Amkor Agreement	Griffin	RMDY, OWNR	Admitted
CX	3076	C	Side-by-Side Comparison of Toshiba and STMicro FBGA's (1/22/2003)	Griffin	RMDY, OWNR	Admitted
CX	3077					Withdrawn
CX	3078	C	Freescale Work Instructions, Document No. 00ASM9781A	Qu	Infrng/Non-infrng	Admitted
CX	3079	C	Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3080	C	ASE Substrate Design	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3081	C	ASE Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3082	C	Reliability Test Report for Qualification Test of TFBGA (10x10) 179L	Qu	Infrng/Non-infrng	Admitted
CX	3083	C	Qualcomm Substrate Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3084	C	Qualcomm Drawing - Assembly Material Set	Qu	Infrng/Non-infrng	Admitted
CX	3085	C	Qualcomm Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3086	C	Qualcomm Bonding Diagram	Qu	Infrng/Non-infrng	Admitted
CX	3087	C	Spansion Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3088	C	Spansion Ball FBGA Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3089	C	Spansion Reliability Qualification	Qu	Infrng/Non-infrng	Admitted
CX	3090					Withdrawn
CX	3091					Withdrawn
CX	3092		Freescale News Release, "Elektrobit and Freescale Cut 3G Handset Development Time with New Reference Phone"		Remedies	Admitted
CX	3093					Withdrawn
CX	3094					Withdrawn
CX	3095					Withdrawn
CX	3096					Withdrawn
CX	3097					Withdrawn
CX	3098					Withdrawn
CX	3099					Withdrawn
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CX	3109					Withdrawn
CX	3110					Withdrawn
CX	3111					Withdrawn
CX	3112					Withdrawn
CX	3113					Withdrawn
CX	3114					Withdrawn
CX	3115					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3116					Withdrawn
CX	3117					Withdrawn
CX	3118					Withdrawn
CX	3119					Withdrawn
CX	3120					Withdrawn
CX	3121					Withdrawn
CX	3122					Withdrawn
CX	3123					Withdrawn
CX	3124		Emerson & Cuming Selector Guide: Electrically Conductive Adhesives	Ivey	VLD/INVLD	Admitted
CX	3125		Emerson & Cuming Selector Guide: Adhesives and Coatings for Passive Components	Ivey	VLD/INVLD	Admitted
CX	3126					Withdrawn
CX	3127					Withdrawn
CX	3128					Withdrawn
CX	3129					Withdrawn
CX	3130					Withdrawn
CX	3131					Withdrawn
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CX	3149					Withdrawn
CX	3150					Withdrawn
CX	3151					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3152					Withdrawn
CX	3153					Withdrawn
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CX	3160					Withdrawn
CX	3161					Withdrawn
CX	3162					Withdrawn
CX	3163					Withdrawn
CX	3164					Withdrawn
CX	3165	C	Nagaraj,B., "Package-To-Board Reliability - Methodology and Case Study on OMPAC Package	Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	3166					Withdrawn
CX	3167					Withdrawn
CX	3168					Withdrawn
CX	3169					Withdrawn
CX	3170					Withdrawn
CX	3171					Withdrawn
CX	3172					Withdrawn
CX	3173					Withdrawn
CX	3174	C	Bonding Diagram, BL90-V6698-1A	Qu	Infrng/Non-infrng	Admitted
CX	3175	C	SPIL Diagram for STF BGA (LF) 259	Qu	Infrng/Non-infrng	Admitted
CX	3176	C	SPIL Diagram for STF BGA (LF) 259	Qu	Infrng/Non-infrng	Admitted
CX	3177	C	Bonding Diagram, PM6652	Qu	Infrng/Non-infrng	Admitted
CX	3178	C	Bonding Diagram, Bal 4050	Qu	Infrng/Non-infrng	Admitted
CX	3179	C	Bonding Diagram, WFB4030	Qu	Infrng/Non-infrng	Admitted
CX	3180	C	Bonding Diagram	Qu	Infrng/Non-infrng	Admitted
CX	3181	C	Bonding Diagram, PM6610	Qu	Infrng/Non-infrng	Admitted
CX	3182					Withdrawn
CX	3183					Withdrawn
CX	3184					Withdrawn
CX	3185					Withdrawn
CX	3186					Withdrawn
CX	3187					Withdrawn
CX	3188					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3189					Withdrawn
CX	3190					Withdrawn
CX	3191					Withdrawn
CX	3192					Withdrawn
CX	3193					Withdrawn
CX	3194		US Patent No. 5,148,266	Ivey	VLD/INVLD	Admitted
CX	3195					Withdrawn
CX	3196	C	Corrected Witness Statement of Jianmin Qu	Qu / Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	3197	C	Direct Witness Statement of Kirk E. Flatow	Flatow	RMDY	Admitted
CX	3198					Withdrawn
CX	3199	C	Direct Witness Statement of Scot A. Griffin	Griffin	RMDY, OWNR	Admitted
CX	3200					Withdrawn
CX	3201	C	Direct Witness Statement of Bruce McWilliams	McWilliams	RMDY, DI	Admitted
CX	3202					Withdrawn
CX	3203					Withdrawn
CX	3204	C	Rebuttal Witness Statement of Christopher Pickett	Pickett	RMDY, OWNR	Admitted
CX	3205	C	Rebuttal Witness Statement of Peter Ivey	Ivey	VLD/INVLD, OWNR	Admitted
CX	3206	C	Rebuttal Witness Statement of Scot Griffin	Griffin	RMDY, OWNR	Admitted
CX	3208	C	Rebuttal Witness Statement of Mike Warner	Warner	RMDY, DI	Admitted
CX	3209					Withdrawn
CX	3210					Withdrawn
CX	3211					Withdrawn
CX	3212					Withdrawn
CX	3213					Withdrawn
CX	3214					Withdrawn
CX	3215					Withdrawn
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CX	3221					Withdrawn
CX	3222					Withdrawn
CX	3223					Withdrawn
CX	3224					Withdrawn
CX	3225					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3226					Withdrawn
CX	3227					Withdrawn
CX	3228					Withdrawn
CX	3229					Withdrawn
CX	3230					Withdrawn
CX	3231					Withdrawn
CX	3232					Withdrawn
CX	3233					Withdrawn
CX	3234					Withdrawn
CX	3235					Withdrawn
CX	3236					Withdrawn
CX	3237					Withdrawn
CX	3238					Withdrawn
CX	3239					Withdrawn
CX	3240					Withdrawn
CX	3241					Withdrawn
CX	3242					Withdrawn
CX	3243					Withdrawn
CX	3244					Withdrawn
CX	3246	C	Respondent STMicroelectronics First Amended and Supplemental Response to Tessera's Second Set of Requests for Admission	Stipulation	Remedies	Admitted
CX	3247					Withdrawn
CX	3248					Withdrawn
CX	3249					Withdrawn
CX	3250					Withdrawn
CX	3251					Withdrawn
CX	3252					Withdrawn
CX	3253					Withdrawn
CX	3254					Withdrawn
CX	3255					Withdrawn
CX	3256					Withdrawn
CX	3257					Withdrawn
CX	3258					Withdrawn
CX	3259					Withdrawn
CX	3260					Withdrawn
CX	3261					Withdrawn
CX	3262					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3263					Withdrawn
CX	3264					Withdrawn
CX	3265					Withdrawn
CX	3266					Withdrawn
CX	3267					Withdrawn
CX	3268					Withdrawn
CX	3269					Withdrawn
CX	3270					Withdrawn
CX	3271					Withdrawn
CX	3272					Withdrawn
CX	3274					Withdrawn
CX	3275					Withdrawn
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CX	3278					Withdrawn
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CX	3290					Withdrawn
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CX	3292					Withdrawn
CX	3293					Withdrawn
CX	3294					Withdrawn
CX	3295					Withdrawn
CX	3296					Withdrawn
CX	3297					Withdrawn
CX	3298					Withdrawn
CX	3299					Withdrawn
CX	3300					Withdrawn
CX	3301					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3302					Withdrawn
CX	3303					Withdrawn
CX	3304	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7114359.	Qu	Infrng/Non-infrng	Admitted
CX	3305	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7609040	Qu	Infrng/Non-infrng	Admitted
CX	3306	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7132897	Qu	Infrng/Non-infrng	Admitted
CX	3307	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7517961	Qu	Infrng/Non-infrng	Admitted
CX	3308	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7517962	Qu	Infrng/Non-infrng	Admitted
CX	3309	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7185086	Qu	Infrng/Non-infrng	Admitted
CX	3310	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7385800	Qu	Infrng/Non-infrng	Admitted
CX	3311	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7286783	Qu	Infrng/Non-infrng	Admitted
CX	3312	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7104670	Qu	Infrng/Non-infrng	Admitted
CX	3313	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7515030	Qu	Infrng/Non-infrng	Admitted
CX	3314	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7131786	Qu	Infrng/Non-infrng	Admitted
CX	3315	C	TMI00433057-59	Warner	RMDY, DI	Admitted
CX	3316	C	TMI00228125-28	Warner	RMDY, DI	Admitted
CX	3317	C	TMI00182137	Warner	RMDY	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3318	C	TMI00263170-73	Warner	RMDY, DI	Admitted
CX	3319	C	TMI00251344-55	Warner	RMDY, DI	Admitted
CX	3320	C	TMI00196053-61	Warner	RMDY, DI	Admitted
CX	3321	C	Corrected Rebuttal Witness Statement of Urbish	Urbish	INFRNG/NON-INFRNG	Admitted
CX	3322		U.S. Patent No. 3, 795, 037 to Luttmer	Ivey	VLD/INVLD	Admitted
CX	3323		Solder-Filled Elastomeric Spacer	Ivey	VLD/INVLD	Admitted
CX	3324					Withdrawn
CX	3325					Withdrawn
CX	3326					Withdrawn
CX	3327					Withdrawn
CX	3328					Withdrawn
CX	3329					Withdrawn
CX	3330	C	Crowder Memo Re: Manufacturing Research	Romankiw	OWNR	Admitted
CX	3331		Corrected Rebuttal Witness Statement of Urbish	Ivey / Urbish	VLD/INVLD	Admitted
CX	3332					Withdrawn
CX	3333	C	Murray Deposition Exhibit #002 - List of all accused small format BGA chips identified by Fresscale	Murray		Admitted
CX	3334					Withdrawn
CX	3335	C	Frankel Deposition Exhibit #002 - Respondent Qualcomm, Inc.'s Fourth Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm, Inc.	Frankel / Stipulation	Importation, Remedies	Admitted
CX	3336					Withdrawn
CX	3337	C	Frankel Deposition Exhibit #004	Frankel	RMDY	Admitted
CX	3338					Withdrawn
CX	3339	C	Frankel Deposition Exhibit #006	Frankel	RMDY	Admitted
CX	3340					Withdrawn
CX	3341	C	Frankel Deposition Exhibit #009	Frankel	RMDY	Admitted
CX	3342	C	Frankel Deposition Exhibit #010	Frankel	RMDY	Admitted
CX	3343					Withdrawn
CX	3344					Withdrawn
CX	3345					Withdrawn
CX	3346					Withdrawn
CX	3347					Withdrawn
CX	3348					Withdrawn
CX	3349					Withdrawn
CX	3350					Withdrawn

Prefix	Exhibit Number	Conf on Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3351					Withdrawn
CX	3352					Withdrawn
CX	3353					Withdrawn
CX	3354					Withdrawn
CX	3355		Hasuman Deposition Exhibit #004 - Commission Opinion on RMNDY in ITC Investigation No. 337-TA-543	Hausman	RMDY	Admitted
CX	3356					Withdrawn
CX	3357	C	Hasuman Deposition Exhibit #006 - Qualcomm's Fourth Supplemental Response to Tessera's First Set of Interrogatories	Hausman / Stipulation	Importation, Remedies	Admitted
CX	3358	C	Hausman Deposition Exhibit #007 - Confidential Exhibit #4 to the Complaint	Hausman	RMDY	Admitted
CX	3359	C	Hasuman Deposition Exhibit #008 - QTSIH 00010507 - 515	Hausman	RMDY	Admitted
CX	3360	C	Hausman Deposition Exhibit #009 - QTSIH 00010516 - 517	Hausman	RMDY	Admitted
CX	3361		Hausman Deposition Exhibit #010 - QTSIH 00520669 - 678	Hausman	RMDY	Admitted
CX	3362		Hausman Deposition Exhibit #011 - Verizon Wireless news release	Hausman	RMDY	Admitted
CX	3363	C	Hausman Deposition Exhibit #012 - QTSI 00908315 - 324	Hausman	RMDY	Admitted
CX	3364		Hausman Deposition Exhibit #013 - Qualcomm, Inc. Form 10-Q for the Quarterly Period Ending 12/30/2007	Hausman / Stipulation	Importation, Remedies	Admitted
CX	3365					Withdrawn
CX	3366					Withdrawn
CX	3367					Withdrawn
CX	3368					Withdrawn
CX	3369					Withdrawn
CX	3370					Withdrawn
CX	3371					Withdrawn
CX	3372					Withdrawn
CX	3373					Withdrawn
CX	3374					Withdrawn
CX	3375	C	ATI's Second Supplemental Responses to Tessera's First Set of Interrogatories		Infrng/Non-infrng	Admitted
CX	3376					Withdrawn
CX	3377					Withdrawn
CX	3378					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3379					Withdrawn
CX	3380	C	Amendment Number One (1) to the Agreement for Exchange of Confidential Information between IBM and Tessera	DiStefano	OWNR	Admitted
CX	3381					Withdrawn
CX	3382					Withdrawn
CX	3383					Withdrawn
CX	3384					Withdrawn
CX	3385					Withdrawn
CX	3386					Withdrawn
CX	3387					Withdrawn
CX	3388					Withdrawn
CX	3389	C	list of ST-NV finished goods and product codes taken from the T&F documents	Qu/Hundt	Infrng/Non-infrng	Admitted
CX	3390		File History of US Patent No. 5,241,133 (Mullen)	Freyman	INFRNG/NON-INFRNG	Admitted
CX	3391	C	Declaration of Matthew D. Smith	Smith	Importation, Remedies	Admitted
CX	3392	C	Motorola's Confidential Response to Complaintant Tessera's Second Set of Requests for Admissions (#3-15)	Stipulation	Infrng/Non-infrng	Admitted
CX	3393					Withdrawn
CX	3395		Murray Ex. # 4: Freescale Semiconductor, Inc. 10-K	Murray / Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3396					Withdrawn
CX	3397					Withdrawn
CX	3398					Withdrawn
CX	3399	C	Correspondence from J. Brown to "Bill" regardign Alan Patricoff Associates, Inc. and IST Associates, inc.	Bottoms	OWNR	Admitted
CX	3399(A)		McLellan Deposition Ex. #123 - AMD 2006 Annual Report on Form 10K	McClellan	Importation, Remedies	Admitted
CX	3400					Withdrawn
CX	3401					Withdrawn
CX	3402					Withdrawn
CX	3403	C	ST-NV'S First Amended Reponse to Tessera's Eighth Set of Interrogatories	Qu	INFRNG/NON-INFRNG	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3404	C	Build sheet assemblies for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00153023); ST_MC_TFBGA_105_3(STTITC00153005); ST_MC_TFBGA_88_2 (STITC00157396); ST_SC_TBGA_64 (STITC00152355); ST_SC_VFBGA_63 (STITC00057247); STM_SC_TFBGA_47 (STITC00152271); STM_SC_TFBGA_324 (STITC00034525); STM_SC_VFBGA_56 (STITC00153181)	Qu	INFRNG/NON-INFRNG	Admitted
CX	3405	C	Package outline diagrams for for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00055882); ST_MC_TFBGA_105_3(STTITC00055882); ST_MC_TFBGA_88_2 (STITC00055433); ST_SC_TBGA_64 (STIT00053860); ST_SC_VFBGA_63 (STITC00055826); STM_SC_TFBGA_47 (STITC00054149); STM_SC_TFBGA_324 (STITC00021237); STM_SC_VFBGA_56 (STITC00054307)	Qu	INFRNG/NON-INFRNG	Admitted
CX	3406	C	Substrate technical documents for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00026645); ST_MC_TFBGA_105_3(STTITC00025704); ST_MC_TFBGA_88_2 (STITC00025696); ST_SC_TBGA_64 (STITC00026074); ST_SC_VFBGA_63 (STITC00024922); STM_SC_TFBGA_47 (STITC00020177); STM_SC_TFBGA_324 (STITC00025013); STM_SC_VFBGA_56 (STITC00024740)	Qu / Sitaraman	INFRNG/NON-INFRNG	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3407	C	Wire bonding diagrams for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00153016); ST_MC_TFBGA_105_3(STTITC00152999); ST_MC_TFBGA_88_2 (STITC00074037); ST_SC_TBGA_64 (STITC00152351); ST_SC_VFBGA_63 (STITC00073889); STM_SC_TFBGA_47 (STITC00152267); STM_SC_TFBGA_324 (STITC00153469); STM_SC_VFBGA_56 (STITC00153177)	Qu	INFRNG/NON-INFRNG	Admitted
CX	3408	C	Table of Packages	Qu	INFRNG/NON-INFRNG	Admitted
CX	3409	C	Geometric Dimensions of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3410	C	Geometric Dimensions of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3411	C	Geometric Dimension of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3412	C	Geometric Dimension of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3413	C	Geometric Dimension of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3414	C	Geometric Dimension of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3415	C	Geometric Dimension of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3416	C	Geometric Dimension of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3417	C	CrossSection of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3418	C	CrossSection of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3419	C	CrossSection of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3420	C	CrossSection of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted

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CX	3421	C	CrossSection of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3422	C	CrossSection of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3423	C	CrossSection of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3424	C	CrossSection of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3425	C	Mesh for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3426	C	Mesh for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3427	C	Mesh for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3428	C	Mesh for STM-MC-TFBGA-103-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3429	C	Mesh for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3430	C	Mesh for STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3431	C	Mesh for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3432	C	Mesh for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3433	C	Material Property FEA Inputs	Qu	INFRNG/NON-INFRNG	Admitted
CX	3434	C	Column Displacement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3435	C	Column Displacement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3436	C	Column Displacement STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3437	C	Column Displacement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3438	C	Column Displacement STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3439	C	Column Displacement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted

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CX	3440	C	Column Displacement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3441	C	Column Displacement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3442	C	AC Movement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3443	C	AC Movement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3444	C	AC Movement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3445	C	AC Movement STM-SC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3446	C	AC Movement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3447	C	AC Movement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3448	C	AC Movement STM-SC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3449	C	AC Movement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3450	C	Plastic Work STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3451	C	Plastic Work STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3452	C	Plastic Work STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3453	C	Plastic Work STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3454	C	Plastic Work STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3455	C	Plastic Work STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3456	C	Plastic Work STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3457	C	Plastic Work STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3458	C	Percentage Life Improvement Table Method 1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3459	C	Symmetry Results Plot	Qu	INFRNG/NON-INFRNG	Admitted
CX	3460	C	Copper Layer Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CX	3461	C	Copper Layer Comparison Table	Qu	INFRNG/NON-INFRNG	Admitted
CX	3462	C	Polar Plot STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3463	C	Polar Plot STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3464	C	Polar Plot STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3465	C	Polar Plot STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3466	C	Polar Plot STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3467	C	Polar Plot STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3468	C	Intentionally left blank	Qu	INFRNG/NON-INFRNG	Admitted
CX	3469	C	Polar Plot STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3470	C	Polar Plot STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3471	C	Plastic Work External STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3472	C	Plastic Work External STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3473	C	Plastic Work External STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3474	C	Plastic Work External STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3475	C	Plastic Work External STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3476	C	Plastic Work External STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3477	C	Plastic Work External STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3478	C	Plastic Work External STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3479	C	Percentage Life Improvement Table Method 2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3480	C	Compression for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3481	C	Compression for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3482	C	Compression for STM-SC-TBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3483	C	Compression for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3484	C	Compression for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3485	C	Compression for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3486	C	Compression for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3487	C	Compression for STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3496					Withdrawn
CX	3497	C	Respondent Qualcomm Incorporated's Fourth Supplemental Response to Tessera, Inc.'s Interrogatory No. 1	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3498	C	IC Package Technology Updates, April 20, 2005	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3499					Withdrawn
CX	3500					Withdrawn
CX	3501					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3502					Withdrawn
CX	3503					Withdrawn
CX	3504					Withdrawn
CX	3505					Withdrawn
CX	3506					Withdrawn
CX	3507					Withdrawn
CX	3508					Withdrawn
CX	3509					Withdrawn
CX	3510	C	Samsung Meeting, December 11, 2006	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3511	C	Technology Review Package Engineering V13	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3512					Withdrawn
CX	3513					Withdrawn
CX	3514					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3515	C	Customer Package Technology Update, January 2007, Preliminary Version V1	Hausman	RMDY	Admitted
CX	3516					Withdrawn
CX	3517	C	Package Engineering: An Eye on the Future	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3518					Withdrawn
CX	3519	C	The Prismark Wireless Technology Report, July 2005	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3520					Withdrawn
CX	3521					Withdrawn
CX	3522	C	The Prismark Wireless Technology Report, October 2005	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3523					Withdrawn
CX	3524	C	ULC GSM Phones: LoCosto and Beyond, December 19, 2007	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3525					Withdrawn
CX	3526		U.S. Patent No. 5,148,265 (Khandros, et al.)	Ivey	Conception, Reduction to Practice, Patent Ownership, Tessera	Admitted
CX	3527		U.S. Patent No. 5,148,266 (Khandros, et al.)	Ivey	Conception, Reduction to Practice, Patent Ownership, Tessera	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3528					Withdrawn
CX	3529					Withdrawn
CX	3530					Withdrawn
CX	3531	C	Smith Declaration 2.21.2008	ST-NV	Importation, Remedies	Admitted
CX	3532	C	2008.02.22 STMicroelectronics First Amended and Supplemental Response to Tessera's Eighth Set of Interrogatories (108-124)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3533	C	STMicroelectronics Second Amended and Supplemental Response to Tessera's Eighth Set of Interrogatories (108-124) served July 3, 2008	Malone	INFRNG/NON-INFRNG	Admitted
CX	3534	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's First Set of Interrogatories (1-5)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3535	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's Fourth Set of Interrogatories (31)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3536	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's Seventh Set of Interrogatories (71-107)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3537	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's First Set of Interrogatories (1-5)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3538	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's Fourth Set of Interrogatories (31)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3539	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's Seventh Set of Interrogatories (71-107)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3540	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's Third Set of RFAs	Malone	INFRNG/NON-INFRNG	Admitted
CX	3541	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's Second Set of RFAs	ST-NV	Importation, Renedy, License Defense	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3542	C	4.16.2008 Chambers Depo. Ex. 3 - STMicroelectronics First Amended and Supplemental Response to Tessera's Eighth Set of Interrogatories (108-124)	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3543		4.16.2008 Chambers Depo. Ex. 4 - One Page from Interrogatory Answers	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3544		4.16.2008 Chambers Depo. Ex. 5 - STMicroelectronics Advertisement	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3545		4.16.2008 Chambers Depo. Ex. 6 - ST Presentation	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3546	C	4.16.2008 Chambers Depo. Ex. 7 - Composite Spreadsheet	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3547		4.16.2008 Chambers Depo. Ex. 8 - Printout of Web Pages from Future Electronics	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3548		4.16.2008 Chambers Depo. Ex. 9 - Advertisement Entitled Speak With More Intelligence	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3549		4.16.2008 Chambers Depo. Ex. 10 - Form 20-F for STMicroelectronics	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3550		4.16.2008 Chambers Depo. Ex. 11 - Press Release by STMicroelectronics	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3551					Withdrawn
CX	3552					Withdrawn
CX	3553					Withdrawn
CX	3554					Withdrawn
CX	3555		4.16.2008 Chambers Depo. Ex. 16 - STMicroelectronics Advertisement Concerning Flash Memory	Chambers	Importation, Remedies	Admitted
CX	3556		4.16.2008 Chambers Depo. Ex. 17 - STMicroelectronics Advertisement Concerning LightFlash	Chambers	Importation, Remedies	Admitted
CX	3557		2.26.2008 Licciardello Depo. Ex. 1 - ST Document titled We Put More Intelligence Into Everything	Licciardello	Importation, Remedies	Admitted
CX	3558		2.26.2008 Licciardello Depo. Ex. 8 - ST Presentation dated 1.23.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3559	C	2.26.2008 Licciardello Depo. Ex. 29 - ST-NV Combined Appendices A and B	Licciardello	Importation, Remedy, Infrng/Non-infrng	Admitted
CX	3560		5.27.2008 Licciardello Depo. Ex. 2 - Securities and Exchange Commission form 6-K, dated 3.31.2008	Liccardello	INFRNG/NON-INFRNG	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3561		5.27.2008 Licciardello Depo. Ex. 3 - Press release entitled STMicroelectronics, Intel, Francisco Partners Close Transaction dated 3.31.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3562		5.27.2008 Licciardello Depo. Ex. 3A - Print-outs from the Future Electronics website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3563		5.27.2008 Licciardello Depo. Ex. 4 - Press release entitled Numonyx Enters Memory Market in a Strong Position dated 3.31.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3564		5.27.2008 Licciardello Depo. Ex. 4A - Print-outs from the Future Electronics website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3565		5.27.2008 Licciardello Depo. Ex. 5 - Print-outs from the Numonyx website concerning memory products and product searches	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3566		5.27.2008 Licciardello Depo. Ex. 5A - Print-outs from the Future Electronics website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3567		5.27.2008 Licciardello Depo. Ex. 6 - Print-outs from the STMicroelectronics website redirecting to the Numonyx website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3568		5.27.2008 Licciardello Depo. Ex. 7 - Master Agreement by and between STMicroelectronics, Intel, Redwood, and Francisco Partners dated 5.22.2007	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3569		5.27.2008 Licciardello Depo. Ex. 7A - Document entitled We Put More Intelligence into Everything	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3570		5.27.2008 Licciardello Depo. Ex. 8A - STMicroelectronics Company Presentation dated 5.14.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3571		5.27.2008 Licciardello Depo. Ex. 9 - Securities and Exchange Commission form 20-F for the period ended 12.21.2006	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3572		5.27.2008 Licciardello Depo. Ex. 12 - Avnet Marketing of ST Products	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3573		5.27.2008 Licciardello Depo. Ex. 18 - ST Lightflash advertisement	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3574		5.27.2008 Licciardello Depo. Ex. 19 - STdocument titled Speak with more intelligence	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3575		5.27.2008 Licciardello Depo. Ex. 20 - Listing of Memory Products from Arrow NAC website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3576		5.23.2008 Perillat Depo Ex. 6 - Document entitled Hitachi Chemical Data Sheet	Perillat	INFRNG/NONINFRNG	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3577					Withdrawn
CX	3578		5.23.2008 Perillat Depo Ex. 5 - Document entitled Loctite Die Attach Materials	Perillat	Infrng/Non-infrng	Admitted
CX	3579		5.23.2008 Perillat Depo Ex. 6 - Document entitled Hitachi Chemical Data Sheet	Perillat	INFRNG/NONINFRNG	Admitted
CX	3580		5.23.2008 Perillat Depo Ex. 7 - Document entitled Die Bonding Paste	Perillat	INFRNG/NONINFRNG	Admitted
CX	3581		5.23.2008 Perillat Depo Ex. 8 - Document entitled Ablebond 2025D	Perillat	INFRNG/NONINFRNG	Admitted
CX	3582	C	5.23.2008 Perillat Depo Ex. 9 - Document entitled Glue Die Attach in Process Control	Perillat	INFRNG/NONINFRNG	Admitted
CX	3583	C	5.23.2008 Perillat Depo Ex. 10 - Product Specification for H5FN*MV86BAA	Perillat	INFRNG/NONINFRNG	Admitted
CX	3584	C	5.23.2008 Perillat Depo Ex. 11 - Document entitled Package Outline Assembly	Perillat	INFRNG/NONINFRNG	Admitted
CX	3585	C	5.23.2008 Perillat Depo Ex. 12 - Product Specification for 75FN*MV86BAA	Perillat	INFRNG/NONINFRNG	Admitted
CX	3586					Withdrawn
CX	3587					Withdrawn
CX	3588					Withdrawn
CX	3589					Withdrawn
CX	3590	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7243987	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3591	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7298388	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3592	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7363848	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3593	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7446062	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3594	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7811789	Qu, Hundt	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3595	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7858639	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3596					Withdrawn
CX	3597					Withdrawn
CX	3598					Withdrawn
CX	3599					Withdrawn
CX	3600					Withdrawn
CX	3601					Withdrawn
CX	3602					Withdrawn
CX	3603					Withdrawn
CX	3604					Withdrawn
CX	3605					Withdrawn
CX	3606					Withdrawn
CX	3607					Withdrawn
CX	3608					Withdrawn
CX	3609					Withdrawn
CX	3610					Withdrawn
CX	3611					Withdrawn
CX	3612					Withdrawn
CX	3613					Withdrawn
CX	3614					Withdrawn
CX	3615					Withdrawn
CX	3616					Withdrawn
CX	3617					Withdrawn
CX	3618					Withdrawn
CX	3619					Withdrawn
CX	3620		Freescale Semiconductor Inc. Form 10-Q for period ended March 28, 2008	Stipulation	Remedies	Admitted
CX	3621		Freescale Semiconductor Inc. Form 10-K for period ended December 31, 2007	Stipulation	Remedies	Admitted
CX	3622		Spansion Inc. Form 10-Q for period ended March 30, 2008	Stipulation	Remedies	Admitted
CX	3623		Spansion Inc. Form 10-K for period ended December 30, 2007	Stipulation	Remedies	Admitted
CX	3624		Qualcomm Inc. Form 10-Q for period ended March 30, 2008	Stipulation	Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3625		Qualcomm Inc. Form 10-K for period ended September 30, 2007	Stipulation	Remedies	Admitted
CX	3626		Motorola Inc. Form 10-Q for period ended March 29, 2008	Stipulation	Remedies	Admitted
CX	3627		Motorola Inc. Form 10-K for period ended December 31, 2007	Stipulation	Remedies	Admitted
CX	3628	C	Motorola's First Supplemental Response to Tessera's Fourth Set of Interrogatories (#31) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3629	C	Motorola's First Supplemental Response to Tessera's Fifth Set of Interrogatories (40, 48-51) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3630	C	Motorola's Second Supplemental Response to Tessera's Sixth Set of Interrogatories (88) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3631	C	Motorola's Second Supplemental Response to Tessera's Third Set of Interrogatories (25, 26) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3632	C	Motorola's Fifth Supplemental Response to Tessera's Second Set of Interrogatories (6, 17, and 20) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3633	C	Motorola's Fifth Supplemental Response to Tessera's First Set of Interrogatories (1-5) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3634					Withdrawn
CX	3635					Withdrawn
CX	3636		Qualcomm Incorporated's Company Overview for 2007	Hausman	RMDY	Admitted
CX	3637					Withdrawn
CX	3638					Withdrawn
CX	3639					Withdrawn
CX	3640					Withdrawn
CX	3641					Withdrawn
CX	3642					Withdrawn
CX	3643					Withdrawn
CX	3644					Withdrawn
CX	3645					Withdrawn
CX	3646					Withdrawn
CX	3647					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
CX	3648					Withdrawn
CX	3649					Withdrawn
CX	3650					Withdrawn
CX	3651					Withdrawn
CX	3652					Withdrawn
CX	3653					Withdrawn
CX	3654					Withdrawn
CX	3655					Withdrawn
CX	3656					Withdrawn
CX	3657					Withdrawn
CX	3658					Withdrawn
CX	3659					Withdrawn
CX	3660					Withdrawn
CX	3661					Withdrawn
CX	3662					Withdrawn
CX	3663					Withdrawn
CX	3664					Withdrawn
CX	3665					Withdrawn
CX	3667					Withdrawn
CX	3668					Withdrawn
CX	3669	C	Supplemental Witness Statement of Dr. Jianmin Qu	Qu/Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	3670	C	Respondent STMicroelectronics N.V.'s Fourth Amended and Supplemental Response to Tessera's Second Set of Requests for Admission (served 07.11.08)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3671		Rule 132 Declaration of Scot A. Griffin from In re Reexamination of US Patent No. 5,679,977	Ivey	Vldy/Invldy	Admitted
CX	3672		Response to Official Action regarding Reexamination of '977 patent	Ivey	Vldy/Invldy	Admitted
CX	3673		Amendment in Response to Official Office Action mailed 03.282008 in the Reexamination of '977 patent	Ivey	Vldy/Invldy	Admitted
CX	3674		Rule 132 Declaration of Scot A. Griffin from In re Reexamination of US Patent No. 5,852,326	Ivey	Vldy/Invldy	Admitted
CX	3675		Declaration of Dr. Ephraim Suhir in the Reexamination of '326 patent	Ivey	Vldy/Invldy	Admitted
CX	3676		Principal Declaration of Glenn Urbish in Reexamination of the '419 patent	Ivey	Vldy/Invldy	Admitted
CX	3677		Tessera Technologies, Inc. Form 10-K	Mitchell	Domestic Industry	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

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Prefix	Exhibit Number	Confid Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JPX	1	C	Bottoms-Up database (Note: This is the physical exhibit version of JX-0075C)	Mitchell	Domestic Industry	Admitted
JPX	2	C	ST NV Chip package XTV0984N (Physical Sample)	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	1		U.S. Patent No. 5,852,326 (Copy of Certfied Copy) - Exhibit #1 to Complaint	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	2		U.S. Patent No. 6,433,419 (Copy of Certified Copy) - Exhibit #2 to Complaint	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	3		File History for U.S. Patent No. 5,852,326	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	4		File History for U.S. Patent No. 6,433,419	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	5	C	Confidential License Agreement with 3M	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	6	C	Confidential License Agreement with Advanced Semiconductor Engineering, Inc. (ASE)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	7	C	Confidential License Agreement with Akita Elpida Memory, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	8	C	Confidential License Agreement with AMD	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	9	C	Confidential License Agreement with Amkor Technology, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	10	C	Confidential License Agreement with Asahi Kasei Microsystems Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	11	C	Confidential License Agreement with ChipMOS Technologies, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	12	C	Confidential License Agreement with ChipPAC, Ltc. (BV1)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	13	C	Confidential License Agreement with Cochlear Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	14	C	Confidential License Agreement with Compeq Manufacturing Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	15	C	Confidential License Agreement with Crane Aerospace, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	16	C	Confidential License Agreement with DPAC Technologies Corp.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	17	C	Confidential License Agreement with EEMS Italia, SpA	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	18	C	Confidential License Agreement with Flexera	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	19	C	Confidential License Agreement with Flextech Holdings, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	20	C	Confidential License Agreement with Fujitsu, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	21	C	Confidential License Agreement with Hitachi Cable, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	22	C	Confidential License Agreement with Hitachi, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	23	C	Confidential License Agreement with Hynix Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	24	C	Confidential License Agreement with Infineon Technologies AG	Pickett	Tessera History, Domestic Industry	Admitted
JX	25	C	Confidential License Agreement with Integrated Packaging Assembly Corp. (now 12A Technologies, Inc.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	26	C	Confidential License Agreement with Intel Co.	Pickett	Tessera History, Domestic Industry	Admitted
JX	27	C	Confidential License Agreement with LG Micron Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	28	C	Confidential License Agreement with Matsushita Electric Industrial Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	29	C	Confidential License Agreement with Micron Technology, Inc.	Pickett	Tessera History, Domestic Industry	Admitted
JX	30	C	Confidential License Agreement with Miecer Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	31	C	Confidential License Agreement with Mitsui High-Tec Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	32	C	Confidential License Agreement with Mitsui Mining & Smelting Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	33	C	Confidential License Agreement with NEC Electronics Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	34	C	Confidential License Agreement with North Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	35	C	Confidential License Agreement with North Dakota State University	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	36	C	Confidential License Agreement with NXP B.V.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	37	C	Confidential License Agreement with Oki Electric Industry Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	38	C	Confidential License Agreement with Orient Semiconductor Electronics Ltd (OSE)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	39	C	Confidential License Agreement with Payton Technolog Corp.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	40	C	Confidential License Agreement with Plexus Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	41	C	Confidential License Agreement with Powertech Technology Inc. (PTI)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	42	C	Confidential License Agreement with Quimoda, AG	Pickett	Tessera History, Domestic Industry	Admitted
JX	43	C	Confidential License Agreement with Renesas Eastern Japan Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	44	C	Confidential License Agreement with Renesas Kyushu Semiconductor Corp.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	45	C	Confidential License Agreement with Renesas Northern Japan Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	46	C	Confidential License Agreement with Renesas Technology Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	47	C	Confidential License Agreement with ROHM Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	48	C	Confidential License Agreement with Samsung Electro-Mechanics Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	49	C	Confidential License Agreement with Samsung Electronics Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	50	C	Confidential License Agreement with Samsung Techwin Co., Ltd (formerly Samsung Aerospace)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	51	C	Confidential License Agreement with Sanyo Electric Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	52	C	Confidential License Agreement with Seiko Epson Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	53	C	Confidential License Agreement with SGS Thompson	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	54	C	Confidential License Agreement with Sharp Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	55	C	Confidential License Agreement with Shinko Electric Industries Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	56	C	Confidential License Agreement with Siemens AG	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	57	C	Confidential License Agreement with Siliconware Precision Industries Co., Ltd. (SPIL)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	58	C	Confidential License Agreement with Sony Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	59	C	Confidential License Agreement with Sunright Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	60	C	Confidential License Agreement with Texas Instruments, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	61	C	Confidential License Agreement with Toshiba Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	62	C	Confidential License Agreement with United Test and Assembly Center Ltd. (UTAC)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	63	C	Confidential License Agreement with United Test Center Inc. (UTC)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	64	C	Confidential License Agreement with University of Alaska	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	65	C	Confidential License Agreement with UTStarcom, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	66	C	Confidential License Agreement with Walton Advanced Electronics, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	67	C	TCC Patent License Agreement (Tessera & Seiko Espon Corp.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	68	C	TCC Master License Agreement (Tessera & Shinko Electronic Industries, Co.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	69	C	DiStefano Deposition Exhibit #148, Confidentail Invoices	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	70	C	DiStefano Deposition Exhibit #150, Declaration of Thomas H. Di Stephano in Support of Tessera's Opposition to TI's Summary Judgment Motion on Standing and Contract Issues and Countermotion	DiStefano	Background / Infrng/Non-infrng / Domestic Industry	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	71	C	License Agreement in conjunction with settlement of pending litigation (Tessera & Texas Instruments, Inc.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	72	C	Photos of Historical Tessera Parts	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	73	C	Settlement Agreement (Tessera & Micron Technology, Inc.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	74	C	Settlement Agreement (Tessera & Infineon Technologies AG, et al.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	75	C	Bottoms-Up database (Note: Corresponds to physical exhibit JPX-001C)	Mitchell	Domestic Industry	Admitted
JX	76	C	ATI Wire Bond Diagram for Customer Device W2240G(B12)	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	77	C	ATI Bonding Diagram for Customer Device No. W2240G(B11)	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	78	C	AT Bonding Diagram for Customer Device W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	79	C	Bond Diagram for Customer Device Name W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	80	C	STATSChipPAC Wire Bond Diagram for Customer Device W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	81	C	Bonding Diagram for Customer Device W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	82	C	Bond Diagram for Customer Device Name W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	83	C	Mawer Deposition Exhibit #022, Freescale Bill of Materials	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	84	C	Chopin Deposition Exhibit #003, Freescale Bill of Materials	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	85	C	Mawer Deposition Exhibit #024, Freescale Bill of Materials	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	86	C	84ARS10504D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	87	C	84ASA10578D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	88					Withdrawn
JX	89					Withdrawn
JX	90	C	84ASA10579D003	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	91					Withdrawn
JX	92	C	84ASA10683D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	93	C	67ARE10702D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	94	C	67ARE10744D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	95	C	67ARE11008D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	96	C	67ARE11080D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	97	C	67ASA11298D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	98	C	67ARE11534D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	99	C	84ARE11574D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	100	C	84ARE11593D002	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	101	C	84ARE11725D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	102	C	Darveaux_and_Mawer_-_Thermal_and_Power_Cycling_Limits_of_PBG.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	103	C	Mawer_Darveaux_and_Petrucci_-_Calculation_of_Thermal_Cyclin.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	104	C	98ARE10502D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	105	C	98ARE10525D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	106	C	98ASA10510D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	107	C	98ARE10527D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	108	C	98ASA10598D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	109	C	Mawer Deposition Exhibit #007, Meeting Notification e-mail for the meeting to Review TEPBGA/-II model and experimental results presentation	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	110	C	Chopin Deposition Exhibit #009, E-mail from R. Matthew to I. Ruzaini et al regarding Low K TEPBGA/-II development TSO	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	111	C	1997 CDF-AEC Rel Symp Foils	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	112	C	1997 IRPS Foils, Part I.ppt	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	113	C	1997 IRPS Foils, Part II.ppt	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	114	C	1999 CTEA Foils.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	115	C	225 & 361 PBGA Build Rprt.doc	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	116	C	BGA Trend Paper-A. Mawer.doc	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	117					Withdrawn
JX	118					Withdrawn
JX	119					Withdrawn
JX	120	C	Darveauz and Mawer - Thermal and Power Cycling Limits of PBGA Assem.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	121	C	SUNY-Binghamton Foils-6-98	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	122	C	McShane Deposition Exhibit #003, Freescale presentation titled, "Introduction to the Plastic Ball Grid Array (PBGA)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	123	C	46 uBGA Brd_Lvl Cycling-6-98.ppt	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	124	C	Montgomery Deposition Exhibit #013, Freescale list regarding Invoices	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	125	C	McShane Deposition Exhibit #012, Motorola Presentation titled,"Tessera-Style µBGA Board Level Thermal Cycling Data"	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	126					Withdrawn

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Info Evidence
JX	127	C	Balog Deposition Exhibit #016, Mobile Devices List, , Jan - Nov 2007, All Products	Qu, Bradley, Gallagher, Banjeri, Beradoni, Gilmore, Karpinia, Reiff, Zollo, Luciano, Richards, Yang, Shurboff, Hyink, Hoffman, Johnson, Balog, Alberth, Olis, Bockol, Collins, Lehrer, Mullen, Brda, Brown, Greb, and/or Hertz	Infrng/Non-infrng	Admitted
JX	128	C	Holmes Deposition Exhibit #007, Qualcomm 409 CSP Package Specification 80-V2970-1 Revision F	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	129	C	Qualcomm Package Outline Drawing, Drawing NO. NT90-VA911-2	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	130	C	Gregorich Deposition Exhibit #004, Peet Test: A Novel Method for Evaluating Pb-Free CSP Solder Joint Reliability	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	131	C	Preecha Deposition Exhibit #004, Qualcomm Document Titled,"Engineering Marking Diagram, QSC6030, 351MSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	132	C	Holmes Deposition Exhibit #016-B, Qualcomm Process Flow Chart Specification for 2-DIE Stacked CSP, MH80-VB600-C1 Rev. B	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	133	C	Holmes Deposition Exhibit #016-C, Qualcomm Process Flow Chart, Specification for 2-DIE Stacked CSP, MH80-VB600-E1 Rev. B	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	134	C	Preecha Deposition Exhibit #003, Qualcomm Report titled,"IC Package Environmental Roadmap"	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	135	C	Holmes Deposition Exhibit #016-D, Qualcomm Process Flow Chart Specification for Single DIE DSP/BGA	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	136	C	Holmes Deposition Exhibit #016-E, Qualcomm Process Flow Chart Specification for 3-DIE Side by Side CSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	137	C	Holmes Deposition Exhibit #016-F, Qualcomm Process Flow Chart Specification for Single Die CSP/BGA	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	138	C	Holmes Deposition Exhibit #016-A, Qualcomm Process Flow Chart Specification for Single DIE DSP/BGA, MH80-VB600-H2 Rev. B	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	139	C	Holmes Deposition Exhibit #016-G, Qualcomm Process Flow Chart Specification for 3-DIE Side by Side CSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	140	C	Holmes Deposition Exhibit #016-H, Qualcomm Process Flow Chart Specification for Wire-Bond Stacked Module Package CSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	141	C	Gregorich Deposition Exhibit #016, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	142	C	Gregorich Deposition Exhibit #017, Email from T. Gregorich to E. Egan et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	143	C	Gregorich Deposition Exhibit #005, Email from R. Horvath to Tom Gregorich	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	144	C	Holmes II Deposition Exhibit #013, Email chain beginning 1/16/2003	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	145	C	Gregorich Deposition Exhibit #11, Email from R. Rice to P. Holmes	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	146	C	Gregorich Deposition Exhibit #21, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	147	C	Holmes II Deposition Exhibit #014, Email chain beginning 8/4/2006 (MSM6550-409CSP)	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	148	C	Preecha Deposition Exhibit #007, 2002 APEX Exhibition Conference Report	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	149	C	Gregorich Deposition Exhibit #008, Email from M. Savoy to E. Reyes et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	150	C	Gregorich Deposition Exhibit #14, Email from R. Palys to N. Anamosa	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	151	C	Gregorich Deposition Exhibit #007, Email from E. Reyes to Tom Gregorich	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	152	C	Veatch Deposition Exhibit #013, Finite Element Analysis	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	153	C	Gregorich Deposition Exhibit #20, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	154	C	Gregorich Deposition Exhibit #009, Email from T. Gregorich to P. Moise et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	155	C	BGA/CSP Package User Guide, July 26, 2002	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	156	C	BGA/CSP Package User Guide	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

Prefix	Exhibit Number	Conf or Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	157	C	Gregorich Deposition Exhibit #24, Email from T. Gregorich to J. Gabriel et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	158	C	Gregorich Deposition Exhibit #10, Email from T. Gregorich R. Horvath et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	159	C	Gregorich Deposition Exhibit #22, "Impact of Ball Via Configurations on Solder Joint Reliability in Tape Based Chip-Scale Packages"	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	160	C	Holmes II Deposition Exhibit #016, Email from Sarah Weldon	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	161	C	Gregorich Deposition Exhibit #15, Email from T. Gregorich to J. Clifford et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf/or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	162	C	Gregorich Deposition Exhibit #006, Email from R. Lane to L. Zhao et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	163	C	Gregorich Deposition Exhibit #26, 320 Chip-Scale-Package (CSP)	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	164	C	Gregorich Deposition Exhibit #25, 320 CSP Mechanical Modeling	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	165	C	Holmes II Deposition Exhibit #017, Email from Rick Horvath	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	166	C	Gregorich Deposition Exhibit #19, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	167	C	Gregorich Deposition Exhibit #27, Email from M. Veatch to S. Weldon et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	168	C	Foong Deposition Exhibit #003, Document entitled "Concode for FBGA & MCP Package Family (Per F09-000)	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	169	C	Spansion Binding Diagram for Device 98M73A	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	170	C	Technical Drawings re LAA080	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	171	C	Technical Drawings re VDE044, Package 28158	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	172	C	Spansion Billings Reports through Q4 2006	Russell	Importation / Remedies	Admitted
JX	173	C	Spansion Billings Reports through 2006	Russell	Importation / Remedies	Admitted
JX	174	C	Malone Deposition - December 12, 2007 - Exhibit 16 - Product List	Malone	Infrng/Non-infrng / Remedy	Admitted
JX	175	C	Built Sheet Assembly for M36W0R7040U0ZC5U	Malone	Infrng/Non-infrng, Remedy	Admitted
JX	176	C	Package Outline Assembly for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
JX	177	C	Substrate Technical Specs. for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
JX	178	C	How to Solder a BGA On a Printed Circuit Board	Qu	Infrng/Non-infrng	Admitted
JX	179	C	Substrate Technical Specs. for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
JX	180	C	Substrate Technical Specs. for XCOZ*W4QN5KO (XCOZW4QN5KOT706U)	Qu	Infrng/Non-infrng	Admitted
JX	181	C	Substrate Technical Specs. for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Qu	Infrng/Non-infrng	Admitted
JX	182	C	Substrate Technical Specs. for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted
JX	183	C	Substrate Technical Specs. for XCAIP5JF5KOB706F	Qu	Infrng/Non-infrng	Admitted
JX	184	C	Substrate Technical Specs. for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
JX	185	C	Package Outline Assembly for XCAIP5JF5KOB706F	Qu	Infrng/Non-infrng	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Info Evidence:
JX	186	C	Package Outline Assembly for XCOZ*W4QN5KO (XCOZW4QN5KOT706U)	Qu	Infrng/Non-infrng	Admitted
JX	187	C	Package Outline Assembly for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
JX	188	C	Mount & Bond Diagram for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
JX	189	C	Company Presentation, January 24, 2007	Qu	Infrng/Non-infrng, Remedy	Admitted
JX	190	C	Malone Deposition - Exhibit 2 - Document Entitled, "Company Presentation - January 24, 2007"	Malone	Infrng/Non-infrng, Remedy	Admitted
JX	191	C	Malone Deposition - Exhibit 15 - Document Entitled, "Subcontractors Quotations for 2000 Q1 - Rev. A"	Malone	Infrng/Non-infrng, Remedy	Admitted
JX	192	C	Built Sheet Assembly for XCAIP5JF5KOB706F	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
JX	193	C	ST Microelectronics Inc. Invoices (multiple dates)	Qu	Infrng/Non-infrng	Admitted
JX	194	C	ST-Inc Invoice to Nokia	Hundt	Infrng/Non-infrng, Remedy, Vldy/Invldy	Admitted
JX	195	C	STMicroelectronics-N.V. Invoices (multiple dates)	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	196	C	ST-NV Invoice to Nokia	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	197					Withdrawn
JX	198	C	Transcript of the Rule 30(b)(6) deposition of Michael J. Hundt in the Tessera, Inc. v. Advanced Micro Devices, Inc. litigation in the United States District Court for the Northern District of California.	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	199	C	Mount & Bond Diagram for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	200	C	Built Sheet Assembly for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Hundt		Admitted
JX	201	C	Malone Deposition - December 12, 2007 - Exhibit 11 - STMicroelectronics Americas Invoice Summary	Qu	Infrng/Non-infrng	Admitted
JX	202	C	Malone Deposition - December 12, 2007 - Exhibit 10 - STMicroelectronics Americas Invoice Summary	Qu	Infrng/Non-infrng	Admitted
JX	203					Withdrawn
JX	204					Withdrawn
JX	205	C	Hundt Deposition - March 28, 2007 - Exhibit 214 - Document entitled "Glue Die Attach in Process Control"	Hundt	Infrng/Non-infrng	Admitted
JX	206					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Confor. Pub.	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	207					Withdrawn
JX	208					Withdrawn
JX	209	C	Hundt Deposition - March 28, 2007 - Exhibit 210 - Procurement Specification for a BGA Substrate	Hundt	Infrng/Non-infrng	Admitted
JX	210	C	Hundt Deposition - March 28, 2007 - Exhibit 217 - Package Outline for TFBGA *x10x1.20 88 F8x10+8 Pitch 0.8	Hundt	Infrng/Non-infrng	Admitted
JX	211	C	Hundt Deposition - March 28, 2007 - Exhibit 226 - Schematic of TFBGA Package	Hundt	Infrng/Non-infrng	Admitted
JX	212					Withdrawn
JX	213	C	Hundt Deposition - March 28, 2007 - Exhibit 209 - Package Outline - BASE TFBGA 47L 6.39X6.37-2L-DP 5.4X4.77MM Pitch 0.75MM	Hundt	Infrng/Non-infrng	Admitted
JX	214					Withdrawn
JX	215					Withdrawn
JX	216					Withdrawn
JX	217	C	Hundt Deposition - March 28, 2007 - Exhibit 234 - Document entitled "Deisgn for Package Board Level Reliability with CAE.	Hundt	Infrng/Non-infrng	Admitted
JX	218	C	Hundt Deposition - March 29, 2007 - Exhibit 237 - Document Entitled "CSP at ST Microelectronics"	Hundt	Infrng/Non-infrng	Admitted
JX	219					Withdrawn
JX	220	C	Hundt Deposition - March 28, 2007 - Exhibit 216 - Build Sheet Assembly for MCOL*5M39598	Hundt	Infrng/Non-infrng	Admitted
JX	221	C	Hundt Deposition - March 28, 2007 - Exhibit 211 - Product Specification for Assembly of a Product	Hundt	Infrng/Non-infrng	Admitted
JX	222	C	Hundt Deposition - March 28, 2007 - Exhibit 212 - Bonding Diagram for KX*A5C0	Hundt	Infrng/Non-infrng	Admitted
JX	223					Withdrawn
JX	224					Withdrawn
JX	225					Withdrawn
JX	226					Withdrawn
JX	227					Withdrawn
JX	228					Withdrawn
JX	229					Withdrawn
JX	230					Withdrawn
JX	231					Withdrawn
JX	232					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	233					Withdrawn
JX	234					Withdrawn
JX	235	C	Combined Deposition Designations for Balog			Admitted
JX	236	C	Combined Deposition Designations for Bradley			Admitted
JX	237	C	Combined Deposition Designations for Brda			Admitted
JX	238	C	Combined Deposition Designations for M. Brown			Admitted
JX	239	C	Combined Deposition Designations for Sheila Chopin			Admitted
JX	240					Withdrawn
JX	241					Withdrawn
JX	242	C	Combined Deposition Designations for Frankel			Admitted
JX	243	C	Combined Deposition Designations for Gerfin			Admitted
JX	244	C	Combined Deposition Designations for Greb			Admitted
JX	245	C	Combined Deposition Designations for Thomas Gregorich			Admitted
JX	246					Withdrawn
JX	247					Withdrawn
JX	248	C	Combined Deposition Designations for Holmes			Admitted
JX	249	C	Combined Deposition Designations for Michael Hundt			Admitted
JX	250					Withdrawn
JX	251					Withdrawn
JX	252	C	Combined Deposition Designations for Kellar			Admitted
JX	253					Withdrawn
JX	254	C	Combined Deposition Designations for Leoni			Admitted
JX	255	C	Combined Deposition Designations for Malone			Admitted
JX	256	C	Combined Deposition Designations for Mawer			Admitted
JX	257	C	Combined Deposition Designations for McLellan			Admitted
JX	258	C	Combined Deposition Designations for McShane			Admitted
JX	259	C	Combined Deposition Designations for Montgomery			Admitted
JX	260					Withdrawn
JX	261	C	Combined Deposition Designations for Murray			Admitted
JX	262	C	Combined Deposition Designations for O'Leary			Admitted
JX	263					Withdrawn
JX	264	C	Combined Deposition Designations for Romankiw			Admitted
JX	265	C	Combined Deposition Designations for Roossien			Admitted
JX	266	C	Combined Deposition Designations for Russell			Admitted
JX	267	C	Combined Deposition Designations for Shah			Admitted
JX	268	C	Combined Deposition Designations for Suresh			Admitted
JX	269					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS (CORRECTED)

August 5, 2008

Prefix	Exhibit Number	Confor Pub	Description	Sponsoring Witness	Stmt of Purpose	Receipt Into Evidence
JX	270	C	Combined Deposition Designations for Veatch			Admitted
JX	271	C	Combined Deposition Designations for Witten			Admitted
JX	272					Withdrawn
JX	273					Withdrawn
JX	274					Withdrawn
JX	275					Withdrawn
JX	276	C	Combined Deposition Designations for Khandros			Admitted
JX	277	C	Combined Deposition Designations for Kim			Admitted
JX	278	C	Combined Deposition Designations for Craig Mitchell			Admitted
JX	279	C	Combined Deposition Designations for Pickett			Admitted
JX	280	C	Combined Deposition Designations for Shimada			Admitted
JX	281					Withdrawn
JX	282	C	Combined Deposition Designations for Licciardello			Admitted
JX	283	C	Combined Deposition Designations for Perillat			Admitted
JX	284					Withdrawn
JX	285	C	Combined Deposition Designations for Chambers			Admitted

UNITED STATES INTERNATIONAL TRADE COMMISSION
WASHINGTON, D.C.

Before the Honorable Theodore R. Essex
Administrative Law Judge

IN THE MATTER OF CERTAIN SEMICONDUCTOR CHIPS WITH MINIMIZED CHIP PACKAGE SIZE AND PRODUCTS CONTAINING SAME	Investigation No. 337-TA-605

RESPONDENTS' EXHIBIT LIST

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1					WITHDRAWN	
RX	2		File History United States Patent No. 5,148,266		INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3					WITHDRAWN	
RX	4					WITHDRAWN	
RX	5		File History United States Patent No. 5,347,159 [QTSI00798818 - QTSI00799247]	Stipulation	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	6		File History for U.S. Patent No. 5, 679, 977	Schaper, Ivey, Lall	VLD/INVLD	ADMITTED	7/17/2008 7/18/2008
RX	7					WITHDRAWN	
RX	8					WITHDRAWN	
RX	9					WITHDRAWN	
RX	10					WITHDRAWN	
RX	11					WITHDRAWN	
RX	12					WITHDRAWN	
RX	13					WITHDRAWN	
RX	14					WITHDRAWN	
RX	15		File History United States Patent No. 6,465,893; [QTSI00703783 - QTSI00704286]	Stipulation	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	16					WITHDRAWN	
RX	17		File History United States Patent No. 7,198,969; [QTSI00823025 - QTSI00823563]	Stipulation	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	18	C				WITHDRAWN	
RX	19	C				WITHDRAWN	
RX	20	C				WITHDRAWN	
RX	21	C				WITHDRAWN	
RX	22	C				WITHDRAWN	
RX	23	C				WITHDRAWN	
RX	24	C				WITHDRAWN	
RX	25					WITHDRAWN	
RX	26					WITHDRAWN	
RX	27	C	Product Group and Package Description for ST Commercial Product Codes	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	28	C	Distributor Agreement between STMicroelectronics N.V. and STMicroelectronics, Inc., dated February 1, 2001	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	29	C	Services Agreement between STMicroelectronics, Inc. and STMicroelectronics N.V., dated June 18, 2000	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	30	C	Front-End Manufacturing Agreement between STMicroelectronics, Inc. and STMicroelectronics N.V., dated February 1, 2001	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	31	C	Sponsored Research and Development Contract between STMicroelectronics N.V. and STMicroelectronics, Inc., dated February 1, 2001	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	32	C				WITHDRAWN	
RX	33	C				WITHDRAWN	
RX	34	C				WITHDRAWN	
RX	35	C				WITHDRAWN	
RX	36	C				WITHDRAWN	
RX	37					WITHDRAWN	
RX	38		United States Patent and Trademark Office ("USPTO") Order Granting Request for Ex Parte Reexamination of the '326 patent, Reexamination Control No. 90/008,483 (April 20, 2007)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	39	C				WITHDRAWN	
RX	40	C				WITHDRAWN	
RX	41	C				WITHDRAWN	
RX	42					WITHDRAWN	
RX	43					WITHDRAWN	
RX	44	C	Rebuttal Expert Report of Dr. Paul S. Min Regarding U.S. Patent Nos. 5,852,326 and 6,433,419	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	45		Exhibit A to the Expert Report of Dr. Paul Min, Resume of Dr. Paul S. Min	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	46		Exhibit B to the Expert Report of Dr. Paul S. Min, List of Publications of Dr. Paul S. Min	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	47		Exhibit C to the Expert Report of Dr. Paul S. Min, List of Reviewed Materials	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	48	C				WITHDRAWN	
RX	49	C				WITHDRAWN	
RX	50		Exhibit F to the Expert Report of Dr. Paul S. Min, '159 patent, File History, July 7, 1993 Amendment	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008 7/22/2008
RX	51		Exhibit G to the Expert Report of Dr. Paul S. Min, U.S. Pat. No. 4,941,033	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	52		Exhibit H to the Expert Report of Dr. Paul S. Min, Declaration of Michael G. Pecht in Support of Texas Instruments Incorporated's Claim Construction Brief, together with exhibits, United States District Court Northern District of California Oakland Division, Case No. C 00 - 02114, January 19, 2001	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	53	C	Exhibit I to the Expert Report of Dr. Paul S. Min, Freescale Drawing No. 67ASA11431D, originally dated June 16, 2004	Qu / MIN / Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/16/2008 7/17/2008
RX	54	C	Exhibit J to the Expert Report of Dr. Paul S. Min, "Circuit Configuration 185 I/O MAP PBGA, 10 x 10 PKG, 0.5 MM Pitch," Freescale Drawing No. 84ASA10683D, originally dated April 27, 2004	MIN / Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008 7/17/2008
RX	55	C	Exhibit K to the Expert Report of Dr. Paul S. Min, "AtlasUL MAP BGA Post - Decap Images," Freescale Presentation by Andrew Mawer, November 2, 2007	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	56	C	Exhibit L to the Expert Report of Dr. Paul S. Min, "Wirebonded Plastic Ball Grid Array Package Assembly Process Characterization," Freescale Document 12MRS03706W, originally dated June 17, 1998.	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	57		Exhibit M to the Expert Report of Dr. Paul S. Min, "Bond Wire Modeling Standard," JEDEC Publication No. EIA/JESD59, dated June 1997	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	58	C	Exhibit N to the Expert Report of Dr. Paul S. Min, Sharp Initial Determination	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	59		Exhibit 0 to the Expert Report of Dr. Paul S. Min, Samsung Electronics Co. v. Tessera Techs., Inc., Jan. 8, 2004 Order	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	60	C				WITHDRAWN	
RX	61		Exhibit Q to the Expert Report of Dr. Paul S. Min, "Metal Package Specification for Microelectronic Packages and Covers," JEDEC Standard No. 9 - A, April 1987	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	62	C				WITHDRAWN	
RX	63	C				WITHDRAWN	
RX	64	C				WITHDRAWN	
RX	65		Exhibit U to the Expert Report of Dr. Paul S. Min, "Compliancy Modeling of an Array Chip Scale Package," Fjelstad, DiStefano, and Perry	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	66		Exhibit V to the Expert Report of Dr. Paul S. Min, "Reliability Prediction Modeling of Area Array CSPs," Clech and Fjelstad	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	67		Exhibit W to the Expert Report of Dr. Paul S. Min, FSL - ITC00133440	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	68	C	Exhibit X to the Expert Report of Dr. Paul S. Min, FSL - ITC00133438	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	69	C				WITHDRAWN	
RX	70		Resume of Carla S. Mulhern	Mulhern	RMDY	ADMITTED	7/18/2008
RX	71		Documents Review and/or Relied Upon	Mulhern	RMDY	ADMITTED	7/18/2008
RX	72	C	List of Products Identified by ST - NV	Mulhern	RMDY	ADMITTED	7/18/2008
RX	73	C	ST - NV Products from Motorola's Responses to Tessera's Interrogatories	Mulhern	RMDY	ADMITTED	7/18/2008
RX	74	C	ST - NV Products from Nokia's Objections to Subpoena Duces Tecum	Mulhern	RMDY	ADMITTED	7/18/2008
RX	75	C	ST - NV Part Numbers Identified in Nokia Handsets	Mulhern	RMDY	ADMITTED	7/18/2008
RX	76	C	Relative Value of ST - NV Products to Products Identified by Motorola	Mulhern	RMDY	ADMITTED	7/18/2008
RX	77		Mobile Handset Net Sales / Unit Volume to the U.S. / North AmericaNokia, Motorola and Sony Ericsson 2006	Mulhern	RMDY	ADMITTED	7/18/2008
RX	78	C	Worldwide NOR Flash Market Shares Q3 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RX	79	C	Worldwide NAND Flash Market Shares Q3 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RX	80		U.S. Imports for ConsumptionCellular Phones and Set - Top BoxesJanuary âˆ’ October 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RX	81	C	U.S. Imports for ConsumptionProduct Types Identified by TesseraJanuary âˆ’ October 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RX	82	C				WITHDRAWN	
RX	83	C				WITHDRAWN	
RX	84	C				WITHDRAWN	
RX	85	C				WITHDRAWN	
RX	86	C				WITHDRAWN	
RX	87	C				WITHDRAWN	
RX	88	C				WITHDRAWN	
RX	89	C				WITHDRAWN	
RX	90	C				WITHDRAWN	
RX	91	C				WITHDRAWN	
RX	92	C				WITHDRAWN	
RX	93	C				WITHDRAWN	
RX	94	C				WITHDRAWN	
RX	95	C				WITHDRAWN	

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	96	C				WITHDRAWN	
RX	97	C				WITHDRAWN	
RX	98	C				WITHDRAWN	
RX	99	C				WITHDRAWN	
RX	100	C				WITHDRAWN	
RX	101	C				WITHDRAWN	
RX	102					WITHDRAWN	
RX	103	C				WITHDRAWN	
RX	104	C				WITHDRAWN	
RX	105	C				WITHDRAWN	
RX	106	C				WITHDRAWN	
RX	107	C				WITHDRAWN	
RX	108	C				WITHDRAWN	
RX	109	C				WITHDRAWN	
RX	110	C				WITHDRAWN	
RX	111	C				WITHDRAWN	
RX	112	C				WITHDRAWN	
RX	113	C				WITHDRAWN	
RX	114	C				WITHDRAWN	
RX	115	C				WITHDRAWN	
RX	116	C				WITHDRAWN	
RX	117	C				WITHDRAWN	
RX	118	C				WITHDRAWN	
RX	119	C				WITHDRAWN	
RX	120	C				WITHDRAWN	
RX	121	C				WITHDRAWN	
RX	122	C				WITHDRAWN	
RX	123	C	TCC License Agreement between Tessera, Inc. and SGS - Thomson Microelectronics, Inc.	Shah / Malone	INFRNG/NON-INFRNG	ADMITTED	7/17/2008 7/18/2008
RX	124	C	9/25/1996 Email re: TBGA 9x9 Development for NMP	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	125	C	November 14, 2002 Letter from Shah to Pickett	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	126	C	May 18, 2004 Presentation from ST to Tessera	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	127	C	April 12, 2005 Presentation from ST to Tessera	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	128	C	June 16, 2003 Presentation from Tessera to ST	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	129	C	January 22, 2004 Presentation from ST to Tessera	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	130	C				WITHDRAWN	
RX	131	C				WITHDRAWN	
RX	132	C				WITHDRAWN	
RX	133	C				WITHDRAWN	
RX	134	C				WITHDRAWN	
RX	135	C				WITHDRAWN	
RX	136	C				WITHDRAWN	
RX	137	C				WITHDRAWN	
RX	138	C	Rebuttal Expert Report of Dr. Suresh K. Sitaraman Regarding Noninfringement of United States Patent Nos. 5,852,326 and 6,433,419	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	139		Curriculum Vitae of Suresh K. Sitaraman	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	140	C				WITHDRAWN	
RX	141	C	Tessera's Admissions (Exhibit 3 to Sitaraman Expert Report)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	142	C	Respondents' Technical Documentation	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	143	C	October 10, 2001 Letter from Chris Pickett to ST Inc. with Updated Attachment A listing additional patents automatically covered by License Agreement	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	144	C				WITHDRAWN	
RX	145	C				WITHDRAWN	
RX	146	C	Purchasing Specification Lead Free Solder Balls Used for BGA & CSP Packages	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	147	C	BGA / LGA TAPE DIE ATTACH IN PROCESS CONTROL	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	148	C	BGA / LGA TAPE DIE ATTACH IN PROCESS CONTROL	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	149	C	Glue Die Attach in Process Control	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	150	C				WITHDRAWN	
RX	151	C				WITHDRAWN	
RX	152	C				WITHDRAWN	
RX	153	C				WITHDRAWN	
RX	154	C				WITHDRAWN	
RX	155	C				WITHDRAWN	
RX	156	C				WITHDRAWN	
RX	157	C				WITHDRAWN	
RX	158	C				WITHDRAWN	
RX	159	C				WITHDRAWN	
RX	160	C				WITHDRAWN	
RX	161	C	Advance Pricing Agreement with IRS	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	162	C	PACKAGE OUTLINE FOR TFBGA 8x10x1.20 88 F8x10+8 Pitch 0.8	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	163	C				WITHDRAWN	
RX	164	C	Document Exchange Register, ST/Tessera	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	165	C				WITHDRAWN	
RX	166	C				WITHDRAWN	
RX	167	C				WITHDRAWN	
RX	168	C				WITHDRAWN	
RX	169	C	Presentation by Bill Carlson entitled "Tessera Manufacturing Overview"	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	170	C				WITHDRAWN	
RX	171	C				WITHDRAWN	
RX	172	C				WITHDRAWN	
RX	173	C				WITHDRAWN	
RX	174	C				WITHDRAWN	
RX	175	C	Trial Planning Chart	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	176	C	BGA Strip Design	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	177	C	PPG 256 BGA PREQUALIFICATION PLAN	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	178	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	179	C	Evaluation Report 0894 - A; Subject: Encapsulation Choice for BGA	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	180	C	Evaluation Report 1094 - B; Subject: Surface Treatment for BGA	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	181	C	Evaluation Report 0295 - A; Subject: EVALUATION OF BGA256 SUBSTRATES	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	182	C	Assembly Traveler for TV-46	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	183	C	July 10, 1997 Memo re: Tessera process	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	184	C	Fax from Carlson to Hundt et al. dated Aug. 27, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	185	C	Batel: Ball Grid Array Technologies for Advanced Telecom Applications	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	186	C	Chip Scale Package - LCC48	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	187	C	Corporate Package DEVT GNB Presentation Content	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	188	C	Email re: BGA status	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	189	C	Patent Cross License between IBM and ST Microelectronics N.V.	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	190	C	Fax from Magni to Blue M Electric dated Aug. 8, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	191	C	Fax re: New BGA design	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	192	C	Diagram - BGA 9x9 64 I/O - Molded Balls Attached	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	193	C	BGA Matrix Strip Study	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	194	C	10/16/1996 Email re: 8x8 BGA for Nokia	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	195	C	10/23/1996 Email re: minutes of BGA meeting	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	196	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	197	C	e-mail from Philippe Geyres to Georges Fillot re: BGA line near a Front End, dated 30/12/1996	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	198	C				WITHDRAWN	
RX	199	C	slides from presentation titled "PPG Packaging," by G. Fillot, presented Nov. 27 - 28, 1996	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	200	C	e-mail from Laurent Herard to DHOPK re: BGA 9*9 and 21*21 meeting, dated 11/27/96	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	201	C	e-mail from Luc Mary to Juhani Kalanti re: µBGA 8x8, dated 10/9/96	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	202	C				WITHDRAWN	
RX	203	C	List of equipment needed to implement uBGA process	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	204	C	ST Presentation entitled "Tessera uBGA EQUIPMENT General" dated July 25, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	205	C	ST Presentation entitled "TESSERA microBGA package structure" dated December, 1998	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	206	C	Qualification plan for uBGA	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	207	C	ST Capital Appropriation Request	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	208	C	Handwritten process description	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	209	C	October 18, 2002 Letter from Pickett to Jorgenson	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	210	C	Tessera uBGA Production Line Description	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	211	C	Specification for Camalot Encapsulation System	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	212	C	Tessera uBGA Equipment List and Status	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	213	C	Email from Brechignac to Magni dated Aug. 4, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	214	C	Email from Brechignac to Magni dated Aug. 4, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	215	C	Fax from Magni to Gemperle dated Aug. 26, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	216	C	Fax from Cigada to Authier dated Oct. 16, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	217	C	Fax from Magni to Ausserladscheider dated Oct. 8, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	218	C	Fax from Magni to Ramsey dated Aug. 7, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	219	C	November 4, 2002 Letter from Shah to Pickett	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	220	C				WITHDRAWN	
RX	221	C	November 4, 2002 Letter from Pickett to Shah	Shah / Pickett	INFRNG/NON-INFRNG, RMDY, OWNR	ADMITTED	7/15/2008 7/17/2008
RX	222	C	Substrate specification for M36LOR8060B7ZAQ; BASE TFBGA 88L 10x8 2LY DP8.4x7.7 MM PITCH 0.8MM	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	223	C	Bond Diagram for M36LOR8060B7ZAQ; Mount and Bond Diagram for: OL*535W	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	224	C				WITHDRAWN	
RX	225	C	Copy of 1997 TCC License Agreement between Tessera and ST - Inc. used in deposition of Chris Pickett in Tessera, Inc. v. Advanced Micro Devices, Inc., et al., Case No. C 05 - 04063 (CW) (N.D. Cal. 2006) ("the AMD Case")	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	226	C				WITHDRAWN	
RX	227					WITHDRAWN	
RX	228	C				WITHDRAWN	
RX	229	C				WITHDRAWN	
RX	230	C	May 7, 2003 Letter from Shah to Griffin	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	231	C				WITHDRAWN	
RX	232	C				WITHDRAWN	
RX	233					WITHDRAWN	
RX	234	C				WITHDRAWN	
RX	235		Order on Cross - Motions for Summary Judgment in the TI case, dated November 14, 2001, which granted TI's motion to dismiss Tessera's patent infringement counterclaims	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	236					WITHDRAWN	
RX	237					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	238					WITHDRAWN	
RX	239	C	May 29, 2003 Letter from Griffin to Shah	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	240					WITHDRAWN	
RX	241	C				WITHDRAWN	
RX	242	C				WITHDRAWN	
RX	243	C				WITHDRAWN	
RX	244	C				WITHDRAWN	
RX	245	C				WITHDRAWN	
RX	246	C				WITHDRAWN	
RX	247	C	July 29, 2004 Email from Jorgenson to Pickett	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	248	C				WITHDRAWN	
RX	249	C				WITHDRAWN	
RX	250	C				WITHDRAWN	
RX	251	C				WITHDRAWN	
RX	252	C	Fax from Galia to Magni dated Nov. 24, 1997	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	253	C				WITHDRAWN	
RX	254					WITHDRAWN	
RX	255					WITHDRAWN	
RX	256					WITHDRAWN	
RX	257	C				WITHDRAWN	
RX	258	C				WITHDRAWN	
RX	259	C				WITHDRAWN	
RX	260	C	Expert Report of Dr. Jianmin Qu - Current Investigation - 337-TA-605	Qu / Sitaraman / Schaper	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/15/2008 7/16/2008 7/18/2008
RX	261	C				WITHDRAWN	
RX	262	C				WITHDRAWN	
RX	263	C				WITHDRAWN	
RX	264	C				WITHDRAWN	
RX	265	C				WITHDRAWN	
RX	266	C				WITHDRAWN	
RX	267	C				WITHDRAWN	

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RX	268	C	Rebuttal Expert Report of Jianmin Qu - Texas Instruments v. Tessera	Qu/Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/16/2008
RX	269	C				WITHDRAWN	
RX	270	C				WITHDRAWN	
RX	271	C				WITHDRAWN	
RX	272	C	Rebuttal Expert Report of Jianmin Qu, Ph.D. (re Dr. Ho & Dr. Lee) - Texas Instruments v. Tessera	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	273	C				WITHDRAWN	
RX	274	C				WITHDRAWN	
RX	275	C				WITHDRAWN	
RX	276	C				WITHDRAWN	
RX	277	C				WITHDRAWN	
RX	278	C				WITHDRAWN	
RX	279	C				WITHDRAWN	
RX	280	C				WITHDRAWN	
RX	281	C				WITHDRAWN	
RX	282	C				WITHDRAWN	
RX	283	C				WITHDRAWN	
RX	284	C				WITHDRAWN	
RX	285	C	Supplemental Expert Report of Jianmin Qu, Ph.D. - Texas Instruments v. Tessera	Qu / Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/16/2008
RX	286	C				WITHDRAWN	
RX	287	C				WITHDRAWN	
RX	288	C				WITHDRAWN	
RX	289	C				WITHDRAWN	
RX	290	C				WITHDRAWN	
RX	291	C	W2182D_2.pdfSubstrate Design 259L STK LFBGA (10x10 MM) (1+2+1 Layers)(ATI-ITC 038077 - ATI-ITC 038089)	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	292	C				WITHDRAWN	
RX	293	C				WITHDRAWN	
RX	294	C				WITHDRAWN	
RX	295	C				WITHDRAWN	
RX	296	C				WITHDRAWN	
RX	297	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	298	C	Wirebonded Plastic Ball Grid Array Package Assembly Process Characterization, Freescale Document 12MRS03706W, originially dated June 1997	Chopin	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	299	C				WITHDRAWN	
RX	300	C				WITHDRAWN	
RX	301	C	1995 SMI Australia Slides.ppt PowerPoint Presentation by Andrew J. Mawer "Implementing Reliability BGA Surface Mount Interconnections" Sept. 20, 1995; - The Sidney Study - [Confidential FSL-ITC 00785127]	Mawer	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	302	C				WITHDRAWN	
RX	303	C				WITHDRAWN	
RX	304	C				WITHDRAWN	
RX	305	C				WITHDRAWN	
RX	306	C				WITHDRAWN	
RX	307	C	AN123~NZ.PDFAndrew Mawer "Plastic Ball Grid Array (PBGA) AN1231" Nov. 4, 1996; [Confidential FSL-ITC 00785139]	Mawer / Sitaraman	RMDY, DI, INFRNG/NON-INFRNG.	ADMITTED	7/16/2008
RX	308	C				WITHDRAWN	
RX	309	C	"Confidential FSL-ITC 00785141 BGA Die Attach Report_ rev a4.ppt"PowerPoint Presentation by FMTC Die Attach Team "Non-Conductive Die Attach Final Recommendation Management Summary" Oct. 17, 2003	Chopin	OWNR, INFRNG/NON-INFRNG.	ADMITTED	7/17/2008
RX	310	C				WITHDRAWN	
RX	311	C				WITHDRAWN	
RX	312	C				WITHDRAWN	
RX	313	C				WITHDRAWN	
RX	314	C				WITHDRAWN	
RX	315	C				WITHDRAWN	
RX	316	C				WITHDRAWN	
RX	317	C				WITHDRAWN	
RX	318	C				WITHDRAWN	
RX	319	C				WITHDRAWN	
RX	320	C				WITHDRAWN	
RX	321	C				WITHDRAWN	
RX	322	C				WITHDRAWN	
RX	323	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	324	C				WITHDRAWN	
RX	325	C				WITHDRAWN	
RX	326	C				WITHDRAWN	
RX	327	C				WITHDRAWN	
RX	328	C				WITHDRAWN	
RX	329	C				WITHDRAWN	
RX	330	C				WITHDRAWN	
RX	331	C				WITHDRAWN	
RX	332	C				WITHDRAWN	
RX	333	C				WITHDRAWN	
RX	334	C				WITHDRAWN	
RX	335	C				WITHDRAWN	
RX	336	C				WITHDRAWN	
RX	337	C				WITHDRAWN	
RX	338	C				WITHDRAWN	
RX	339	C				WITHDRAWN	
RX	340	C	Confidential FSL-ITC 00785186 Non-Conductive Epoxy Status (R).pdfPowerPoint Presentation by Calvin and TB Lau "New Non-Conductive Die Attach Material Selection: FMTC Asia/FMTC Austin" Jan. 30, 2003	Chopin	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	341	C				WITHDRAWN	
RX	342	C				WITHDRAWN	
RX	343	C				WITHDRAWN	
RX	344	C				WITHDRAWN	
RX	345	C				WITHDRAWN	
RX	346	C				WITHDRAWN	
RX	347	C				WITHDRAWN	
RX	348	C				WITHDRAWN	
RX	349	C				WITHDRAWN	
RX	350	C				WITHDRAWN	
RX	351	C				WITHDRAWN	
RX	352	C				WITHDRAWN	
RX	353	C				WITHDRAWN	
RX	354	C				WITHDRAWN	
RX	355	C				WITHDRAWN	
RX	356	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	357	C				WITHDRAWN	
RX	358	C				WITHDRAWN	
RX	359	C				WITHDRAWN	
RX	360	C				WITHDRAWN	
RX	361	C				WITHDRAWN	
RX	362	C				WITHDRAWN	
RX	363	C				WITHDRAWN	
RX	364	C				WITHDRAWN	
RX	365	C				WITHDRAWN	
RX	366	C				WITHDRAWN	
RX	367	C				WITHDRAWN	
RX	368	C				WITHDRAWN	
RX	369	C				WITHDRAWN	
RX	370	C				WITHDRAWN	
RX	371	C				WITHDRAWN	
RX	372	C				WITHDRAWN	
RX	373	C				WITHDRAWN	
RX	374	C				WITHDRAWN	
RX	375	C				WITHDRAWN	
RX	376	C				WITHDRAWN	
RX	377	C				WITHDRAWN	
RX	378	C				WITHDRAWN	
RX	379	C				WITHDRAWN	
RX	380	C				WITHDRAWN	
RX	381	C				WITHDRAWN	
RX	382	C				WITHDRAWN	
RX	383	C				WITHDRAWN	
RX	384	C				WITHDRAWN	
RX	385	C				WITHDRAWN	
RX	386		Bond Wire Modeling Standard, JEDEC Publication No. EIA/JESD59 dated June 1997	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	387	C				WITHDRAWN	
RX	388	C	"QTSI00001164-65 PM6652 BL90.pdf" Bonding Diagram, PM6652, PMIC3-HT2, 6x6MM, 97 CSP, Supplier (QTSI 000001164 - QTSI 000001165)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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RX	389	C	"QTSI00164822 msm6800a NT90.pdf" Package Outline Drawing, 432NSP, 11 x 11 x 1.0 MM, S210, M530 (QTSI 00164822 - 000164823)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	390	C	SD90-V675-3, Rev. A, Substrate Drawing, XXX R1.0, 9x9MM, 216CSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	391	C	"QTSI00811766 MSM6800A BL90.pdf"Bonding Diagram, XXX, 11x11 MM, 432NSP, Supplier (QTSI 00811766 - QTSI 00722771) [BL90-V6698-2A, Rev. A]	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	392	C	"QTSI00820906 MH80 Single Die Flexsmart.pdf"Process Flow Chart Specification for Single Die CSP, SCS - Flexmart (QTSI 00820906 - QTSI 00820912)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	393	C	"QTSI00845360 qsc6010 NT90.pdf" Package Outline Drawing, 351MSP, 15x15x1.2MM, S260, M650 (QTSI 00845360 - QTSI 00845361)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	394	C	"QTSI00852037 PM6640 SD90.pdf" PM6640 Substrate Drawing (QTSI 00852037 - QTSI 00852042)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	395	C				WITHDRAWN	
RX	396	C				WITHDRAWN	
RX	397	C				WITHDRAWN	
RX	398	C				WITHDRAWN	
RX	399	C				WITHDRAWN	
RX	400	C				WITHDRAWN	
RX	401	C	"SPA-S-SCT.pdf"Reliability Qualification(SPAN-ITC 067770 - SPAN-ITC 067776 SPAN-ITC 067756 - SPAN-ITC 067769)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	402	C				WITHDRAWN	
RX	403	C				WITHDRAWN	
RX	404	C				WITHDRAWN	
RX	405	C				WITHDRAWN	
RX	406	C	"F04-0028082.pdf"Hitachi Chemical HS232 Insulated Film Die Attach Adhesive(SPAN-ITC 105317 - SPAN-ITC 105319)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	407	C				WITHDRAWN	
RX	408	C				WITHDRAWN	
RX	409	C				WITHDRAWN	
RX	410	C				WITHDRAWN	
RX	411	C				WITHDRAWN	
RX	412	C				WITHDRAWN	
RX	413	C				WITHDRAWN	
RX	414	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	415	C				WITHDRAWN	
RX	416	C				WITHDRAWN	
RX	417	C				WITHDRAWN	
RX	418	C				WITHDRAWN	
RX	419	C				WITHDRAWN	
RX	420	C				WITHDRAWN	
RX	421	C				WITHDRAWN	
RX	422	C				WITHDRAWN	
RX	423	C				WITHDRAWN	
RX	424	C				WITHDRAWN	
RX	425	C				WITHDRAWN	
RX	426	C				WITHDRAWN	
RX	427	C				WITHDRAWN	
RX	428		Joseph Fjelstad, Thomas Di Stefano, and Michael Perry "Compliancy Modeling of an Area Array Chip Scale Package" Proceedings of the Technical Program, Vol. I. Sept. 10, 1996 (TESST0229037-9044, TESS500104-0111)	DiStefano	OWNR	ADMITTED	7/14/2008
RX	429	C				WITHDRAWN	
RX	430	C				WITHDRAWN	
RX	431	C				WITHDRAWN	
RX	432	C	FuBGA Plan. Oct. 21, 1999 (TESST348285-8286, TESS070887-0888)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	433	C				WITHDRAWN	
RX	434	C	Initial Determination ITC Inv. No. 337-TA-432 (TMI00384052-4410)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	435		Dr. Min's CV	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	436		Dr. Min's List of Materials Considered	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	437	C				WITHDRAWN	
RX	438	C	Amendment to the Response to Office Action in the Reexamination of U.S. Patent No. 6, 433, 419, Aug. 6, 2007	Schaper	VLD/INVLD	ADMITTED	7/18/2008 7/22/2008
RX	439	C	Response to Office Action in the Reexamination of U.S. Patent 6, 433, 419, Aug. 6, 2007	Schaper	VLD/INVLD	ADMITTED	7/18/2008 7/22/2008
RX	440	C				WITHDRAWN	
RX	441	C				WITHDRAWN	

Prefix	No.	Status	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	442	C				WITHDRAWN	
RX	443	C				WITHDRAWN	
RX	445	C	Document for Epoxy 11ATH00144A049 / H00144A049A (FSL-ITC 00000318-0340)	Sitaraman/Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	446	C	Standard Notes 00ASM97181A (FSL-ITC 00000337-0415)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	447	C	Document for Mold 11MSA10005D / A10005D(FSL-ITC 00000341-0344)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	448	C	Document for Wire 30ASB24082A / B24082A(FSL-ITC 00000359-0367)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	449	C	Document for Wire 30ASB24082A / B24082A(FSL-ITC 00000368-0376)	Sitaraman/Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	450	C	Document for Filler 11ASA10102D (FSL-ITC 00000419-0422)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	451	C	Document for Mold 11ASA10153D (FSL-ITC 00000431-0434)	Sitaraman/Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	452	C	Document for Mold 11ASA10190D (FSL-ITC 00000435-0440)	Sitaraman/Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	453	C	Document for Epoxy 11ATH00144A049 / H00144A049A (FSL-ITC 00000463-0485)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	454	C	Document for Epoxy 11ATH00144A049 / H00144A049A (FSL-ITC 00000486-0509)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	455	C	Document for SODBF 76ASH70271A (FSL-ITC 00000735-0740)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	456	C	Document for Wire Bond Diagram 67ARE10705D (FSL-ITC 00023412-3412)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	457	C	Document for Substrate 84ASA10889D (FSL-ITC 00023944-3944)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	458	C	Document for Wire Bond Diagram 67ARE11041D(FSL-ITC 00024478-4478)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	459	C	Document for Wire Bond Diagram 67ARE11224D(FSL-ITC 00025374-5374)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	460	C	Document for Substrate 84ARH11575D(FSL-ITC 00026727-6727)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	461	C	Document for Substrate 84ARE11614D(FSL-ITC 00027909-7909)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	462	C	Document for Wire Bond Diagram 67ASA12115D(FSL-ITC 00029367-9367)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	463	C	Document for Wire Bond Diagram 67ASA12278D(FSL-ITC 00029498-9498)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	464	C	Document for Wire Bond Diagram 67ASA62409B(FSL-ITC 00031027-1023)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	465	C	Document for Substrate 84ARH98416A(FSL-ITC 00031585-1585)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	466	C	Freescale Current and Recently PBGA Test Information	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	467	C	Document 12MCT0090A.008 (FSL-ITC 00133692-3744)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	468	C	Document for Tool Outline 98ARE10526D (FSL-ITC 00251547-1547)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	469	C	Document for Tool Outline 98ARE10567D (FSL-ITC 00251616-1616)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	470	C	Document for Case Outline 98ARE10569D(FSL-ITC 00251629-1629)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	471	C	Document for Tool Outline 98ARE10577(FSL-ITC 00251638-1638)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	472	C	Document for Case Outline 98ARE10587D(FSL-ITC 00251658-1658)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	473	C	Document for Tool Outline 98ARE10588D(FSL-ITC 00251675-1675)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	474	C	Document for Tool Outline 98ARS10507D(FSL-ITC 00251743-1743)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	475	C	Document for Tool Outline 98ASA10519D(FSL-ITC 00251813-1813)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	476	C	Document for Tool Outline 98ASA10599D(FSL-ITC 00251894-1894)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	477	C	Document for Case Outline 98ARE10645D (FSL-ITC 00251968-1968)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	478	C	Document for Tool Outline 98ASA10637D(FSL-ITC 00252045-2045)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	479	C	Document for Case Outline 98ASA10638D (FSL-ITC 00252061-2061)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

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RX	480	C	Document for Case Outline 98ASH70694A(FSL-ITC 00252664-2664)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	481	C	Document for Strip Configuration 84ARH98226A (FSL-ITC 00252673-2673)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	482	C	Document for Strip Configuration 84ARH87242A(FSL-ITC 00252843-2843)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	483	C	Document for Strip Configuration 84ARH98244A(FSL-ITC 00252912-2912)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	484	C	Document for Strip Configuration 84ARH98246A(FSL-ITC 00252974-2974)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	485	C	Document for Case Outline 98ARH98217A(FSLITC00523052-3052)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	486	C	Document for Strip Configuration 84ARH98306A(FSL-ITC 00253098-3098)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	487	C	Document for Tool Outline 98ARH98445A (FSL-ITC 00253169-3169)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	488	C	Document for Strip Configuration 84ARH99132A(FSL-ITC 00253194-3194)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008 7/16/2008
RX	489	C	Document for Tool Outline 98ASA99233D(FSL-ITC 00263562-3562)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	490	C				WITHDRAWN	
RX	491	C	Confidential FSL-ITC 00781755 BLT_and_Fillet_height_assessment_-_832x(confirmation_run)[1].PPTPowerPoint Presentation "832x BLT and fillet height study plan"	Chopin	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	492	C				WITHDRAWN	
RX	493	C	"Confidential FSL-ITC 00781784 DieAttachDevelopmentSpecification-05-19-2006a.doc"Word document discussing "12MWS00047B	Chopin	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	494	C				WITHDRAWN	
RX	495	C				WITHDRAWN	
RX	496	C				WITHDRAWN	
RX	497	C				WITHDRAWN	
RX	498	C				WITHDRAWN	
RX	499	C	PowerPoint Presentation by Andrew Mawer "AtlasUL MAP BGA Post-Decamp Images" Nov. 2, 2007 [FSL-ITC 00789747-0001 - FSL-ITC 00789747-0011]	Stipulation	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	500	C	Neptune LTE2C90 UMC CZ Report Nov. 05, 2005 (FSL-ITC 00010363 - 0583)	Chopin	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	501	C				WITHDRAWN	
RX	502	C				WITHDRAWN	
RX	503	C				WITHDRAWN	
RX	504	C				WITHDRAWN	
RX	505	C				WITHDRAWN	
RX	506	C				WITHDRAWN	
RX	507	C				WITHDRAWN	
RX	508	C				WITHDRAWN	
RX	509	C				WITHDRAWN	
RX	510	C				WITHDRAWN	
RX	511	C				WITHDRAWN	
RX	512	C				WITHDRAWN	
RX	513	C	Declaration of Michael G. Pecht in Support of Texas Instruments Incorporated Claim Construction Brief. N.D. C-00-2114 Dec. 22, 2000 (TMI00344170-4206)	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	514					WITHDRAWN	
RX	515	C	"SPA-M-H-1.pdf"Reliability Qualification (SPAN-ITC 064009 - SPAN-ITC 064036)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	516	C	"F04-0027803.pdf"Hitachi Chemical HS-231W Insulated Film Die Attach Adhesive(SPAN-ITC 105298 - SPAN-ITC 105300)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	517	C				WITHDRAWN	
RX	518	C				WITHDRAWN	
RX	519	C				WITHDRAWN	
RX	520	C				WITHDRAWN	
RX	521	C	"STITC00016412.pdf"Product Specification for N5FN*MV86BAA(STITC00016412 - STITC00016418)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	522	C	"STITC00018722.pdf"Package Outline Assembly TFBGA 6x6x1.2 84 3R10x10 Pitch 0.5 Ball 0.3 (STITC00018722 - STITC00018723)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	523	C				WITHDRAWN	
RX	524	C				WITHDRAWN	
RX	525	C				WITHDRAWN	
RX	526	C				WITHDRAWN	
RX	527	C				WITHDRAWN	
RX	528	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	529	C				WITHDRAWN	
RX	530		Finite Element Analysis of a Compliant Chip Scale Ball Grid Array Package, Chipcon '96	DiStefano/Fjelstad	OWNR, INFRNG/NON-INFRNG.	ADMITTED	7/14/2008 7/22/08
RX	531		Diagrams with handwritten dimensions	Shimada		ADMITTED	7/22/2008
RX	532	C				WITHDRAWN	
RX	533					WITHDRAWN	
RX	534	C				WITHDRAWN	
RX	535					WITHDRAWN	
RX	536					WITHDRAWN	
RX	537					WITHDRAWN	
RX	538					WITHDRAWN	
RX	539					WITHDRAWN	
RX	540					WITHDRAWN	
RX	541	C				WITHDRAWN	
RX	542	C	Khandros Inventor Notebook	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	542	A C	Khandros Inventor Notebook (color version)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	543	C				WITHDRAWN	
RX	544					WITHDRAWN	
RX	545		Response to Official Action dated 8/6/2007 - 419 Reexam	Schaper, Stipulation	VLD/INVLD	ADMITTED	7/18/2008 7/22/2008
RX	546					WITHDRAWN	
RX	547	C				WITHDRAWN	
RX	548					WITHDRAWN	
RX	549		Japanese Patent Publication No. S61-177759 (Okinaga)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	550		US Patent No. 4,700,473	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	551					WITHDRAWN	
RX	552	C				WITHDRAWN	
RX	553	C				WITHDRAWN	
RX	554	C	Selected pages from April 10, 2001 ITC Hearing	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	555	C	Selected pages from April 11, 2001 ITC Hearing	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	556	C				WITHDRAWN	
RX	557					WITHDRAWN	
RX	558	C				WITHDRAWN	
RX	559	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	560	C				WITHDRAWN	
RX	561					WITHDRAWN	
RX	562					WITHDRAWN	
RX	563					WITHDRAWN	
RX	564	C				WITHDRAWN	
RX	565	C				WITHDRAWN	
RX	566	C				WITHDRAWN	
RX	567	C				WITHDRAWN	
RX	568	C				WITHDRAWN	
RX	569	C				WITHDRAWN	
RX	570	C				WITHDRAWN	
RX	571	C				WITHDRAWN	
RX	572		Schematic Drawing	Sitaraman / Freyman	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/15/2008 7/16/2008
RX	573		41st Electronic Components & Technology Conference dated May 11-16, 1991	Qu	INFRNG/NON-INFRNG	ADMITTED	7/15/2008
RX	574	C				WITHDRAWN	
RX	575	C				WITHDRAWN	
RX	576	C				WITHDRAWN	
RX	577		Suzuki - Development of Low Elastic Modules Die Attach Material and Clean Curegarding Process	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	578	C				WITHDRAWN	
RX	579	C				WITHDRAWN	
RX	580	C				WITHDRAWN	
RX	581	C				WITHDRAWN	
RX	582	C				WITHDRAWN	
RX	583	C				WITHDRAWN	
RX	584					WITHDRAWN	
RX	585	C				WITHDRAWN	
RX	586	C				WITHDRAWN	
RX	587	C				WITHDRAWN	
RX	588					WITHDRAWN	
RX	589	C				WITHDRAWN	
RX	590	C				WITHDRAWN	
RX	591					WITHDRAWN	
RX	592	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	593	C				WITHDRAWN	
RX	594	C				WITHDRAWN	
RX	595	C				WITHDRAWN	
RX	596	C				WITHDRAWN	
RX	597	C				WITHDRAWN	
RX	598	C				WITHDRAWN	
RX	599	C				WITHDRAWN	
RX	600	C				WITHDRAWN	
RX	601	C				WITHDRAWN	
RX	602	C				WITHDRAWN	
RX	603	C				WITHDRAWN	
RX	604					WITHDRAWN	
RX	605	C				WITHDRAWN	
RX	606	C				WITHDRAWN	
RX	607	C				WITHDRAWN	
RX	608	C				WITHDRAWN	
RX	609	C	Expert Report of Michael Gerard Pecht regarding U.S. PatentsNos. 5,679,977 and 5,852,326 from Texas Instruments, Inc. v. Tessera, Inc. (includes exhibits)	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	610					WITHDRAWN	
RX	611					WITHDRAWN	
RX	612	C				WITHDRAWN	
RX	613	C				WITHDRAWN	
RX	614	C				WITHDRAWN	
RX	615	C				WITHDRAWN	
RX	616	C				WITHDRAWN	
RX	617	C				WITHDRAWN	
RX	618	C				WITHDRAWN	
RX	619	C				WITHDRAWN	
RX	620	C				WITHDRAWN	
RX	621	C				WITHDRAWN	
RX	622	C				WITHDRAWN	
RX	623	C				WITHDRAWN	
RX	624	C				WITHDRAWN	
RX	625					WITHDRAWN	
RX	626					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	627	C				WITHDRAWN	
RX	628					WITHDRAWN	
RX	629	C				WITHDRAWN	
RX	630	C				WITHDRAWN	
RX	631					WITHDRAWN	
RX	632	C				WITHDRAWN	
RX	633					WITHDRAWN	
RX	634					WITHDRAWN	
RX	635					WITHDRAWN	
RX	636	C				WITHDRAWN	
RX	637	C				WITHDRAWN	
RX	638	C				WITHDRAWN	
RX	639	C				WITHDRAWN	
RX	640	C				WITHDRAWN	
RX	641	C				WITHDRAWN	
RX	642	C				WITHDRAWN	
RX	643	C				WITHDRAWN	
RX	644	C				WITHDRAWN	
RX	645	C				WITHDRAWN	
RX	646	C				WITHDRAWN	
RX	647	C				WITHDRAWN	
RX	648	C				WITHDRAWN	
RX	649	C				WITHDRAWN	
RX	650	C				WITHDRAWN	
RX	651	C				WITHDRAWN	
RX	652	C				WITHDRAWN	
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RX	654	C				WITHDRAWN	
RX	655	C				WITHDRAWN	
RX	656	C				WITHDRAWN	
RX	657	C				WITHDRAWN	
RX	658	C				WITHDRAWN	
RX	659	C				WITHDRAWN	
RX	660	C				WITHDRAWN	
RX	661	C				WITHDRAWN	
RX	662	C				WITHDRAWN	

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	663	C				WITHDRAWN	
RX	664	C				WITHDRAWN	
RX	665	C				WITHDRAWN	
RX	666	C				WITHDRAWN	
RX	667	C				WITHDRAWN	
RX	668	C				WITHDRAWN	
RX	669	C				WITHDRAWN	
RX	670	C				WITHDRAWN	
RX	671	C				WITHDRAWN	
RX	672	C				WITHDRAWN	
RX	673	C				WITHDRAWN	
RX	674	C				WITHDRAWN	
RX	675	C				WITHDRAWN	
RX	676	C				WITHDRAWN	
RX	677	C				WITHDRAWN	
RX	678	C				WITHDRAWN	
RX	679	C				WITHDRAWN	
RX	680	C				WITHDRAWN	
RX	681	C				WITHDRAWN	
RX	682	C				WITHDRAWN	
RX	683	C				WITHDRAWN	
RX	684	C				WITHDRAWN	
RX	685	C				WITHDRAWN	
RX	686	C				WITHDRAWN	
RX	687	C				WITHDRAWN	
RX	688	C				WITHDRAWN	
RX	689	C				WITHDRAWN	
RX	690	C				WITHDRAWN	
RX	691	C				WITHDRAWN	
RX	692	C				WITHDRAWN	
RX	693	C				WITHDRAWN	
RX	694	C				WITHDRAWN	
RX	695					WITHDRAWN	
RX	696					WITHDRAWN	
RX	697	C				WITHDRAWN	
RX	698					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	699	C				WITHDRAWN	
RX	700	C				WITHDRAWN	
RX	701					WITHDRAWN	
RX	702	C				WITHDRAWN	
RX	703	C				WITHDRAWN	
RX	704					WITHDRAWN	
RX	705	C				WITHDRAWN	
RX	706	C				WITHDRAWN	
RX	707	C				WITHDRAWN	
RX	708	C				WITHDRAWN	
RX	709	C				WITHDRAWN	
RX	710	C				WITHDRAWN	
RX	711	C				WITHDRAWN	
RX	712	C				WITHDRAWN	
RX	713	C				WITHDRAWN	
RX	714	C				WITHDRAWN	
RX	715	C				WITHDRAWN	
RX	716	C				WITHDRAWN	
RX	717	C				WITHDRAWN	
RX	718	C				WITHDRAWN	
RX	719	C				WITHDRAWN	
RX	720	C				WITHDRAWN	
RX	721	C				WITHDRAWN	
RX	722	C				WITHDRAWN	
RX	723	C				WITHDRAWN	
RX	724	C				WITHDRAWN	
RX	725					WITHDRAWN	
RX	726		Subcontractor's Agreement - Spec 03-070.17 F	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	727					WITHDRAWN	
RX	728		US Patent 5,852,326	Ivey	VLD/INVLD	ADMITTED	7/18/2008
RX	729					WITHDRAWN	
RX	730	C	Expert Report of Qu Sharp/ITC	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	731	C	Expert Report of Dr. Jianmin Qu	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

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RX	732	C	Expert Report of Dr. Jianmin Qu	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	733		Declaration of Qu ISO Tessera's Proposed Claim Construction, Samsung v. Tessera	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	734	C	Hearing Vol 3 Sharp/ITC 4/9/01	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	735	C				WITHDRAWN	
RX	736	C				WITHDRAWN	
RX	737	C				WITHDRAWN	
RX	738		Supplemental Expert Report of Werner Engelmaier	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	739	C				WITHDRAWN	
RX	740	C	Rebuttal Expert Report of Suhir, Samsung v. Tessera	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	741	C				WITHDRAWN	
RX	742	C	Day 4, Samsung v. Tessera	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	743	C				WITHDRAWN	
RX	744					WITHDRAWN	
RX	745	C				WITHDRAWN	
RX	746	C				WITHDRAWN	
RX	747					WITHDRAWN	
RX	748					WITHDRAWN	
RX	749					WITHDRAWN	
RX	750					WITHDRAWN	
RX	751	C	W2240G Bond diagram	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	752	C	W2240G Bond diagram	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	753	C	W2240G Bond diagram	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	754	C	W2240A Bond diagram	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	755	C				WITHDRAWN	
RX	756	C	W2240A Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008

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RX	757	C	W2240A Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	758	C	W2282J Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	759	C	W2282J Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	760	C	W2282J Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	761	C	W2284J Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	762	C	W2284J Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	763	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	764	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	765	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	766	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	767	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	768	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	769	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	770	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	771	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	772	C	W2240G Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	773	C	W2250 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	774	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	775	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	776	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	777	C	W2282 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	778	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	779	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	780	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	781	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	782	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	783	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	784	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	785	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	786	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	787	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	788	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	789	C	W2282 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	790	C	W2284D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	791	C	W2284D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	792	C	W2182D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	793	C	W2182D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	794	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	795	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	796	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	797	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	798	C	W2282 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	799	C	W2282D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	800	C	W2284D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	801	C	W2182D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	802	C	W2182D Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	803	C	W2262 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	804	C	W2262 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	805	C	W2262 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	806	C	W2262 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	807	C	W2262 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	808	C	W2262 Bond diagram	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	809	C	98U08A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	810	C	98K34A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	811	C	98M54A1 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	812	C	98R46A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	813	C	98M54A1 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	814	C	98M39A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	815	C	98K03ABT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	816	C	98K03ABT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	817	C	98K09BBT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	818	C	98K09BBT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	819	C	98K08ABT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	820	C	98R29A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	821	C	98R29A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	822	C	98R32AU Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	823	C	98R29A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	824	C	98R32AU Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	825	C	98M53A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	826	C	98K35A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	827	C	98H19A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	828	C	98F10A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

Prefix	No.	Status	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	829	C	98K35A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	830	C	98M54A Bond diagram [incorrect description. corrected: 98M58A Bond diagram]	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	831	C	98K33A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	832	C	98K33A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	833	C	98M48A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	834	C	98H19A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	835	C	98K31A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	836	C	98H18A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	837	C	98F03ABT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	838	C	98488ABT Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	839	C	98H10A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	840	C	SM53AM0 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	841	C	SM53AM0 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	842	C	SM53AL2 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	843	C	SM53AE7 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	844	C	SM53AK9 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	845	C	SM53A48 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	846	C	SM53AK7 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	847	C	SM53A0DU Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	848	C	SM53AK7 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	849	C	SM53AK9 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	850	C	SM53AM0 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	851	C	98R29A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	852	C	98R20B Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	853	C	98R12B Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	854	C	98M73A2 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	855	C	98M60A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	856	C	98M58A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	857	C	98M43A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	858	C	98M39A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	859	C	98K35A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	860	C	98K31A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	861	C	98883A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	862	C	98445A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	863	C	98364B Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	864	C	98U07A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	865	C	98R47A2 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	866	C	98R32AU Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	867	C	98R31A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	868	C	98R20B Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	869	C	98R12B Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	870	C	98M73A2 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	871	C	98M60A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	872	C	98M58A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	873	C	98M43A Bond diagram	Suresh / Ivey	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/17/2008 7/18/2008
RX	874	C	98M39A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	875	C	98K35A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	876	C	98K31A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	877	C	98883A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	878	C	98445A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	879	C				WITHDRAWN	
RX	880	C	98364B Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	881	C	98K35A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	882	C	98440A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	883	C	98440A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	884	C	98U09A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	885	C	98U09A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	886	C	98U07A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	887	C	98U07A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	888	C	98U09A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	890	C	98440A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	891	C	98445A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	892	C	98363AS Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	893	C	98P05A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	894	C	98P04A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	895	C	98P03A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	896	C	98P04A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	897	C	SR24AH5 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	898	C	S726ADD0 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	899	C				WITHDRAWN	
RX	900	C	S726A0EY Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	901	C	XS726ADC9 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	902	C	XS726ADK5 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	903	C	XS454A0N5 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	904	C	S454A1N5 Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	905	C	S726A0EY Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	906	C	98N01A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	907	C	98726A Bond diagram	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	908	C	letter dated 10/16/97 from C. Pickett to Leo Dwork and John Hunter	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	909		AMD Announces New Chip-Scale Packaging for Flash Memory"	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	910					WITHDRAWN	
RX	911		AM29SL800B 8 Megabit 1.8 Volt-only Flash Memory	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	912		The AMD Fine-pitch Ball Grid Array (FBGA) for Flash Memory	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	913	C	Chip Scale Packaging for AMD Flash Memory Products	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	914	C	Fax dated 1/8/98 freom Chris Pickett to AMD	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	915		Trends in Advanced Component Technologies	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	916		*handwritten notes*	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	917	C	TCC License Agreement	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	918	C	string of emails dated 3/20/98 from Pickett to Pitruzzella	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	919	C	memo dated 3/19/98 from Pickett to AMD	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	920	C	Tessera License Agreement	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	922	C	letter dated 4/1/98 from Pickett to Pitruzzella	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	923	C	Tessera License Agreement	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	924		AMD Tessera CSP Deal Causes Ripples	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	925					WITHDRAWN	
RX	926					WITHDRAWN	
RX	927	C				WITHDRAWN	
RX	928	C				WITHDRAWN	
RX	929	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	930					WITHDRAWN	
RX	931					WITHDRAWN	
RX	932					WITHDRAWN	
RX	933					WITHDRAWN	
RX	934	C	E-mail dated 4-5-96 17 from S. Kanno	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	935		Tessera Inc - S-1, Registration Statement, date filed 9-5-2000	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	936	C	FBGA Package Analysis	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	937	C				WITHDRAWN	
RX	938	C				WITHDRAWN	
RX	939	C				WITHDRAWN	
RX	940	C				WITHDRAWN	
RX	941	C				WITHDRAWN	
RX	942	C				WITHDRAWN	
RX	943	C				WITHDRAWN	
RX	944	C				WITHDRAWN	
RX	945	C				WITHDRAWN	
RX	946	C				WITHDRAWN	
RX	947	C				WITHDRAWN	
RX	948	C				WITHDRAWN	
RX	949	C				WITHDRAWN	
RX	950	C				WITHDRAWN	
RX	951	C				WITHDRAWN	
RX	952	C				WITHDRAWN	
RX	953	C				WITHDRAWN	
RX	954	C				WITHDRAWN	
RX	955	C				WITHDRAWN	
RX	956	C				WITHDRAWN	
RX	957	C				WITHDRAWN	
RX	958	C				WITHDRAWN	
RX	959	C				WITHDRAWN	
RX	960	C				WITHDRAWN	
RX	961	C				WITHDRAWN	
RX	962	C				WITHDRAWN	
RX	963	C				WITHDRAWN	
RX	964	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	965	C				WITHDRAWN	
RX	966	C				WITHDRAWN	
RX	967	C				WITHDRAWN	
RX	968	C				WITHDRAWN	
RX	969	C				WITHDRAWN	
RX	970	C				WITHDRAWN	
RX	971	C				WITHDRAWN	
RX	972	C				WITHDRAWN	
RX	973	C				WITHDRAWN	
RX	974	C				WITHDRAWN	
RX	975	C				WITHDRAWN	
RX	976	C				WITHDRAWN	
RX	977	C				WITHDRAWN	
RX	978	C				WITHDRAWN	
RX	979	C				WITHDRAWN	
RX	980	C				WITHDRAWN	
RX	981	C				WITHDRAWN	
RX	982	C				WITHDRAWN	
RX	983	C				WITHDRAWN	
RX	984	C				WITHDRAWN	
RX	985	C				WITHDRAWN	
RX	986	C				WITHDRAWN	
RX	987	C				WITHDRAWN	
RX	988	C				WITHDRAWN	
RX	989	C				WITHDRAWN	
RX	990	C				WITHDRAWN	
RX	991	C				WITHDRAWN	
RX	992	C				WITHDRAWN	
RX	993	C				WITHDRAWN	
RX	994	C				WITHDRAWN	
RX	995	C				WITHDRAWN	
RX	996	C				WITHDRAWN	
RX	997	C	"Manufacturing and Component Specifications for the Assembly and Design of Printed Circuit Boards"71G13933J02	Bradley	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	998	C				WITHDRAWN	
RX	999	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1000	C				WITHDRAWN	
RX	1001	C				WITHDRAWN	
RX	1002	C				WITHDRAWN	
RX	1003	C				WITHDRAWN	
RX	1004	C				WITHDRAWN	
RX	1005	C				WITHDRAWN	
RX	1006	C	Data Sheet for Taiyo PSR 4000 G23K Soldermask	Bradley	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1007	C				WITHDRAWN	
RX	1008	C				WITHDRAWN	
RX	1009	C				WITHDRAWN	
RX	1010	C	Schematic, "PCB - Main CDMA"	Bradley	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1011	C	Schematic, "PCB, Hawaii XCVR Board"	Bradley / Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008 7/18/2008
RX	1012	C	Letter from Taiyo with Properties PSR 4000 G23K.	Bradley	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1013	C				WITHDRAWN	
RX	1014	C	Motorola-IBM License Agreement	Balog	RMDY	ADMITTED	7/18/2008
RX	1015					WITHDRAWN	
RX	1016	C				WITHDRAWN	
RX	1017	C				WITHDRAWN	
RX	1018	C				WITHDRAWN	
RX	1019		U.S. Patent No. 4,700,276	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1020	C				WITHDRAWN	
RX	1021	C	Proceedings of The Technical Program, Volume I, San Jose, CA, September 10-12, 1996	DiStefano / Fjelstad	INFRNG/NON-INFRNG, OWNR	ADMITTED	7/14/2008
RX	1022	C				WITHDRAWN	
RX	1023	C				WITHDRAWN	
RX	1024	C				WITHDRAWN	
RX	1025	C				WITHDRAWN	
RX	1026	C				WITHDRAWN	
RX	1027	C				WITHDRAWN	
RX	1028	C				WITHDRAWN	
RX	1029	C				WITHDRAWN	

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1030	C				WITHDRAWN	
RX	1031	C				WITHDRAWN	
RX	1032	C				WITHDRAWN	
RX	1033	C				WITHDRAWN	
RX	1034	C				WITHDRAWN	
RX	1035	C				WITHDRAWN	
RX	1036	C				WITHDRAWN	
RX	1037	C				WITHDRAWN	
RX	1038	C				WITHDRAWN	
RX	1039	C				WITHDRAWN	
RX	1040	C				WITHDRAWN	
RX	1041	C				WITHDRAWN	
RX	1042	C				WITHDRAWN	
RX	1043	C				WITHDRAWN	
RX	1044	C				WITHDRAWN	
RX	1045	C				WITHDRAWN	
RX	1046	C				WITHDRAWN	
RX	1047	C				WITHDRAWN	
RX	1048	C				WITHDRAWN	
RX	1049	C				WITHDRAWN	
RX	1050	C				WITHDRAWN	
RX	1051	C				WITHDRAWN	
RX	1052	C				WITHDRAWN	
RX	1053	C	Response to Official Action dated 8/6/2007 - 419 Reexam	Schaper	VLD/INVLD	ADMITTED	7/18/2008 7/22/2008
RX	1054	C	Diagrams with handwritten dimensions	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1055	C				WITHDRAWN	
RX	1056	C				WITHDRAWN	
RX	1057	C				WITHDRAWN	
RX	1058	C				WITHDRAWN	
RX	1059	C				WITHDRAWN	
RX	1060	C				WITHDRAWN	
RX	1061	C				WITHDRAWN	
RX	1062	C				WITHDRAWN	
RX	1063	C				WITHDRAWN	

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1064	C				WITHDRAWN	
RX	1065	C				WITHDRAWN	
RX	1066	C				WITHDRAWN	
RX	1067	C				WITHDRAWN	
RX	1068	C				WITHDRAWN	
RX	1069	C				WITHDRAWN	
RX	1070	C				WITHDRAWN	
RX	1071	C				WITHDRAWN	
RX	1072	C				WITHDRAWN	
RX	1073	C				WITHDRAWN	
RX	1074	C				WITHDRAWN	
RX	1075	C				WITHDRAWN	
RX	1076	C				WITHDRAWN	
RX	1077	C				WITHDRAWN	
RX	1078	C				WITHDRAWN	
RX	1079	C				WITHDRAWN	
RX	1080	C				WITHDRAWN	
RX	1081	C				WITHDRAWN	
RX	1082	C				WITHDRAWN	
RX	1083	C				WITHDRAWN	
RX	1084	C				WITHDRAWN	
RX	1085	C				WITHDRAWN	
RX	1086	C				WITHDRAWN	
RX	1087	C				WITHDRAWN	
RX	1088	C				WITHDRAWN	
RX	1089	C				WITHDRAWN	
RX	1090	C				WITHDRAWN	
RX	1091	C				WITHDRAWN	
RX	1092	C				WITHDRAWN	
RX	1093	C				WITHDRAWN	
RX	1094	C				WITHDRAWN	
RX	1095	C				WITHDRAWN	
RX	1096	C				WITHDRAWN	
RX	1097	C				WITHDRAWN	
RX	1098	C				WITHDRAWN	
RX	1099	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1100	C				WITHDRAWN	
RX	1101	C				WITHDRAWN	
RX	1102	C				WITHDRAWN	
RX	1103	C				WITHDRAWN	
RX	1104	C				WITHDRAWN	
RX	1105	C				WITHDRAWN	
RX	1106	C				WITHDRAWN	
RX	1107	C				WITHDRAWN	
RX	1108	C				WITHDRAWN	
RX	1109	C				WITHDRAWN	
RX	1110	C				WITHDRAWN	
RX	1111	C				WITHDRAWN	
RX	1112	C				WITHDRAWN	
RX	1113	C				WITHDRAWN	
RX	1114	C				WITHDRAWN	
RX	1115	C				WITHDRAWN	
RX	1116	C				WITHDRAWN	
RX	1117	C				WITHDRAWN	
RX	1118	C				WITHDRAWN	
RX	1119	C				WITHDRAWN	
RX	1120	C				WITHDRAWN	
RX	1121	C				WITHDRAWN	
RX	1122	C				WITHDRAWN	
RX	1123	C				WITHDRAWN	
RX	1124	C				WITHDRAWN	
RX	1125	C				WITHDRAWN	
RX	1126	C				WITHDRAWN	
RX	1127	C				WITHDRAWN	
RX	1128	C				WITHDRAWN	
RX	1129	C				WITHDRAWN	
RX	1130	C				WITHDRAWN	
RX	1131	C				WITHDRAWN	
RX	1132	C				WITHDRAWN	
RX	1133	C				WITHDRAWN	
RX	1134	C				WITHDRAWN	
RX	1135	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1136	C				WITHDRAWN	
RX	1137	C				WITHDRAWN	
RX	1138	C				WITHDRAWN	
RX	1139	C				WITHDRAWN	
RX	1140	C				WITHDRAWN	
RX	1141	C				WITHDRAWN	
RX	1142	C				WITHDRAWN	
RX	1143	C				WITHDRAWN	
RX	1144	C				WITHDRAWN	
RX	1145	C				WITHDRAWN	
RX	1146	C				WITHDRAWN	
RX	1147	C				WITHDRAWN	
RX	1148	C				WITHDRAWN	
RX	1149	C				WITHDRAWN	
RX	1150	C				WITHDRAWN	
RX	1151	C				WITHDRAWN	
RX	1152	C				WITHDRAWN	
RX	1153	C				WITHDRAWN	
RX	1154	C				WITHDRAWN	
RX	1155					WITHDRAWN	
RX	1156	C				WITHDRAWN	
RX	1157	C				WITHDRAWN	
RX	1158	C				WITHDRAWN	
RX	1159	C				WITHDRAWN	
RX	1160	C				WITHDRAWN	
RX	1161	C				WITHDRAWN	
RX	1162	C				WITHDRAWN	
RX	1163	C				WITHDRAWN	
RX	1164	C				WITHDRAWN	
RX	1165	C				WITHDRAWN	
RX	1166	C				WITHDRAWN	
RX	1167	C				WITHDRAWN	
RX	1168	C				WITHDRAWN	
RX	1169	C				WITHDRAWN	
RX	1170	C				WITHDRAWN	
RX	1171	C				WITHDRAWN	

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1172	C				WITHDRAWN	
RX	1173	C				WITHDRAWN	
RX	1174	C				WITHDRAWN	
RX	1175	C				WITHDRAWN	
RX	1176	C				WITHDRAWN	
RX	1177	C				WITHDRAWN	
RX	1178	C				WITHDRAWN	
RX	1179	C				WITHDRAWN	
RX	1180	C				WITHDRAWN	
RX	1181	C				WITHDRAWN	
RX	1182	C				WITHDRAWN	
RX	1183	C				WITHDRAWN	
RX	1184	C				WITHDRAWN	
RX	1185	C				WITHDRAWN	
RX	1186	C				WITHDRAWN	
RX	1187	C				WITHDRAWN	
RX	1188	C				WITHDRAWN	
RX	1189	C				WITHDRAWN	
RX	1190	C				WITHDRAWN	
RX	1191	C				WITHDRAWN	
RX	1192	C				WITHDRAWN	
RX	1193	C				WITHDRAWN	
RX	1194	C				WITHDRAWN	
RX	1195	C				WITHDRAWN	
RX	1196	C				WITHDRAWN	
RX	1197	C				WITHDRAWN	
RX	1198	C				WITHDRAWN	
RX	1199	C				WITHDRAWN	
RX	1200	C				WITHDRAWN	
RX	1201	C				WITHDRAWN	
RX	1202	C				WITHDRAWN	
RX	1203	C				WITHDRAWN	
RX	1204	C				WITHDRAWN	
RX	1205	C				WITHDRAWN	
RX	1206	C				WITHDRAWN	
RX	1207	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1208	C				WITHDRAWN	
RX	1209	C				WITHDRAWN	
RX	1210	C				WITHDRAWN	
RX	1211	C				WITHDRAWN	
RX	1212	C				WITHDRAWN	
RX	1213	C				WITHDRAWN	
RX	1214	C				WITHDRAWN	
RX	1215	C				WITHDRAWN	
RX	1216	C				WITHDRAWN	
RX	1217	C				WITHDRAWN	
RX	1218	C				WITHDRAWN	
RX	1219	C				WITHDRAWN	
RX	1220	C				WITHDRAWN	
RX	1221	C				WITHDRAWN	
RX	1222	C				WITHDRAWN	
RX	1223	C				WITHDRAWN	
RX	1224	C				WITHDRAWN	
RX	1225	C				WITHDRAWN	
RX	1226	C				WITHDRAWN	
RX	1227	C				WITHDRAWN	
RX	1228	C				WITHDRAWN	
RX	1229					WITHDRAWN	
RX	1230	C				WITHDRAWN	
RX	1231					WITHDRAWN	
RX	1232	C				WITHDRAWN	
RX	1233	C				WITHDRAWN	
RX	1234	C				WITHDRAWN	
RX	1235					WITHDRAWN	
RX	1236	C				WITHDRAWN	
RX	1237	C	Documents for product name MBP1600	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1238	C				WITHDRAWN	
RX	1239	C				WITHDRAWN	
RX	1240	C				WITHDRAWN	
RX	1241	C				WITHDRAWN	
RX	1242	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1243	C				WITHDRAWN	
RX	1244	C				WITHDRAWN	
RX	1245	C				WITHDRAWN	
RX	1246	C				WITHDRAWN	
RX	1247	C				WITHDRAWN	
RX	1248	C				WITHDRAWN	
RX	1249	C				WITHDRAWN	
RX	1250	C				WITHDRAWN	
RX	1251	C				WITHDRAWN	
RX	1252	C				WITHDRAWN	
RX	1253	C				WITHDRAWN	
RX	1254	C				WITHDRAWN	
RX	1255	C				WITHDRAWN	
RX	1256	C				WITHDRAWN	
RX	1257	C				WITHDRAWN	
RX	1258	C				WITHDRAWN	
RX	1259	C				WITHDRAWN	
RX	1260	C				WITHDRAWN	
RX	1261	C				WITHDRAWN	
RX	1262	C				WITHDRAWN	
RX	1263	C				WITHDRAWN	
RX	1264	C				WITHDRAWN	
RX	1265	C				WITHDRAWN	
RX	1266	C				WITHDRAWN	
RX	1267	C				WITHDRAWN	
RX	1268	C				WITHDRAWN	
RX	1269	C				WITHDRAWN	
RX	1270	C				WITHDRAWN	
RX	1271	C				WITHDRAWN	
RX	1272	C				WITHDRAWN	
RX	1273	C				WITHDRAWN	
RX	1274	C				WITHDRAWN	
RX	1275	C				WITHDRAWN	
RX	1276	C				WITHDRAWN	
RX	1277	C				WITHDRAWN	
RX	1278	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1279	C				WITHDRAWN	
RX	1280	C	Tessera's Supplemental Objections and Responses to QUALCOMM's 5th Set of Interrogatories (Nos. 56-58)	Mitchell	RMDY, DI	ADMITTED	7/15/2008
RX	1281	C	Confidential Exhibit 4 - List of Licensees of the Asserted Patents	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	1282	C				WITHDRAWN	
RX	1283	C				WITHDRAWN	
RX	1284	C				WITHDRAWN	
RX	1285	C				WITHDRAWN	
RX	1286	C				WITHDRAWN	
RX	1287	C				WITHDRAWN	
RX	1288	C				WITHDRAWN	
RX	1289					WITHDRAWN	
RX	1290	C				WITHDRAWN	
RX	1291	C				WITHDRAWN	
RX	1292	C				WITHDRAWN	
RX	1293	C				WITHDRAWN	
RX	1294	C				WITHDRAWN	
RX	1295	C				WITHDRAWN	
RX	1296	C				WITHDRAWN	
RX	1297					WITHDRAWN	
RX	1298	C				WITHDRAWN	
RX	1299					WITHDRAWN	
RX	1300	C				WITHDRAWN	
RX	1301	C				WITHDRAWN	
RX	1302	C				WITHDRAWN	
RX	1303	C				WITHDRAWN	
RX	1304		U.S. Patent No. 4,975,765 (Ackermann)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	1305					WITHDRAWN	
RX	1306					WITHDRAWN	
RX	1307					WITHDRAWN	
RX	1308	C				WITHDRAWN	
RX	1309	C				WITHDRAWN	
RX	1310					WITHDRAWN	
RX	1311	C				WITHDRAWN	
RX	1312	C				WITHDRAWN	
RX	1313					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Ruling	Status	Date
RX	1314	C				WITHDRAWN	
RX	1315	C				WITHDRAWN	
RX	1316	C				WITHDRAWN	
RX	1317		Order Granting Re-Examination of '419 by USPTO dated May 4, 2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	1318		Office Action in the Re-examination of 419 dated June 5, 2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	1319		Response to June 5, 2007 Office Action in the Re-examination of 419 dated august 6, 2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	1320		Comments by Siliconware in '419 Re-examination dated September 5, 2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	1321		Supplemental Response to June 5, 2007 Office Action in the '419 Re-examination dated November 6, 2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	1322		Request for Re-examination of '326 dated April 20, 2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	1323	C				WITHDRAWN	
RX	1324	C				WITHDRAWN	
RX	1325	C				WITHDRAWN	
RX	1326	C				WITHDRAWN	
RX	1327					WITHDRAWN	
RX	1328	C				WITHDRAWN	
RX	1329	C				WITHDRAWN	
RX	1330	C				WITHDRAWN	
RX	1331	C				WITHDRAWN	
RX	1332	C				WITHDRAWN	
RX	1333	C				WITHDRAWN	
RX	1334	C				WITHDRAWN	
RX	1335	C				WITHDRAWN	
RX	1336	C				WITHDRAWN	
RX	1337	C				WITHDRAWN	
RX	1338	C				WITHDRAWN	
RX	1339	C				WITHDRAWN	
RX	1340	C				WITHDRAWN	
RX	1341	C				WITHDRAWN	
RX	1342	C				WITHDRAWN	
RX	1343	C				WITHDRAWN	
RX	1344	C				WITHDRAWN	
RX	1345	C				WITHDRAWN	
RX	1346	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1347	C				WITHDRAWN	
RX	1348	C				WITHDRAWN	
RX	1349	C	Complainant Tessera, Inc.'s Responses to Respondent Qualcomm Incorporated's Second Set of Requests for Admissions filed on December 14, 2007	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1350	C				WITHDRAWN	
RX	1351	C				WITHDRAWN	
RX	1352	C				WITHDRAWN	
RX	1353	C				WITHDRAWN	
RX	1354	C				WITHDRAWN	
RX	1355	C				WITHDRAWN	
RX	1356	C				WITHDRAWN	
RX	1357	C				WITHDRAWN	
RX	1358	C				WITHDRAWN	
RX	1359	C				WITHDRAWN	
RX	1360	C				WITHDRAWN	
RX	1361	C				WITHDRAWN	
RX	1362	C				WITHDRAWN	
RX	1363	C				WITHDRAWN	
RX	1364	C				WITHDRAWN	
RX	1365	C				WITHDRAWN	
RX	1366	C				WITHDRAWN	
RX	1367	C				WITHDRAWN	
RX	1368	C				WITHDRAWN	
RX	1369	C				WITHDRAWN	
RX	1370	C				WITHDRAWN	
RX	1371	C				WITHDRAWN	
RX	1372	C				WITHDRAWN	
RX	1373	C				WITHDRAWN	
RX	1374	C				WITHDRAWN	
RX	1375	C				WITHDRAWN	
RX	1376	C				WITHDRAWN	
RX	1377	C				WITHDRAWN	
RX	1378	C				WITHDRAWN	
RX	1379	C				WITHDRAWN	
RX	1380	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1381	C				WITHDRAWN	
RX	1382	C				WITHDRAWN	
RX	1383	C				WITHDRAWN	
RX	1384	C				WITHDRAWN	
RX	1385	C				WITHDRAWN	
RX	1386	C				WITHDRAWN	
RX	1387	C				WITHDRAWN	
RX	1388	C				WITHDRAWN	
RX	1389	C	Tessera FBGA Test Result, January 2000 at 2-3	Mulhern	RMDY	ADMITTED	7/18/2008
RX	1390	C				WITHDRAWN	
RX	1391	C				WITHDRAWN	
RX	1392	C				WITHDRAWN	
RX	1393	C	DiStefano Analysis of Microstar Package, May 14, 1999 at 3	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1394		Fjelstad et. al, "Finite Element Analysis of a Compliant Chip Scale Ball Grid Array Package, Semiconductor Technology Center, Inc., 1996 at 57	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1395	C				WITHDRAWN	
RX	1396	C				WITHDRAWN	
RX	1397	C				WITHDRAWN	
RX	1398	C				WITHDRAWN	
RX	1399	C				WITHDRAWN	
RX	1400	C				WITHDRAWN	
RX	1401	C				WITHDRAWN	
RX	1402	C				WITHDRAWN	
RX	1403	C				WITHDRAWN	
RX	1404	C				WITHDRAWN	
RX	1405	C				WITHDRAWN	
RX	1406	C				WITHDRAWN	
RX	1407	C				WITHDRAWN	
RX	1408		Fax Message from Freyman to Mundwiller	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1409		OverMolded Pad Array Carrier Development Activities - Citizen Watch Co.	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1410	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1411	C	Email from Dulaney and Rollins to Rivas re RC15 Team Trip Report	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1412	C	Figure	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1413		Figure	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1414		Photographs of Chip	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1415		Letter Wilson to Mundwiller re "Tiny Thin Module"	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1416		Letter from Ohi to Wilson re Motorola Pad Arrau Carrier for HC11 IC	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1417	C				WITHDRAWN	
RX	1418	C				WITHDRAWN	
RX	1419	C				WITHDRAWN	
RX	1420	C				WITHDRAWN	
RX	1421	C				WITHDRAWN	
RX	1422	C				WITHDRAWN	
RX	1423	C				WITHDRAWN	
RX	1424	C				WITHDRAWN	
RX	1425	C				WITHDRAWN	
RX	1426	C				WITHDRAWN	
RX	1427	C				WITHDRAWN	
RX	1428	C				WITHDRAWN	
RX	1429	C				WITHDRAWN	
RX	1430	C				WITHDRAWN	
RX	1431	C	Memo dated 4/15/1996 to Mr. Shuichi Kanno from Chris Pickett	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	1432	C				WITHDRAWN	
RX	1433	C	Document titled "Motorola OMPAC is Different"	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	1434	C	Document titled "FBGA User's Guide"	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1435	C	Document titled "Proceedings of The Chip Scale Packaging Symposium"	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1436	C				WITHDRAWN	
RX	1437	C	Document titled "The CSP of Choice, FBGAs, For Flash Memories"	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1438	C				WITHDRAWN	
RX	1439		Document titled "Tessera Inc s-1, Registration Statement"	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	1439	A	Document titled "Tessera Inc s-1, Registration Statement"	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	1440	C				WITHDRAWN	
RX	1441	C				WITHDRAWN	
RX	1442	C				WITHDRAWN	
RX	1443	C				WITHDRAWN	
RX	1444	C				WITHDRAWN	
RX	1445	C				WITHDRAWN	
RX	1446					WITHDRAWN	
RX	1447					WITHDRAWN	
RX	1448					WITHDRAWN	
RX	1449	C				WITHDRAWN	
RX	1450	C				WITHDRAWN	
RX	1451	C				WITHDRAWN	
RX	1452	C				WITHDRAWN	
RX	1453	C				WITHDRAWN	
RX	1454	C				WITHDRAWN	
RX	1455	C				WITHDRAWN	
RX	1456	C				WITHDRAWN	
RX	1457	C				WITHDRAWN	
RX	1458	C	Tessera Dictionary	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	1459	C				WITHDRAWN	
RX	1460	C				WITHDRAWN	
RX	1461	C				WITHDRAWN	
RX	1462	C				WITHDRAWN	
RX	1463	C	Compliancy Mechanisms, Joe Fjelstad, Tessera	DiStefano / Fjelstad	INFRNG/NON-INFRNG, OWNR	ADMITTED	7/14/2008
RX	1464	C				WITHDRAWN	
RX	1465	C				WITHDRAWN	
RX	1466	C	Series of E-mails, first one from Craig Mitchell to Yasuhisa Nakamura, Subject: Elastomer Pad thickness [TESST0118037 - TESST0118039]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	1467	C				WITHDRAWN	
RX	1468	C				WITHDRAWN	
RX	1469	C				WITHDRAWN	
RX	1470	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1471	C				WITHDRAWN	
RX	1472	C				WITHDRAWN	
RX	1473	C				WITHDRAWN	
RX	1474	C				WITHDRAWN	
RX	1475	C				WITHDRAWN	
RX	1476	C				WITHDRAWN	
RX	1477	C				WITHDRAWN	
RX	1478	C				WITHDRAWN	
RX	1479	C				WITHDRAWN	
RX	1480	C				WITHDRAWN	
RX	1481	C				WITHDRAWN	
RX	1482	C				WITHDRAWN	
RX	1483	C				WITHDRAWN	
RX	1484	C				WITHDRAWN	
RX	1485	C				WITHDRAWN	
RX	1486	C				WITHDRAWN	
RX	1487	C				WITHDRAWN	
RX	1488	C				WITHDRAWN	
RX	1489	C				WITHDRAWN	
RX	1490	C				WITHDRAWN	
RX	1491	C				WITHDRAWN	
RX	1492	C				WITHDRAWN	
RX	1493	C				WITHDRAWN	
RX	1494	C				WITHDRAWN	
RX	1495	C				WITHDRAWN	
RX	1496	C				WITHDRAWN	
RX	1497	C				WITHDRAWN	
RX	1498	C				WITHDRAWN	
RX	1499	C				WITHDRAWN	
RX	1500	C	IPAC 310 (FBGA)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1501	C	Reliability Modeling of FBGA Package - Current Status Report	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1502	C				WITHDRAWN	
RX	1503		U.S. Patent No. 5,148,265	Schaper / Ivey/Khandros	VLD/INVLD, OWNR	ADMITTED	7/18/2008 7/22/08

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1504	C				WITHDRAWN	
RX	1505	C				WITHDRAWN	
RX	1506	C				WITHDRAWN	
RX	1507	C				WITHDRAWN	
RX	1508	C				WITHDRAWN	
RX	1509	C	•			WITHDRAWN	
RX	1510	C				WITHDRAWN	
RX	1511	C				WITHDRAWN	
RX	1512	C				WITHDRAWN	
RX	1513	C				WITHDRAWN	
RX	1514	C				WITHDRAWN	
RX	1515	C				WITHDRAWN	
RX	1516	C				WITHDRAWN	
RX	1517	C				WITHDRAWN	
RX	1518		Article titled "Method of Testing Chips and Joining Chips to Substrates"	Khandros	OWNR	ADMITTED	7/22/2008
RX	1519	C				WITHDRAWN	
RX	1520	C				WITHDRAWN	
RX	1521	C				WITHDRAWN	
RX	1522	C				WITHDRAWN	
RX	1523	C	Memo to file from DiStefano, May 14, 1999, Analysis of TI Micro Star	DiStefano	OWNR	ADMITTED	7/14/2008
RX	1524	C				WITHDRAWN	
RX	1525	C				WITHDRAWN	
RX	1526	C				WITHDRAWN	
RX	1527	C				WITHDRAWN	
RX	1528	C				WITHDRAWN	
RX	1529		"The Impact of CSPs on Encapsulation Materials," DiStefano and Fjelstad	DiStefano / Sitaraman / Fjelstad	OWNR / INFRNG/NON-INFRNGe	ADMITTED	7/14/2008 7/16/2008
RX	1530		Proceedings, the 34th ISHM-Nordic Annual Conference	Fjelstad	INFRNG/NON-INFRNG	ADMITTED	
RX	1531		Infrastructure for uBGA packaging	Fjelstad	INFRNG/NON-INFRNG	ADMITTED	
RX	1532	C				WITHDRAWN	
RX	1533	C	Bumped Flex on Chip: A Novel Approach to High Density Chip Packaging	Fjelstad	INFRNG/NON-INFRNG	ADMITTED	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1534					WITHDRAWN	
RX	1535	C				WITHDRAWN	
RX	1536	C	Declaration of Joseph Fjelstad	Fjelstad	INFRNG/NON-INFRNG	ADMITTED	
RX	1537	C				WITHDRAWN	
RX	1538	C				WITHDRAWN	
RX	1539	C				WITHDRAWN	
RX	1540	C				WITHDRAWN	
RX	1541	C				WITHDRAWN	
RX	1542	C				WITHDRAWN	
RX	1543	C	"Reliable BGAs emerge i micro form," DiStefano Article	DiStefano	OWNR	ADMITTED	7/14/2008
RX	1544	C				WITHDRAWN	
RX	1545	C				WITHDRAWN	
RX	1546	C				WITHDRAWN	
RX	1547	C				WITHDRAWN	
RX	1548	C				WITHDRAWN	
RX	1549	C				WITHDRAWN	
RX	1550	C				WITHDRAWN	
RX	1551	C				WITHDRAWN	
RX	1552	C				WITHDRAWN	
RX	1553	C				WITHDRAWN	
RX	1554	C				WITHDRAWN	
RX	1555	C				WITHDRAWN	
RX	1556	C				WITHDRAWN	
RX	1557	C				WITHDRAWN	
RX	1558	C				WITHDRAWN	
RX	1559	C				WITHDRAWN	
RX	1560	C				WITHDRAWN	
RX	1561	C				WITHDRAWN	
RX	1562		US Patent No. 6,433,419	Ivey	VLD/INVLD	ADMITTED	7/18/2008
RX	1563	C	TI Article	DiStefano	OWNR	ADMITTED	7/14/2008
RX	1564	C				WITHDRAWN	
RX	1565					WITHDRAWN	
RX	1566	C				WITHDRAWN	
RX	1567	C				WITHDRAWN	
RX	1568	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Rulings	Status	Date
RX	1569	C				WITHDRAWN	
RX	1570	C				WITHDRAWN	
RX	1571	C				WITHDRAWN	
RX	1572	C				WITHDRAWN	
RX	1573	C				WITHDRAWN	
RX	1574	C				WITHDRAWN	
RX	1575	C				WITHDRAWN	
RX	1576		Photographs of chips	Schaper / Freyman	VLD/INVLD, INFRNG/NON-INFRNG.	ADMITTED	7/15/2008 7/18/2008
RX	1577		Citizen Overmold PCB Design Guidelines	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1578		Hitachi Photosensitive Film Photec SR-2300G	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1579		Citizen's Motorola OMPGA Package Assembly Process	Freyman / Ivey	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/15/2008 7/18/2008
RX	1580	C	CCL-HL832&HL830 GHPL-830 For Plastic Package Use dated 10/13/1999	Sitaraman / Freyman	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/15/2008 7/16/2008
RX	1581	C	SR-2300G-75	Sitaraman / Freyman	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/15/2008 7/16/2008
RX	1582	C	AMICON C-990J #333	Sitaraman / Freyman / Ivey	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/15/2008 7/16/2008
RX	1583	C	AMICON C-990J #333M-1 Presentation	Sitaraman / Freyman	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/15/2008 7/16/2008
RX	1584	C	Citizen Epoxy Molding Compound dated 7/11/1988	Sitaraman / Freyman	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/15/2008 7/16/2008
RX	1585	C	Detail Line-up of overmold OMPAC Packages	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1586	C				WITHDRAWN	
RX	1587	C				WITHDRAWN	
RX	1588	C				WITHDRAWN	
RX	1589	C	Photographs of Chips	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008
RX	1590	C				WITHDRAWN	
RX	1591	C	Photographs of Chips	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1592	C				WITHDRAWN	
RX	1593	C	Invoice dated 9/27/1989	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1594	C				WITHDRAWN	
RX	1595	C				WITHDRAWN	
RX	1596		Schematic Drawings of multichip module	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008
RX	1597	C				WITHDRAWN	
RX	1598		Photographs of Chip	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008
RX	1599		Fax from Ron Mundwiller to Mike McShane re Motorola 114 Pin PPGA Package dated 12/4/1987	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1600	C				WITHDRAWN	
RX	1601	C				WITHDRAWN	
RX	1602	C	Letter to Ron Mundwiller from Howard Wilson dated 5/9/1989	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1603	C				WITHDRAWN	
RX	1604	C				WITHDRAWN	
RX	1605	C	Memo from M. Ohi to Howard Wilson re Motorola Pad Array Carrier for HC11 1C dated 7/3/1989	Sitaraman / Schaper	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/16/2008 7/18/2008
RX	1606	C				WITHDRAWN	
RX	1607		Fax from Howard Wilson to K. Komatsu dated 7/11/1989	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RX	1608		Memo from Howard Wilson to M. Ohi dated 7/19/1989 re: Soft Tooling Issues 100 PAC Questions	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008
RX	1609	C				WITHDRAWN	
RX	1610		Photographs of chip	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008
RX	1611	C				WITHDRAWN	
RX	1612	C				WITHDRAWN	
RX	1613	C				WITHDRAWN	
RX	1614		Bruce Freyman business card with handwritten note	Shimada	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/22/2008
RX	1615	C				WITHDRAWN	
RX	1616	C				WITHDRAWN	
RX	1617	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1618					WITHDRAWN	
RX	1619					WITHDRAWN	
RX	1620	C				WITHDRAWN	
RX	1621	C				WITHDRAWN	
RX	1622	C				WITHDRAWN	
RX	1623	C				WITHDRAWN	
RX	1624	C				WITHDRAWN	
RX	1625	C				WITHDRAWN	
RX	1626	C				WITHDRAWN	
RX	1627	C				WITHDRAWN	
RX	1628	C				WITHDRAWN	
RX	1629	C				WITHDRAWN	
RX	1630	C				WITHDRAWN	
RX	1631	C	The CSP of Choice, FBGAs, For Flash Memories	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1632	C				WITHDRAWN	
RX	1633	C				WITHDRAWN	
RX	1634	C				WITHDRAWN	
RX	1635	C				WITHDRAWN	
RX	1636	C				WITHDRAWN	
RX	1637	C				WITHDRAWN	
RX	1638	C				WITHDRAWN	
RX	1639	C				WITHDRAWN	
RX	1640	C				WITHDRAWN	
RX	1641	C				WITHDRAWN	
RX	1642					WITHDRAWN	
RX	1643	C				WITHDRAWN	
RX	1644	C				WITHDRAWN	
RX	1645	C				WITHDRAWN	
RX	1646	C				WITHDRAWN	
RX	1647	C				WITHDRAWN	
RX	1648	C				WITHDRAWN	
RX	1649	C				WITHDRAWN	
RX	1650	C				WITHDRAWN	
RX	1651	C				WITHDRAWN	
RX	1652	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1653	C				WITHDRAWN	
RX	1654	C				WITHDRAWN	
RX	1655	C	TCC License Agreement entered into between Tessera Inc. and Samsung Electronics Co., Ltd [TESST0010238 - TESST0010258]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	1656	C				WITHDRAWN	
RX	1657	C				WITHDRAWN	
RX	1658	C				WITHDRAWN	
RX	1659	C				WITHDRAWN	
RX	1660	C				WITHDRAWN	
RX	1661	C				WITHDRAWN	
RX	1662	C				WITHDRAWN	
RX	1663	C				WITHDRAWN	
RX	1664	C				WITHDRAWN	
RX	1665	C				WITHDRAWN	
RX	1666	C				WITHDRAWN	
RX	1667	C				WITHDRAWN	
RX	1668	C				WITHDRAWN	
RX	1669	C				WITHDRAWN	
RX	1670	C				WITHDRAWN	
RX	1671	C				WITHDRAWN	
RX	1672	C				WITHDRAWN	
RX	1673	C				WITHDRAWN	
RX	1674	C				WITHDRAWN	
RX	1675	C				WITHDRAWN	
RX	1676	C				WITHDRAWN	
RX	1677	C				WITHDRAWN	
RX	1678	C				WITHDRAWN	
RX	1679	C				WITHDRAWN	
RX	1680	C				WITHDRAWN	
RX	1681	C				WITHDRAWN	
RX	1682	C				WITHDRAWN	
RX	1683	C				WITHDRAWN	
RX	1684	C				WITHDRAWN	
RX	1685	C				WITHDRAWN	
RX	1686	C				WITHDRAWN	
RX	1687	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1688	C				WITHDRAWN	
RX	1689	C				WITHDRAWN	
RX	1690	C				WITHDRAWN	
RX	1691	C				WITHDRAWN	
RX	1692	C				WITHDRAWN	
RX	1693	C				WITHDRAWN	
RX	1694	C				WITHDRAWN	
RX	1695	C				WITHDRAWN	
RX	1696	C				WITHDRAWN	
RX	1697	C				WITHDRAWN	
RX	1698	C				WITHDRAWN	
RX	1699	C				WITHDRAWN	
RX	1700	C				WITHDRAWN	
RX	1701	C				WITHDRAWN	
RX	1702	C				WITHDRAWN	
RX	1703	C				WITHDRAWN	
RX	1704	C				WITHDRAWN	
RX	1705	C				WITHDRAWN	
RX	1706	C				WITHDRAWN	
RX	1707	C				WITHDRAWN	
RX	1708	C				WITHDRAWN	
RX	1709	C				WITHDRAWN	
RX	1710	C				WITHDRAWN	
RX	1711	C				WITHDRAWN	
RX	1712	C				WITHDRAWN	
RX	1713	C				WITHDRAWN	
RX	1714	C				WITHDRAWN	
RX	1715	C				WITHDRAWN	
RX	1716	C				WITHDRAWN	
RX	1717	C				WITHDRAWN	
RX	1718	C				WITHDRAWN	
RX	1719	C				WITHDRAWN	
RX	1720	C				WITHDRAWN	
RX	1721	C				WITHDRAWN	
RX	1722	C				WITHDRAWN	
RX	1723	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1724		Article titled "Assembly-level Reliability Characterization of Chip-Scale Packages" authored by Pradeep Lall and Kingshuk Banerji	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	1725	C				WITHDRAWN	
RX	1726	C				WITHDRAWN	
RX	1727	C				WITHDRAWN	
RX	1728	C				WITHDRAWN	
RX	1729	C				WITHDRAWN	
RX	1730	C				WITHDRAWN	
RX	1731	C				WITHDRAWN	
RX	1732	C				WITHDRAWN	
RX	1733	C				WITHDRAWN	
RX	1734	C				WITHDRAWN	
RX	1735	C				WITHDRAWN	
RX	1736	C				WITHDRAWN	
RX	1737	C				WITHDRAWN	
RX	1738	C				WITHDRAWN	
RX	1739	C				WITHDRAWN	
RX	1740	C				WITHDRAWN	
RX	1741	C				WITHDRAWN	
RX	1742	C				WITHDRAWN	
RX	1743	C				WITHDRAWN	
RX	1744					WITHDRAWN	
RX	1745	C				WITHDRAWN	
RX	1746	C				WITHDRAWN	
RX	1747	C				WITHDRAWN	
RX	1748	C				WITHDRAWN	
RX	1749	C				WITHDRAWN	
RX	1750	C				WITHDRAWN	
RX	1751	C				WITHDRAWN	
RX	1752	C				WITHDRAWN	
RX	1753	C				WITHDRAWN	
RX	1754	C	FÎ¼BGA Transfer Document, September 25, 1990	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1755	C				WITHDRAWN	
RX	1756	C	Section 6. Process and material Characterization	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1757	C	Section 7. Reliability Modeling and Analysis	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1758	C	Section 8. Reliability Tests and Failure Analysis	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1759	C				WITHDRAWN	
RX	1760	C				WITHDRAWN	
RX	1761	C				WITHDRAWN	
RX	1762	C				WITHDRAWN	
RX	1763	C				WITHDRAWN	
RX	1764	C				WITHDRAWN	
RX	1765	C				WITHDRAWN	
RX	1766	C	Werner Engelmaier ISTO Tessera's Motion for Summary Judgment	Qu / Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1767	C				WITHDRAWN	
RX	1768	C				WITHDRAWN	
RX	1769	C				WITHDRAWN	
RX	1770	C				WITHDRAWN	
RX	1771	C				WITHDRAWN	
RX	1772	C				WITHDRAWN	
RX	1773	C				WITHDRAWN	
RX	1774	C				WITHDRAWN	
RX	1775	C				WITHDRAWN	
RX	1776	C				WITHDRAWN	
RX	1777	C				WITHDRAWN	
RX	1778	C				WITHDRAWN	
RX	1779	C				WITHDRAWN	
RX	1780	C				WITHDRAWN	
RX	1781	C				WITHDRAWN	
RX	1782	C				WITHDRAWN	
RX	1783	C				WITHDRAWN	
RX	1784	C				WITHDRAWN	
RX	1785	C				WITHDRAWN	
RX	1786	C				WITHDRAWN	
RX	1787	C	TCC License Agreement entered into between Tessera Inc. and Advanced Semiconductor Engineering, Inc. [TMI00016041 - TMI00016060]	Mitchell	RMDY, DI	ADMITTED	7/15/2005

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1788	C				WITHDRAWN	
RX	1789	C				WITHDRAWN	
RX	1790	C				WITHDRAWN	
RX	1791	C				WITHDRAWN	
RX	1792	C				WITHDRAWN	
RX	1793	C				WITHDRAWN	
RX	1794	C	Design and Reliability Study of Center Bonded lead Î¼BGA Package for Rambus DRAM	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1795	C				WITHDRAWN	
RX	1796	C				WITHDRAWN	
RX	1797	C				WITHDRAWN	
RX	1798	C	CSP Design and Reliability: Lead Design Guide for Center Pad Î¼BGA Package	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1799	C				WITHDRAWN	
RX	1800	C				WITHDRAWN	
RX	1801	C				WITHDRAWN	
RX	1802	C				WITHDRAWN	
RX	1803	C				WITHDRAWN	
RX	1804	C				WITHDRAWN	
RX	1805	C				WITHDRAWN	
RX	1806	C	The Elastomer Index for Î¼BGA Reliability Analysis	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1807	C	IPAC FBGA Qualification Summary	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1808	C				WITHDRAWN	
RX	1809	C				WITHDRAWN	
RX	1810	C				WITHDRAWN	
RX	1811	C				WITHDRAWN	
RX	1812	C				WITHDRAWN	
RX	1813	C				WITHDRAWN	
RX	1814	C				WITHDRAWN	
RX	1815	C				WITHDRAWN	
RX	1816	C				WITHDRAWN	
RX	1817	C				WITHDRAWN	
RX	1818	C				WITHDRAWN	
RX	1819	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1820	C				WITHDRAWN	
RX	1821	C	E-mail from Bill Carlson dated 4/26/2000	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1822	C				WITHDRAWN	
RX	1823	C				WITHDRAWN	
RX	1824	C				WITHDRAWN	
RX	1825	C				WITHDRAWN	
RX	1826	C				WITHDRAWN	
RX	1827	C				WITHDRAWN	
RX	1828	C				WITHDRAWN	
RX	1829	C				WITHDRAWN	
RX	1830	C				WITHDRAWN	
RX	1831	C				WITHDRAWN	
RX	1832	C				WITHDRAWN	
RX	1833	C				WITHDRAWN	
RX	1834	C				WITHDRAWN	
RX	1835	C				WITHDRAWN	
RX	1836	C				WITHDRAWN	
RX	1837	C				WITHDRAWN	
RX	1838	C				WITHDRAWN	
RX	1839	C				WITHDRAWN	
RX	1840	C	Restated TCC License Agreement entered into between Tessera Inc. and Samsung Electronics Co., Ltd.[TMI00278447 - TMI00278473]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	1841	C				WITHDRAWN	
RX	1842	C				WITHDRAWN	
RX	1843	C				WITHDRAWN	
RX	1844	C				WITHDRAWN	
RX	1845	C				WITHDRAWN	
RX	1846	C				WITHDRAWN	
RX	1847	C				WITHDRAWN	
RX	1848	C				WITHDRAWN	
RX	1849	C				WITHDRAWN	
RX	1850	C				WITHDRAWN	
RX	1851	C				WITHDRAWN	
RX	1852	C				WITHDRAWN	
RX	1853	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1854	C	Electronic Packaging Technology and Design Case Study, dated March 26, 2003	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1855	C				WITHDRAWN	
RX	1856	C				WITHDRAWN	
RX	1857	C				WITHDRAWN	
RX	1858	C				WITHDRAWN	
RX	1859	C				WITHDRAWN	
RX	1860	C				WITHDRAWN	
RX	1861	C				WITHDRAWN	
RX	1862	C				WITHDRAWN	
RX	1863	C				WITHDRAWN	
RX	1864	C				WITHDRAWN	
RX	1865	C				WITHDRAWN	
RX	1866	C				WITHDRAWN	
RX	1867	C				WITHDRAWN	
RX	1868	C				WITHDRAWN	
RX	1869	C				WITHDRAWN	
RX	1870	C				WITHDRAWN	
RX	1871	C				WITHDRAWN	
RX	1872	C				WITHDRAWN	
RX	1873	C				WITHDRAWN	
RX	1874	C				WITHDRAWN	
RX	1875	C				WITHDRAWN	
RX	1876	C				WITHDRAWN	
RX	1877	C				WITHDRAWN	
RX	1878	C				WITHDRAWN	
RX	1879	C				WITHDRAWN	
RX	1880	C				WITHDRAWN	
RX	1881	C				WITHDRAWN	
RX	1882	C				WITHDRAWN	
RX	1883	C				WITHDRAWN	
RX	1884	C				WITHDRAWN	
RX	1885	C				WITHDRAWN	
RX	1886	C				WITHDRAWN	
RX	1887	C				WITHDRAWN	
RX	1888	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1889	C				WITHDRAWN	
RX	1890	C				WITHDRAWN	
RX	1891	C				WITHDRAWN	
RX	1892	C				WITHDRAWN	
RX	1893	C				WITHDRAWN	
RX	1894	C				WITHDRAWN	
RX	1895	C				WITHDRAWN	
RX	1896	C				WITHDRAWN	
RX	1897	C				WITHDRAWN	
RX	1898	C				WITHDRAWN	
RX	1899	C				WITHDRAWN	
RX	1900	C				WITHDRAWN	
RX	1901	C				WITHDRAWN	
RX	1902	C				WITHDRAWN	
RX	1903	C				WITHDRAWN	
RX	1904	C				WITHDRAWN	
RX	1905	C				WITHDRAWN	
RX	1906	C				WITHDRAWN	
RX	1907	C				WITHDRAWN	
RX	1908	C				WITHDRAWN	
RX	1909	C				WITHDRAWN	
RX	1910	C				WITHDRAWN	
RX	1911	C				WITHDRAWN	
RX	1912	C				WITHDRAWN	
RX	1913	C				WITHDRAWN	
RX	1914		First International Conference on Flex Circuits, Flexcon 1994	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1915		A Compliant Chip-Size Packaging Technology	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1916	C				WITHDRAWN	
RX	1917	C				WITHDRAWN	
RX	1918	C				WITHDRAWN	
RX	1919	C				WITHDRAWN	
RX	1920	C				WITHDRAWN	
RX	1921	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1922	C	Wafer level packaging of compliant, chip size Ics	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	1923	C				WITHDRAWN	
RX	1924	C				WITHDRAWN	
RX	1925	C				WITHDRAWN	
RX	1926	C				WITHDRAWN	
RX	1927	C				WITHDRAWN	
RX	1928	C				WITHDRAWN	
RX	1929	C				WITHDRAWN	
RX	1930	C				WITHDRAWN	
RX	1931	C				WITHDRAWN	
RX	1932	C				WITHDRAWN	
RX	1933	C				WITHDRAWN	
RX	1934	C	Teck-Gyu Kang to Mike Warner	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	1935	C				WITHDRAWN	
RX	1936	C				WITHDRAWN	
RX	1937	C				WITHDRAWN	
RX	1938	C				WITHDRAWN	
RX	1939	C				WITHDRAWN	
RX	1940	C				WITHDRAWN	
RX	1941	C				WITHDRAWN	
RX	1942	C				WITHDRAWN	
RX	1943	C				WITHDRAWN	
RX	1944	C				WITHDRAWN	
RX	1945	C				WITHDRAWN	
RX	1946	C				WITHDRAWN	
RX	1947	C				WITHDRAWN	
RX	1948	C				WITHDRAWN	
RX	1949	C				WITHDRAWN	
RX	1950	C				WITHDRAWN	
RX	1951	C				WITHDRAWN	
RX	1952	C				WITHDRAWN	
RX	1953	C				WITHDRAWN	
RX	1954	C				WITHDRAWN	
RX	1955	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1956	C				WITHDRAWN	
RX	1957	C				WITHDRAWN	
RX	1958	C				WITHDRAWN	
RX	1959	C				WITHDRAWN	
RX	1960	C				WITHDRAWN	
RX	1961	C				WITHDRAWN	
RX	1962	C				WITHDRAWN	
RX	1963	C				WITHDRAWN	
RX	1964	C				WITHDRAWN	
RX	1965	C				WITHDRAWN	
RX	1966	C				WITHDRAWN	
RX	1967	C				WITHDRAWN	
RX	1968	C				WITHDRAWN	
RX	1969	C				WITHDRAWN	
RX	1970	C				WITHDRAWN	
RX	1971	C				WITHDRAWN	
RX	1972	C				WITHDRAWN	
RX	1973	C				WITHDRAWN	
RX	1974	C				WITHDRAWN	
RX	1975	C				WITHDRAWN	
RX	1976	C				WITHDRAWN	
RX	1977	C				WITHDRAWN	
RX	1978	C				WITHDRAWN	
RX	1979	C				WITHDRAWN	
RX	1980	C				WITHDRAWN	
RX	1981	C				WITHDRAWN	
RX	1982	C				WITHDRAWN	
RX	1983	C				WITHDRAWN	
RX	1984	C				WITHDRAWN	
RX	1985	C				WITHDRAWN	
RX	1986	C				WITHDRAWN	
RX	1987	C				WITHDRAWN	
RX	1988	C				WITHDRAWN	
RX	1989	C				WITHDRAWN	
RX	1990	C				WITHDRAWN	
RX	1991	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	1992	C				WITHDRAWN	
RX	1993	C	Motorola OMPAC is Different	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	1994	C				WITHDRAWN	
RX	1995	C				WITHDRAWN	
RX	1996	C				WITHDRAWN	
RX	1997	C				WITHDRAWN	
RX	1998	C				WITHDRAWN	
RX	1999	C				WITHDRAWN	
RX	2000	C				WITHDRAWN	
RX	2001	C				WITHDRAWN	
RX	2002	C				WITHDRAWN	
RX	2003	C				WITHDRAWN	
RX	2004	C	FBGA Package Analysis	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2005	C				WITHDRAWN	
RX	2006	C				WITHDRAWN	
RX	2007	C				WITHDRAWN	
RX	2008	C				WITHDRAWN	
RX	2009	C				WITHDRAWN	
RX	2010	C				WITHDRAWN	
RX	2011	C	Tessera's verified Complaint Filed 4/17/2007	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2012	C	Tessera's Proposed Claim Construction filed Dec. 17, 2007	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2013	C				WITHDRAWN	
RX	2014	C				WITHDRAWN	
RX	2015	C				WITHDRAWN	
RX	2016		Gannamani et al., .Reliability Evaluation of Chip Scale Packages., Proceedings of The Chip Scale Packaging Symposium, San Jose, California, September 12-16, 1999, pp. 116-121	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2017	C	FBGA Transfer Document, September 25,2000	Lall / Ivey	VLD/INVLD	ADMITTED	7/17/2008 7/18/2008
RX	2018	C				WITHDRAWN	
RX	2019	C				WITHDRAWN	
RX	2020		United States Patent No. 5,347,159	MIN / Schaper	INFRNG/NON-INFRNGe., Invalid	ADMITTED	7/17/2008 7/18/2008
RX	2021	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2022	C				WITHDRAWN	
RX	2023	C				WITHDRAWN	
RX	2024	C				WITHDRAWN	
RX	2025	C				WITHDRAWN	
RX	2026	C				WITHDRAWN	
RX	2027	C				WITHDRAWN	
RX	2028	C				WITHDRAWN	
RX	2029	C				WITHDRAWN	
RX	2030	C				WITHDRAWN	
RX	2031	C				WITHDRAWN	
RX	2032	C				WITHDRAWN	
RX	2033	C				WITHDRAWN	
RX	2034	C				WITHDRAWN	
RX	2035	C				WITHDRAWN	
RX	2036	C				WITHDRAWN	
RX	2037	C				WITHDRAWN	
RX	2038	C				WITHDRAWN	
RX	2039	C				WITHDRAWN	
RX	2040	C				WITHDRAWN	
RX	2041	C				WITHDRAWN	
RX	2042	C	Process Flow Chart Specification for 2 DIE Stacked CSP, XXX KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2043	C				WITHDRAWN	
RX	2044	C	Process Flow Chart Specification for 3 DIE Stacked CSP, XXX CHUGLI MH80-VB600-D1 Rev. A	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2045	C				WITHDRAWN	
RX	2046	C				WITHDRAWN	
RX	2047	C				WITHDRAWN	
RX	2048	C				WITHDRAWN	
RX	2049	C				WITHDRAWN	
RX	2050	C				WITHDRAWN	
RX	2051	C	Bill of Materials for Product MSM6250A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2052	C				WITHDRAWN	
RX	2053	C				WITHDRAWN	

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RX	2054	C	SD90-VE412-1,	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2055	C	MS90-V6698-H1(XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2056	C	MS90-VE007-C, ASSEMBLY MATERIAL SET, BTS4020/BALI, 60CSP, 4.5X4.5MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2057	C	Package Outline Drawing, MSM6800A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2058	C	NT90-VE412-1, 60 CSP, 4.5X4.5X 1.0 MM, S220, M450	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2059	C	"QTSI00586642 MSM6800A SD90.pdf" Substrate Drawing, NALCON65 R1.0 11x11 MM, 432NSP (QTSI 00586642 - QTSI 00586649)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2060	C	Bonding Diagram	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2061	C				WITHDRAWN	
RX	2062	C	188 Ball FBGA 13.00mm X 8.00mm Body	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2063	C	Reliability Qualification	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2064	C				WITHDRAWN	
RX	2065	C				WITHDRAWN	
RX	2066	C				WITHDRAWN	
RX	2067	C				WITHDRAWN	
RX	2068	C				WITHDRAWN	
RX	2069	C				WITHDRAWN	
RX	2070		Select Pages from Webster's Ninth New Collegiate Dictionary	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2071	C				WITHDRAWN	
RX	2072	C				WITHDRAWN	
RX	2073	C				WITHDRAWN	
RX	2074	C				WITHDRAWN	
RX	2075	C				WITHDRAWN	
RX	2076	C	208 FBGA Package Specification [80-V0700-1 rev. H]	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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RX	2077	C	Engineering Bonding Diagram PM6652, PMIC3-HT2BL90-VC275-1A, PM6652/PMIC3 6X6MM 97CSP SUPPLIER;	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2078	C	Engineering Bonding Diagram MBP1600, MBP1610 BL90-VB850-1A, BIGBIRD UBM (MBP1600, MBP1610), 9X9MM, 216CSP, SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2079	C	Engineering Bonding Diagram MSM7600BL90-VB720-1A, XXX_SMP 15X15MM 543CSP SUPPLIER	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2080	C	Engineering Bonding Diagram BTS4050 BL90-VE415-1A	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2081	C	Engineering Bonding Diagram; BL90-VE340-1A, WFB4030/TAURUS, 17X17MM, 400FBGA, SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2082	C				WITHDRAWN	
RX	2083	C				WITHDRAWN	
RX	2084	C	Engineering Bonding Diagram MSM6260/MSM6255A/MSM6245 BL90-VD156-1A, MSM6260/MSM6255A/MSM6245, (FALCON65/SATURN2), 11X11MM, 432NSP SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2085	C				WITHDRAWN	
RX	2086	C				WITHDRAWN	
RX	2087	C	Engineering Bonding Diagram MSM7200	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2088	C				WITHDRAWN	
RX	2089	C				WITHDRAWN	
RX	2090	C				WITHDRAWN	
RX	2091	C				WITHDRAWN	
RX	2092	C	BL90-V9050-3A, Rev. A, Bonding Diagram Jaugar90_UMC+XXX, 14x14MM, 409CSP, Supplier	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2093	C				WITHDRAWN	
RX	2094	C				WITHDRAWN	
RX	2095	C				WITHDRAWN	
RX	2096	C				WITHDRAWN	
RX	2097	C				WITHDRAWN	
RX	2098	C	Engineering Bonding Diagram MSM7500 BL90-V6930-2A, PHOENIX_SMP 15X15MM 543CSP SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2099	C	Engineering Bonding Diagram MSM6800A BL90-V6698-2A,	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2100	C	Engineering Bonding Diagram MSM6800A BL90-V6698-1A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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RX	2101	C				WITHDRAWN	
RX	2102	C				WITHDRAWN	
RX	2103	C				WITHDRAWN	
RX	2104	C				WITHDRAWN	
RX	2105	C				WITHDRAWN	
RX	2106	C				WITHDRAWN	
RX	2107	C	Engineering Bonding Diagram BTS4020	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2108	C	Engineering Bonding Diagram	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2109	C	Engineering Bonding Diagram [(MSM6000), 208FBGP, BL90-V3050-1, Rev.B]	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2110	C	Engineering Bonding Diagram MSM6500	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2111	C	BL90-V7815-1, Rev. B, Bonding Diagram, MSM6100 (Cougar90/Jupiter), 13x13MM, 341CSP, TSMC	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2112	C	BL90-V7890-1A, Rev. A, Bonding Diagram XXX90/XXX, 14x14mm, 409CSP, Supplier	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2113	C	License Agreement dated May 9th, 1996 between Tessera and Amkor Electronics [TMI00016001 - TMI00016039]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2114	C				WITHDRAWN	
RX	2115	C	Settlement Agreement between Tessera and Texas Instruments [TESST389665 - TESST3896696]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2116	C	Settlement and Release Agreement; Immunity Agreement with attachments between Tessera and Sharp Corporation [TESST389627 - TESST389645]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2117	C	Amendment to Immunity Agreement dated July 6, 2004 between Tessera and Sharp [TESSEXP4592 - TESSEXP4594]	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2118	C				WITHDRAWN	
RX	2119	C				WITHDRAWN	
RX	2120	C				WITHDRAWN	
RX	2121	C				WITHDRAWN	
RX	2122	C				WITHDRAWN	
RX	2123	C	Research Staff Members Accomplishment Planning & Documentation of I. Khandros	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2124	C	Letter to distribution dated October 30, 1989 from Marvin S. Pittler	Romankiw	OWNR	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2125	C				WITHDRAWN	
RX	2126	C				WITHDRAWN	
RX	2127	C				WITHDRAWN	
RX	2128	C				WITHDRAWN	
RX	2130	C	License Agreement between Tessera and Intel dated October 22, 1996	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2130	C				WITHDRAWN	
RX	2131	C				WITHDRAWN	
RX	2132	C				WITHDRAWN	
RX	2133	C				WITHDRAWN	
RX	2134	C				WITHDRAWN	
RX	2135	C	Khandros Statement of Understanding dated April 20, 1990	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2136	C				WITHDRAWN	
RX	2137	C				WITHDRAWN	
RX	2138	C				WITHDRAWN	
RX	2139	C				WITHDRAWN	
RX	2140	C				WITHDRAWN	
RX	2141	C	DiStefano Manager's Report of Separation	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2142	C				WITHDRAWN	
RX	2143	C				WITHDRAWN	
RX	2144	C				WITHDRAWN	
RX	2145	C				WITHDRAWN	
RX	2146	C	IBM Confidentiality Agreement signed by Igor Khandros	Ivey	OWNR	ADMITTED	7/18/2008
RX	2147	C				WITHDRAWN	
RX	2148	C				WITHDRAWN	
RX	2149	C				WITHDRAWN	
RX	2150	C				WITHDRAWN	
RX	2151	C				WITHDRAWN	
RX	2152	C	MS90-VB850-H, ASSEMBLY MATERIAL SET, MBP1600 (UBM), 216 CSP, SCK; MS90-VB850-H (XXX);	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX-	2153	C				WITHDRAWN	
RX	2154	C				WITHDRAWN	
RX	2155	C	MS90-VE415-D, ASSEMBLY MATERIAL SET, BTS4050, 84MSP, 7X7MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2156	C	NT90-VE419-1, Rev. A,	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2157	C	SD90-VE419-1B	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2158	C	SD90-VE419-1 Rev. A, Substrate Drawing	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2159	C	MS90-VB850-C, ASSEMBLY MATERIAL SET, MBP1600 (UBM), 216 CSP, XXX; MS90-VB850-C (XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2160	C	NT90-VC675-1, 216 CSP, 9X9X1.2MM, S210,M700	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2161	C	SD90-VC675-3C, XXX R1.0, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2162	C	80-V2070-1, Rev. H; 320 FBGA Package Specification	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2163	C	HB90-V2400-1, MSM5500 (TAZ3) PRODUCT208 FBGA	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2164	C				WITHDRAWN	
RX	2165	C				WITHDRAWN	
RX	2166	C	MB90-V2400-17	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2167	C	80-V4339-1, Rev. D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2168	C				WITHDRAWN	
RX	2169	C				WITHDRAWN	
RX	2170	C	MB90-V7815-5, Rev. A, MSM6100 (COUGAR90/JUPITER), 341CSP, TSMC	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2171	C	000367K RevA (StatsChipPAC)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2172	C	MS90-V6685-E, Rev. A, Assembly Material Set, MSM6125 (XXX/XXX), 409CSP, 14X14, XXX-K, TAIWAN	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2173	C	MS90-V6685-H, Assembly Material Set MSM6125 (XXX/XXX), 409CSP, 14X14, XXX, KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2174	C	NT90-V2970-1, Rev. A, Package Outline Drawing, 409CSP, 14X14X1.20MM, S260, M650	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2175	C	NT90-V2970-2, Rev. A, Package outline drawwing 409CSP, 14X14X1.20MM, S210, M700	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2176	C				WITHDRAWN	
RX	2177	C				WITHDRAWN	

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RX	2178	C	A-STEL409-14-06 (STATSChipPAC)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2179	C	MS90-VA140-E, Rev. B, Assembly Material Set, XXX65, 409CSP, 14x14mm, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2180	C	MS90-VA140-H , XXX65, 409CSP, 14X14MM, XXX KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2181	C	SD90-V2970-18B, Rev. A., Supplier Substrate Spec., XXX65 R1.0, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2182	C	MB90-V7850-H, Rev. A, Assembly Material Set, MSM6150 (Birdie), 409CSP, 14mm x 14mm XXX (Korea)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2183	C				WITHDRAWN	
RX	2184	C	MS90-V4690-H, Rev. A, Assembly Material Set, XXX, 409CSP, 14mm x 14mm, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2185	C				WITHDRAWN	
RX	2186	C	000365D (ASE Drawings)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2187	C	MS90-VB240-C, XXX65, 409CSP, 14X14MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2188	C	MS90-VB240-H, XXX65, 409CSP, 14X14MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2189	C	MS90-VB245-H, XXX65, 409CSP, 14X14MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2190	C	MS90-VD163-C, ASSEMBLY MATERIAL SET, XXX65, 409PCSP, 14X14MM, XXX KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2191	C	SD90-V2970-18C, Substrate specficaitonXXX65 R1.0, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2192	C	MS90-VA140-H ,	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2194	C	NT90-VC920-1, 409PCSP, 14X14X1.03MM, S300, M400	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2195	C	MS90-VD156-C (XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2196	C	MS90-VD156-H, ASSEMBLY MATERIAL SET, NALCON65, 432NSP, 11X11MM, XXX KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2197	C	MS90-VE589-E (XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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RX	2198	C	80-VA911-1, Rev. B, 432NSP Package Specification	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2199	C	SD90-VA911-3, Rev. B (Drawing)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2200	C				WITHDRAWN	
RX	2201	C				WITHDRAWN	
RX	2202	C	MB90-V5815-6;	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2203	C	MS90-V0704-C, MSM6280 (XXX90/XXX2), 409 CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2204	C	MS90-V0704-H, MSM6280 (XXX90/XXX2), 409CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2205	C	NL90-V0694-1, 14X14MM, 409CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2206	C				WITHDRAWN	
RX	2207	C	SD90-V2970-14A, RAVEN90 R1.0, STATSCHIPPAC	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2208	C	MS90-V0704-H1, XXX90, 432NSP, 11X11MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2209	C	MS90-V0704-H1, Rev. E (XXX);	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2210	C	MS90-V0704-C1 (XXX);	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2211	C	MS90-V0704-E1 (XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2212	C				WITHDRAWN	
RX	2213	C	NT90-VA911-3; NT90-VA911-3, 432NSP, 11X11X1.0MM, S210, M530	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2214	C	SD90-VA911-3, Rev. B, NAVEN R1.0, XXX,	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2215	C				WITHDRAWN	
RX	2216	C	MB90-V7310-5	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2218	C	MB90-V3195-8 [Assembly Material Set, Marking Diagram]	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2219	C				WITHDRAWN	

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RX	2220	C				WITHDRAWN	
RX	2221	C				WITHDRAWN	
RX	2222	C				WITHDRAWN	
RX	2223	C				WITHDRAWN	
RX	2224	C				WITHDRAWN	
RX	2225	C				WITHDRAWN	
RX	2226	C				WITHDRAWN	
RX	2227	C				WITHDRAWN	
RX	2228	C				WITHDRAWN	
RX	2229	C				WITHDRAWN	
RX	2230	C				WITHDRAWN	
RX	2231	C				WITHDRAWN	
RX	2232	C				WITHDRAWN	
RX	2233	C				WITHDRAWN	
RX	2234	C	MS90-V9050-C, MSM6500, 409CSP, 14X14, XXX K4	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2235	C	MS90-V9050-E, MSM6500, 409CSP, 14X14, XXX-K, TAIWAN	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2236	C	MS90-V9050-H, MSM6500, 409CSP, 14X14MM, XXX, KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2237	C	SD90-V2970-19 XXX65 R1.0, 14X14MM, 409CSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2238	C				WITHDRAWN	
RX	2239	C				WITHDRAWN	
RX	2240	C				WITHDRAWN	
RX	2241	C	MB90-V5850-4	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2242	C				WITHDRAWN	
RX	2243	C	BL90-V5850-1, MSM6550 (XXX/XXX) 14X14 409CSP TSMC (XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2244	C				WITHDRAWN	
RX	2245	C	MS90-V5890-1, MSM6550 (XXX90+XXX), 409CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2246	C	MS90-V5890-C, MSM6550 (XXX90+XXX), 409 CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2247	C				WITHDRAWN	

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RX	2248	C	MS90-V6698-H, MSM6800 (XXX), 409CSP, 14 X 14MM, XXX KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2249	C	SD90-V2970-16A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2250	C	SD90-V2970-16C (XXX),	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2251	C				WITHDRAWN	
RX	2252	C	MS90-VC657-E, Rev. A (XXX);	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2253	C	MS90-V6698-H1, MSM6800, 432NSP, 11X11MM	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2254	C	NL90-V6698-2, MSM6800, 11X11MM, 432NSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2255	C	SD90-VA911-2,	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2256	C				WITHDRAWN	
RX	2257	C				WITHDRAWN	
RX	2258	C	MS90-VA780-H, Rev. D. [Assembly Material Set, PLLC3, 341 CSP]	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2259	C	MS90-VA780-H, [Rev. F. - Assembly Material Set, MSM7200 (XXX/XXX/XXX2), 543CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2260	C	MS90-VA780-C (XXX)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2261	C	SD90-V9070-5, SUBSTRATE DRAWING, CHIMERA R3.0, 15X15MM, 543CSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2262	C	SD90-V9070-5A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2263	C	80-VE407-1, Rev. B,	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2264	C	80-VE408-1, Rev. B,	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2265	C	MS90-VE345-C, ASSEMBLY MATERIAL SET, WFB4130/XXX, 289FBGA, 15X15MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2266	C	BL90-VE345-1A, WFB4130, 15X15MM, 289FBGA, SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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RX	2267	C	SD90-VE407-1C, XXX1 R1.0, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2268	C	SD90-VE408-1C, , TAURUS2 R1.0, AMKOR	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2269	C	MS90-VE340-C, ASSEMBLY MATERIAL SET, WFB4030/XXX, 400FBGA, 17X17MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2270	C	MS90-V9225-C, XXX (TEST), 351MSP, 15MM X 15MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2271	C	NT90-V6560-1, 351MSP, 15X15X1.2MM, S260, M650	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2272	C	SD90-V6560-5 (Drawing), XXX R1.0, 15X15MM, 351 MSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2273	C	SD90-V6560-5C (XXX), XXX R1.0, 15X15MM, 351 MSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2274	C	SD90-V6560-5A (XXX), XXX R1.0, 15X15MM, 351 MSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2275	C	NL90-V9690-1, (SC1X), 15X15, 351MSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2276	C	NL90-V9790-1, 15X15MM, 351MSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2277	C	MS90-V9690-C, XXX, 351MSP, 15MM X 15MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2278	C	MS90-V9690-H (XXX), XXX, 351MSP, 15MM X 15MM, XXX, KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2279	C	MS90-V9690-E, Rev A (XXX),	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2280	C	MS90-V9790-5, PANORAMIX (TEST), 351MSP, 15MM X 15MM	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2281	C	MS90-V9650-5, 351MSP, 15MM X 15MM	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2282	C	BL90-V9690-1A, 15X15 MM 351MSP SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2283	C	SD90-VD515-1A (SCI), PM7540, REL. 1.0, SCI	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2284	C	SD90-VD515-1C (XXX), PM7530/40, REL. 1.0, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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RX	2285	C	MS90-VD247-C (XXX K4), ASSEMBLY MATERIAL SET, PM7540, 137CSP, 7X7MM, XXX K4	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2286	C				WITHDRAWN	
RX	2287	C				WITHDRAWN	
RX	2288	C	MS90-VD247-H (XXX), ASSEMBLY MATERIAL SET, PM7540, 137CSP, 7X7MM, XXX-KOREA	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2289	C				WITHDRAWN	
RX	2290	C	NT90-VD515-1, 137 CSP, 7X7X1.2MM, S210, M650	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2291	C				WITHDRAWN	
RX	2292	C	NL90-VC273-1, PM6658/PMIC3, 6X6MM, 97CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2293	C	NL90-VC853-1, PACKAGE PINMAP/NETLIST, PM6658, 6X6MM, 97CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2294	C	NT90-VC330-1, 97CSP, 6X6X1.2MM, S210, M700	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2295	C	SD90-VC330-5, SUBSTRATE DRAWING, PMIC4-TC2, R1.0, 6X6MM, 97CSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2296	C	NL90-VC274-1, PM6655/PMIC3, 6X6MM, 97CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2297	C	NL90-VE073-1, PACKAGE PINMAP/NETLIST, PM6655, 6X6MM, 97CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2298	C	MS90-VC853-H1 (XXX),	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2299	C	BL90-VC275-1, PM6652/PMIC3 6X6MM 97CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2300	C	MS90-VC275-C, MARKING DIAGRAM, PM6652/PMIC3, 97CSP, 6X6MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2301	C	MS90-VC275-H	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2302	C	SD90-VC330-2C, PM6652/55/58/58A RELEASE 2.0	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2303	C	SD90-VC330-3A (SCI), PM6652/55/58 RELEXXX 3.0, SCI	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2304	C	NL90-VC275-1, PM6652/PMIC3, 6X6MM, 97CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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RX	2305	C	NT90-VA010-1, 64CSP,5X5X1.2MM, S210, M700	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2306	C	HB90-V2402-1, PM6640/PM6630 (PMIC3-MT) FSL SMOS7LV	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2307	C	HB90-V7653-1, PM6640/PM6630 PMIC3-MT FSL SMOS7LV	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2308	C	BL90-V2402-1, PM6640/PM6630 (PMIC3-MT) TEST CHIP8X8MM56QFN	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2309	C	BL90-V7653-1, PM6640/PM6630 PMIC3-MT 5X5MM 64CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2310	C	NL90-V7653-1, PM6640/PM6630,PMIC3-MT, 5X5MM, 64CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2311	C	NL90-V2402-1, PM6640/PM6630,PMIC3-MT, 8X8MM, 56QFN	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2312	C	MS90-V7653-9, PM6640, 64CSP, FREESCALE	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2313	C				WITHDRAWN	
RX	2314	C	SD90-VA010-3C (XXX), PM6640/PM6630, PMIC3-MT RELEASE 3.0, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2315	C	SD90-VA010-3A (XXX), PM6640/PM6630, PMIC3-MT RELEASE 3.0,XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2316	C				WITHDRAWN	
RX	2317	C	SD90-V9070-6,	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2318	C	MS90-VB720-H (XXX), ROC, 543CSP, 15X15MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2319	C	MS90-VB720-C (XXX),	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2320	C				WITHDRAWN	
RX	2321	C				WITHDRAWN	
RX	2322	C				WITHDRAWN	
RX	2323	C				WITHDRAWN	
RX	2324	C				WITHDRAWN	
RX	2325	C				WITHDRAWN	
RX	2326	C	CP90-V6930-12,	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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RX	2327	C				WITHDRAWN	
RX	2328	C				WITHDRAWN	
RX	2329	C				WITHDRAWN	
RX	2330	C				WITHDRAWN	
RX	2331	C	SD90-V9070-1 (Drawing), XXX RELEASE 1.0	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2332	C	SD90-V9070-1C (AMKOR Spec)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2333	C	SD90-V9070-1A (SCP Spec)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2334	C	MB90-V6930-C, MSM7500	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2335	C				WITHDRAWN	
RX	2336	C	MS90-V6930-C (XXX), MSM7500 (XXX), 543CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2337	C				WITHDRAWN	
RX	2338	C	MS90-V6930-2 (XXX), ASSEMBLY MATERIAL SET, MSM7500 (XXX), 543CSP, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2339	C	HB90-V6925-1	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2340	C	BL90-VA175-1A, STAND-ALONE 15X15MM 543CSP SUPPLIERRev. A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2341	C	SD90-VC675-3, Rev. C, SUBSTRATE DRAWING, XXX R1.0, 9X9MM, 216CSP	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2342	C	SD90-VC675-3A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2343	C	MB90-V7815-2, MSM6100, 341CSP	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2344	C	MS90-VB245-C, XXX65, 409CSP, 14X14MM, XXX	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2345	C				WITHDRAWN	
RX	2346	C				WITHDRAWN	
RX	2347	C	80-V9070-1, Rev. B,	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2348	C				WITHDRAWN	

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RX	2349	C	MS90-VD515-C, ASSEMBLY MATERIAL SET, EVERGLADE DAISY CHAIN, 137CSP, 7X7MM, AMKOR K4	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2350	C	BL90-VD515-1A, EVERGLADE, 137CSP, DAISY CHAIN, 7X7MM, SUPPLIER	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2351		Compliancy Modeling of an Area Array Chip Scale Package	Sitaraman / Fjelstad	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	2352	C				WITHDRAWN	
RX	2353	C	Hitachi Chemical Datasheet	Sitaraman / Schaper	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/16/2008 7/18/2008
RX	2354	C				WITHDRAWN	
RX	2355	C	I.Khandros/ G. Grube "Rigid Carrier" Research and diagrams (10/24/88)	Grube / Schaper	OWNR, VLD/INVLD	ADMITTED	7/17/2008 7/18/2008
RX	2356	C	Elastomeric Interconnections	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2357	C				WITHDRAWN	
RX	2358	C				WITHDRAWN	
RX	2359	C				WITHDRAWN	
RX	2360	C				WITHDRAWN	
RX	2361	C				WITHDRAWN	
RX	2362	C				WITHDRAWN	
RX	2363	C				WITHDRAWN	
RX	2364	C				WITHDRAWN	
RX	2365	C				WITHDRAWN	
RX	2366	C	S. Ehrenberg et al, "Method of Testing Chips and Joining Chips to Substrates." Sketches attached to publication.	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2367	C				WITHDRAWN	
RX	2368	C				WITHDRAWN	
RX	2369	C				WITHDRAWN	
RX	2370					WITHDRAWN	
RX	2371					WITHDRAWN	
RX	2372					WITHDRAWN	
RX	2373					WITHDRAWN	
RX	2374					WITHDRAWN	
RX	2375					WITHDRAWN	
RX	2376					WITHDRAWN	
RX	2377					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2378		US 5,148,265 File History; [PAITC012883 - PAITC013024]	Stipulation	VLD/INVLD; INFRNG/NON-INFRNG; State of Art	ADMITTED	7/22/2008
RX	2379					WITHDRAWN	
RX	2380					WITHDRAWN	
RX	2381					WITHDRAWN	
RX	2382		US 5,685,885 File History; [PAITC013672 - PAITC013944]	Stipulation	VLD/INVLD; INFRNG/NON-INFRNG; State of Art	ADMITTED	7/22/2008
RX	2383					WITHDRAWN	
RX	2384		US 5,950,304 File History: [PAITC014106 - PAITC014304]	Stipulation	VLD/INVLD; INFRNG/NON-INFRNG; State of Art	ADMITTED	7/22/2008
RX	2385		US 6,133,627 File History; [PAITC014305 - PAITC014517]	Stipulation	VLD/INVLD; INFRNG/NON-INFRNG; State of Art	ADMITTED	7/22/2008
RX	2386		US 6,392,306 File History; [PAITC014518 - PAITC014773]	Stipulation	VLD/INVLD; INFRNG/NON-INFRNG; State of Art	ADMITTED	7/22/2008
RX	2387					WITHDRAWN	
RX	2388					WITHDRAWN	
RX	2389					WITHDRAWN	
RX	2390					WITHDRAWN	
RX	2391					WITHDRAWN	
RX	2392					WITHDRAWN	
RX	2393					WITHDRAWN	
RX	2394					WITHDRAWN	
RX	2395					WITHDRAWN	
RX	2396					WITHDRAWN	
RX	2397					WITHDRAWN	
RX	2398					WITHDRAWN	
RX	2399					WITHDRAWN	
RX	2400					WITHDRAWN	
RX	2401					WITHDRAWN	
RX	2402					WITHDRAWN	
RX	2403					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2404					WITHDRAWN	
RX	2405					WITHDRAWN	
RX	2406					WITHDRAWN	
RX	2407					WITHDRAWN	
RX	2408					WITHDRAWN	
RX	2409					WITHDRAWN	
RX	2410					WITHDRAWN	
RX	2411					WITHDRAWN	
RX	2412		JP63-51196 with certified translation (Saito)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2413					WITHDRAWN	
RX	2414					WITHDRAWN	
RX	2415					WITHDRAWN	
RX	2416					WITHDRAWN	
RX	2417					WITHDRAWN	
RX	2418	C	Inventor notebooks of Dr. Igor Y. Khandros	Bottoms / Ivey	OWNR	ADMITTED	7/17/2008 7/18/2008
RX	2419	C				WITHDRAWN	
RX	2420	C	Expert Report of Dr. Leonard Schaper dated 1/11/08 & Corresponding Exhbits	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2421	C	REDACTED Rebutall/Supplemental Report of Dr. Leonard Schaper dated 1/18/08 & Corresponding Exhibits	Schaper / Ivey	VLD/INVLD	ADMITTED	7/18/2008
RX	2422		File Wrapper of Third-Party Inter Parte Reexamination No. 95/000,229 of U.S. Patent No. 6,465,893	Stipulation	INFRNG/NON-INFRNG; VLD/INVLD; State of Art	ADMITTED	7/22/2008
RX	2423		File Wrapper of Third-Party Inter Parte Reexamination No. 95/000,227 of U.S. Patent No. 6,433,419	Stipulation	INFRNG/NON-INFRNG; VLD/INVLD; State of Art	ADMITTED	7/22/2008
RX	2424		File Wrapper of Third-Party Ex Parte Reexamination No. 90/008,483 of U.S. Patent No. 5,852,326	Stipulation	INFRNG/NON-INFRNG; VLD/INVLD; State of Art	ADMITTED	7/22/2008
RX	2425	C				WITHDRAWN	
RX	2426	C				WITHDRAWN	
RX	2427	C				WITHDRAWN	
RX	2428	C				WITHDRAWN	
RX	2429	C				WITHDRAWN	
RX	2430	C				WITHDRAWN	

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RX	2431	C				WITHDRAWN	
RX	2432	C				WITHDRAWN	
RX	2433					WITHDRAWN	
RX	2434	C				WITHDRAWN	
RX	2435	C				WITHDRAWN	
RX	2436					WITHDRAWN	
RX	2437					WITHDRAWN	
RX	2438					WITHDRAWN	
RX	2439	C				WITHDRAWN	
RX	2440	C				WITHDRAWN	
RX	2441	C	Khandros Resignation Letter 4/9/1990	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2442	C	Roamnkiw IBM Employee History Record	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2443	C				WITHDRAWN	
RX	2444	C				WITHDRAWN	
RX	2445	C				WITHDRAWN	
RX	2446	C				WITHDRAWN	
RX	2447	C				WITHDRAWN	
RX	2448	C				WITHDRAWN	
RX	2449	C				WITHDRAWN	
RX	2450	C				WITHDRAWN	
RX	2451	C				WITHDRAWN	
RX	2452	C				WITHDRAWN	
RX	2453	C				WITHDRAWN	
RX	2454	C				WITHDRAWN	
RX	2455	C				WITHDRAWN	
RX	2456	C				WITHDRAWN	
RX	2457	C				WITHDRAWN	
RX	2458	C				WITHDRAWN	
RX	2459	C				WITHDRAWN	
RX	2460	C				WITHDRAWN	
RX	2461	C				WITHDRAWN	
RX	2462	C				WITHDRAWN	
RX	2463	C				WITHDRAWN	
RX	2464	C				WITHDRAWN	
RX	2465	C				WITHDRAWN	
RX	2466	C				WITHDRAWN	

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Desig.	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2467	C	I. Khandros et al., "Elastomeric Interconnections" packet of diagrams and research	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2468	C				WITHDRAWN	
RX	2469	C				WITHDRAWN	
RX	2470					WITHDRAWN	
RX	2471	C				WITHDRAWN	
RX	2472		US Patent No. 4601526(A) (White)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2473					WITHDRAWN	
RX	2474					WITHDRAWN	
RX	2475		US Patent No. 4,700,276 Freyman	Stipulation	INFRNG/NON-INFRNG; VLD/INVLD; State of	ADMITTED	7/22/2008
RX	2476					WITHDRAWN	
RX	2477					WITHDRAWN	
RX	2478					WITHDRAWN	
RX	2479					WITHDRAWN	
RX	2480					WITHDRAWN	
RX	2481					WITHDRAWN	
RX	2482					WITHDRAWN	
RX	2483					WITHDRAWN	
RX	2484					WITHDRAWN	
RX	2485					WITHDRAWN	
RX	2486		US Patent No. 5216278(A,X6) (Lin)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2487		US Patent No. 5241133(A) (Mullen)	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2488					WITHDRAWN	
RX	2489					WITHDRAWN	
RX	2490					WITHDRAWN	
RX	2491					WITHDRAWN	
RX	2492					WITHDRAWN	
RX	2493					WITHDRAWN	
RX	2494					WITHDRAWN	
RX	2495					WITHDRAWN	
RX	2496					WITHDRAWN	
RX	2497					WITHDRAWN	
RX	2498					WITHDRAWN	
RX	2499					WITHDRAWN	

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RX	2500					WITHDRAWN	
RX	2501					WITHDRAWN	
RX	2502		Otsuka et al - High Reliability Mechanism of New Silicone Gel Sealing in Accelerated Environment Test	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2503		Suhir - Die Attachment Design and Its Influence on Thermal Stresses in the Die and the Attachment-1	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2504					WITHDRAWN	
RX	2505		Tummala - Micro-Electronics Packaging Handbook-1	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2506					WITHDRAWN	
RX	2507					WITHDRAWN	
RX	2508					WITHDRAWN	
RX	2509		Shoraka - Finite Element Analysis of Compliant Coating	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2510		Vaccaro - Stress Management via Low Modulus Urethane Adhesives for Electronic Apps	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2511		Lutz - Flexible Silicone Adhesive with High Electrical Conductivity-1	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2512		Heinen - Die Attach Reliability Prediction	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2513					WITHDRAWN	
RX	2514					WITHDRAWN	
RX	2515	C				WITHDRAWN	
RX	2516	C				WITHDRAWN	
RX	2517	C				WITHDRAWN	
RX	2518	C	Method of Testing Chips and Joining Chips to Substrates	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2519	C	Apply Siloxane	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2520	C	Ehrenberg et al, "Method of Testing Chips and Joining Chips to Substrates" (Y0888-0493) contains 91A060504	Grube / Schaper / Ivey	OWNR, VLD/INVLD	ADMITTED	7/17/2008 7/18/2008
RX	2521	C				WITHDRAWN	
RX	2522	C				WITHDRAWN	
RX	2523	C	Letter dated April 24, 1990 from Philip Feig, subject, Notes of Exit Interview with Igor Khandros	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2524	C				WITHDRAWN	
RX	2525	C	Invention Disclosure of Khandros and Grube	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2526	C	Direct Chip Attach (I.Khandros and G. Grube	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2527	C	Study entitled Polymer-Metal Composite Joining for Parallel Fabrication of Polymer/TF Packages	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2528	C	IBM strategy plan - Business Perspective	Romankiw	OWNR	ADMITTED	7/22/2008

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RX	2529	C	Carlos Sambucetti Letter regarding Resigning Employee, Security Request	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2530	C	Handwritten notes regarding Exit Interview	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2531	C	Projects in Order of Priority	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2532	C	Letter dated November 16, 1989 from Edward Sussenguth, subject Technical Agenda Report	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2533	C	Academic Institution Interactions	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2534	C	Letter to Billy Crowder from Annmarie Guilbeault, dated August 10, 1988	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2535	C	Handwritten Note from Romankiw; Letter from Pittler regarding First Plateau Invention Reward; Managers Report of Separation	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2536	C				WITHDRAWN	
RX	2537	C				WITHDRAWN	
RX	2538	C	Y010210 - IBM Technical Notebook - Igor Khandros Notes undated	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2539	C				WITHDRAWN	
RX	2540	C				WITHDRAWN	
RX	2541	C				WITHDRAWN	
RX	2542	C				WITHDRAWN	
RX	2543	C				WITHDRAWN	
RX	2544	C				WITHDRAWN	
RX	2545	C				WITHDRAWN	
RX	2546	C				WITHDRAWN	
RX	2547	C				WITHDRAWN	
RX	2548	C				WITHDRAWN	
RX	2549	C				WITHDRAWN	
RX	2550	C				WITHDRAWN	
RX	2551	C				WITHDRAWN	
RX	2552	C				WITHDRAWN	
RX	2553	C				WITHDRAWN	
RX	2554	C				WITHDRAWN	
RX	2555	C				WITHDRAWN	
RX	2556	C				WITHDRAWN	
RX	2557	C				WITHDRAWN	
RX	2558	C				WITHDRAWN	
RX	2559	C				WITHDRAWN	

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RX	2560	C	L. Romankiw's Electrochemical Technology, Progress Report for January March 1990	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2561	C				WITHDRAWN	
RX	2562	C	Engineering Bonding Diagram MSM6280	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2563	C	Engineering Bonding Diagram MSM5500	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2564	C	BL90-V4690-2, Rev. A, Bonding Diagram, MSM6250 (XXX/XXX), 14x 14mm, 409CSP, TSMC	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2565	C	Engineering Bonding Diagram MSM6275	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2566	C	Engineering Bonding Diagram MSM6550	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2567	C	Engineering Bonding Diagram MSM6550A	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2568	C	Engineering Bonding Diagram MSM7500	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2569	C	Engineering Bonding Diagram MSM6300 BL90-V7310-1, MSM6300 LEOPARD3 (COUGAR3/JUPITER) 13X13MM 341CSP IBM	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2570	C	Engineering Bonding Diagram	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2571	C	BL90-V7850-1A, Rev. A, Bonding Diagram, MSM6150 (XXX/XXX)14X14MM, 409CSP, TSMC	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2572	C	BL90-V7890-1, Rev. B, Bonding Diagram MSM6225/6250A (XXX90/XXX) 14X14mm, 409CSP, TSMC	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2573	C	Engineering Bonding Diagram MSM6255A	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2574	C	Engineering Bonding Diagram PM6658	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2575	C	Engineering Bonding Diagram MSM6260/6255/6245	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2576	C	Engineering Bonding Diagram PM7540	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2577	C	Engineering Bonding Diagram BTS4020	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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RX	2578	C	Engineering Bonding Diagram WFB4030	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2579	C	Engineering Bonding Diagram WFB4130	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2580	C				WITHDRAWN	
RX	2581	C				WITHDRAWN	
RX	2582	C				WITHDRAWN	
RX	2583	C				WITHDRAWN	
RX	2584	C				WITHDRAWN	
RX	2585	C				WITHDRAWN	
RX	2586	C				WITHDRAWN	
RX	2587	C				WITHDRAWN	
RX	2588	C				WITHDRAWN	
RX	2589		PCT US91/06920	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2590	C	Tessera, Inc.'s Complaint, Pre-Hearing Statement, from In the Matter of Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same, ITC Investigation No. 337-TA-432	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2591					WITHDRAWN	
RX	2592	C				WITHDRAWN	
RX	2593					WITHDRAWN	
RX	2594	C				WITHDRAWN	
RX	2595	C				WITHDRAWN	
RX	2596	C				WITHDRAWN	
RX	2597	C				WITHDRAWN	
RX	2598					WITHDRAWN	
RX	2599					WITHDRAWN	
RX	2600					WITHDRAWN	
RX	2601	C				WITHDRAWN	
RX	2602					WITHDRAWN	
RX	2603					WITHDRAWN	
RX	2604	C				WITHDRAWN	
RX	2605	C				WITHDRAWN	
RX	2606	C				WITHDRAWN	
RX	2607	C				WITHDRAWN	
RX	2608	C				WITHDRAWN	
RX	2609	C				WITHDRAWN	

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RX	2610	C				WITHDRAWN	
RX	2611	C				WITHDRAWN	
RX	2612	C				WITHDRAWN	
RX	2613	C				WITHDRAWN	
RX	2614	C				WITHDRAWN	
RX	2615		ÂµBGA Figure	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2616	C				WITHDRAWN	
RX	2617	C				WITHDRAWN	
RX	2618	C				WITHDRAWN	
RX	2619	C				WITHDRAWN	
RX	2620	C				WITHDRAWN	
RX	2621	C				WITHDRAWN	
RX	2622	C				WITHDRAWN	
RX	2623	C				WITHDRAWN	
RX	2624	C				WITHDRAWN	
RX	2625		Appl. No. 09/488,268 Amendment dated August 20, 2001	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2626	C				WITHDRAWN	
RX	2627	C				WITHDRAWN	
RX	2628	C				WITHDRAWN	
RX	2629	C				WITHDRAWN	
RX	2630	C				WITHDRAWN	
RX	2631	C				WITHDRAWN	
RX	2632	C	Bonding Diagram BTS4020	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2633	C	Bonding Diagram MBP1600/MBP1610	Gregorich / Madenci / Qu	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/18/2008
RX	2634	C	Bonding Diagram MSM6280	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2635	C	Bonding Diagram MSM6800A 409CSP	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2636	C	Bonding Diagram MSM6800A 432NSP [BL90-V6698-2A, Rev. A; XXX]	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2637	C	Bonding Diagram PM6640/PM6630	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2638	C	Bonding Diagram QSC6010	Madenci/Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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RX	2639	C	BTS4020 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2640	C	BTS4050 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2641	C				WITHDRAWN	
RX	2642	C				WITHDRAWN	
RX	2643	C				WITHDRAWN	
RX	2644	C				WITHDRAWN	
RX	2645	C				WITHDRAWN	
RX	2646	C				WITHDRAWN	
RX	2647	C				WITHDRAWN	
RX	2648	C				WITHDRAWN	
RX	2649	C	Curriculum Vitae of Dr. Erdogan Madenci	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2650	C				WITHDRAWN	
RX	2651	C				WITHDRAWN	
RX	2652	C				WITHDRAWN	
RX	2653		Curriculum Vitae of Pradeep Lall	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2654	C				WITHDRAWN	
RX	2655	C				WITHDRAWN	
RX	2656	C				WITHDRAWN	
RX	2657	C				WITHDRAWN	
RX	2658	C				WITHDRAWN	
RX	2659	C				WITHDRAWN	
RX	2660	C				WITHDRAWN	
RX	2661	C				WITHDRAWN	
RX	2662	C	Declaration of Werner Engelmaier in Support of Tessera's Summary Judgment Papers of August 10, 2001	Qu / Lall	INFRNG/NON-INFRNG, VLD/INVLD	ADMITTED	7/15/2008 7/17/2008
RX	2663	C				WITHDRAWN	
RX	2664	C				WITHDRAWN	
RX	2665	C				WITHDRAWN	
RX	2666	C				WITHDRAWN	
RX	2667	C				WITHDRAWN	
RX	2668	C				WITHDRAWN	
RX	2669	C				WITHDRAWN	
RX	2670	C				WITHDRAWN	

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RX	2671	C				WITHDRAWN	
RX	2672	C				WITHDRAWN	
RX	2673	C				WITHDRAWN	
RX	2674		Excerpt from Certified File History of '558 Patent (including inventor's declaration); [QTSIH00000037 - QTSIH00000049]	Stipulation	OWNR	ADMITTED	7/22/2008
RX	2675	C				WITHDRAWN	
RX	2676	C				WITHDRAWN	
RX	2677	C				WITHDRAWN	
RX	2678	C				WITHDRAWN	
RX	2679	C				WITHDRAWN	
RX	2680		Excerpts from United States Patent No. 5,852,326 (Khandros Dep. Exh. IK 124)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	2681	C				WITHDRAWN	
RX	2682	C				WITHDRAWN	
RX	2683	C				WITHDRAWN	
RX	2684	C				WITHDRAWN	
RX	2685	C				WITHDRAWN	
RX	2686	C				WITHDRAWN	
RX	2687	C	Expert Report of Pradeep Lall, Ph.D.	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2688	C				WITHDRAWN	
RX	2689	C	FBGA Highlights	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2690	C	FBGA Highlights, 1/19/00 (Mitchell Dep. Exh. 19)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	2691	C	Figure 26 from '326 and '419 patent (pp. 26 of Lall Expert Report)	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	2692	C				WITHDRAWN	
RX	2693	C				WITHDRAWN	
RX	2694	C				WITHDRAWN	
RX	2695	C				WITHDRAWN	
RX	2696	C				WITHDRAWN	
RX	2697	C	Freescale Bond Diagram [67ASA11431D]	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2698	C	Freescale Bond Diagram [84ASA10683D]	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2699	C				WITHDRAWN	
RX	2700	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2701	C	FuBGA Plan [dated 10/21/1999]	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2702	C				WITHDRAWN	
RX	2703	C				WITHDRAWN	
RX	2704	C				WITHDRAWN	
RX	2705	C				WITHDRAWN	
RX	2706	C				WITHDRAWN	
RX	2707	C				WITHDRAWN	
RX	2708	C				WITHDRAWN	
RX	2709	C				WITHDRAWN	
RX	2710	C				WITHDRAWN	
RX	2711	C				WITHDRAWN	
RX	2712	C				WITHDRAWN	
RX	2713	C				WITHDRAWN	
RX	2714	C				WITHDRAWN	
RX	2715	C				WITHDRAWN	
RX	2716	C				WITHDRAWN	
RX	2717	C				WITHDRAWN	
RX	2718	C				WITHDRAWN	
RX	2719		Patent No. 6,433,419 Inter Partes Reexamination Communication Mailed 6/5/2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	2720	C				WITHDRAWN	
RX	2721	C	IPAC (FBGA)	Kim	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2722	C				WITHDRAWN	
RX	2723	C				WITHDRAWN	
RX	2724	C				WITHDRAWN	
RX	2725	C				WITHDRAWN	
RX	2726	C				WITHDRAWN	
RX	2727	C				WITHDRAWN	
RX	2728	C				WITHDRAWN	
RX	2729	C				WITHDRAWN	
RX	2730	C				WITHDRAWN	
RX	2731		Lall, Pradeep, and Kingshuk Banergi, "Assembly-level reliability of flex-substrate BGA, elastomer-on-flex packages and 0.5 mm pitch partial array packages," Microelectronics Reliability, 2000,	Lall	VLD/INVLD	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2732	C				WITHDRAWN	
RX	2733	C				WITHDRAWN	
RX	2734	C				WITHDRAWN	
RX	2735	C				WITHDRAWN	
RX	2736	C				WITHDRAWN	
RX	2737	C				WITHDRAWN	
RX	2738	C				WITHDRAWN	
RX	2739	C				WITHDRAWN	
RX	2740	C	MBP1600 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2741	C	MBP1610 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2742	C				WITHDRAWN	
RX	2743	C				WITHDRAWN	
RX	2744	C				WITHDRAWN	
RX	2745	C				WITHDRAWN	
RX	2746	C	MSM6100 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2747	C	MSM6125 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2748	C	MSM6150 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2749	C	MSM6225 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2750	C	MSM6245 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2751	C	MSM6250 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2752	C	MSM6250A Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2753	C	MSM6255A Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2754	C	MSM6260-1 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2755	C	MSM6260-2 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2756	C	MSM6260-3 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2757	C	MSM6275 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2758	C	MSM6280-1 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2759	C	MSM6280-2 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2760	C	MSM6300 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2761	C	MSM6500 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2762	C	MSM6550 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2763	C	MSM6550-1 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2764	C	MSM6800-1 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2765	C	MSM6800-2 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2766	C	MSM7200-1 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2767	C	MSM7200-2 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2768	C	MSM7500 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2769	C	MSM7600 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2770	C				WITHDRAWN	
RX	2771	C				WITHDRAWN	
RX	2772	C				WITHDRAWN	
RX	2773	C				WITHDRAWN	
RX	2774	C				WITHDRAWN	
RX	2775	C				WITHDRAWN	
RX	2776	C				WITHDRAWN	
RX	2777		OMPAC-PBGA Figure	Lall	VLD/INVLD	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2778	C				WITHDRAWN	
RX	2779	C				WITHDRAWN	
RX	2780	C				WITHDRAWN	
RX	2781	C				WITHDRAWN	
RX	2782	C	OverMolded Pad Array Carrier Development Activities - Citizen Watch Co. (Freyman Dep. Exh. 226)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	2783	C				WITHDRAWN	
RX	2784	C				WITHDRAWN	
RX	2785	C				WITHDRAWN	
RX	2786		Patent No. 6,433,419 Inter Partes Reexamination Communication Mailed 5/4/2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	2787		Patent No. 6,433,419 Inter Partes Reexamination Communication Dated Mailed: 6/5/2007	Stipulation, Schaper	VLD/INVLD	ADMITTED	7/22/2008 7/18/2008
RX	2788		Patent No. 6,433,419 Request for Inter Partes Reexamination Transmittal Form Inter Partes Reexamination Communication Mailed 2/9/2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	2789	C				WITHDRAWN	
RX	2790	C				WITHDRAWN	
RX	2791	C	PM6630 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2792	C	PM6640 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2793	C	PM6652 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2794	C	PM6658 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2795	C	PM7540 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2796	C				WITHDRAWN	
RX	2797	C				WITHDRAWN	
RX	2798	C				WITHDRAWN	
RX	2799		Proceedings of the Chip Scale Packaging Symposium	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	2800	C				WITHDRAWN	
RX	2801	C	Process Flow Chart Specification for Package on Package (POP) CSP, XXX Korea, MH80-VB600-C4 Rev. A	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2802	C	Product Criteria Chart	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2803	C				WITHDRAWN	
RX	2804	C				WITHDRAWN	
RX	2805	C				WITHDRAWN	
RX	2806	C				WITHDRAWN	
RX	2807	C				WITHDRAWN	
RX	2808	C				WITHDRAWN	
RX	2809	C				WITHDRAWN	
RX	2810	C				WITHDRAWN	
RX	2811	C				WITHDRAWN	
RX	2812	C				WITHDRAWN	
RX	2813	C				WITHDRAWN	
RX	2814	C				WITHDRAWN	
RX	2815	C	QSC6010 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2816	C	QSC6020 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2817	C	QSC6030 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2818	C				WITHDRAWN	
RX	2819	C	Rebuttal Expert Report of Dr. Erdogan Madenci Regarding United States Patent Nos. 5,852,326 and 6,433,419	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2820	C				WITHDRAWN	
RX	2821	C				WITHDRAWN	
RX	2822	C				WITHDRAWN	
RX	2823	C				WITHDRAWN	
RX	2824	C				WITHDRAWN	
RX	2825	C				WITHDRAWN	
RX	2826	C				WITHDRAWN	
RX	2827	C				WITHDRAWN	
RX	2828	C				WITHDRAWN	
RX	2829	C				WITHDRAWN	
RX	2830	C				WITHDRAWN	
RX	2831	C				WITHDRAWN	
RX	2832	C				WITHDRAWN	

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2833	C				WITHDRAWN	
RX	2834	C				WITHDRAWN	
RX	2835	C				WITHDRAWN	
RX	2836	C				WITHDRAWN	
RX	2837	C				WITHDRAWN	
RX	2838	C				WITHDRAWN	
RX	2839	C				WITHDRAWN	
RX	2840	C				WITHDRAWN	
RX	2841	C				WITHDRAWN	
RX	2842	C				WITHDRAWN	
RX	2843	C				WITHDRAWN	
RX	2844	C				WITHDRAWN	
RX	2845	C				WITHDRAWN	
RX	2846	C				WITHDRAWN	
RX	2847	C				WITHDRAWN	
RX	2848	C				WITHDRAWN	
RX	2849	C				WITHDRAWN	
RX	2850	C				WITHDRAWN	
RX	2851	C				WITHDRAWN	
RX	2852	C				WITHDRAWN	
RX	2853		Tessera's Opposition to TI's Summary Judgment Motion on Patent Issues and Countermotion in Texas Instruments, Aug. 10, 2001	Qu / Lall	VLD/INVLD	ADMITTED	7/15/2008 7/17/2008
RX	2854	C				WITHDRAWN	
RX	2855	C				WITHDRAWN	
RX	2856	C				WITHDRAWN	
RX	2857	C				WITHDRAWN	
RX	2858	C				WITHDRAWN	
RX	2859	C				WITHDRAWN	
RX	2860	C				WITHDRAWN	
RX	2861	C				WITHDRAWN	
RX	2862	C				WITHDRAWN	
RX	2863		United States Patent No. 5,679,977	Ivey / Schaper	INFRNG/NON-INFRNGe., VLD/INVLD	ADMITTED	7/18/2008
RX	2864	C				WITHDRAWN	
RX	2865	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2866	C				WITHDRAWN	
RX	2867	C				WITHDRAWN	
RX	2868	C				WITHDRAWN	
RX	2869	C				WITHDRAWN	
RX	2870	C				WITHDRAWN	
RX	2871	C				WITHDRAWN	
RX	2872	C				WITHDRAWN	
RX	2873	C				WITHDRAWN	
RX	2874		US Patent No. 5,148,266	Lall / Schaper	VLD/INVLD	ADMITTED	7/17/2008 7/18/2008
RX	2875	C				WITHDRAWN	
RX	2876	C				WITHDRAWN	
RX	2877	C				WITHDRAWN	
RX	2878	C				WITHDRAWN	
RX	2879	C	WFB4030 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2880	C	WFB4130 Wire Bond Photographs	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2881	C				WITHDRAWN	
RX	2882	C				WITHDRAWN	
RX	2883	C				WITHDRAWN	
RX	2884	C	BL90-V9690-2A, XXX 15X15 MM 351MSP SUPPLIER	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2885	C	PowerPoint Presentation "BAT-1 CBGA Ball Attach Solder Paste and Ball Type Qualification Results" Mar. 15, 2002 (FSL-ITC 00010995-1012)	Mawer	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	2886	C				WITHDRAWN	
RX	2887	C	Email from Tom Gregorich to J. Clifford, C. Shea, N. Selby-Thomas regarding Tessera Meeting Report	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2888	C	Advanced Stacking Options for MSM Products Containing Up to 3 Memory Dies, December 11, 2003, v.11	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2889	C	Email from Tom Gregorich to Nick Yu regarding Folding Package	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2890	C				WITHDRAWN	
RX	2891	C	IC Package Options for MSM Products Containing up to 4 Dies, November 2, 2003, v.6	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2892	C	Module Packaging Options for Higher Levels of Integration presentation, dated 8/2003	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2893	C				WITHDRAWN	
RX	2894	C				WITHDRAWN	
RX	2895	C	Email from Tom Gregorich regarding Stacked BGA Paper @ ECTC	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2896	C	Email from Ed Reyes to Tom Gregorich regarding Sharp Triple Stack dated 11/10/1999	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2897	C				WITHDRAWN	
RX	2898	C	Package Technology Roadmap presentation, February 2006	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2899	C				WITHDRAWN	
RX	2900					WITHDRAWN	
RX	2901	C				WITHDRAWN	
RX	2902	C				WITHDRAWN	
RX	2903	C				WITHDRAWN	
RX	2904	C				WITHDRAWN	
RX	2905	C	Supplemental & Rebuttal Secondary Considerations Expert Report of Leonard W. Schaper regarding United States Patents Nos. 5,852,326 & 6,433,419	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	2906	C				WITHDRAWN	
RX	2907	C				WITHDRAWN	
RX	2908	C				WITHDRAWN	
RX	2909	C				WITHDRAWN	
RX	2910	C				WITHDRAWN	
RX	2911		Complainant Tessera's First Set of Interrogatories (1-5) to Respondent Qualcomm, Inc.	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	2912	C				WITHDRAWN	
RX	2913	C				WITHDRAWN	
RX	2914	C	Corrected rebuttal expert report of Peter Ivey	Ivey	VLD/INVLD, OWNR	ADMITTED	7/18/2008
RX	2915	C				WITHDRAWN	
RX	2916	C				WITHDRAWN	
RX	2917	C				WITHDRAWN	
RX	2918	C				WITHDRAWN	
RX	2919	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2920		Patent No. 6,433,419 Inter partes reexamination communication Mailed 6/5/2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	2921		Patent No. 5,852,326 Reexamination communication dated 4/20/2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	2922	C				WITHDRAWN	
RX	2923	C				WITHDRAWN	
RX	2924	C				WITHDRAWN	
RX	2925	C	Khandros Notebook	Ivey	OWNR	ADMITTED	7/18/2008
RX	2926	C				WITHDRAWN	
RX	2927	C	Document for Substrate 84ASA10638D (FSL-ITC 00022983-2983)	Sitaraman, Qu	INFRNG/NON-INFRNG	ADMITTED	7/16/2008 7/22/2008
RX	2927	C	Document for Substrate 84ASA10638D (FSLITC00022983-2983)	Qu	INFRNG/NON-INFRNG	ADMITTED	7/15/2008
RX	2928	C				WITHDRAWN	
RX	2929					WITHDRAWN	
RX	2930					WITHDRAWN	
RX	2931					WITHDRAWN	
RX	2932		US Patent 6,133,627	Stipulation	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2933		US Patent 6,465,893	Stipulation	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2934					WITHDRAWN	
RX	2935					WITHDRAWN	
RX	2936					WITHDRAWN	
RX	2937					WITHDRAWN	
RX	2938					WITHDRAWN	
RX	2939					WITHDRAWN	
RX	2940					WITHDRAWN	
RX	2941					WITHDRAWN	
RX	2942	C	Witness Statement I of Mark L. Balog	Balog	RMDY	ADMITTED	7/18/2008
RX	2943	C				WITHDRAWN	
RX	2944	C				WITHDRAWN	
RX	2945	C				WITHDRAWN	
RX	2946	C				WITHDRAWN	
RX	2947	C				WITHDRAWN	
RX	2948	C				WITHDRAWN	
RX	2949	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2950	C	REDACTED (Last paragraph of Q. 502 Stricken) - Fifth Corrected Witness Statement of Dr. Leonard W. Schaper	Schaper	VLD/INVLD	ADMITTED REJECTED	7/18/2008
RX	2951	C				WITHDRAWN	
RX	2952	C				WITHDRAWN	
RX	2953	C				WITHDRAWN	
RX	2954	C				WITHDRAWN	
RX	2955	C				WITHDRAWN	
RX	2956	C				WITHDRAWN	
RX	2957	C				WITHDRAWN	
RX	2958	C				WITHDRAWN	
RX	2959	C				WITHDRAWN	
RX	2960	C				WITHDRAWN	
RX	2961	C				WITHDRAWN	
RX	2962	C				WITHDRAWN	
RX	2963	C				WITHDRAWN	
RX	2964	C				WITHDRAWN	
RX	2965	C				WITHDRAWN	
RX	2966	C				WITHDRAWN	
RX	2967	C				WITHDRAWN	
RX	2968	C				WITHDRAWN	
RX	2969	C	M. Pittler Letter to I. Khandros regarding employment at IBM regarding achievement award	Romankiw	OWNR	ADMITTED	7/22/2008
RX	2970	C				WITHDRAWN	
RX	2971	C	SD90-VD515-1C, REV. B, SUPPLIER SUBSTRATE SPECIFICATION, PM7530/40 RELEASE 1.0, XXX; PM7540	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2972	C	SD90-VC920-1C, REV. A, SUPPLIER SUBSTRATE SPECIFICATION, XXX65_POP R1.0, XXX; MSM6260 (409pcsp)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2973	C	SD90-VC675-3A, REV. B, SUPPLIER SUBSTRATE SPECIFICATION, XXX R1.0, XXX; MBP1600	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2974	C	SD90-VC330-3C, SUPPLIER SUBSTRATE SPECIFICATION, PM6652/55/58 RELEASE 3.0, XXX; PM6658	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2975	C	SD90-VA911-2C, REV. A, SUPPLIER SUBSTRATE SPECIFICATION, XXX R1.0, XXX; MSM6800A (432NSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2976	C	SD90-VA911-2B, REV. A SUPPLIER SUBSTRATE SPECIFICATION, XXX R1.0, ASE; MSM6800A (432NSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2977	C	SD90-VA911-2A, REV. B, SUPPLIER SUBSTRATE SPECIFICATION, XXX R1.0, XXX; MSM6800A (432NSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2978	C	SD90-V2970-15C, SUPPLIER SUBSTRATE SPECIFICATION, XXX90 R1.0, XXX; MSM6550A	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2979	C	SD90-V2970-14C, XXX90 R1.0, XXX; MSM6280 (409 CSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2980	C	MS90-VE007-M, ASSEMBLY MATERIAL SET, BTS4020, 60CSP, 4.5X4.5MM, XXX; BTS4020	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2981	C	MS90-VB715-H, ASSEMBLY MATERIAL SET, ROC, 543CSP, 15X15MM, XXX;	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2982	C	MS90-V6560-C, ASSEMBLY MATERIAL SET, 351MSP DAISY CHAIN, 15MM X 15MM, XXX; QSC60xx	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2983	C	MS90-VA140-C (XXX Korea) Revision C, ASSEMB;Y MATERIAL SET, XXX65, 409CSP, 14X14MM; MSM6255A, MSM6260 (409)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2984	C	MS90-V5850-E, ASSEMBLY MATERIAL SET, XXX/XXX, 409CSP, 14X14MM, ASE KAHOSIUNG; MSM6550	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2985	C	NT90-V9070-2, REV. A, PACKAGE OUTLINE DRAWING, 543CSP, LITE, 15X15X1.06MM, S240, M540;	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2986	C	NT90-VE408-1, REV. A, PACKAGE OUTLINE DRAWING, 289FBGA, 15X15X1.42MM, S240, M900; WFB4130	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2987	C	NT90-VE407-1, REV. A, PACKAGE OUTLINE DRAWING, 400FBGA, 17X17X1.42MM, S340, M700; WFB4030	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2988	C	NT90-VC920-1, 409PCSP, 14X14X1.03MM, S300, M400; MSM6125 -- This is not for 6125	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	2989	C	NT90-VC675-1, REV. B, PACKAGE OUTLINE DRAWING, 216 CSP, 9X9X1.2MM, S210,M700; MBP1600, MBP1610	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2990	C	NT90-VA911-1, REV. E, PACKAGE OUTLINE DRAWING, 432NSP, 11X11X1.0MM, S210, M540; MSM6260 (432nsp)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2991	C	MB90-VB850-H, REV. AB, MARKING DIAGRAM, MBP1600 (XXX), 216CSP (9X9MM), XXX; MBP1600	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2992	C	MB90-V7890-3, Rev. A, Marking Diagram, Material Set, MSM6250A (XXX90), 409CSP, TSMC	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2993	C	MB90-V7840-2, REV. A, Marking Diagram, Material Set, MSM6225 (XXX90), 409CSP, TSMC; MSM6225	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2994	C	MB90-V4690-4, Rev. G, Marking Diagram/Assembly Material Set, MSM6250 (XXX), 409CSP, TSMC	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	2995	C	MB90-V4404-5, REV. C, Marking Diagram/ Assembly Material Set, MSM6300 (LEOPARD2), 341CSP, TSMC; MSM6300	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2996	C	MB90-VA608-J, REV. AC, MARKING DIAGRAM, PM6640 (PMIC3 MT), 64CSP, XXX SINGAPORE; PM6640	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2997	C	MB90-V9690-H, REV. AE, MARKING DIAGRAM, QSC6010 (XXX SC1X), 351CSP, XXX; QSC6010	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2998	C	MB90-VC657-H, REV. AD, MARKING DIAGRAM, MSM6800A (XXX65), 432NSP, (11MM X 11MM), XXX; MSM6800A (432NSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	2999	C	MB90-VA608-C, REV. AC, MARKING DIAGRAM, PM6640 (PMIC3 MT), 64CSP, XXX; PM6640	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3000	C				WITHDRAWN	
RX	3001	C	MB90-VB850-C, REV. AC, MARKING DIAGRAM, MBP1600 (XXX), 216CSP (9X9MM), XXX; MBP1600	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3002	C	MB90-VC275-C, REV. AC, MARKING DIAGRAM, PM6652 (PMIC3), 97CSP (6MM X 6MM), XXX K4 KOREA; PM6652	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3003	C	MB90-VC657-C, REV. AD, MARKING DIAGRAM, MSM6800A (XXX65), 432NSP (11MM X 11MM), XXX; MSM6800A (432NSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3004	C	SD90-VE408-1C, REV. A, SUPPLIER SUBSTRATE SPECIFICATION, XXX R2.0, XXX; WFB4130	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3005	C	MS90-VC657-C, REV. A, ASSEMBLY MATERIAL SET, MSM6800A (XXX65/XXX), 432NSP, 11X11MM, XXX, KOREA; MSM6800A (432NSP)	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3006	C	80-V4339-1, REV. C, 341 CSP PACKAGE SPECIFICATION; MSM6100, MSM6300	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3007	C	MS90-VC275-H, REV. A, ASSEMBLY MATERIAL SET, PM6652, 97CSP, 6X6MM, STATS CHIP-PAC; PM6652	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3008	C	NT90-VC330-1, REV. B, PACKAGE OUTLINE DRAWING, 97CSP, 6X6X1.2MM, S210, M700; PM6652	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3009	C	BL90-VD163-1A, REV. A, BONDING DIAGRAM, XXX65_POP, 14X14MM, 409PCSP, SUPPLIER; MSM6260 (PCSP)	Gregorich / Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3010	C	MS90-V6926-1, XXX DIGITAL + XXX2 ANALOG, 543CSP, XXX; MSM7500	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3011	C				WITHDRAWN	
RX	3012	C				WITHDRAWN	
RX	3013	C				WITHDRAWN	
RX	3014	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3015	C				WITHDRAWN	
RX	3016	C				WITHDRAWN	
RX	3017	C				WITHDRAWN	
RX	3018	C				WITHDRAWN	
RX	3019	C				WITHDRAWN	
RX	3020	C				WITHDRAWN	
RX	3021	C				WITHDRAWN	
RX	3022	C				WITHDRAWN	
RX	3023	C				WITHDRAWN	
RX	3024	C				WITHDRAWN	
RX	3025	C				WITHDRAWN	
RX	3026	C				WITHDRAWN	
RX	3027	C	Product Specification for MCOL*535WS99 in manufacturing phase ASSY (Build Sheet Assembly)	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3028	C	Product Specification for MCOL*535WS99 in manufacturing phase T&F	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3029	C	Flow Chart Assembly for Stacked BGA - Muar	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3030	C	Glue Die Attach In Process Control	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3031	C	Document for wire bond diagram 67ARE10950D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3032	C	Document for wire bond diagram 67ARE11108D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3033	C	Document for wire bond diagram 67ARE11110D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3034	C	Document for wire bond diagram 67ARS10564D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3035	C	Document for wire bond diagram 67ASA11096D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3036	C	Document for wire bond diagram 67ASA11334D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3037	C	Document for wire bond diagram 67ASA12031D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3038	C	Document for wire bond diagram 67ASA12161D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3039	C	Document for wire bond diagram 67ASA12162D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3040	C	Document for substrate 84ARE11178D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3041	C	Document for substrate 84ARE11274D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3042	C	Document for substrate 84ARE11585D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3043	C	Document for substrate 84ARS10508D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3044	C	Document for substrate 84ARS10527D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3045	C	Document for substrate 84ASA10572D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3046	C	Document for substrate 84ASA10581D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3047	C	Document for substrate 84ASA10606D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3048	C	Document for substrate 84ASA99338D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3049	C	Document for wire bond diagram 67ARE10164D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3050	C	Document for wire bond diagram 67ARE10252D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3051	C	Document for wire bond diagram 67ARE10762D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3052	C	Document for wire bond diagram 67ARE10847D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3053	C	Document for wire bond diagram 67ARE10865D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3054	C	Document for wire bond diagram 67ARE10925D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3055	C	Document for wire bond diagram 67ARE10940D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3056	C	Document for wire bond diagram 67ARE10941D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3057	C	Document for wire bond diagram 67ARE10942D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3058	C	Document for wire bond diagram 67ARE10943D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3059	C	Document for wire bond diagram 67ARE10945D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3060	C	Document for wire bond diagram 67ARE10946D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3061	C	Document for wire bond diagram 67ARE10947D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3062	C	Document for wire bond diagram 67ARE10948D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3063	C	Document for wire bond diagram 67ARE10949D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3064	C	Portelligent Database Extract- Qualcomm BGA Package	Gregorich/J.Brown	INFRNG/NON-INFRNG	REJECTED	7/18/2008
RX	3065	C	KWC BGA Underfill Acceptance Criteria, 80-N8952-1	Bora	INFRNG/NON-INFRNG	REJECTED	
RX	3066	C	Ball Grid Array Underfill Process Qualification	Bora	INFRNG/NON-INFRNG	REJECTED	
RX	3067	C	ZYMET- CN-1703 Reworkable Underfill Encapsulant	Bora	INFRNG/NON-INFRNG	REJECTED	
RX	3068	C	Document for wire bond diagram 67ARE11135D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3069	C	Document for substrate 84ARE11592D	Mawer / Qu	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/17/2008
RX	3070	C	Document for wire bond diagram 67ARE10258D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3071	C	Document for substrate 84ARS23981W	Mawer / Qu	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/17/2008
RX	3072	C	Document for wire bond diagram 67ARE10525D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3073	C	Document for substrate 84ARS24000W	Mawer	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3074	C	Document for wire bond diagram 67ARE10177D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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Prefix	No.	Status	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3075	C	Document for substrate 84ARS23991W	Mawer	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3076	C	Freescale's 1st Supplemental Response to Tessera's 1st Set of Interrogatories	Stipulation	INFRNG/NON-INFRNG, Importation, Remedies	ADMITTED	7/22/2008
RX	3077	C				WITHDRAWN	
RX	3078	C				WITHDRAWN	
RX	3079	C				WITHDRAWN	
RX	3080	C				WITHDRAWN	
RX	3081	C				WITHDRAWN	
RX	3082	C				WITHDRAWN	
RX	3083	C				WITHDRAWN	
RX	3084	C				WITHDRAWN	
RX	3085	C				WITHDRAWN	
RX	3086	C	1/18/08 Dr. Leonard Schaper Supplemental & Rebuttal Expert Report Exhibit 4	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3087		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 2	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3088		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 4	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3089	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6A	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3090	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6B	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3091		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6C	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3092		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6D	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3093		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6E	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3094	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6F	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3095		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6G	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3096	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6H	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3097	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6I	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3098	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 6J	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3099		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7A	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3100	C	1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7B	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3101		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7C	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3102		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7D	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3103		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7E	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3104		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7F	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3105		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7G	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3106		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7H	Schaper	VLD/INVLD	ADMITTED	7/18/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3107		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7I	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3108		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7J	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3109		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7K	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3110		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7L	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3111		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7M	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3112		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7N	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3113		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7O	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3114		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7P	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3115		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7Q	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3116		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7R	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3117		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7S	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3118		1/11/08 Dr. Leonard Schaper Expert Report Exhibit 7T	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3119	C				WITHDRAWN	
RX	3120					WITHDRAWN	
RX	3121	C				WITHDRAWN	
RX	3122		Memorandum Opinion & Order 3/22/06 in Tessera v. Micron	Mitchell	RMDY, DI	ADMITTED	7/15/2005
RX	3123					WITHDRAWN	
RX	3124	C	Third Corrected Version of Dr. Pradeep Lall Witness Statement	Lall	VLD/INVLD	ADMITTED	7/17/2008
RX	3125	C	Thomas Matthew Gregorich Witness Statement	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3126	C	IBM and AMD License Agreement	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	3127	C	Witness Statement of LakshminarayanK. Suresh	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3128	C	Witness Statement of Neal McLellan	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	3129	C	Corrected Witness Statement of Bruce Freyman	Freyman / Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/15/2008 7/16/2008
RX	3130	C				WITHDRAWN	
RX	3131	C	Corrected Witness Statement of Archibald Malone	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3132	C	Nainesh Shah Corrected Witness Statement	Shah	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3133	C	Michael Hundt Corrected Witness Statement	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3134	C	Corrected Witness Statement of Laurent Herard	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3135	C	Supplemental Exhibit 2 to the Expert Report of Carla S. Mulhern	Mulhern	RMDY	ADMITTED	7/18/2008
RX	3136	C	Supplemental Exhibit 4 to the Expert Report of Carla S. Mulhern	Mulhern	RMDY	ADMITTED	7/18/2008
RX	3137	C	Supplemental Exhibit 7 to the Expert Report of Carla S. Mulhern	Mulhern	RMDY	ADMITTED	7/18/2008
RX	3138	C	Supplemental Exhibit 13 to the Expert Report of Carla S. Mulhern	Mulhern	RMDY	ADMITTED	7/18/2008
RX	3139	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3140	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3141	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3141	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3142	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3143	C	Invoices from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3144	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3145	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3146	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3147	C	Invoice from STMicroelectronics, Inc. to STMicroelectronics, N.V.;	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3148	C	Invoices from STMicroelectronics, N.V. to customers; Excerpted from Exh. C to Malone Decl.	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3149	C				WITHDRAWN	
RX	3150	C				WITHDRAWN	
RX	3151	C				WITHDRAWN	
RX	3152	C				WITHDRAWN	
RX	3153	C				WITHDRAWN	
RX	3154	C				WITHDRAWN	
RX	3155	C				WITHDRAWN	
RX	3156	C	Letter to Brown from Distefano dated 02/28/1991	Bottoms	OWNR	ADMITTED	7/17/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3157	C				WITHDRAWN	
RX	3158	C				WITHDRAWN	
RX	3159	C				WITHDRAWN	
RX	3160	C				WITHDRAWN	
RX	3161	C				WITHDRAWN	
RX	3162	C				WITHDRAWN	
RX	3163	C				WITHDRAWN	
RX	3164	C				WITHDRAWN	
RX	3165	C				WITHDRAWN	
RX	3166	C				WITHDRAWN	
RX	3167	C				WITHDRAWN	
RX	3168	C				WITHDRAWN	
RX	3173		Declaration of Ephraim Suhir in the Reexamination of U.S. Patent No. 6,433,419 dated 7/27/2007	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3174	C				WITHDRAWN	
RX	3175					WITHDRAWN	
RX	3176	C	Errata to February 8, 2008 Dr. Leonard Schaper Witness Statement	Dr. Leonard Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3177	C				WITHDRAWN	
RX	3178	C				WITHDRAWN	
RX	3179	C	REDACTED (Q. 421, 422, 427-432, 436-441 Stricken) - Third Corrected Witness Statement of Suresh K. Sitaraman Ph.D	Sitaraman	INFRNG/NON-INFRNG	ADMITTED REJECTED	7/16/2008
RX	3180	C				WITHDRAWN	
RX	3181	C	Infrastructure Development, The Key to Accurate Cost Modeling by M. Warner, dated 06_2	Mawer	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3182	C	Nipon Micrometal Corporation 30-Mar-06	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3183	C	Mold compound data sheets for Sumitomo G770GL	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3184	C	PSR-4000 AUS Series Test Data	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3185	C	PowerPoint Presentation "Base Materials for PKG" Oct. 05	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3186	C	PowerPoint Presentation "Base Materials for BGA, Csp, & BOC MCL-E-679FGB(S)"	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3187	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness(es)	Purpose	Status	Date
RX	3188					WITHDRAWN	
RX	3189					WITHDRAWN	
RX	3190		Robert Darveaux "Effect of Simulation Methodology on Solder Joint Crack Growth Correlation" 2000	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3191		Ben Nagaraj "Package-To-Board Attach Reliability - Methodology and Case Study on OMPAC Package" 1993	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3192	C				WITHDRAWN	
RX	3193	C	1st Errata to Dr. Sitaraman's Report	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3194	C	2nd Errata to Dr. Sitaraman's Report	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3195	C	3rd Errata to Dr. Sitaraman's Report	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3196	C				WITHDRAWN	
RX	3197	C	Non-Party Nokia's Objections to Subpoena Duces Tecum and Attachment A	Leonard	RMDY	ADMITTED	7/22/2008
RX	3198	C	Appendix A, "Mobile Devices," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's First Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3199	C	Appendix B, "Connected Home Solutions," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's First Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3200	C				WITHDRAWN	
RX	3201	C	Appendix D, "Networks," Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's First Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3202	C				WITHDRAWN	
RX	3203	C				WITHDRAWN	
RX	3204	C				WITHDRAWN	
RX	3205	C	Appendix C, "Mobile Devices," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3206	C	Appendix D, "Connected Home Solutions," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3207	C	Appendix E, "Enterprise (Formerly Symbol Technologies)," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3208	C	Appendix F, "Government & Public Safety," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3209	C	Appendix G, "Mobile Devices," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog, Brda	RMDY	ADMITTED	7/18/2008
RX	3210	C	Appendix H, "Connected Home Solutions," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3211	C				WITHDRAWN	
RX	3212	C	Appendix J, "Networks," from Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3213	C				WITHDRAWN	
RX	3214	C				WITHDRAWN	
RX	3215	C				WITHDRAWN	
RX	3216	C				WITHDRAWN	
RX	3217	C				WITHDRAWN	
RX	3218	C				WITHDRAWN	
RX	3219	C				WITHDRAWN	
RX	3220	C				WITHDRAWN	
RX	3221	C				WITHDRAWN	
RX	3222	C				WITHDRAWN	
RX	3223	C	Appendix N, "Enterprise (Formerly Symbol Technologies)" from Respondent Motorola, Inc.'s Fourth Amended Confidential Responses and Objections to Tessera's Second Set of Interrogatories	Balog	RMDY	ADMITTED	7/18/2008
RX	3224	C				WITHDRAWN	
RX	3225	C				WITHDRAWN	
RX	3226	C				WITHDRAWN	
RX	3227	C				WITHDRAWN	
RX	3228	C				WITHDRAWN	

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RX	3229	C	Appendix L, "Mobile Devices," from Respondent Motorola, Inc.'s Confidential Supplemental Responses and Objections to Complainant Tessera's Interrogatory Nos. 20, 32, 36, 40 & 51	Balog	RMDY	ADMITTED	7/18/2008
RX	3230	C	Appendix M, "Connected Home Solutions" from Respondent Motorola, Inc.'s Confidential Supplemental Responses and Objections to Complainant Tessera's Interrogatory Nos. 20, 32, 36, 40 & 51	Balog	RMDY	ADMITTED	7/18/2008
RX	3231	C				WITHDRAWN	
RX	3232	C				WITHDRAWN	
RX	3233	C	Expert Report of Dr. Gregory Leonard	Leonard	RMDY	ADMITTED	7/18/2008
RX	3234	C	Expert Report of Dr. Gregory Leonard; Table 1A (i) Chip Royalty Fee as a Percentage of Product Price; Complaint-Listed Phones from the Mobile Devices Division YTD September 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3235	C	Expert Report of Dr. Gregory Leonard; Table 1A (ii) Chip Packaging Cost as a Percentage of Product Price; Complaint-Listed Phones from the Mobile Devices Division YTD September 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3236	C	Expert Report of Dr. Gregory Leonard; Table 1A (iii) Chip Cost as a Percentage of Product Price; Complaint-Listed Phones from the Mobile Devices Division YTD September 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3237	C	Expert Report of Dr. Gregory Leonard; Table 1A (iv) Chip Royalty Fee as a Percentage of Chip Cost; Complaint-Listed Phones from the Mobile Devices Division YTD September 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3238	C	Expert Report of Dr. Gregory Leonard; Table 1B (i) Chip Royalty Fee as a Percentage of Product Price; Products from the Networks Division YTD October 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3239	C	Expert Report of Dr. Gregory Leonard; Table IB (ii) Chip Packaging Cost as a Percentage of Product Price; Products from the Networks Division YTD October 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3240	C	Expert Report of Dr. Gregory Leonard; Table 1B (iii) Chip Cost as a Percentage of Product Price; Products from the Networks Division YTD October 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3241	C	Expert Report of Dr. Gregory Leonard; Table 1B (iv) Chip Royalty Fee as a Percentage of Chip Cost; Products from the Networks Division YTD October 2007	Leonard	RMDY	ADMITTED	7/18/2008

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RX	3242	C	Expert Report of Dr. Gregory Leonard; Table 1C (i) Chip Royalty Fee as a Percentage of Product Price; Sample of 15 Products from the Government & Public Safety Division FY 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3243	C	Expert Report of Dr. Gregory Leonard; Table 1C (ii) Chip Packaging Cost as a Percentage of Product Price; Sample of 15 Products from the Government & Public Safety Division FY 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3244	C	Expert Report of Dr. Gregory Leonard; Table 1C (iii) Chip Cost as a Percentage of Product Price; Sample of 15 Products from the Government & Public Safety Division FY 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3245	C	Expert Report of Dr. Gregory Leonard; Table 1C (iv) Chip Royalty Fee as a Percentage of Chip Cost; Sample of 15 Products from the Government & Public Safety Division FY 2007	Leonard	RMDY	ADMITTED	7/18/2008
RX	3246	C	Expert Report of Dr. Gregory Leonard; Table 2A Motorola Potential Annual Loist Profits; Mobile Devices Division	Leonard	RMDY	ADMITTED	7/18/2008
RX	3247	C	Expert Report of Dr. Gregory Leonard; Table 2B Motorola Potential Annual Lost Profits; Networks Division	Leonard	RMDY	ADMITTED	7/18/2008
RX	3248	C	Expert Report of Dr. Gregory Leonard; Table 2C Motorola Potential Annual Lost Profits; Government & Public Safety Division	Leonard	RMDY	ADMITTED	7/18/2008
RX	3249	C	Expert Report of Dr. Gregory Leonard; Table 2D Motorola Potential Annual Lost Profits; Connected Home Division	Leonard	RMDY	ADMITTED	7/18/2008
RX	3250	C	Expert Report of Dr. Gregory Leonard; Table 2E Summary of Motorola Revenue, Profits, and Lost Profits; Mobile Devices, Connected Home, Networks, and Government & Public Safety Divisions	Leonard	RMDY	ADMITTED	7/18/2008
RX	3251	C	Expert Report of Dr. Gregory Leonard; Table 3 Estimated Annual Consumer Surplus for Motorola's Excluded Products; Mobile Devices Division	Leonard	RMDY	ADMITTED	7/18/2008
RX	3252	C				WITHDRAWN	
RX	3253	C	Documents and Information Considered; Exhibit B from the Expert Report of Dr. Gregory Leonard	Leonard	RMDY	ADMITTED	7/18/2008
RX	3254	C				WITHDRAWN	
RX	3255	C				WITHDRAWN	
RX	3256	C				WITHDRAWN	
RX	3257	C				WITHDRAWN	
RX	3258	C	Networks Profits & Losses	Brda	RMDY	ADMITTED	7/18/2008
RX	3259	C	Mobile Devices Market Share by Carrier	Brda	RMDY	ADMITTED	7/18/2008
RX	3260	C	Mobile Devices Market Share in North America	Brda	RMDY	ADMITTED	7/18/2008

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RX	3261	C	Government & Public Safety Profits & Losses With Below Line Costs	Brda	RMDY	ADMITTED	7/18/2008
RX	3262	C	Mobile Devices Profits & Losses Q3 '07	Brda	RMDY	ADMITTED	7/18/2008
RX	3263	C	Mobile Devices All Products with Financial Data	Brda	RMDY	ADMITTED	7/18/2008
RX	3264	C	Government & Public Safety Schaumburg Data	Balog	RMDY	ADMITTED	7/18/2008
RX	3265	C				WITHDRAWN	
RX	3266	C				WITHDRAWN	
RX	3267	C	1 page from pad information, "71G13933J03"	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3268	C	IPC 4101	Bradley	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3269	C				WITHDRAWN	
RX	3270	C	Schematic, "PCB, Hawaii XCVR Board"	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3271	C				WITHDRAWN	
RX	3272	C	Home & Networks Mobility Q3 '07 Comparative Profits & Losses	Brda	RMDY	ADMITTED	7/18/2008
RX	3273	C				WITHDRAWN	
RX	3274	C	www.freescale.com	Leonard	RMDY	ADMITTED	7/18/2008
RX	3275	C				WITHDRAWN	
RX	3276	C				WITHDRAWN	
RX	3277	C				WITHDRAWN	
RX	3278	C	Second Corrected Witness Statement II of Mark L. Balog	Balog	RMDY	ADMITTED	7/18/2008
RX	3279	C	Corrected Witness Statement of Bruce Brda	Brda	RMDY	ADMITTED	7/18/2008
RX	3280	C	Witness Statement of Dr. Gregory Leonard	Leonard	RMDY	ADMITTED	7/18/2008
RX	3280	R C	Revised Witness Statement of Dr. Gregory Leonard	Leonard	RMDY	ADMITTED	7/18/2008
RX	3281	C				WITHDRAWN	
RX	3282	C				WITHDRAWN	
RX	3283	C	Government & Public Safety Product Information	Balog	RMDY	ADMITTED	7/18/2008
RX	3284	C	Government & Public Safety Product Information	Balog	RMDY	ADMITTED	7/18/2008
RX	3285	C				WITHDRAWN	
RX	3286	C				WITHDRAWN	
RX	3287	C				WITHDRAWN	
RX	3288	C				WITHDRAWN	
RX	3289	C				WITHDRAWN	
RX	3290	C				WITHDRAWN	
RX	3291	C				WITHDRAWN	
RX	3292	C				WITHDRAWN	

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RX	3293	C				WITHDRAWN	
RX	3294	C				WITHDRAWN	
RX	3295	C				WITHDRAWN	
RX	3296	C				WITHDRAWN	
RX	3297					WITHDRAWN	
RX	3298	C				WITHDRAWN	
RX	3299					WITHDRAWN	
RX	3300	C	Respondent Qualcomm Incorporated's Fourth Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated, Appendix A	Hausman	RMDY	ADMITTED	7/16/2008
RX	3301					WITHDRAWN	
RX	3302					WITHDRAWN	
RX	3303	C	Expert Report of Jerry A. Hausman	Hausman	RMDY	ADMITTED	7/16/2008
RX	3304	C				WITHDRAWN	
RX	3305	C				WITHDRAWN	
RX	3306	C				WITHDRAWN	
RX	3307	C				WITHDRAWN	
RX	3308		Tessera, "Tessera Licensees," <www.tessera.com.company/licensees>, accessed January 22, 2008 [Better copy collected Jan. 29, 2008]	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3309	C				WITHDRAWN	
RX	3310		Curriculum Vitae of Jerry Hausman	Hausman	RMDY	ADMITTED	7/16/2008
RX	3311		Daniel L. McFadden and Glenn A. Woroch, "The Costs of the ITC Downstream Exclusion Order to the U.S. Economy," July 10, 2007	Hausman	RMDY	ADMITTED	7/16/2008
RX	3312					WITHDRAWN	
RX	3313					WITHDRAWN	
RX	3314					WITHDRAWN	
RX	3315					WITHDRAWN	
RX	3316		List of Documents Relied Upon by Jerry A. Hausman	Hausman	RMDY	ADMITTED	7/16/2008
RX	3317		Permanent Injunction, Broadcom Corporation v. Qualcomm Incorporated, Case No. SACV 05-467JVS (RNBx), dated Dec. 31, 2007	Hausman	RMDY	ADMITTED	7/16/2008
RX	3318	C				WITHDRAWN	
RX	3319					WITHDRAWN	
RX	3320	C				WITHDRAWN	
RX	3321	C				WITHDRAWN	
RX	3322	C	Projected Product Revenue Chart	Hausman	RMDY	ADMITTED	7/16/2008

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RX	3323	C				WITHDRAWN	
RX	3324	C				WITHDRAWN	
RX	3325	C				WITHDRAWN	
RX	3326					WITHDRAWN	
RX	3327	C				WITHDRAWN	
RX	3328	C				WITHDRAWN	
RX	3329					WITHDRAWN	
RX	3330	C	Respondent Qualcomm Incorporated's Fourth Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated, Appendix A	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3331	C				WITHDRAWN	
RX	3332	C	MSM6500 LG VX8700 Teardown Analysis.	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3333	C	Respondent Qualcomm Incorporated's Fourth Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated, Appendix B	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3334					WITHDRAWN	
RX	3335	C	NT90-V9070-1, Rev. A, Package Outline Drawing, 543 CSP, 15x15x1.4mm, S240, M900	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3336	C	GZ One Type-V Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3337	C	LG KU970 Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3338	C				WITHDRAWN	
RX	3339	C	Samsung SCH-u620 Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3340	C	Samsung SGH-i600 Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3341	C	SGH-U700 Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3342	C	SGH-Z130 Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3343	C	SGH-Z500V Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3344	C	SGH-Z510V Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008

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RX	3345	C	SGH-Z560V Teardown Analysis	Gregorich	INFRNG/NON-INFRNG	REJECTED	7/17/2008
RX	3346	C				WITHDRAWN	
RX	3347	C	Michael Hundt Rebuttal Witness Statement	Hundt	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3348	C	Corrected Rebuttal Witness Statement of Laurent Herard	Herard	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3349	C	Rebuttal Witness Statement of Archibald Malone	Malone	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3350	C	Redacted Second Revised Witness Statement of Carla S. Mulhern	Mulhern	RMDY	ADMITTED	7/18/2008
RX	3351	C	Bonding Wire Photograph of MSM6500	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3352	C	Bonding Wire Photograph of MSM6500	Gregorich	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3353	C	Package Code Nomenclature for Single Chip Packages	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3354	C	Rebuttal Witness Statement of L.K. Suresh	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3355	C	Rebuttal Witness Statement of Robert Russell	Russell	RMDY	ADMITTED	7/17/2008
RX	3356	C	Rebuttal Witness Statement of R. Neil McLellan	McLellan	INFRNG/NON-INFRNG, RMDY	ADMITTED	7/17/2008
RX	3357	C	Witness Statement of Edwin Bradley	Bradley	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3358	C	Witness Statement of Shelia Chopin	Chopin	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3359	C	Witness Statement of Andrew Mawer	Mawer	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3360	C	Witness Statement of Dr. Paul Min	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3361					WITHDRAWN	
RX	3362	C	67ARE10244D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3363	C	67ARE10513D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3364	C	67ARL10557D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008

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RX	3365	C	84ASA10610D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3366	C	84ASA10642D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3367	C	67ARE11027D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3368	C	67ARE11263D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3369	C	67ASA11241D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3370	C	84ARE11469D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3371	C	84ARS24105D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3372	C	84ARH98395A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3373	C	84ASA99274D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3374	C	98ARS23882W	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3375	C	98ARS24106D	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3376	C	98ARH98219	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3377	C	98ARH98220A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3378	C	98ARH98282A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3379	C	84ARH99132A	Qu	INFRNG/NON-INFRNG	ADMITTED	7/22/2008
RX	3380	C	Second Corrected Rebuttal Witness Statement of Dr. Leonard W. Schaper	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RX	3381	C				WITHDRAWN	
RX	3382	C				WITHDRAWN	
RX	3383	C				WITHDRAWN	

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3384	C	REDACTED (Q. 133-150 Stricken) - Corrected Revised Rebuttal Witness Statement of Thomas Matthew Gregorich	Gregorich	INFRNG/NON-INFRNG	ADMITTED REJECTED	7/18/2008
RX	3385		Ablebond 2025 Datasheet 07/05	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3386	C				WITHDRAWN	
RX	3387	C				WITHDRAWN	
RX	3388	C				WITHDRAWN	
RX	3389	C				WITHDRAWN	
RX	3390	C	Witness Statement of M. Bora (Kyocera)	Bora	INFRNG/NON-INFRNG	REJECTED	
RX	3391	C	Dr. Erdogan Madenci Rebuttal Direct Witness Statement	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RX	3392	C	Witness Statement of J. Brown (Portelligent)	J. Brown	INFRNG/NON-INFRNG	REJECTED	
RX	3393	C				WITHDRAWN	
RX	3394	C	Expert Report of Dr. Gregory Leonard; Table 1D (i) Chip Royalty Fee as a Percentage of Product Price; Sample 15 Products from the Connected Home Solutions Divisions	Leonard	RMDY	ADMITTED	7/18/2008
RX	3395	C	Expert Report of Dr. Gregory Leonard; Table 1D (ii) Chip Royalty Fee as a Percentage of Product Price; Sample 15 Products from the Connected Home Solutions Divisions	Leonard	RMDY	ADMITTED	7/18/2008
RX	3396	C	Expert Report of Dr. Gregory Leonard; Table 1D (iii) Chip Royalty Fee as a Percentage of Product Price; Sample 15 Products from the Connected Home Solutions Divisions	Leonard	RMDY	ADMITTED	7/18/2008
RX	3397	C	Expert Report of Dr. Gregory Leonard; Table 1D (iv) Chip Royalty Fee as a Percentage of Product Price; Sample 15 Products from the Connected Home Solutions Divisions	Leonard	RMDY	ADMITTED	7/18/2008
RX	3398	C	Witness Statement of Professor Jerry A. Hausman	Hausman	RMDY	ADMITTED	7/16/2008
RX	3399	C				WITHDRAWN	
RX	3400	C				WITHDRAWN	
RX	3401		Dexter Technical Information CB011 Series	Suresh	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RX	3402		Action Closing Prosecution, February 15, 2008, U.S. Patent 6,465,893, Reexamination Control No. 95/000,229	Stipulation	INFRNG/NON-INFRNG; INFRNG/NON-INFRNG; VLD/INVLD	ADMITTED	7/22/2008

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3403		Reexam Petition Decision Dismissed for U.S. Patent No. 6,433,419	Stipulation	INFRNG/NON-INFRNG; INFRNG/NON-INFRNG; VLD/INVLD	ADMITTED	7/22/2008
RX	3404		Action Closing Prosecution ("ACP I"), February 19, 2008, U.S. Patent 6,433,410, Reexamination Control No. 95/000,227	Stipulation	INFRNG/NON-INFRNG; INFRNG/NON-INFRNG; VLD/INVLD	ADMITTED	7/22/2008
RX	3405	C				WITHDRAWN	
RX	3406	C				WITHDRAWN	
RX	3408	C	Drawing	Bottoms	OWNR	ADMITTED	7/17/2008
RX	3409	C				WITHDRAWN	
RX	3410	C				WITHDRAWN	
RX	3411	C				WITHDRAWN	
RX	3412	C				WITHDRAWN	
RX	3413	C				WITHDRAWN	
RX	3414	C				WITHDRAWN	
RX	3415	C				WITHDRAWN	
RX	3416	C	1996.04.05 email re: potential Sony interest in Tessera package - Ex. 53 to Dep. of Chris Pickett, 337-TA-605, Oct. 12, 2007	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	3417	C	1996.04.15 email re: negotiation of license bet. Sony & Tessera - Ex. 54 to Dep. of Chris Pickett, 337-TA-605, Oct. 12, 2007	Pickett	RMDY, OWNR	ADMITTED	7/15/2005
RX	3418	C				WITHDRAWN	
RX	3419	C				WITHDRAWN	
RX	3420					WITHDRAWN	
RX	3421					WITHDRAWN	
RX	3422					WITHDRAWN	
RX	3423					WITHDRAWN	
RX	3424					WITHDRAWN	
RX	3425					WITHDRAWN	
RX	3426					WITHDRAWN	
RX	3427					WITHDRAWN	
RX	3428					WITHDRAWN	
RX	3429	C				WITHDRAWN	
RX	3430	C				WITHDRAWN	
RX	3431	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3432	C				WITHDRAWN	
RX	3433	C				WITHDRAWN	
RX	3434	C				WITHDRAWN	
RX	3435	C				WITHDRAWN	
RX	3436	C				WITHDRAWN	
RX	3437	C				WITHDRAWN	
RX	3438	C	Excerpt from BOM	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3439		Office Action, February 21, 2008, U.S. Patent 5,852,326, Reexamination Control No. 90/008,483	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3440		Order Granting Request For Ex Parte Reexamination of U.S. Patent No. 5,679,977 (Control No. 90/008,484)	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3441		Order Granting Request For Ex Parte Reexamination of U.S. Patent No. 5,679,977 (Control No. 90/008,528)	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3442		Order Granting Request for ex parte reexamination grant for U.S. Patent No. 6,133,627	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3443	C				WITHDRAWN	
RX	3444	C				WITHDRAWN	
RX	3445		Action Closing Prosecution ("ACP II"), June 13, 2008, U.S. Patent 6,433,419, Reexamination Control No. 95/000,227	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3446					WITHDRAWN	
RX	3447					WITHDRAWN	
RX	3448					WITHDRAWN	
RX	3449		Tessera Press Release: "Tessera Addresses Mischaraterization of Patent Validity and Legal Process", March 6, 2008	McWilliams	RMDY, DI	ADMITTED	7/14/2008
RX	3450		Office Action in Ex Parte Reexamination, U.S. Patent No. 5,679,977 ('977 Patent), March 28, 2008, USPTO	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3451		Third Party Requestors' Comments in Response to Patent Owner's Response to ACP and Opposition to Patent Owner's Petition to Vacate Action Closing Prosecution re Inter Party Reexamination of U.S. Patent No. 6,433,419 ('419 Patent), April 2, 2008, USPTO	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3452		Patent Owner's Comments Pursuant to 37 C.F.R. 1.951 in Response to the Action Closing Prosecution re Reexamination of U.S. Patent No. 6,465,893 ('893 Patent), April 15, 2008, USPTO	Stipulation	VLD/INVLD	ADMITTED	7/22/2008

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3453		Amendment to Response to Office Action mailed February 21, 2008 re Reexamination of U.S. Patent No. 5,852,326, ('326 Patent), April 21, 2008, USPTO	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3454		Interview Summary re Reexamination of U.S. Patent No. 5,852,326, ('326 Patent), May 19, 2008, USPTO	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3455		Response to Official Action re Reexamination of U.S. Patent No. 5,679,977 ('977 Patent), May 28, 2008, USPTO	Schaper	VLD/INVLD	ADMITTED	7/22/2008 7/18/2008
RX	3456		Sinnadurai, The Handbook of Microelectronics Packaging and Interconnection Technologies, Electrochemical Publications Ltd., 1985, pp. 224-225 ("Sinnadurai")	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3457		Lea, A Scientific Guide to Surface Mount Technology," Electrochemical Publications Ltd., 1988, Chapter 3 ("Lea")	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3458		Tessera's PICs in AMD (exhibit OTH-A to '419 reexam request) [SPAN-ITC 118002-SPAN-ITC 118138]	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3459		March 19, 2008, Tessera comments to the ACP, U.S. Patent 6,433,419, Reexamination Control No. 95/000,227	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3460		April 2, 2008, Third Party Requester's Comments, U.S. Patent 6,433,419, Reexamination Control No. 95/000,227	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3461		May 19, 2008 Tessera interview summary, U.S. Patent 5,852,326, Reexamination Control No. 90/008,483	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3462		April 21, 2008 Tessera Response to Office Action, U.S. Patent 5,852,326, Reexamination Control No. 90/008,483	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3463		April 21, 2008 Tessera Amendment, U.S. Patent 5,852,326, Reexamination Control No. 90/008,483	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3464		Office Action in the "977	Ivey	VLD/INVLD	ADMITTED	7/18/2008
RX	3465		February 29, 2008 Office Action, U.S. Patent 6,133,627, Reexamination Control No. 90/008,485	Stipulation	VLD/INVLD	ADMITTED	7/22/2008
RX	3466					WITHDRAWN	
RX	3467	C				WITHDRAWN	
RX	3468	C				WITHDRAWN	
RX	3469	C				WITHDRAWN	
RX	3470	C				WITHDRAWN	
RX	3471	C				WITHDRAWN	
RX	3472	C				WITHDRAWN	
RX	3473	C				WITHDRAWN	
RX	3474	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RX	3475	C				WITHDRAWN	
RX	3476	C				WITHDRAWN	
RX	3477	C				WITHDRAWN	
RX	3478	C				WITHDRAWN	
RX	3479	C				WITHDRAWN	
RX	3480	C				WITHDRAWN	
RX	3481	C	On-board terminal to chip displacement from Dr. Qu's different treatements of upper copper trace layer in STM_SC_TFBGA_47	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3482	C	On-board & Off-board terminal to chip movement results From Dr. Qu's models (charts)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3483	C	On-board & Off-board terminal to chip movement results from Dr. Qu's models (table)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RX	3484	C				WITHDRAWN	
RX	3485	C				WITHDRAWN	
RX	3486					WITHDRAWN	
RX	3487					WITHDRAWN	
RX	3488					WITHDRAWN	
RX	3489					WITHDRAWN	
RX	3490					WITHDRAWN	
RX	3491					WITHDRAWN	
RX	3492					WITHDRAWN	
RX	3493					WITHDRAWN	
RX	3494					WITHDRAWN	
RX	3495					WITHDRAWN	
RX	3496					WITHDRAWN	
RX	3497					WITHDRAWN	
RX	3498					WITHDRAWN	
RX	3499					WITHDRAWN	
RX	3500	C	License Agreement dated 3/31/2008 between International Business Machines Corp. and QUALCOMM [QTSIH00012974 - QTSIH00012982]	Stipulation	OWNR; Non-INFRNG/NON-INFRNG; VLD/INVLD	ADMITTED	7/22/2008
RPX	1					WITHDRAWN	
RPX	2					WITHDRAWN	
RPX	3					WITHDRAWN	
RPX	4					WITHDRAWN	
RPX	5					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RPX	6					WITHDRAWN	
RPX	7					WITHDRAWN	
RPX	8					WITHDRAWN	
RPX	9		Sitaraman Rebuttal Report Supporting Information Hard Drive	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RPX	10					WITHDRAWN	
RPX	11					WITHDRAWN	
RPX	12					WITHDRAWN	
RPX	13					WITHDRAWN	
RPX	14					WITHDRAWN	
RPX	15					WITHDRAWN	
RPX	16					WITHDRAWN	
RPX	17					WITHDRAWN	
RPX	18					WITHDRAWN	
RPX	19					WITHDRAWN	
RPX	20					WITHDRAWN	
RPX	21					WITHDRAWN	
RPX	22					WITHDRAWN	
RPX	23					WITHDRAWN	
RPX	24					WITHDRAWN	
RPX	25					WITHDRAWN	
RPX	26					WITHDRAWN	
RPX	27					WITHDRAWN	
RPX	28					WITHDRAWN	
RPX	29					WITHDRAWN	
RPX	30					WITHDRAWN	
RPX	31					WITHDRAWN	
RPX	32					WITHDRAWN	
RPX	33					WITHDRAWN	
RPX	34					WITHDRAWN	
RPX	35					WITHDRAWN	
RPX	36					WITHDRAWN	
RPX	37					WITHDRAWN	
RPX	38					WITHDRAWN	
RPX	39					WITHDRAWN	
RPX	40					WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RPX	41					WITHDRAWN	
RPX	42					WITHDRAWN	
RPX	43					WITHDRAWN	
RPX	44					WITHDRAWN	
RPX	45					WITHDRAWN	
RPX	46					WITHDRAWN	
RPX	47					WITHDRAWN	
RPX	48					WITHDRAWN	
RPX	49					WITHDRAWN	
RPX	50					WITHDRAWN	
RPX	51					WITHDRAWN	
RPX	52					WITHDRAWN	
RPX	53					WITHDRAWN	
RPX	54					WITHDRAWN	
RPX	55					WITHDRAWN	
RPX	56					WITHDRAWN	
RPX	57					WITHDRAWN	
RPX	58					WITHDRAWN	
RPX	59					WITHDRAWN	
RPX	60					WITHDRAWN	
RPX	61					WITHDRAWN	
RPX	62					WITHDRAWN	
RPX	63	C	Board Showing Motorola Packages	MIN	INFRNG/NON-INFRNG	ADMITTED	7/17/2008
RPX	64		68HC11A1 uP AMT IC PKG LAB	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RPX	65		68HC11F1 uP AMT IC PKG LAB	Freyman	INFRNG/NON-INFRNG	ADMITTED	7/15/2005
RPX	66					WITHDRAWN	
RPX	67					WITHDRAWN	
RPX	68					WITHDRAWN	
RPX	69					WITHDRAWN	
RPX	70					WITHDRAWN	
RPX	71					WITHDRAWN	
RPX	72					WITHDRAWN	
RPX	73					WITHDRAWN	

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Prefix	Nos.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RPX	74					WITHDRAWN	
RPX	75					WITHDRAWN	
RPX	76					WITHDRAWN	
RPX	77					WITHDRAWN	
RPX	78					WITHDRAWN	
RPX	79					WITHDRAWN	
RPX	80					WITHDRAWN	
RPX	81					WITHDRAWN	
RPX	82					WITHDRAWN	
RPX	83					WITHDRAWN	
RDX	1					WITHDRAWN	
RDX	2					WITHDRAWN	
RDX	3					WITHDRAWN	
RDX	4					WITHDRAWN	
RDX	5	C				WITHDRAWN	
RDX	6					WITHDRAWN	
RDX	7					WITHDRAWN	
RDX	8	C				WITHDRAWN	
RDX	9	C				WITHDRAWN	
RDX	10	C				WITHDRAWN	
RDX	11	C				WITHDRAWN	
RDX	12	C	Qualcomm Packages Analyzed	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	13		326 Patent Claim 1	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	14		Criteria Perimeter	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	15		Criteria Area	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	16		Criteria Distance	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	17		419 Patent, Represenative Claim 1	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	18	C	Package in Package Structure	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008

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RDX	19	C	MSM7200 Package (encapsulant removed)	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	20	C	QSC6010 Package (encapsulant removed)	Madenci	INFRNG/NON-INFRNG	ADMITTED	7/18/2008
RDX	21					WITHDRAWN	
RDX	22					WITHDRAWN	
RDX	23					WITHDRAWN	
RDX	24					WITHDRAWN	
RDX	25					WITHDRAWN	
RDX	26					WITHDRAWN	
RDX	27					WITHDRAWN	
RDX	28					WITHDRAWN	
RDX	29					WITHDRAWN	
RDX	30					WITHDRAWN	
RDX	31					WITHDRAWN	
RDX	CM- 1	C	List of ST-NV products accused by Tessera and potential downstream products	Mulhern	RMDY	ADMITTED	7/18/2008
RDX	CM- 2		Mobile Handset Net Sales / Unit Volume to the U.S. / North America in 2006	Mulhern	RMDY	ADMITTED	7/18/2008
RDX	CM- 3		Worldwide NOR Flash Market Shares Q3 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RDX	CM- 4		U.S. Imports for Consumption - January - October 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RDX	CM- 5		U.S. Imports for Consumption - January - November 2007	Mulhern	RMDY	ADMITTED	7/18/2008
RDX	GKL- 1	C	Chip Assembly Price as Percentage of Downstream Product Price	Dr. Gregory K. Leonard	RMDY	ADMITTED	7/18/2008
RDX	GKL- 2	C				WITHDRAWN	
RDX	GKL- 3	C				WITHDRAWN	
RDX	GKL- 4	C	Motorola Annual Lost Profits in Event of Downstream RMNDY	Dr. Gregory K. Leonard	RMDY	ADMITTED	7/18/2008
RDX	JAH- 1		Impact of a Downstream Exclusion Order	Hausman	RMDY	ADMITTED	7/16/2008
RDX	JAH- 2	C				WITHDRAWN	
RDX	JAH- 3		Impact of a Downstream Exclusion Order on Carriers	Hausman	RMDY	ADMITTED	7/16/2008
RDX	JAH- 4		Impact of Downstream Exclusion Order on US Public	Hausman	RMDY	ADMITTED	7/16/2008
RDX	LWS-08		Claim Construction Chart: "Semiconductor Assembly"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-20		Saito VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008

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RDX	LWS-01		Claim Construction Chart: Backing element	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-02		Claim Construction Chart: Bonding wires extending downwardly alongside said edges of said chip"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-03		Claim Construction Chart: Central Region Aligned With Said Chip," "Central Region," and "Central Region Of Said Backing Element"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-04		Claim Construction Chart: "Compliant" and "Compliant Layer"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-05		Claim Construction Chart: Lead Portions	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-06		Claim Construction Chart: "Movable and movement"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-07		Claim Construction Chart: "Overlie," "Overlying" and "Overlies"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-09		Claim Construction Chart: "Substrate Adapted to Physically Support the Chip"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-10		Claim Construction Chart: "Terminal"	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-11		Color Coded Figure 26 of Asserted Patents	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-12					WITHDRAWN	
RDX	LWS-13		1989 OMPAC VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-14		Mullen VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-15		Lin VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-16		Freyman VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-17		Okinaga VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-18		Otsuka VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-19		White VLD/INVLD Chart	Schaper	VLD/INVLD	ADMITTED	7/18/2008

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RDX	LWS-21					WITHDRAWN	
RDX	LWS-22					WITHDRAWN	
RDX	LWS-23					WITHDRAWN	
RDX	LWS-24					WITHDRAWN	
RDX	LWS-25					WITHDRAWN	
RDX	LWS-26					WITHDRAWN	
RDX	LWS-27					WITHDRAWN	
RDX	LWS-28	C				WITHDRAWN	
RDX	LWS-29					WITHDRAWN	
RDX	LWS-30	C				WITHDRAWN	
RDX	LWS-31					WITHDRAWN	
RDX	LWS-32	C				WITHDRAWN	
RDX	LWS-33	C				WITHDRAWN	
RDX	LWS-34					WITHDRAWN	
RDX	LWS-35					WITHDRAWN	
RDX	LWS-36	C				WITHDRAWN	
RDX	LWS-37	C				WITHDRAWN	
RDX	LWS-38	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RDX	LWS-39					WITHDRAWN	
RDX	LWS-40	C				WITHDRAWN	
RDX	LWS-41	C				WITHDRAWN	
RDX	LWS-42	C				WITHDRAWN	
RDX	LWS-43					WITHDRAWN	
RDX	LWS-44	C				WITHDRAWN	
RDX	LWS-45					WITHDRAWN	
RDX	LWS-46	C				WITHDRAWN	
RDX	LWS-47					WITHDRAWN	
RDX	LWS-48	C				WITHDRAWN	
RDX	LWS-49					WITHDRAWN	
RDX	LWS-50	C				WITHDRAWN	
RDX	LWS-51					WITHDRAWN	
RDX	LWS-52					WITHDRAWN	
RDX	LWS-53					WITHDRAWN	
RDX	LWS-54	C				WITHDRAWN	
RDX	LWS-55		Figure 1 of the IBM TDB	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-56		Figure 2 of the IBM TDB	Schaper	VLD/INVLD	ADMITTED	7/18/2008

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RDX	LWS-57	C	11/14/1998 Entry within TDB Y010210 Technical Notebook	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-58	C	Drawing, "Apply Siloxane" Step-by-Step handwritten diagrams	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-59	C	Representative depiction of chip meeting the limitation of a sheetlike dielectric interposer	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-60		Interposer shown in Figure 2 of '266 Patent	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-61	C	Chart showing how the IBM TDB and other IBM documents meet each particular element of claim 1 of the '266 Patent	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-62	C	Chart identifying how the IBM TDB and other IBM documents meet each particular element of claim 20 of the '266 Patent	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-63	C	Diagram regarding Test Dice Join and Substrate	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-64	C	Chart identifying how the IBM TDB and other IBM documents meet each particular element of claim 1 of the '977 Patent	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	LWS-65	C	Chart identifying how the IBM TDB and other IBM documents meet each particular element of claim 17 of the '977 Patent	Schaper	VLD/INVLD	ADMITTED	7/18/2008
RDX	MIN-01	C				WITHDRAWN	
RDX	MIN-02	C				WITHDRAWN	
RDX	MIN-03	C				WITHDRAWN	
RDX	MIN-04	C				WITHDRAWN	
RDX	MIN-05	C				WITHDRAWN	
RDX	MIN-06	C				WITHDRAWN	
RDX	MIN-07	C				WITHDRAWN	
RDX	MIN-08	C				WITHDRAWN	
RDX	MIN-09	C				WITHDRAWN	
RDX	MIN-10	C				WITHDRAWN	
RDX	MIN-11	C				WITHDRAWN	
RDX	MIN-12	C				WITHDRAWN	
RDX	MIN-13	C				WITHDRAWN	
RDX	MIN-14	C				WITHDRAWN	
RDX	MIN-15	C				WITHDRAWN	
RDX	MIN-16	C				WITHDRAWN	
RDX	MIN-17	C				WITHDRAWN	
RDX	MIN-18	C				WITHDRAWN	

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Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RDX	MIN-19	C				WITHDRAWN	
RDX	MIN-20	C				WITHDRAWN	
RDX	MIN-21	C				WITHDRAWN	
RDX	MIN-22	C				WITHDRAWN	
RDX	MIN-23	C				WITHDRAWN	
RDX	MIN-24	C				WITHDRAWN	
RDX	MIN-25	C				WITHDRAWN	
RDX	MIN-26	C				WITHDRAWN	
RDX	MIN-27	C				WITHDRAWN	
RDX	MIN-28	C				WITHDRAWN	
RDX	SIT-01	C	Sharp's Single-Layer Accused Product	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-02	C	Sharp's Double-Layer Accused Product	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-03	C	Various Flaws in Dr. Qu's Analysis	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-04	C	Dr. Qu's Baseline in Texas Instruments	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-05	C	Dr. Qu's Baseline in Samsung	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-06	C	Dr. Qu's Baseline in Micron	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-07	C	Dr. Qu's Baseline in Amkor	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-08	C	Dr. Qu's Prescent Baseline	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-09	C	Modeled and Actual Geometries and Materials for the STM-TFBGA-84	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-10	C	Modeled and Actual Geometries and Materials for the ATI-S-H-1	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-11	C	Modeled and Actual Thicknesses and Materials for the qua_mc_nsp_432	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-12	C	Modeled and Actual Thicknesses and Materials for the qua_sc_csp_060	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-13	C	Modeled and Actual Geometries and Materials for the SPA-M-H-1	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RDX	SIT-14	C	Modeled and Actual Geometries and Materials for the SPA-M-H-2	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-15	C	Modeled and Actual Geometries and Materials for the stm_mc_tfbga_105	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-16	C	Modeled and Actual Geometries and Materials for the stm_mc_tfbga_44_1	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-17	C	Modeled and Actual Geometries and Materials for FRE-S-HCB	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-18	C	Dr. Qu's Modeled Ball Layout Versus Actual Ball Layout for ATI W2182WD	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-19	C	Dr. Qu's Misuse of Symmetry for Qualcomm's MSM6800A Package	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-20	C	Dr. Qu's Misuse of Symmetry for Qualcomm's MBP1600A Package	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-21	C	Polar Plots Showing Terminal Displacement Off-Board And On-Board for Freescale 99SC13890P234	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-22	C	Relative Displacement (mm) at -40° C for 1989 OMPAC 68 Pin Package and Dr. Qu's Baseline	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-23	C				WITHDRAWN	
RDX	SIT-24	C	Coffin-Manson Eqution and Ratio of Coffin-Manson Equations	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-25	C	Plastic Work and Enhanced Reliability of 1989 OMPAC Compared to Baseline	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-26	C	Relative Terminal-to-Chip Movement at -40°C for Freescale 99SC13890P23A Package and 1989 OMPAC 68 Package On-Board and Off-Board	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-27	C	Relative Terminal-to-Chip Movement at -40°C for 1989 OMPAC 68 and Freescale 99SC13890P23A Packages On/Off Board (Normalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-28	C	Relative Terminal-to-Chip Movement at -25°C for fre_sc_pbga_280 Package On/Off Board (Nomalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-29	C	Relative Terminal-to-Chip Movement at -25°C for fre_sc_pbga_289 Package On/Off Board (Nomalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-30	C	Relative Terminal-to-Chip Movement at -25°C for qua_sc_csp_060 Package On/Off Board (Normalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

Master Combined List Of Respondents' Exhibits

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RDX	SIT-31	C	Relative Terminal-to-Chip Movement at -25°C for qua_mc_nsp_432 Package On/Off Board (Normalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-32	C	Relative Terminal_to_chip Movement at -25°C for Top chip (B-A) of qua_mc_nsp_432 Package On/Off Board (Normalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-33	C	Relative Terminal-to-Chip Movement at -25°C for ati_sc_tfbga_104_2 Package On/Off Board (Normalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-34	C	Relative Terminal-to-Chip Movement at -25°C for stm_sc_lbga_288 Package On/Off Board	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-35	C	Relative Terminal-to-Chip Movement at -25°C for spa_mc_lrbga_064 Package On/Off Board (Normalized in Right Bar Chart)	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-36	C	Plastic Work Per Cycle for Freescale 99SC13890P23A	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-37	C	Comparison of Total Dissipated Plastic Work for Freescale 99SC13890P23A with Organic Substrate Versus Package with Silicon Substrate	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-38	C	Average Values of Displacements from Laser Moiré Interferometry and From Simulation for Freescale 99SC13890P23A	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-39	C	Comparison of Total Displacements Between Points	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-40	C	Excerpts from '326 patent	Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-41	C	Time-Temperature Profile for Thermal Cycles Between 125° C and -40° C	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-42	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-43	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-44	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-45	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-46	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-47	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

Prefix	No.	Suffix	Exhibit Description	Sponsoring Witness	Purpose	Status	Date
RDX	SIT-48	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-49	C	Freescale 99SC13890P23A Moiré Experiment and Simulation Comparison	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-50	C	Single-Layer and Double-Layer Die Attach Structure	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-51	C	Domaine of Compliancy	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-52	C	Relative Terminal-to-Chip Movement at -25°C for Top Chip (B-A) of spa_mc_lrbga064 Package On/Off Board (Normalized in Right Bar Chart)	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-53	C	Laser Moiré Sample Preparation - Applying Epoxy with Optical Tissue	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-54	C	X-ray Image of the Uncut and Cut Freescale 99SC13890P23A	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-55	C	Freescale 99SC13890P23A Package for Moiré Validation	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-56	C	Freescale 99SC13890P23A Package	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-57	C	Time Temperature Profile Used for The Laser Moiré Study	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-58	C	Excerpt from "The Impact of CSP's on Encapsulant Materials"	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-59	C	1989 OMPAC Finite Element Model	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-60	C	Freescale 99SC13890P23A Finite Element Model	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-61	C	Moiré Sample Preparation for The Freescale 99SC13890P23A Package	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-62	C	Dr. Qu's Analysis for QUALCOMM MSM6800A	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008
RDX	SIT-63	C	Dr. Qu's Analysis for QUALCOMM MBP1600	Suresh Sitaraman	INFRNG/NON-INFRNG	ADMITTED	7/16/2008

CERTAIN SEMICONDUCTOR CHIPS WITH MINIMIZED CHIP PACKAGE SIZE AND PRODUCTS CONTAINING SAME **Inv. No. 337-TA-605**

PUBLIC CERTIFICATE OF SERVICE

I, Marilyn R. Abbott, hereby certify that the attached **Initial Determination** has been served by hand upon the Commission Investigative Attorney, **Jeffrey T. Hsu, Esq. and Kecia J. Reynolds, Esq.**,and the following parties as indicated on February 9, **2009**.

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PUBLIC VERSION

UNITED STATES INTERNATIONAL TRADE COMMISSION

Washington, D.C. 20436

In the Matter of **CERTAIN SEMICONDUCTOR CHIPS WITH MINIMIZED CHIP PACKAGE SIZE AND PRODUCTS CONTAINING SAME**	**Inv. No. 337-TA-605**

COMMISSION OPINION

I. PROCEDURAL BACKGROUND

On May 21, 2007, the Commission instituted an investigation under section 337 of the Tariff Act of 1930, 19 U.S.C. § 1337, based on a complaint filed by Tessera, Inc. of San Jose, California ("Tessera"), alleging a violation of section 337 in the importation into the United States, the sale for importation, and the sale within the United States after importation of certain semiconductor chips with minimized chip package size or products containing same by reason of infringement of one or more of claims 1, 2, 6, 12, 16-19, 21, 24-26, and 29 of U.S. Patent No. 5,852,326 ("the '326 patent") and claims 1-11, 14, 15, 19, and 22-24 of U.S. Patent No. 6,433,419 ("the '419 patent"). 72 *Fed. Reg.* 28522 (May 21, 2007). The complainant named Spansion, Inc. and Spansion, LLC, both of Sunnyvale, California; QUALCOMM, Inc. of San Diego, California; ATI Technologies of Thornhill, Ontario, Canada; Motorola, Inc. of Schaumburg, Illinois; STMicroelectronics N.V. of Geneva, Switzerland; and Freescale Semiconductor, Inc. of Austin, Texas, as respondents.

On February 22, 2008, respondents filed a joint motion to stay these proceedings pending reexamination of the '326 and '419 patents by the United States Patent and Trademark Office

("PTO").[1] Reexamination of the asserted patents before the PTO was requested on February 9, 2007, by Siliconware Precision Industries Co., Ltd. ("Siliconware"), which is not a party to this investigation but is a party in a related litigation with Tessera in the United Stated District Court for the Northern District of California. In particular, Siliconware requested *ex parte* reexamination of claims 1-3, 6, 11, 12, 16-19, 21, 24-26, and 29 of the '326 patent and *inter partes* reexamination of claims 1-19, 22-24, and 27 of the '419 patent. On April 20, 2007, the petition for *ex parte* reexamination of the '326 patent was granted stating that a "substantial new question of patentability" exists with respect to all of the claims for which the requester seeks reexamination. On May 4, 2007, the petition for *inter partes* reexamination of the '419 patent was granted.

The hearing in this investigation was scheduled to begin on February 25, 2008. On February 25, 2008, the presiding administrative law judge ("ALJ") held oral argument on respondents' motion to stay rather than start the hearing. On the same day, Tessera filed an opposition to the motion for stay. On February 26, 2008, respondents filed a motion for leave to file a reply in further support of their motion to stay.

On February 26, 2008, the ALJ issued "Order No. 52: Initial Determination Granting Respondents' Motion for Stay Pending Examination" in which the ALJ granted respondents' motions for stay and for leave to file a reply. On March 4, 2008, Tessera and the Commission investigative attorney ("IA") each filed a petition for review of Order No. 52. On March 11,

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[1] Respondents' motion is a renewal of an earlier motion filed in June 2007. Respondents ultimately abandoned the earlier motion, stating that it was no longer ripe for adjudication. *See* Parties' Joint Report of Meet and Confer Regarding Outstanding Motions, Pursuant to Order No. 28 (filed on Jan. 18, 2008).

2008, respondents filed their opposition to the petitions for review.

II. INTERLOCUTORY APPEALS

Order No. 52 does not fall within the scope of Commission Rule 210.42 enumerating initial determinations. *See* 19 C.F.R. § 210.42. We note, however, that Commission Rule 210.24(b) provides for interlocutory appeals where, *inter alia*, "an immediate appeal from the [ALJ] ruling may materially advance the ultimate completion of the investigation or subsequent review will be an inadequate remedy." 19 C.F.R. § 210.24(b). In the present case, we consider the petitions for review filed by the IA and Tessera as applications for review of a ruling by the ALJ, and the ALJ's styling of Order No. 52 as an "initial determination" and certification as leave of the ALJ for an immediate appeal of Order No. 52 to the Commission. *See id.* Accordingly, we determine to treat Order No. 52 as subject to an immediate appeal and to review it.

III. DISCUSSION

In determining whether to stay an investigation when there are ongoing reexamination proceedings at the PTO, Commission ALJs have weighed the following factors: (1) the state of discovery and the hearing date; (2) whether a stay will simplify the issues and hearing of the case; (3) the undue prejudice or clear tactical disadvantage to any party; (4) the stage of the PTO proceedings; and (5) the efficient use of Commission resources.[2,3] *See, e.g., Personal*

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[2] The presiding ALJ correctly noted that the Commission has considered a sixth factor – the availability of alternative remedies in Federal Court – in some past investigations. ID at 4; *Certain Personal Computer/Consumer Electronic Convergent Devices, Components Thereof, and Products Containing Same,* 337-TA-558, Order No. 6 (unreviewed) (Feb. 7, 2006); and *Certain High-Voltage Circuit Interruptors and Components Thereof,* 337-TA-64, Comm'n. Op., 204 USPQ 50; 54-55 (1979). Despite those past examples, we give no weight to that

Computer/Consumer Electronic Convergent Devices, Components Thereof, and Products Containing Same, Inv. No. 337-TA-558, Order No. 6 at 11-12 (Feb. 7, 2006) ("*Personal Computers*"); *accord, In re Laughlin Prods., Inc.*, 265 F. Supp. 2d 525, 530 (E.D. Pa. 2003); *Xerox Corp. v. 3Com Corp.*, 69 F. Supp. 2d 404, 406 (W.D.N.Y. 1999).

In the present investigation, the ALJ granted the stay as a result of his consideration of the factors listed above.[4] For the reasons discussed below, we determine, however, that the balance of the factors weighs against granting a stay. This is particularly true in the present case because a stay effectively terminates the investigation, in light of the fact that the patents at issue are virtually certain to expire before the PTO's reexamination is completed. Accordingly, we

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consideration in determining whether to grant the stay motion here. The statute provides that the remedies available for violation of section 337 are "in addition to any other provision of law . . . ." 19 U.S.C. § 1337(a)(1). Because section 337 remedies are in addition to, and not instead of, other remedies at law, we believe that remedies potentially available in the courts are irrelevant to our analysis of whether to stay this proceeding. In addition, we consider that it is the right of the aggrieved party to select the forum (with its attendant remedies) in which to pursue relief. *Compare Certain Baseband Processor Chips and Chipsets, Transmitter and Receiver (Radio) Chips, Power Control Chips, and Products Containing Same, Including Cellular Telephone Handsets*, 337-TA-543, Comm'n Op. (Majority) on Remedy, the Public Interest, and Bonding at 47 n.175 (rejecting contention that the Commission should decline to grant certain relief in a section 337 investigation because alternative remedies were available in the courts).

[3] Commissioner Pinkert would not eliminate the sixth factor for purposes of considering whether to stay an investigation and therefore does not join in footnote 2. Nevertheless, Commissioner Pinkert agrees that the sixth factor should be given no weight here given the facts of this case. Complainant's patents are currently under reexamination and will likely expire prior to the completion of those proceedings. Thus, a stay of this investigation will, in essence, serve as its termination. As the statute provides that the remedies available for violation of section 337 are "in addition to any other provision of law ...," 19 U.S.C. § 1337(a)(1), limiting Tessera to district court remedies is inconsistent with the statute.

[4] The ALJ determined that all of the relevant factors weigh in favor of granting a stay. *See* Order No. 52.

determine to reverse Order No. 52 and deny respondents' motion for a stay. In reaching our determination, we consider each factor in turn, as follows.

A. Factor 1: The State of Discovery and the Hearing Date

We note that the present investigation has reached an advanced stage. The ALJ entertained argument on respondents' renewed motion at 10:00 a.m. on February 25, 2008, the morning of the hearing. At that point, the parties had expended significant resources preparing for the hearing, which Tessera relates as follows:

> After Respondents filed their initial, unsuccessful stay motion, and in the eight months leading up to the February 25, 2008 Hearing, the parties conducted fact and witness discovery, exchanging tens of millions of pages of documents (cumulatively, more than a terabyte of information), taking scores of depositions, and preparing over 2400 pages of expert reports (not including exhibits). The parties filed dozens of motions, including multiple motions for summary determination, and the assigned ALJ issued over 50 orders. During the final weeks before the Hearing, the parties lodged thousands of exhibits, and the parties, including the Staff, submitted Prehearing Briefs totaling over 800 pages. Shortly before the Hearing, Judge Essex ordered that direct testimony be submitted in the form of written witness statements. Consequently, the parties submitted witness statements for nearly 40 opening and rebuttal witnesses, and the parties also submitted written objections to this testimony.
>
> In monetary terms, Tessera spent many millions of dollars preparing this case for trial, and the parties cumulatively spent tens of millions of dollars with the expectation that the case would proceed to a trial on the merits on February 25, 2008. The Investigative Staff also invested substantial time and resources preparing for the February 25 Hearing.

Tessera's Petition at 10. Respondents do not disagree. *See* Respondents' Opposition.

A decision to deny a stay pending reexamination in *Certain Microsphere Adhesives, Process For Making Same, and Products Containing Same, Including Self-Stick Repositionable*

Notes, Inv. No. 337-TA-366, Order No. 16 (November 1994) ("*Microsphere Adhesives*") provides support for our evaluation of this factor. In denying the motion for stay in *Microsphere Adhesives*, Judge Saxon stated:

> The hearing in the Section 337 case is scheduled to commence on Monday November 7, less than a week from today. The parties already have spent a large amount of time and money in discovery and preparing the case for hearing. Experts have been retained and are prepared to testify. There is no good reason for the case not to be heard now.

Microsphere Adhesives at 1. This reasoning similarly applies under the facts of the present investigation and supports our conclusion that the first factor weighs against the stay.

Importantly, this conclusion is consistent with Congress's mandate that section 337 investigations be expeditiously adjudicated, 19 U.S.C. § 1337(b), and the Commission policy that, to the extent practicable and consistent with requirements of law, investigations be conducted expeditiously to avoid delay. 19 C.F.R. § 210.2; *accord, Certain Organizer Racks and Products Containing Same*, Inv. No. 337-TA-466, Commission Opinion at 3-4 (Feb. 8, 2002); *Certain High-Brightness Light Emitting Diodes and Products Containing Same*, Inv. No. 337-TA-556, Commission Opinion at 18-19 (Sep. 11, 2007); *Certain EPROM, EEPROM, Flash Memory, and Flash Microcontroller Semiconductor Devices and Products Containing Same*, Inv. No. 337-TA-395, Commission Opinion at 90 (Dec. 11, 2000). This provides additional support for finding that the first factor weighs against granting a stay.

In sum, we determine that the first factor weighs against granting a stay in this investigation.

B. Factor 2: Whether a Stay Will Simplify the Issues and Hearing of the Case

We agree with the ALJ and respondents that the second factor weighs in favor of a stay. The ALJ stated that "regardless of the final outcome of the reexamination process, the record created during reexam will be of considerable worth in construing the claim terms at issue in this investigation." Order No. 52. The ALJ also noted that "[i]n considering the issue of patent validity, th[e] Commission would certainly benefit in being able to consider the Patent and Trademark Office's ultimate determination on the patentability of the claims involved in the reissue proceeding . . ." Order No. 52 at 6 *citing Certain High-Voltage Circuit Interrupters and Components Thereof*, Inv. No. 337-TA-64, Commission Notice and Order of Suspension of Investigation at 7, 204 USPQ 50, 53 (Nov. 16, 1979). *See also* Respondents' Opposition at 29-30.

We disagree, however, with the ALJ's conclusion that "[t]hus, this factor weighs *highly* in favor of granting a stay." Order No. 52 at 6 (emphasis added). The above considerations are, to a great extent, of a general nature and may apply in virtually any dispute over whether the stay pending reexamination is appropriate. The weight of this factor is limited here because the ALJ's analysis of the potential further developments in this investigation is based substantially on the general considerations rather than on the particular facts specific to the present case. *See, e.g.*, Order No. 52 at 6 ("While Tessera has a right to comment on the '419 patent action, and to present matters in the '326 patent action, it appears unlikely that the claims in either will survive intact. If the patents are determined in the end to be valid, it is probable that some or all of the claims would be narrowed in scope. If this were the case, even if the claims survived, this investigation would have to begin again, because if the claims change in a substantive manner, they must be reinterpreted and the infringement allegations based on those claims reinvestigated."). *See also* Tessera's Petition at 35.

Moreover, we take into account Tessera's argument that the issue of whether a stay would simplify the issues and hearing of the case may become moot if the reexamination proceedings are not completed in time for Tessera to obtain any relief from the Commission. Tessera's Petition at 37. As discussed in greater detail *infra*, there is a reasonable likelihood that this may happen, which further reduces the weight of this factor under the facts of this investigation.

Accordingly, we find that, while the second factor weighs to some extent in favor of granting a stay, its weight is substantially limited and is not determinative under the facts of this case.

C. Factor 3: The Undue Prejudice or Clear Tactical Disadvantage to Any Party

We determine that this factor weighs heavily against granting a stay. In light of the fact that both the '326 and '419 patents are due to expire in September 2010, and the known backlog at the PTO, staying this investigation pending the completion of both reexaminations will likely deprive Tessera of any opportunity to obtain relief from the Commission based upon its still valid patents.[5] As the IA notes, "if the reexaminations continue at the current pace, they will likely not reach 'completion . . . by the PTO' prior to the expiration of the patent term for both the '326 and '419 patents." IA's Petition at 10 (citations omitted). *See also* Manbeck Declaration ¶51.

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[5] As the IA points out, "[s]tatistics show that the time frame for completing an *ex parte* reexamination is on average 30 months, even under special dispatch," and "[l]ikewise, the time frame for completing an *inter partes* reexamination is on average 30 months." IA's Petition at 9. Importantly, the facts of the present case appear to be consistent with these averages. *See, e.g.*, *id.* at 10.

Respondents' motion has brought to light the possibility of a situation in which a respondent may attempt effectively to reduce the life of an asserted patent by requesting reexamination of patents at the PTO, and then seeking to stay a section 337 investigation involving those patents. The temptation would be especially great in cases, such as the one at hand, in which the patents at issue are relatively close to their expiration date. As the effect of such actions could be to override the statutory mandate to presume the patents are valid, we caution the presiding ALJ to carefully weigh the possibility of such manipulation in order to avoid undue prejudice to patent holders seeking to enforce their rights. Such consideration may also prevent unjustified limitations on the Commission's ability to complete section 337 investigations as soon as practicable according to its mandate.

Furthermore, the facts of the present case are similar to *Microsphere Adhesives* with respect to this factor. In that investigation, the ALJ recognized that staying an investigation pending reexamination was disfavored if the patent was near its expiration date. Because, *inter alia*, the patents were due to expire before reexamination could be completed, the ALJ denied the motion to stay. *See Microsphere Adhesives*.

Moreover, according to Craig Mitchell, Tessera's Senior Vice President of Advanced Packaging and Interconnect, Tessera has invested over $100 million in the research, development, and commercialization of technology related to the asserted patents since Tessera's inception in 1990. Presently, Tessera continues to make substantial investments in the further research and development of that technology. At its San Jose headquarters alone, more than 50 Tessera employees (*e.g.*, engineers, technicians and assembly line workers) work in research and development activities related to the asserted patents. *See* Declaration of Craig Mitchell in Support of Tessera's Opposition to Respondents' Joint Motion to Stay Commission Proceedings, Exhibit C, ¶¶ 16-18. *See also* Tessera's Petition at 39. Tessera's substantial investments could be lost irrespective of the merits of the patent dispute in question if the stay is granted.

Based on the foregoing, we find that this factor weighs heavily against a stay.

D. Factor 4: The Stage of the PTO Proceedings

We find that this factor weighs against granting a stay. The record demonstrates that the '326 patent is at one of the initial stages of the reexamination process, *see* Manbeck Declaration ¶20, and that the '419 patent reexamination proceedings also are at a relatively early stage of a lengthy process that "almost certainly will not be completed until well after the patent's expiration," Tessera's Petition at 43-44.[6] Moreover, in both reexamination proceedings, the patentee has maintained that the asserted claims are patentable as issued.

The IA notes that an adverse office action in the reexamination process is fairly routine and is not an indication that the patent claims are going to be rejected or amended. Furthermore, as the IA argues, once a request for reexamination is granted, a first office action generally issues repeating the arguments in the third party's request. IA's Petition at 8 *citing* 37 C.F.R. § 1.935; MPEP § 2660. Likewise, a second office action will issue later addressing the remarks of the patentee and third party requester. "This second office action is not a final office action and is only an 'Action Closing Prosecution' if no new issues were raised by the patentee's remarks." IA's Petition at 8 *citing* 37 C.F.R. § 1.949; MPEP § 2671.01.

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[6] Importantly, the ALJ has not found that any of the office actions relied on by respondents to request a stay is final. *See* Order No. 52.

With respect to the present investigation, the IA points out that in the '326 reexamination proceeding, a first office action issued repeating the arguments of the third-party requester, which "was routine," whereas with respect to the '419 patent, a second office action, an Action Closing Prosecution, issued, "which is normal if no new issues are raised since the first office action." IA's Petition at 8-9 (citations omitted). The IA further points out that Tessera did not submit substantive comments or amend the claims, but amended the specification, and the amendments were not entered by the examiner, "so it was not surprising that this second Office Action[] adopt[s] the comments of the third-party requester." IA's Petition at 9 *citing* Appendix A to Order No. 52 at 13. The IA further notes that the second office action is not a final office action, and that when Tessera attempted to submit supplemental remarks addressing the third-party requester's comments, the PTO stated that "the patent owner will have ample opportunity to overcome such rejections as prosecution of the present *inter partes* proceeding continues." IA's Petition at 9 (citations omitted).

The ALJ found that the reexamination proceedings were at an advanced stage and weighed this factor heavily in favor of a stay. We agree with the IA and Tessera, however, that the proceedings are still at initial phases. We find the IA's and Tessera's arguments persuasive. Furthermore, we disagree with respondents' contention that the present investigation is akin to the *Personal Computers* investigation with respect to the factor in question. *See* Respondents' Opposition at 34 ("At such a stage of the reexamination proceeding, precedent supports staying an investigation. *See Personal Computers*, Inv. No. 337-TA-558, Order No. 6, 2006 ITC LEXIS 52 (Judge Barton ordered a stay when only an initial Office Action had issued and a response made to that Office Action).”). While by the time Order No. 6 issued in *Personal Computers* the final office action had not issued, Judge Barton reasonably anticipated that it would issue shortly after the issuance of his Order No. 6. *See Personal Computers*, Inv. No. 337-TA-558, Order No. 6 at 12 (“While I do not know when the PTO will issue a final action, there is every indication that it will be issued in a timely manner.”). In fact, by the time Order No. 6 reached the Commission, the final office action issued. Furthermore, in *Personal Computers*, the patentee had already amended the claims making it nearly impossible for the original claims to reissue. These facts distinguish *Personal Computers* from the present investigation and support the conclusion that factor 4 weighs in favor of denying respondents’ motion for a stay in the present investigation.

In sum, we determine that the subject factor weighs against a stay.

E. Factor 5: The Efficient Use of Commission Resources

We agree with the ALJ and respondents that this factor weighs in favor of a stay, but we find that it does not overcome the other factors. The IA does not address this factor in her petition. As for Tessera, we believe that its petition has failed to adequately challenge the ALJ’s determination regarding this factor. *See* Tessera’s Petition at 44-47.

If the claims are canceled in whole or in part as a result of the reexamination, the stay granted by the ALJ may conserve public and private resources by enabling the Commission to avoid duplicative work and, potentially, obviate the necessity of any hearing at all. Furthermore, if the PTO Board upholds the examiner’s rejection of the claims in light of the prior art, all efforts and resources expended at this stage would be wasted. Moreover, even if the claims were only moderately changed or if there were new prosecution history that changes the meaning of the claims, the Commission might be able to save resources by implementing a stay. *See, e.g.*, *Certain Cryogenic Ultramicrotome Apparatus*, Inv. No. 337-TA-256, Order No. 14, ID Suspending Inv. at 3 (Mar. 12, 1987) ("Should the [PTO] give complainant the relief requested in the reexamination proceeding, or modify the patent, it might result in a second proceeding before the Commission on similar, but modified issues. Such a result would be an undue imposition on the Commission and the parties to this investigation.").

In determining how much weight to assign this factor, we bear in mind that the proceedings before the ALJ have reached a relatively advanced stage, which diminishes the extent of Commission resources needed to complete the investigation. We also note that the ALJ has not made any findings that rely on the specific facts pertinent to the subject investigation that would affect the weighing of this factor, as opposed to general considerations that may apply to any investigation with parallel reexamination proceedings. Accordingly, while we agree with the ALJ that a stay will save the Commission resources and avoid duplicative proceedings, we do not find this factor to be determinative.

F. Conclusion

Having considered each of the above listed factors, we determine that the balance of the equities in this investigation mandates a denial of respondents' motion for a stay. Based on the foregoing, we determine to reverse Order No. 52 and deny respondents' motion to stay.

By Order of the Commission.

Marilyn R. Abbott
Secretary to the Commission

Issued: May 27, 2008

CERTAIN SEMICONDUCTOR CHIPS WITH MINIMIZED CHIP PACKAGE SIZE AND PRODUCTS CONTAINING SAME **337-TA-605**

PUBLIC CERTIFICATE OF SERVICE

I, Marilyn R. Abbott, hereby certify that the attached **PUBLIC OPINION** has been served by hand upon the Commission Investigative Attorney, Kecia J. Reynolds, Esq., and the following parties as indicated, on May 27, 2008.

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